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DEPARTMENT OF THE ARMY
AND HEADQUARTERS, MARINE CORPS

Washington, DC, 15 September 1991

GENERAL SUPPORT MAINTENANCE MANUAL

FOR

OSCILLOSCOPE OS-288/G

(TEKTRONIX MODEL 2465B)

(NSN 6625-01-272-8054)

(EIC: N/A)

REPORTING ERRORS AND RECOMMENDING IMPROVEMENTS

You can help improve this manual. If you find any mistakes, or if you know of a way to improve the procedures, please let us know. Mail your letter, DA Form 2028 (Recommended Changes to Publications and Blank Forms) or DA Form 2028-2 located in back of this manual direct to: Commander, US Army Communications–Electronics Command and Fort Monmouth, ATTN: AMSEL–LC-LM-LT, Fort Monmouth, New Jersey 07703-5007. Marine Corps units, submit NAVMC 10772 (Recommended Changes to Technical Publications) to: Commanding GeneraL, Marine Corps Logistics Base (Code 850) Albany, Georgia 31 704–5000. In either case, a reply will be furnished to you.

This manual is an authentication of the manufacturer's commercial literature which, through usage, has been found to cover the data required to operate and maintain this equipment. Since the manual was not prepared in accordance with military specifications, the format has not been structured to consider levels of maintenance.

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Section 0
INTRODUCTION

SCOPE

This manual contains instructions for the General Support Maintenance of the Oscilloscope OS–288/G. Throughout this manual, the oscilloscope is referred to as the instrument, the TEK 2465B, or the OS–288/G.

CONSOLIDATED INDEX OF ARMY PUBLICATIONS AND BLANK FORMS

Refer to the latest issue of DA Pam 25-30 to determine whether there are new editions, changes, or additional publications pertaining to the equipment.

MAINTENANCE FORMS, RECORDS, AND REPORTS

a. Reports of Maintenance and Unsatisfactory Equipment. Department of the Army forms and procedures used for equipment maintenance will be those prescribed by DA Pam 738–750, as contained in Maintenance Management Update. Marine Corps personnel refer to the latest issue of SL-1–2 to determine whether there are any new additions.

b. Reporting of Item and Packaging Discrepancies. Fill out and forward SF 364 (Report of Discrepancy (ROD)) as prescribed in AR 735-11–2/DLAR 4140.55/SECNAVINST 4355.18/AFR 400-54/MCO 4430.3J.

c. Transportation Discrepancy Report (TDR) (SF 367). Fill out and forward Transportation Discrepancy Report (TDR) (SF 361) as prescribed in AR 55-38/ NAVSUPINST 4610.33C/AFR75-18/MCO P4610.19D/ DLAR 4500.15.

REPORTING EQUIPMENT IMPROVEMENT RECOMMENDATIONS (EIR)

a. *Army.* If your equipment needs improvement, let us know. Send us an EIR. You, the user, are the only one who can tell us what you don't like about your equipment. Let us know why you don't like the design or performance. Put it on an SF 368 (Product Quality Deficiency Report). Mail it to: Commander, US Army Communications–Electronics Command and Fort Monmouth, ATTN: AMSEL–ED–PH, Fort Monmouth, New Jersey 07703-5007. We'll send you a reply.

b. Marine Corps. QDR shall be reported on SF 368 in accordance with MCO P4855.10, Product Quality Deficiency Report Manual. Submit to Commanding General, Marine Corps Logistics Base (Code 850), Albany, Georgia 31 704–5000.

ADMINISTRATIVE STORAGE

Administrative storage of equipment issued to and used by Army activities will have Preventive Maintenance Checks and Services (PMCS) performed before storing. When removing the equipment from administrative storage, the PMCS checks should be performed to assure operational readiness.

DESTRUCTION OF ARMY ELECTRONICS MATERIEL TO PREVENT ENEMY USE

Destruction of Army electronics materiel to prevent enemy use shall be in accordance with TM 750-244-2.

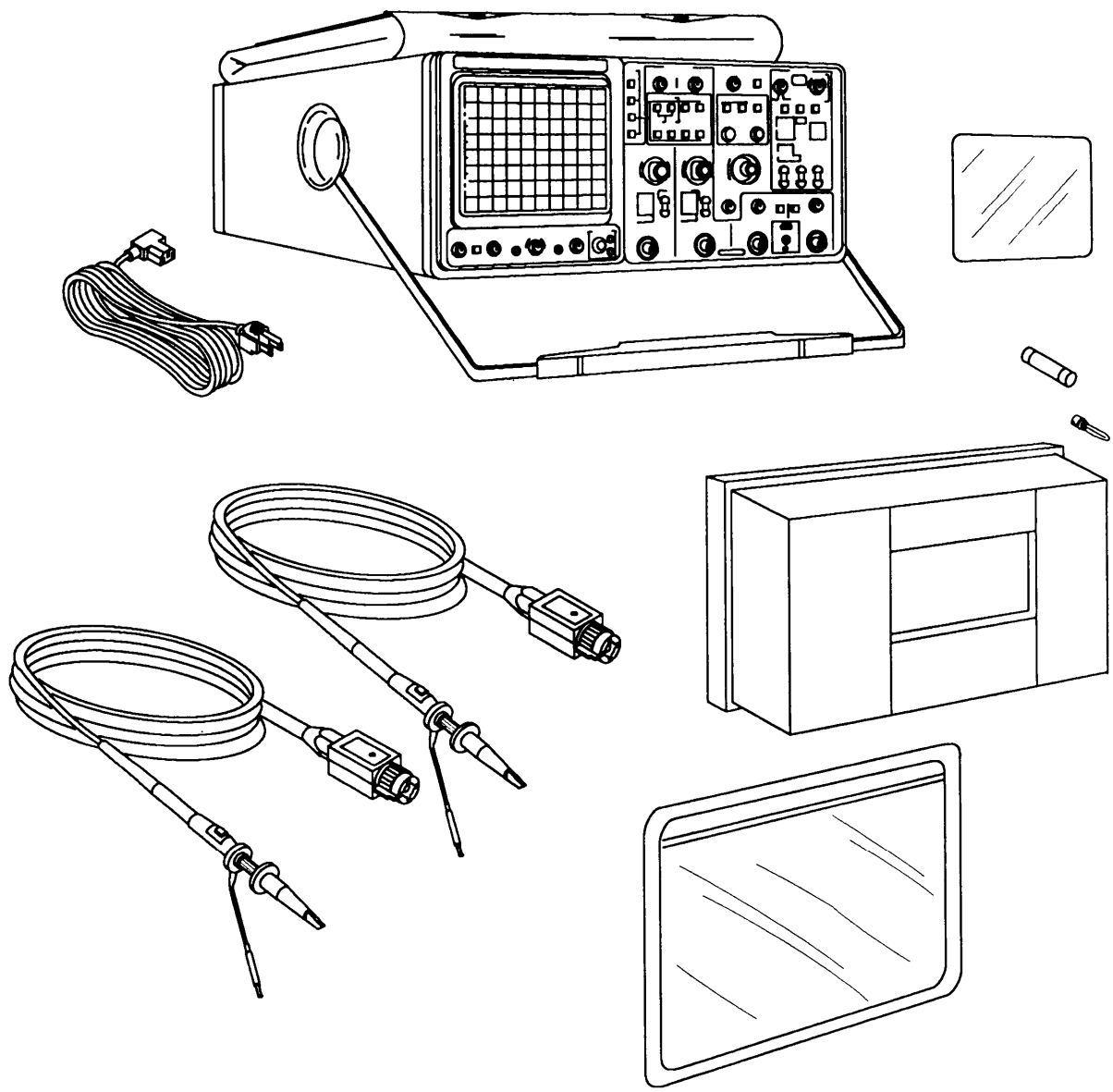


Figure 0-1. Oscilloscope OS-288/G

Section 1
SPECIFICATION

INTRODUCTION

The TEKTRONIX 2465B Oscilloscope is a portable 400-MHz bandwidth instrument with a four-channel vertical deflection system. Channel 1 and Channel 2 provide calibrated deflection factors from 2 mV per division to 5 V per division. For each of these channels, input impedance is selectable between two values: either 1 M Ω in parallel with 15 pF, or 50 Ω internal termination. Input-signal coupling with 1 M Ω impedance can be selected as either AC or DC. Channel 3 and Channel 4 have deflection factors of either 0.1 V or 0.5 V per division. Each of these channels has an input impedance of 1 M Ω in parallel with 15 pF, with DC input-signal coupling.

The trigger system works automatically for most signals. It operates in various modes, from any channel, with couplings for a wide range of signals. The trigger system gives stable displays from DC to 500 MHz.

The horizontal deflection system provides calibrated sweep speeds from 1.5s per division to 500 ps per division, including the effects of the X10 magnifier and the calibrated variable between the 1-2-5 steps. Horizontal displays include A-Sweep, B-Sweep (delayed), A alternated with B, and CH 1 (for X/Y displays).

The AUTO, SAVE, and RECALL features save time and prevent errors. Pressing the AUTO SETUP button gives a workable setup for almost any signal. For repetitive measurements, the SAVE and RECALL functions record and immediately or sequentially restore as many as 30 instrument setups. The SETUP buttons operate all instrument functions.

Direct, on-screen readouts of time measurements, voltage measurements, scale factors, trigger levels, and auxiliary information also save time and improve operator confidence.

PERFORMANCE CONDITIONS

The following electrical characteristics (Table 1-1) are valid for the instrument when it has been adjusted at an ambient temperature between + 20°C and + 30°C, has had a warm-up period of at least 20 minutes, and is operating at an ambient temperature between -15°C and +55°C (unless otherwise noted).

Items listed in the “Performance Requirements” column define the measurement capabilities of the instrument. Operating characteristics and instrument dimensions are also provided in Table 1-1.

Table 1-1
Electrical Characteristics

Characteristics	Performance Requirements
WEIGHT	
With Accessories and Pouch	22.4 lb (10.2 kg)
Weight without Accessories and Pouch	20.5 lb (9.3 kg)
Domestic Shipping Weight	28.2 lb (12.8 kg)
DIMENSIONS	
Height without Pouch	6.29 in (160 mm)
Height with Feet and Pouch	7.96 in (202 mm)
Width with Handle	13.31 in (338 mm)
Depth with Front Cover	17.1 in (434 mm)
Depth with Handle Extended	20.0 in (508 mm)
OPERATING CHARACTERISTICS	
Power Source	90 VAC to 250 VAC, 48 to 440 Hz
Maximum Power Consumption	120 watts (180 VA)
Line Fuse	2 A, 250 V, AGC/3AG fast blow or 1.6 A, 250 V, 5 × 20 mm quick acting
Operating Temperature	5° to 131°F (-15° to 55°C)
Operating Altitude	Up to 15,000 ft. (4,500 m)
VERTICAL DEFLECTION SYSTEM—CHANNEL 1 AND CHANNEL 2	
Deflection Factor	
Range	2 mV/Division to 5 V/Division
Accuracy	
59° to 95°F (15° to 35°C)	
On Graticule	Within ± 2%
ΔV Accuracy	± (1.25% of reading + 0.03 div + signal aberrations)
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add ± 2% of reading
50 ohm Coupling	Add ± 1% of reading
CH 2 Inverted	Add ± 1% of reading
ΔV Measurement Range	± 8 divisions times the VOLTS/DIV setting
VOLTS/DIV VAR Range	Extends deflection factor to > 12.5 V/division, continuously var.
Frequency Response	
-3 dB Bandwidth	
59° to 95°F (15° to 35°C)	≥ 5 mV/DIV: DC to 400 MHz; 2 mV/DIV: DC to 350 MHz
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	≥ 5 mV/DIV: DC to 350 MHz; 2 mV/DIV: DC to 300 MHz
-4.7 dB Bandwidth	
5° to 95°F (-15° to 35°C)	≥ 5 mV/DIV: DC to 400 MHz; 2 mV/DIV: DC to 300 MHz
95° to 131°F (35° to 55°C)	≥ 5 mV/DIV: DC to 350 MHz: 2 mV/DIV: DC to 300 MHz

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
VERTICAL DEFLECTION SYSTEM – CHANNEL 1 AND CHANNEL 2 (cont)	
AC Coupled, Lower -3 dB Frequency	10 Hz or less
With Standard Accessory Probe	1 Hz or less
Step Response Time (Tr = 0.35/BW)	≥ 5 mV/DIV: ≤ 875 ps, 2 mV/DIV: ≤ 1 ns
Channel Isolation	≥ 100:1 at 100 MHz; ≥ 50:1 at 400 MHz
Displayed Channel 2 Signal Delay With Respect to the Channel 1 Signal	-500 ps to +500 ps, adjustable
Input R and C (1 Megohm)	
Resistance	1 Megohm ± 0.5%
Capacitance	15 pF ± 2 pF
Maximum Input Voltage (DC, AC, or GND Coupled)	400 V (DC + peak AC) 800 V p-p AC: ≤ 10 kHz
Input R (50 ohms)	
Resistance	50 ohms ± 1%
VSWR, DC to 300 MHz	≤ 1.45:1
VSWR, 300 to 400 MHz	≤ 1.6:1
Maximum Input Voltage	5 V rms, averaged for 1 s; ± 50 V peak
Cascaded Operation	
Deflection Factor	200 μV/DIV ± 10%
CMRR (ADD Mode with Channel 2 Inverted)	≥ 20:1 at 50 MHz for common-mode signals of eight divisions or less
VERTICAL DEFLECTION SYSTEM - CHANNEL 3 AND CHANNEL 4	
Deflection Factor	
Values	100 mV/division and 500 mV/division
Accuracy	Within ± 10%
Frequency Response	
-3 dB Bandwidth	
59° to 95°F (15° to 35°C)	DC to 400 MHz
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	DC to 350 MHz
-4.7 dB Bandwidth	
59° to 95°F (15° to 35°C)	DC to 400 MHz
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	DC to 350 MHz
Step Response Time (Tr = 0.35/BW)	≤ 875 ps
Channel Isolation	≥ 50:1 at 100 MHz with an 8 division input signal
Signal Delay Between Channel 1 and either Channel 3 or Channel 4	Within ± 1.0 ns

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
VERTICAL DEFLECTION SYSTEM - CHANNEL 3 AND CHANNEL 4 (cont)	
Input Resistance	1 Megohm ± 1%
Input Capacitance	15 pF ± 3 pF
Maximum Input Voltage (DC, AC, or GND Coupled)	400 V (DC + peak AC) 800 V p-p AC: ≤ 10 kHz
VERTICAL DEFLECTION SYSTEM - ALL CHANNELS	
Low-frequency Linearity	0.1 division or less compression or expansion of a two-division, center-screen signal
Bandwidth Limiter	Reduces upper 3 dB bandpass to a limit of 13 MHz to 24 MHz
Vertical Signal Delay	≥ 30 ns of the sweep is displayed before the triggering event if SEC/DIV set ≥ 10 ns/DIV. At 5 ns/DIV, ≥ 10 ns of sweep is displayed before the triggering event
Chopped Mode Switching Rate	With SEC/DIV between 20 µs and 2 µs/DIV, the switching rate is 2.5 MHz ± 0.2%. Otherwise, the rate is 1 MHz ± 0.2%
TRIGGERING	
Minimum peak-to-peak Signal Amplitude for Stable Triggering from CH 1 or CH 2 Source	
DC Coupled	0.35 division from DC to 50 MHz; 1.0 division at 300 MHz; 1.5 divisions at 500 MHz
NOISE REJ Coupled	≤ 1.2 divisions from DC to 50 MHz; 3 divisions at 300 MHz; 4.5 divisions at 500 MHz
AC Coupled	0.35 division from 60 Hz to 50 MHz; 1.0 division at 300 MHz; 1.5 divisions at 500 MHz; attenuates signals below 60 Hz
HF REJ Coupled	0.5 division from DC to 30 kHz
LF REJ Coupled	0.5 division from 80 kHz to 50 MHz; 1.0 division at 300 MHz; 1.5 divisions at 500 MHz
Minimum p-p Signal Amplitude for Stable Triggering from ADD Source	Add 0.5 division to CH 1 or CH 2 requirement at 300 MHz and 500 MHz
Minimum p-p Signal Amplitude for Stable Triggering from CH 3 or CH 4 Source	0.5 times the CH 1 or CH 2 requirement
Minimum p-p Signal Amplitude for Stable Triggering from Composite, Multiple Channel Source, ALT Vertical Mode	Add 1 division to the single-channel source specification
Maximum p-p Signal Rejected by NOISE REJ COUPLING Signals Within the Vertical Bandwidth	
CH 1 or CH 2 SOURCE	≥ 0.4 division for VOLTS/DIV ≥ 10 mV/DIV
CH 3 or CH 4 SOURCE	≥ 0.2 division
Jitter	≤ 50 ps with 5 divisions of 400 MHz at 500 ps/division

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
TRIGGERING (cont)	
LEVEL Control Range	
CH 1 or CH 2 SOURCE	± 18 divisions times the VOLTS/DIV setting
CH 3 or CH 4 SOURCE	± 9 divisions times the VOLTS/DIV setting
LEVEL Readout Accuracy	
CH 1 or CH 2 SOURCE	
59° to 95°F (15° to 35°C)	Within ± (3% of reading + 3% of p-p signal + 0.2 division + 0.5 mV + (0.5 mV × probe attenuation factor)) (Vertical Input at 1 Megohm DC, CH 2 Source not Inverted, and the TRIGGER DC Coupled)
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add 1.5 mV times the probe attenuation to (59° to 95°F) spec
50 ohm Input	Add ± 1% to 1 Megohm Input spec.
CH 2 Inverted	Add ± 1% of reading to the non-inverted spec.
NOISE REJ Coupled	Add ± 0.6 division to the DC Coupled spec.
CH 3 or CH 4 SOURCE	Within ± (3% of reading + 4% of p-p signal + 0.1 division + (0.5 mV × probe attenuation factor))
NOISE REJ Coupled	Add ± 0.3 division to the DC Coupled spec.
AUTO LVL Mode Maximum Triggering Signal Period	
A SEC/DIV Setting	
< 10 ms	≥ 20 ms
10 ms to 50 ms	At least four times the A SEC/DIV setting
> 50 ms	≥ 200 ms
AUTO Mode Maximum Triggering Signal Period	
A SEC/DIV Setting	
< 10 ms	≥ 80 ms
10 ms to 50 ms	At least 16 times the A/SEC/DIV setting
> 50 ms	≥ 800 ms
AUTO LVL Mode Trigger Acquisition Time	8 to 100 times the AUTO LVL Mode maximum triggering signal period
TRIGGER HOLDOFF	
Minimum	1 μs at 5 ns/div; A SEC/DIV setting or 2 μs (+ 33% to -10%), whichever is greater, at other A SEC/DIV setting values
Variable	10 to 25 times the minimum holdoff
SLOPE Selection	Conforms to trigger source waveform or AC power-source waveform

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
HORIZONTAL DEFLECTION SYSTEM	
A Sweep Time Base Range	500 ms/DIV to 5 ns/DIV; X10 MAG extends maximum sweep rate to 500 ps/DIV
B Sweep Time Base Range	50 ms/DIV to 5 ns/DIV; X10 MAG extends maximum sweep speed to 500 ps/DIV
A Sweep Timing Accuracy 59° to 95°F (15° to 35°C)) SEC/DIV = 100 ms/DIV or faster Sweep Accuracy Unmagnified	± (0.7% of time interval + 0.6% of full scale)
Δt Accuracy with Cursors, Unmagnified	± (0.5% of time interval + 0.3% of full scale)
Δt Accuracy with Sweep Delay	± (0.3% of time interval + 0.1% of full scale + 200 ps)
Delay Accuracy, A Sweep Trigger to Start B Sweep; + 0 to -25 ns	± (0.3% of delay setting + 0.6% of full scale)
B Sweep Accuracy and Δt Accuracy with Cursors on B Sweep	Add ± 0.3% of time interval to A Sweep spec.
X10 MAG Accuracy	Add ± 0.5% of time interval to the unmagnified Sweep and Δt Cursor spec. Exclude the first 0.5 division after the sweep starts.
A Sweep 500 ms or 200 ms/DIV Timing Accuracy	Add ± 0.5% of time interval to spec. for A SEC/DIV = 100 ms or faster
SEC/DIV VAR Timing Accuracy	Add ± 2% of time interval to sweep accuracy spec.
TIMING ACCURACY 5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add ± 0.2% of time interval to all Δt and delay specs. Add ± 0.5% of time interval to all sweep specs.
Δt Readout Resolution	Greater of either 10 ps or 0.025% of full scale
Δt Range	± 10 times A SEC/DIV setting with cursors; ± 9.95 times A SEC/DIV setting with Sweep Delay
Sweep Delay Range	0 to 9.95 times the A SEC/DIV setting from 500 ms to 10 ns
Delay Jitter	Within 0.004% of the maximum available delay + 50 ps
X10 MAG Registration	Within 0.5 division from graticule center at 1 ms SEC/DIV setting (X10 MAG on to X10 MAG off)
Horizontal POSITION Range	Start of 1 ms/DIV sweep can be positioned from right of graticule center to at least 10 divisions left of graticule center
X-Y Operation X-Axis Deflection Factor Range, Variable, and Input Characteristics	Same as CH 1
Deflection Factor Accuracy	Same as CH 1
X-Axis Bandwidth	DC to 3 MHz
Phase Difference Between X and Y with BW LIMIT Off	≤ 1° from DC to 1 MHz; ≤ 3° from 1 MHz to 2 MHz

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
HORIZONTAL DEFLECTION SYSTEM (cont)	
X-Axis, Low-frequency Linearity	≤ 0.1 division compression or expansion of a two-division, center-screen signal
DISPLAY	
Cursor Position Range	
Delta Volts (ΔV)	At least the center 7.6 vertical divisions
Delta Time (Δt)	At least the center 9.6 horizontal positions
Graticule	3.15 in × 3.94 in (80 mm × 100 mm)
Size	
Markings	8 major divisions vertically and 10 major divisions horizontally, with auxiliary markings
Trace Rotation Range	Adequate to align trace with center horizontal graticule line
Visual Writing Speed	≥ 20 divisions/μs
Z-AXIS INPUT	
Sensitivity	
DC to 2 MHz	Positive voltage decreases intensity; + 2 V blanks a maximum intensity trace
2 MHz to 20 MHz	+ 2 V modulates a normal intensity trace
Input Impedance	(10 kilohms ± 10%) 10 kilohms
Maximum Input Voltage	± 25 V peak; 25 V p-p AC at 10 kHz or less
SIGNAL OUTPUTS	
CALIBRATOR	
Output Voltage and Current	0.4 V ± 1% into a 1 Megohm load, 0.2 V ± 1.5% into a 50 ohm load; or 8 mA ± 1.5% into a short circuit
Repetition Period	Two times the A SEC/DIV setting for 100 ns to 100 ms
Accuracy	± 0.1% during sweep time
CH 2 SIGNAL OUT	
Output Voltage	20 mV/DIV ± 10% into 1 Megohm; 10 mV/DIV ± 10% into 50 ohms
Offset	± 20 mV into 1 Megohm when DC Balance has been performed within ± 5°C of operating temperature
A GATE OUT and B GATE OUT	
Output Voltage	2.4 V to 5 V positive-going pulse, starting at 0 V to 400 mV
Output Drive	400 μA during HI state; Sinks 2 mA during LO state

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
PARAMETRIC MEASUREMENTS	
Period	
Accuracy	
59° to 95°F (15° to 35°C)	0.9% + 0.5 ns + Jitter Error
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add 0.3%
Minimum Period	≤ 2 ns
Maximum Period	≥ 100 ms (minimum frequency = 10 Hz)
Minimum Signal Amplitude	≤ (60 mV × probe attenuation factor) p-p; if DC coupled at a VOLTS/DIV setting that gives a p-p signal ≥ 4 divisions, the peak signal + DC offset must be ≤ 12 divisions
Frequency	Calculated as 1/period
Volts (+Peak, -Peak, Peak-to-Peak, and Average)	
Accuracy	
59° to 95°F (15° to 35°C)	5% of reading + 5 mV + (0.5 mV × probe attenuation) + signal aberrations + 1 least significant digit
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add (1.5 mV × probe attenuation)
Minimum Width at Peak Amplitude	≤ 10 ns
Maximum Sine Wave Frequency	
59° to 95°F (15° to 35°C)	≥ 1 MHz
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add 2%
Pulse Width (High or Low)	
Accuracy	
59° to 95°F (15° to 35°C)	0.9% of reading + 1.0 ns + jitter error + (2 × offset error)
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add 0.3%
Minimum Pulse Width	≤ 5 ns
Minimum Repetition Rate	≤ 10 Hz (minimum frequency = 10 Hz)
Duty Cycle	Calculated from Pulse Width and Period

Table 1-1
Electrical Characteristics (cont)

Characteristics	Performance Requirements
PARAMETRIC MEASUREMENTS (cont)	
Rise Time, Fall Time, and Time Interval	
Rise/Fall Time Accuracy	
59° to 95°F (15° to 35°C)	5% of reading + 3.0 ns + jitter error + offset error
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add 2%
Time Interval Accuracy	
59° to 95°F (15° to 35°C)	0.5% of reading + 5% of start event transition time + 5% of stop event transition time + 3.0 ns + jitter error + offset error; add 0.5 ns if measurement is made between CH 1 and CH 2
5° to 59°F and 95° to 131°F (-15° to 15°C and 35° to 55°C)	Add 2%
Minimum Time	$\leq$ 5 ns
Minimum Repetition Rate	$\leq$ 10 Hz (minimum frequency = 10 Hz)

Section 2
OPERATING INFORMATION

NOTE

This instrument may be damaged if operated with the LINE VOLTAGE SELECTOR switch set for the wrong applied ac input-source voltage or if the wrong line fuse is installed.

LINE VOLTAGE SELECTION

The oscilloscope operates from either a 115 V or a 230 V nominal AC power-line with any frequency from 48 Hz to 440 Hz. Before connecting the power cord to a power source, verify that the LINE VOLTAGE SELECTOR switch, located on the rear panel (see fig. 2-1), is set correctly (see table 6-13) and that the line fuse is correct. To convert the instrument for operation on the other line-voltage range, move the LINE VOLTAGE SELECTOR switch to the correct nominal ac source-voltage setting. The detachable power cord may have to be replaced to match the particular power source.

LINE FUSE

To verify the instrument power-input fuse rating, do the following steps:

a. Press in the fuse-holder cap and release it with a slight counterclockwise rotation. Pull the cap (with the attached fuse inside) out of the fuse holder.

b. Verify that the fuse is of the type listed on the back of the instrument. Then install the proper fuse and reinstall the proper fuse-holder cap. The two types of fuses listed are not directly interchangeable; they require different types of fuse caps. Included in the accessory pouch is a 5 x 20 mm fuse-holder cap for use with 1.6A, 250V, 5 x 20mm (IEC 127) fuses.

POWER CORD

This instrument has a detachable, three-wire power cord with a three-contact plug for connection to both the power source and protective ground. The power cord is secured to the rear panel by a cord-set-securing clamp. The protective ground contact on the plug connects through the power cord to the external metal parts of the instrument. For electrical shock protection, insert this plug into a power source outlet that has a properly grounded protective ground contact.

INSTRUMENT COOLING

To prevent instrument damage from internally generated heat, adequate airflow must be maintained. Before turning on the power, verify that the spaces around the air-intake holes on the bottom of the cabinet and the fan-exhaust holes in the rear panel are free of any obstruction to airflow.

OPERATING INFORMATION

All operating information pertaining to the use of this instrument may be found in TM 11-6625-3234-12, Operator's and Unit Maintenance Manual.

START-UP

The oscilloscope automatically performs a set of diagnostic tests each time the instrument is turned on. These tests warn the user of any available indication that the instrument may not be fully functional. The tests run for several seconds after power is applied. If no faults are encountered, the instrument operates normally. A failure of any of the power-up tests will be indicated by either a flashing TRIG'D indicator on the instrument front panel or a bottom-line readout on the CRT in the form: **TEST XX FAIL YY** (where XX is the test number and YY is the failure code of the failed test).

If a failure of any power-up test occurs, the instrument may still be usable for some applications. To operate the instrument after a power-up test failure, press the A/B TRIG button. Even if the instrument then functions for your particular measurement requirement, it should be repaired by a qualified service technician at the earliest convenience. Additional information on the power-up tests and troubleshooting may be found in the "Maintenance" section of this manual.

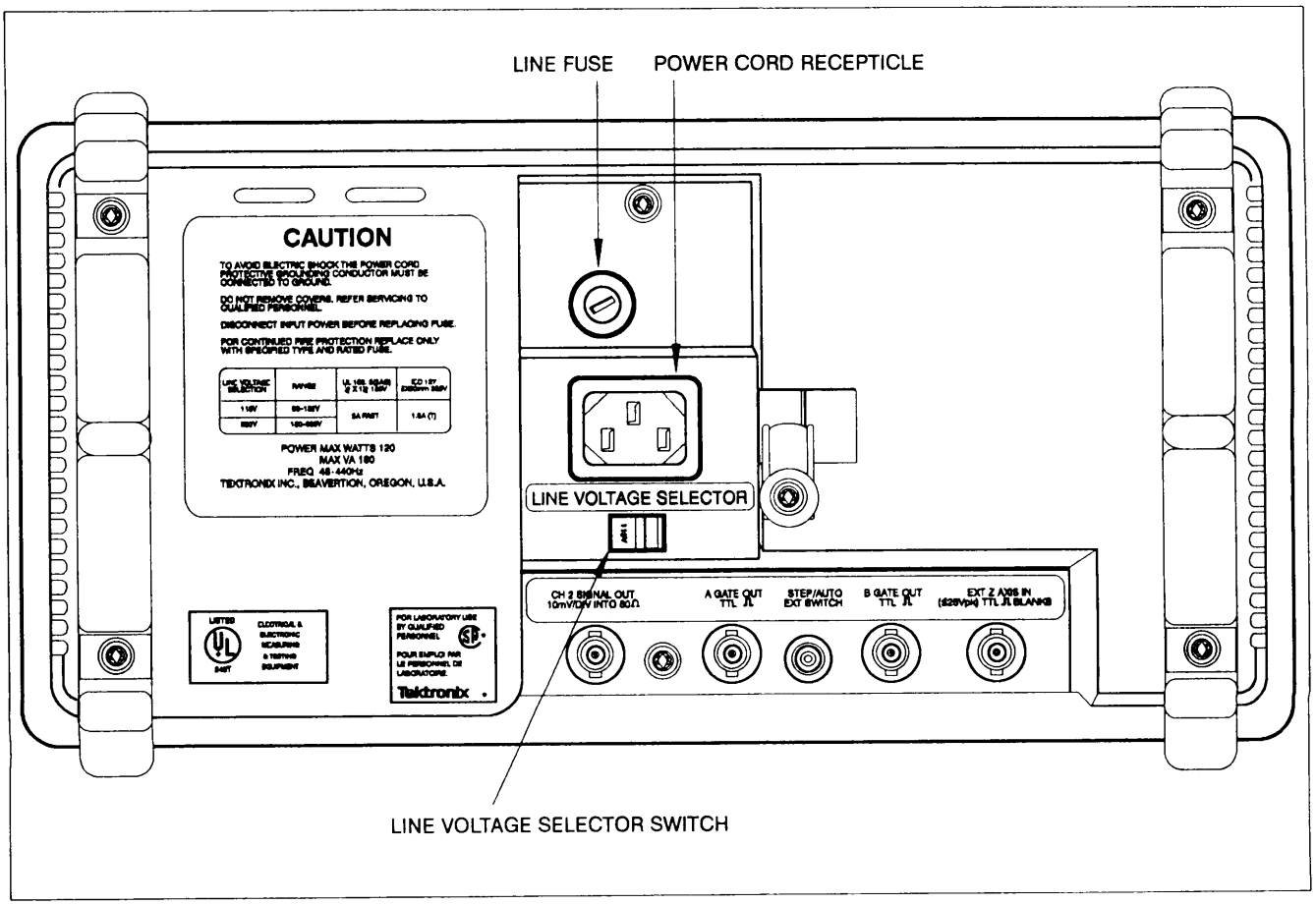


Figure 2-1. Line voltage selector switch, line fuse, and power cord recepticle.

REPACKAGING FOR SHIPMENT

If this instrument is to be shipped by commercial transportation, it should be packaged in the original manner. The carton and packaging material in which your instrument was shipped to you should be retained for this purpose.

If the original packaging is unfit for use or is not available, repackage the instrument as follows:

a. Obtain a corrugated cardboard shipping carton having inside dimensions at least six inches greater than the instrument dimensions and having a carton test strength of at least 275 pounds.

b. Wrap the instrument with polyethylene sheeting or equivalent to protect the outside finish and prevent entry of packing materials into the instrument.

c. Cushion the instrument on all sides by tightly packing dunnage or urethane foam between the carton and the instrument, allowing three inches on each side.

d. Seal the carton with shipping tape or with an industrial stapler.

Section 3
THEORY OF OPERATION

INTRODUCTION

SECTION ORGANIZATION

This section contains a functional description of the instrument circuitry. The discussion begins with an overview of the instrument functions and continues with detailed explanations of each major circuit. Reference is made to supporting schematic and block diagrams which will facilitate understanding of the text. These diagrams show interconnections between parts of the circuitry, identify circuit components, list specific component values, and indicate interrelationships with front-panel controls.

The block diagram and the schematic diagrams are located in the foldout section at the rear of this manual, while smaller functional diagrams are contained within this section near their respective text. The particular schematic diagram associated with each circuit description is identified in the text, and the foldout number is shown on the appropriate foldout page. Diagrams within the foldout section are numbered sequentially and preceded by "FO." For optimum understanding of the circuit being described, refer to both the applicable schematic diagram and the functional block diagram.

HYBRID AND INTEGRATED CIRCUIT DESCRIPTIONS

Digital Logic Conventions

Digital Iogic circuits perform many functions within this instrument. The operation of these circuits is represented by specific logic symbology and terminology. Most logic-function descriptions contained in this manual use the positive-logic convention. Positive logic is a system of notation whereby the more positive of two levels is the TRUE (or 1) state; the more negative level is the FALSE (or 0) state. In the logic descriptions, the TRUE state is referred to as HI, and the FALSE state is referred to as LO. The specific voltages which constitute a HI or, a LO state vary between individual devices. For specific device characteristics, refer to the manufacturer's data book.

Hybrids

Some of the circuits in this instrument are implemented in hybrid devices. The hybrids are specialized electronic devices combining thick-film and semiconductor technologies. Passive, thick-film components and active, semiconductor components are interconnected to form the circuit on a ceramic carrier. The end result is a relatively small "building block" with enhanced performance characteristics, all in one package. Hybrid circuits are shown on schematics simply as blocks with inputs and outputs. Information about hybrid functioning is contained in the related portion of the Detailed Circuit Description.

Linear Devices

The operation of individual linear integrated circuit devices is described in this section using waveforms or other graphic techniques to illustrate their operation.

BLOCK DIAGRAM

The following discussion is provided to aid in understanding the overall operation of the instrument circuitry before the individual circuits are discussed in detail. A block diagram of the instrument showing basic interconnections is shown in fig. FO-1. The FO numbers in each block refer to the foldout figure(s) in which the related circuitry is located.

BLOCK DESCRIPTION

The Low Voltage Power Supply is a high efficiency, switching supply with active output regulation that transforms the AC source voltage to the various DC voltages required by the instrument. The High Voltage Power Supply circuit develops the high accelerating potentials required by the CRT using voltage multiplication techniques, and the DC Restorer provides interfacing for the low potential intensity signals from the Z-Axis Amplifier to the CRT control grid.

Most of the activities of the instrument are directed by a Microprocessor. The Microprocessor, under firmware control (firmware is the programmed instructions contained in read-only memory that tells the processor how to operate), monitors instrument functions and sets up the operating modes according to the instructions received.

Various types of data read to and from the Microprocessor (program instructions, constants, control data, etc.) are all transferred over a group of eight bidirectional signal lines called the Data Bus. The Data Bus is dedicated solely to microprocessor-related data transfer.

Another group of signal lines, called the Address Bus, is responsible for selecting or "addressing" the memory location or device that the Microprocessor wants to communicate with. Typically, depending on the instruction being executed, the processor places an address on the Address Bus to-identify the location the Microprocessor must communicate with. This address, along with some enabling logic, opens up an appropriate data path between the processor and the device or memory location via the Data Bus, and data is either read from or written to that location by the processor.

While executing the control program, the Microprocessor retrieves previously stored calibration constants and front-panel settings and as necessary places program-generated data in temporary storage for later use. The battery backed up RAM provides these storage functions.

When power is applied to the instrument, a brief initialization sequence is performed, and then the processor begins scanning the front-panel controls. The switch settings detected and the retrieved front-panel data from the battery backed up RAM causes the processor to set various control registers and control voltages within the instrument that define the operating mode of the instrument. These register settings and voltage levels control the vertical channel selection and deflection factors, the sweep rate, the triggering parameters, the readout activity, and sequencing of the display. Loading the control data into the various registers throughout the instrument is done using a common serial data line (CD). Individual control clock signals (CC) determine which register is loaded from the common data line.

Coordination of the vertical, horizontal, and Z-Axis (intensity) components of the display must be done in real time. Due to the speed of these display changes and the precise timing relationships that must be maintained between display events, direct sequencing of the display is beyond the capabilities of the processor control. Instead, control data from the processor is sent to the Display Sequencer (a specialized integrated circuit) which responds by setting up the various signals that control the stages handling real-time display signals. The controlled stages are stepped through a predefine sequence that is determined by the control data. Typically, as the sequence is being executed, the Display Sequencer will be changing vertical signal sources, Z-Axis intensity levels, triggering sources, and horizontal sweep signal sources. The specific activities being carried out by the Display Sequencer depend on the display mode called for by the control data.

Vertical deflection for CRT displays comes from one or more of the four front-panel vertical inputs and, when displaying readout information, from the Readout circuitry. Signals applied to the front-panel Channel 1 and Channel 2 inputs are connected to their respective Preamplifiers via processor controlled Attenuator networks. Control data from the Microprocessor defining the attenuation factor for each channel is serially loaded into the Auxiliary Control Register and then strobed into the Attenuator Mag-Latch Relays in parallel. The relay switches of each Attenuator network are either opened or closed, depending on the data supplied to the Mag-Latch Relay Drivers. The relays are magnetically latched and remain as set until new control data is strobed in. The Auxiliary Control Register is therefore available, and different mode data is clocked into the register to set up other portions of the instrument.

Attenuated Channel 1 and Channel 2 input signals are amplified by their respective Preamplifiers. The gain factor for the Channel 1 and Channel 2 Preamplifiers is settable by control data from the processor. The Channel 3 and Channel 4 input signals are amplified by their respective Preamplifiers by either of two gain factors set by control bits from the Auxiliary Control Register. All four of these preamplifier signals are applied to the Vertical Channel Switch where they are selected by the Display Sequencer for display when required.

Each of the vertical signals is also applied to the A and B Trigger circuitry via trigger pickoff outputs from the Preamplifier stages. Any one of the signals may be selected as the trigger SOURCE for either the A or the B Trigger circuitry as directed by the Display Sequencer. The line trigger signal provides an added trigger source for A Sweeps only. Control data from the Microprocessor is written to the Trigger circuitry to define the triggering LEVEL, SLOPE, and COUPLING criteria. When the se-

lected trigger signal meets these requirements, a sweep can be initiated. The Trigger circuit initiates both the A Sweep and the B Sweep as required by the display mode selected.

In the case of A Sweeps, the LO state of the THO (trigger holdoff) signal from the Display Sequencer enables the A Sweep circuit and the next A trigger initiates the sweep. For B sweeps, and in the case of intensified sweeps, the A Sweep delay gate signal (DG) enables the B Sweep circuit. Depending on the B trigger mode selected, a B Sweep will be initiated either immediately (RUN AFT DLY) or on the next B trigger signal (TRIG AFT DLY). The slope of the sweep ramp is dependent on Microprocessor-generated control data loaded into the internal control register of the A and B Sweep circuit hybrids.

Sweep signals generated by each of the Sweep hybrids are applied to the Horizontal Amplifier. The Horizontal Amplifier is directed by the Display Sequencer to select one of the sweep ramps for amplification in sequence. In the case of Readout and X-Y displays, the X-Readout and CH 1 input signals preselected to be amplified, also under direction of the Display Sequencer.

To control the display intensity, the Display Sequencer directs the Z-Axis circuit to unblank the display at the appropriate time for the sweeps and readout displays. When the display is unblanked, the Display Sequencer selects the display intensity for either waveform displays or for readout displays by switching control of the Z-Axis beam current between the front-panel INTENSITY and READOUT INTENSITY potentiometers as appropriate.

During readout displays, the vertical dot-position signal from the Readout circuitry is applied to the Vertical Amplifier via the Vertical Channel Switch. Horizontal dot-position deflection for the readout display is selected by internal switching in the Horizontal Amplifier.

The vertical, horizontal, and Z-Axis signals are applied to their respective amplifiers where they are raised to CRT-drive levels. The output signals from the Vertical and Horizontal Amplifiers are applied directly to the CRT deflection plates. The Z-Axis Amplifier output signal requires interfacing to the high-potential CRT environment before application to the CRT control grid. The necessary Z-Axis interfacing is provided by the DC Restorer circuit located on the High-Voltage circuit board. The resulting display may be of waveforms, alphanumeric readout, or a combination of both.

DETAILED CIRCUIT DESCRIPTION

INTRODUCTION

The following discussion provides detailed information concerning the electrical operation and circuit relationships of the instrument. Circuitry unique to the instrument is described in detail, while circuits common in the electronics industry are not. The descriptions are accompanied by supporting illustrations and tables. Diagrams identified in the text, on which associated circuitry is shown, are located at the rear of this manual in the foldout pages.

PROCESSOR AND DIGITAL CONTROL

The Processor and Digital Control circuitry (fig. FO-3, sheets 1 and 2) directs the operation of most oscilloscope functions by following firmware control instructions stored in memory. These instructions direct the Microprocessor to monitor the front-panel controls and to send control signals that set up the various signal processing circuits accordingly.

Microprocessor

The Microprocessor (U2140) is the center of control activities. It has an 8-bit, bidirectional data bus for data display transfer (D0 through D7) and a 16-bit address bus (A0 through A15) for selecting the source or destination of the data. Precise timing of instruction execution, addressing, and data transfer is provided by an external, crystal-controlled clock signal.

The clock signal is developed by the Microprocessor Clock stage and applied to the Microprocessor at pin 39. Using the external clock as a reference, the Microprocessor generates synchronized control output signals, R/$\overline{W}$ (read-write), E (enable), and VMA (valid memory address) that maintain proper timing relationships throughout the instrument.

Microprocessor Clock

The Microprocessor Clock stage generates a 5-MHz square-wave clock signal to the Microprocessor and a 10-MHZ clock signal to portions of the Readout circuitry. Inverter U2540A acts as an oscillator with crystal Y2540 providing feedback at the resonant frequency. The required phase shift for oscillation to occur is produced by C2550, C2551, R2545, and the crystal. The RC network composed of R2543, C2640, R2541, and R2542 biases

input pin 1 of U2540A in the active region and establishes approximate symmetry of the oscillator output. The signal is buffered and inverted by U2540B to provide the 10-MHz clock signal.

Flip-flop U2440A is a divide-by-two circuit that reduces the 10-MHZ clock down to a 5-MHz square-wave signal used to clock the Microprocessor and the Display Sequencer. The 10-MHZ clock is supplied to the Readout Board for dot timing.

Reset Control

The Reset Control circuitry ensures that, at power up, the Microprocessor begins program execution from a known point in memory and with all the processor registers in known states. It also allows the processor to reset itself when power is turned off so that the instrument powers down in a known state.

POWER UP SEQUENCE. Reset generator U2240 generates the power-up reset. As power is applied to the instrument U2240 tests the voltage at U2240 pin 7. The reset generator forces U2240 pin 5 LO, and the LO is applied to the processor $\overline{\text{RESET}}$ input (pin 40). After the SENSE input reaches its nominal voltage level, the reset condition continues to allow the microprocessor system time to reset. The reset continues for the time determined by C2350. The effect of power supply transients is reduced by C2240. After the supplies reach their nominal level and the delay period ends U2240 pin 5 goes HI. The RESET signal to the processor then goes HI to enable normal execution to begin, and the processor is directed to the starting address of the power-up routine, which it then performs.

POWER DOWN SEQUENCE. When the instrument power switch is turned off, the PWR UP signal from J251 pin 12 immediately goes LO. This LO generates the NMI (non-maskable interrupt) request to the processor on pin 6 which causes the processor to branch to the power-down routine. Under direction of that routine, the processor begins shutting down the instrument in an orderly fashion before the power supply outputs can drop below the operating thresholds. This routine disconnects the CH1 and CH2 50 Ω input terminations to protect them from accidental application of excessive voltage during storage or bench handling.

As the operating voltages are falling, the Reset circuitry must not generate a false RESET signal to the processor. Such a restart when the power supply voltages are outside their normal operating range would produce unpredictable processor operation that could alter the contents of the battery backed up RAM. When the processor has completed all the other power-down tasks, it finally sets the PWR DOWN signal HI via U2310 (fig. FO-4, sheet 1). This signal is applied to inverter U2650C at pin 11. Pin 9 of U2650C goes LO and immediately pulls pin 2 of Reset Generator U2240 LO to prevent a reset to the processor. Reset Generator U2240 immediately switches state to assert the $\overline{\text{RESET}}$ signal to the processor. The $\overline{\text{RESET}}$ signal is held LO until the power supplies have fully discharged.

For diagnostic purposes, the PWR DOWN reset signal can be disabled. Moving jumper P503 to the DIAG (diagnostic) position keeps U2240 pin 2 Hi. The RESET signal is therefore held HI, and the processor can execute a free-running NOP (no operation) loop without interruption if the PWR DOWN bit is set HI while the Address Bus is incrementing.

Data Bus

Tri-state buffer U2350 is used to buffer the data signals to the Microprocessor from other devices on the bus. When not enabled, the device is switched to isolate the processor from the buffered Data Bus. Buffer U2350 is enabled via the Read-Write Latch U2440B when the processor reads data from another device on the bus.

When the processor writes data onto the bus, Octal Latch U2450 is enabled by the Read-Write Latch U2440B. When the E (enable) signal at pin 11 of U2450 is HI, processor data bits are passed asynchronously through the latch to the buffered data bus. When the E signal goes LO, data bits meeting setup times are latched into the device. The latched Q outputs provide the required drive current to the various devices on the bus and ensure that data hold times are met for correct data transfer. When the Read-Write Latch places a HI on pin 1 of U2450, latch U2450 is disabled, and the outputs are switched to their high-impedance state.

Data transfers to and from the processor may be interrupted by removing Diag/Norm Jumper P503. This forces a NOP (no operation) condition that is useful for verifying the functionality of the processor (when a data-bus device is suspected of causing a system failure) or for troubleshooting the Address Bus and Address Decode circuitry. Removing the jumper removes the operating power from both U2350 and U2450 to disconnect the Microprocessor from the buffered Data Bus. With the Data Bus disconnected, a resistor network pulls the processor Data Bus lines (D0 through D7) to a NOP (no operation) instruction. A NOP causes the Microprocessor to continuously increment through its address field. The Address Decode circuitry may then be checked to determine if it is operating properly.

Address Decode

The Address Decode circuitry generates enabling signals and strobes that allow the Microprocessor to control the various devices and circuit functions. The controlling signals are generated as a result of the Microprocessor placing specific addresses on the Ad-

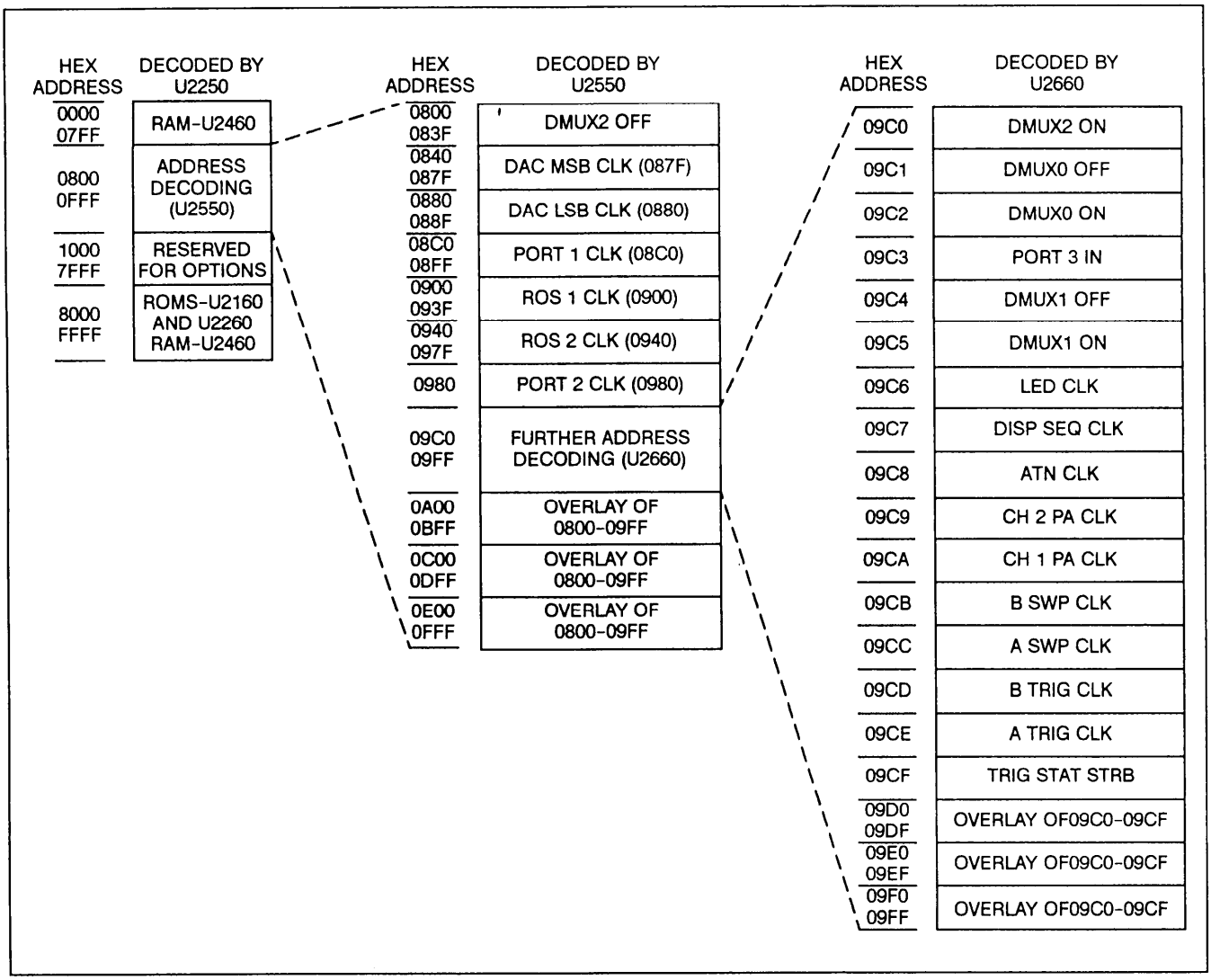


Figure 3-1. Address decoding.

dress Bus. Figure 3-1 illustrates the enables and strobes generated by the Address Decode circuitry.

Address decoding is performed by a programmable array logic device, a three-line-to-eight-line decoder, and a four-line-to-sixteen-line decoder attached to the Address Bus. The five most significant address bits are decoded by U2250. This device initially separates the total addressable-memory space (64 Kbytes) into thirty-two, 2 Kbyte blocks. Addresses in the top 32 Kbytes (address bit A15 HI) select one of two read-only memories (ROM), U2160, or U2260. When the VMA (Valid Memory Address) and E (Enable) outputs from the Microprocessor go HI, the selected ROM is enabled, and the data from the selected address location is read from the ROM.

The programmable array logic device also generates the $\overline{OE}$ and $\overline{WE}$ signals to the random-access memory (RAM). This RAM can be accessed with addresses 8000 to 9FFF if either PB0, PB1, or PB2 signals are HI. In this mode the ROMS, U2160 and U2260 are not accessible in this address range.

Of the bottom 32 Kbytes of addresses, only the lowest 4 Kbytes are further decoded. Addresses in the lowest 2 Kbyte block of addresses will cause U2250 to generate an enable signal to the RAM, U2460. Addresses in the next 2 Kbyte block of addresses will enable U2550 to do the next stage of address decoding.

The level of decoding performed by U2550 uses address bits A6, A7, and A8 to separate the addresses within the 2 Kbyte block of addresses 0800 thru 0FFF into 32 groups of 64 addresses. Address bits A9 and A10 are not used in the decoding scheme, so each of these 32 blocks is not uniquely identified. This results in four duplicate

sections within the address block, each consisting of eight groups of 64 addresses. The upper three sections in the address space are never used; therefore, decoding by U2550 may be more simply thought of as eight groups of 64 address locations. Addresses within these eight groups generate control signals to other portions of the instrument.

The final level of address decoding is done by four-line-to-sixteen-line decoder U2660. When enabled by the Y7 output of U2550, this decoder separates the highest 64-address group decoded by U2550 into 16 individual control signals. In this level of decoding, address bits A4 and A5 are not decoded, so that the 64 possible addresses consist of four overlayed blocks of 16 addresses each.

Each of the control signals generated by the Address Decode circuitry are present only as long as the specific address defining that signal is present on the Address Bus. However, one of the addressable control signals decoded by U2550 and five of the addressable control signals decoded by U2660 are used to either set or reset flip-flops U2650A, U2650B, and U2650D. The control signals are, in effect, latched and remain present to enable multiplexer U2521, U2530, (fig. FO-4, sheets 1 and 2) and U170 (fig. FO-9, sheet 1), When enabled, these multiplexer route analog control signals from DAC (digital-to-analog converter) U2101 (fig. FO-4, sheet 2) to the various analog control circuits.

Read-only Memory (ROM)

The Read-only Memory consists of one, 128 Kbyte ROM or two, 64 Kbyte ROMs that contain operating instructions (firmware) used to control processor (and thus oscilloscope) operation. Addresses from the Microprocessor that fall within the top 32 Kbytes of addressable space cause one of the two read-only memory integrated circuits to be enabled. (See Address Decode description.) instructions are read out of the enabled ROM (or PROM) IC from the address location present on its 16 address input pin (A0 through A14, Page Select). The eight-bit data byte from the addressed locations is placed onto the Buffered Data bus (BD0 through BD7) to be read by the Microprocessor.

Random-Access Memory (RAM)

The RAM consists of integrated circuit U2460 and provides the Microprocessor with 8 Kbytes of battery backed up temporary storage space for data that is developed during the execution of a routine. The RAM is enabled whenever an address in the lowest 2 Kbyte of addresses is placed on the Address Bus or whenever an address of 8000 thru 9FFF is placed on the Address bus with either PB0, PB1, or PB2 set HI. When writing into the RAM, the write-enable signal (WE) on pin 27 of U2460 is set LO along with the chip enable (CE1) signal on pin 20. At the sometime, the output-enable (OE) on pin 22 is Hl to disable the RAM output drivers. Data is then written to the location addressed by the Microprocessor. If data is to be read from the RAM, the WE signal is set Hl to place the RAM in the read mode, and the OE signal is set LO to enable the output drivers. This places the data from the addressed location on the buffered Data Bus where it can be read by the Microprocessor.

The RAM also provides non-volatile storage for the calibration constants and the power-down front-panel settings. When power is applied to the instrument, the Microprocessor reads the calibration constants and generates control voltages to set up the analog circuitry. The front-panel settings that were present at power-off are recalled and the instrument is set to the operating mode previous power off.

Battery Circuitry

The Battery circuit composed of BT2570, R2770, CR2770, CR2370, CR2371, and C2470 provides the standby voltage necessary to maintain the contents of the CMOS RAM (U2460). The circuit composed of R2530, U2620C, R2504, and R2506 provides the microprocessor a means of monitoring the battery voltage to detect when the battery needs to be replaced.

Timing Logic

The Timing Logic circuit composed of U2440B, and U2540F generates time- and mode-dependent signals from control signals output from the Microprocessor. The enable (E) signal output from the Microprocessor is a 1.25 MHz square wave used to synchronize oscilloscope functions to processor timing.

Data applied to the Address Bus, Data Bus, and various control signals are allowed to settle (become valid) before any of the addressed devices are enabled. This is accomplished by switching the E signal HI a short time after each processor cycle begins. Inverter U2540F inverts the polarity of the delayed enable signal and enables the Address Decode stage only after the address bus has settled.

Read-Write Latch U2440B is used to delay the processor's read/write signal (R/$\overline{W}$) from the Microprocessor to meet hold-time requirements of the RAM. At the same time, it generates delayed read and write enabling signals of both polarities to meet the requirements of Buffer U2350 and Latch U2450 (in the Microprocessor Data Bus) and various other devices in the Readout circuitry (fig. FO-13, sheets 1 and 2).

When R/$\overline{W}$ goes LO for a write cycle, Read-Write Latch U2440B is reset, and Q output (pin 9) is held LO, Latch U2450 is in its transparent state at this time, and data from the Microprocessor is applied asynchronously to the buffered Data Bus. At the end of the write cycle, the R/$\overline{W}$ signal goes Hl, and the reset to U2440B is removed. The E

signal also goes through a negative transition, and data on the Microprocessor data bus lines is latched into U2450. The next positive transition of the 1.25-MHz E signal (1/2 E cycle after the R/$\overline{W}$ signal goes HI) clocks the HI level at U2440B pin 12 (the D input) to the Q output, and the $\overline{Q}$ output (pin 8) goes LO. The 1/2 E cycle delay between the time R/$\overline{W}$ goes HI and the time that the Q output of U2440B goes HI keeps Latch U2450 outputs on long enough to meet the data hold time for the RAM. At the end of that delay time, pin 1 of U2450 goes HI, and the Latch outputs are switched to the high-impedance state to isolate it from the buffered Data Bus.

READOUT FRAMING AND INTERRUPT TIMING. Binary counter U2640 is used to generate a readout-framing clock to the Readout circuitry and a real-time interrupt request to the Microprocessor via inverter U2540E. The readout-framing clock is a regular square-wave signal obtained from U2640 pin 12, 14 or 15 by dividing the 1.25-MHz E signal by 512 (2^9), 1024 (2^{10}), or 2048 (2^{11}). This clock tells the readout circuitry to load the next block (subframe) of readout information to be displayed. Pin 12 is for a reduced interfere mode for TV applications, pin 14 is used for retrofitability into older 2 line instruments, and pin 15 is for newer 4 line readout instruments. (See "Readout" description for further information concerning alphanumeric display.) The real-time interrupt request, which occurs every 3.3 ms, is obtained from pin 2 by dividing the E signal by 8192 (2^{13}).

When the real-time request occurs, $\overline{IRQ}$ (pin 4 of U2140) goes LO, and the processor breaks from execution of its mainline program. The Microprocessor first resets Binary Counter U2640 by setting pin 19 of U2301 (fig. FO-4, sheet 2) HI (to generate the reset), then it resets pin 19 LO to allow the counter to start again. At this time, the Microprocessor sets analog control voltages and reads trigger status from the Display Sequencer (fig. FO-10, sheets 1 and 2). When this is completed, it reverts back to the mainline program.

in addition to the analog control and trigger status update that occurs with each interrupt, on every fifth interrupt cycle, the Microprocessor also scans the front-panel potentiometers. Every tenth interrupt cycle, scanning the front-panel switches and checking the 50- Ω DC inputs for overloads is added to the previously mentioned tasks. If all the tasks are not completed at the end of one interrupt cycle, the real-time interrupt request restarts the analog updates, but as soon as those are accomplished, the Microprocessor will pick up with its additional tasks where it was before the interrupt occurred. This continues until all tasks are completed. if any pot or switch changes are detected, the Microprocessor updates the analog control voltages and the control register data to reflect those changes prior to reverting back to the mainline program instructions.

FRONT-PANEL SCANNING AND ANALOG CONTROLS

The Analog Control circuitry (fig. FO-4, sheets 1 and 2), under Microprocessor control, reads the front-panel controls and sets various analog control voltages to reflect these front-panel settings. The calibration constants determined during instrument calibration and the last "stable" front-panel setup conditions are stored in battery backed up RAM. At power-on the stored front panel information is used to return the instrument to its previous state.

Hardware I/O

Data transfer from the Analog Control circuitry to the Microprocessor is via Status Buffer U2220. Data bits applied to the input pins are buffered onto the Data Bus when enabled by the Address Decode circuitry. Via the Status Buffer, the processor is able to (1) determine the settings of front- and rear-panel pots and switches, (2) determine instrument type (2465 B), (3) determine if a triggered sweep is in progress, and (4) read the contents of the Readout RAM. When disabled, the buffer outputs are switched to high impedance states to isolate them from the buffered Data Bus.

Data transfer from the Microprocessor to the Analog Control circuitry is via registers U2210 and U2310. Via register U2210, the Microprocessor is able to select the pot-scanning multiplexers, turn the trigger LED on and off, and control other hardware via serial control data and the attenuator strobe. Via register U2310, the processor controls pot selection, ROM addressing, and power down timing.

Front-Panel Switch Scanning

The Front-Panel Switches prearranged in a matrix often rows and five columns. Most of the row-column intersections contain a switch. When a switch is closed, one of the row lines is connected to one of the column lines through a diode. Reading of the switches is accomplished by setting a single row line LO and then checking each of the five column lines sequentially to determine if a LO is present (signifying that a switch is closed). After each of the five columns have been checked, the current row line is reset HI and the next row line is set LO for the next column scan cycle. A complete Front-Panel scan consists of all ten row lines LO in sequence and performing a five-column scan for each of the rows.

Row lines are set LO when the microprocessor writes a LO to one of the flip-flops in octal registers U2301 or U2201. The row data placed on the buffered Data Bus by the Microprocessor is clocked into the registers as two, eight-bit words by clocks from the Address Decode circuitry (DAC LSB CLK for the lower eight bits and DAC MSB CLK for the upper eight bits). All eight outputs of

register U2201 and two outputs of U2301 drive the ten rows of the front-panel switch matrix (the fifth line of the matrix is not used). Series resistors in the lines limit current flow and eliminate noise problems associated with excessive current flow.

While each row is selected, the processor will scan each of the five column lines in sequence. To scan the columns, the processor increments three data select bits from U2301 that define the column to be checked. Eight-line data selector U2410 connects the associated column line to Status Buffer U2220. As each line is selected, the Microprocessor reads the Status Buffer to determine if the associated switch is open or closed.

In addition to the front-panel switches, the CAL/NO CAL jumper (P501) is checked to determine whether the instrument should be allowed to execute the calibration routines. The levels on U2410 pin 7 and 9 are read by scanning two additional columns at power-up. If the jumper is pulling the CAL bit LO, the operator will be allowed to use the calibration routines stored in firmware. If the NO CAL bit is pulled LO, the calibration routines may not be performed. If the jumper is removed, and neither bit is pulled LO, the Microprocessor is forced into a special diagnostic mode (CYCLE) used to record certain operating failures during long-term testing of the instrument. (See the “Maintenance” section for an explanation of the diagnostic modes.) Removing P501 or switching it between the CAL and NO CAL positions will not be recognized by the Microprocessor until the instrument is powered down and then turned back on.

The resistors in series with the input lines to U2410 are current-limiting resistors that protect the CMOS eight-line data selector from static discharges. The resistors connected from the input lines to the + 5 V supply are pull-up resistors for the front-panel column lines.

Digital-to-Analog Converter (DAC)

DAC U2101 is used to set the various analog references in the instrument and is used to determine the settings of the front panel potentiometer. The 12-bit digital values to be converted are written to octal registers U2301 and U2201 for application to the DAC input pins. The DAC then outputs two complementary analog currents that are proportional to the digital input data. (Complementary, in this case, means that the sum of the two output currents is always equal to a fixed value.)

The maximum range of the output currents is established by a voltage-divider network composed of R2010, R2012, R2013, and R2011 connected to the positive and negative reference current inputs of the DAC (pins 14 and 15 respectively). A + 10-V reference voltage applied to the DAC through R2013 sets the basic reference current. Resistor R2011 and potentiometer R2010 provides means to adjust this current over a small range for calibration purposes. The nominal reference current is 1 mA, the DAC full-scale output current is 4 mA. The output currents flow through series resistors R2520 and R2521, connected to the + 1.36 V reference, and proportional voltages result.

Pot Scanning

The Pot Scanning circuitry, in conjunction with the DAC, derives digital values for each of the various front-panel potentiometers. Scanning of the pots is accomplished by data selectors U2401, U2501, and U2601. Three bits are written to register U2310 and select the pot to be read. The bits are latched in the register and keep the pot selected until the register is reset. The Microprocessor writes a LO to the inhibit input pin (pin 6) of either U2401, U2501 or U2601 via register U2210 to enable the device. The enabled data selector connects the analog voltage at the wiper of the selected pot to comparator U2510.

Comparator U2510 compares the analog voltage of each pot to the output voltage from the DAC (pin 18). To determine the potentiometer output voltage, the processor performs a binary search routine that changes the output voltage from the DAC in an orderly fashion until it most closely approximates the voltage from the pot.

The conversion algorithm is similar to successive approximation and generates an eight-bit representation of the analog level. When the pot’s value is determined, the Microprocessor stores that value in memory. Once all of the pots have been read and the initial value of each has been stored, the processor uses a shorter routine to determine if any pot setting changes. To do this the DAC output is set to the last known value of the pot (plus and minus a small drift value), and the status bit is read to see that a HI and LO occurs. If within the limits, the processor assumes that the pot setting has not changed and scans the next pot. When the processor detects that a pot setting has changed, it does another binary search routine to find the new value of that pot.

Analog Control

The operating mode and status of the instrument requires that various analog voltages (for controlling instrument functions) be set and updated. The digital values of the controlling voltages are generated by the Microprocessor and converted by the DAC. Analog multiplexer U2521 and U2530 (fig. FO-4, sheets 1 and 2) and U170 (fig. FO-9, sheet 1) route the DAC voltages to sample-and-hold circuits that maintain the control voltages between updates.

The Microprocessor writes three selection bits to register U2301 that directs the DAC output to the appropriate sample-and-hold circuit and charges a capacitor (or capacitors) to the level of the DAC. When the processor disconnects the DAC voltage from the sample-and-hold circuit (by disabling the multiplexer) the capacitor(s) remains charged and holds the control voltage near the

level set by the DAC. Due to the extremely high input impedance of the associated operational amplifiers, the charge on the capacitor(s) remains nearly constant between updates.

FRONT-PANEL CONTROLS

The Front Panel is the operator's interface for controlling the user-selectable oscilloscope functions. Along with the CRT, it provides visual feedback to the user about the present operating state of the instrument.

Most of the Front-Panel controls (fig. FO-6, sheets 1 and 2) are "cold" controls; i.e., they are not connected directly into the signal path. Therefore, associated circuits are not influenced by the physical parameters (such as capacitance, resistance, and inductance) of the controls. In addition, translating the analog output levels of most of the potentiometers to digital equivalents allows the processor to handle the data in ways that result in a variety of enhanced control features.

To maintain the front-panel operating setup between uses of the instrument, the digitized values of the potentiometers and front-panel switch settings are stored in battery backed up RAM so that when the instrument power is turned off, these control settings are not lost. Then, when power is next applied, the instrument will power up to the same configuration as when the power was last removed (assuming the settings of the non-digitized pots and switches remain the same).

The Front-Panel Controls also allow the user to initiate and direct the diagnostic routines (and when enabled, the calibration routines) programmed into the read-only memory (ROM). These routines are explained in the Maintenance section of this manual.

Front-Panel Switches

The Front Panel Switches are arranged in a ten-row-by-five-column matrix, with each switch assigned a unique location within the matrix (see fig. 3-2). A closed switch connects a row and a column together through an isolating diode. To detect a switch closure, the switch matrix is scanned once every 32 ms (every tenth Microprocessor interrupt cycle). When scanning, the Microprocessor sequentially sets each individual row line LO. A closed switch enables the LO to be passed through the associated diode to a column line. When the processor checks each of the five column lines associated with the selected row, the LO column is detected. The intersection of the selected row and the detected column uniquely identifies the switch that is closed. Further information about switch scanning is found in the "Front-Panel Scanning" description located in the "Analog Control" discussion.

As each switch is read, the processor compares the present state of the switch to its last-known state (stored in memory) and, if the same, advances to check the next switch. When a switch is detected as having changed, the processor immediately reconfigures the setup conditions to reflect the mode change and stores the new state of the switch in memory. The detected status of the switch on each of the following scan cycles is then compared against the new stored data to determine if the switch changes again. The 32-ins delay between the time a switch is detected as having changed and the next time it is read effectively eliminates the effects of switching noise (switch bounce) that may occur after the switch is actuated.

Front-Panel Pots

The thirteen Front-Panel Potentiometers, READOUT INTENSITY, and INTENSITY are "cold" controls that control the linear functions of the instrument. (SCALE ILLUM and FOCUS are not considered part of the Front-Panel Control circuitry for the purposes of this description.) All are digitized and control their functions indirectly. Data Selectors U2401, U2501, and U2601 in the Analog Control circuitry (fig. FO-4, sheets 1 and 2) route the wiper arm voltage of the pot being read to comparator U2510 where it is compared with the output of DAC U2101. The processor changes the DAC output until it most closely matches the output voltage of the pot, then stores the digital value of the "match". See the "Pot Scanning" description in the "Analog Control" discussion for further information on the reading of pot values.

Like the switch matrix scanning, the Front-Panel pot scanning routine is performed every 16ms. When entered, the routine reads the settings of the "last-moved" pot and one 'unmoved" pot. Each succeeding scan continues to read the last-moved pot in addition to anew unmoved pot. In this way, each pot is monitored, but most of the scan time is devoted to the pot that is still moving (needing continuous updating).

As the initial pot settings are determined, a digital representation of each value is stored in memory. The processor then checks each pot against its last-known value to determine if a pot has moved. If a pot is detected as moving, the processor executes a routine that converts the movement (displacement from last-set value) into a corresponding control voltage.

When producing the actual analog control levels, the processor can manipulate the digital values read for the various pots before sending the output data to the DAC. This allows many of the oscilloscope parameters to vary in an enhanced fashion. The pot data is manipulated by the processor in a manner that produces such features as variable resolution, continuous rotation, fine-resolution backlash, and electrically detented controls.

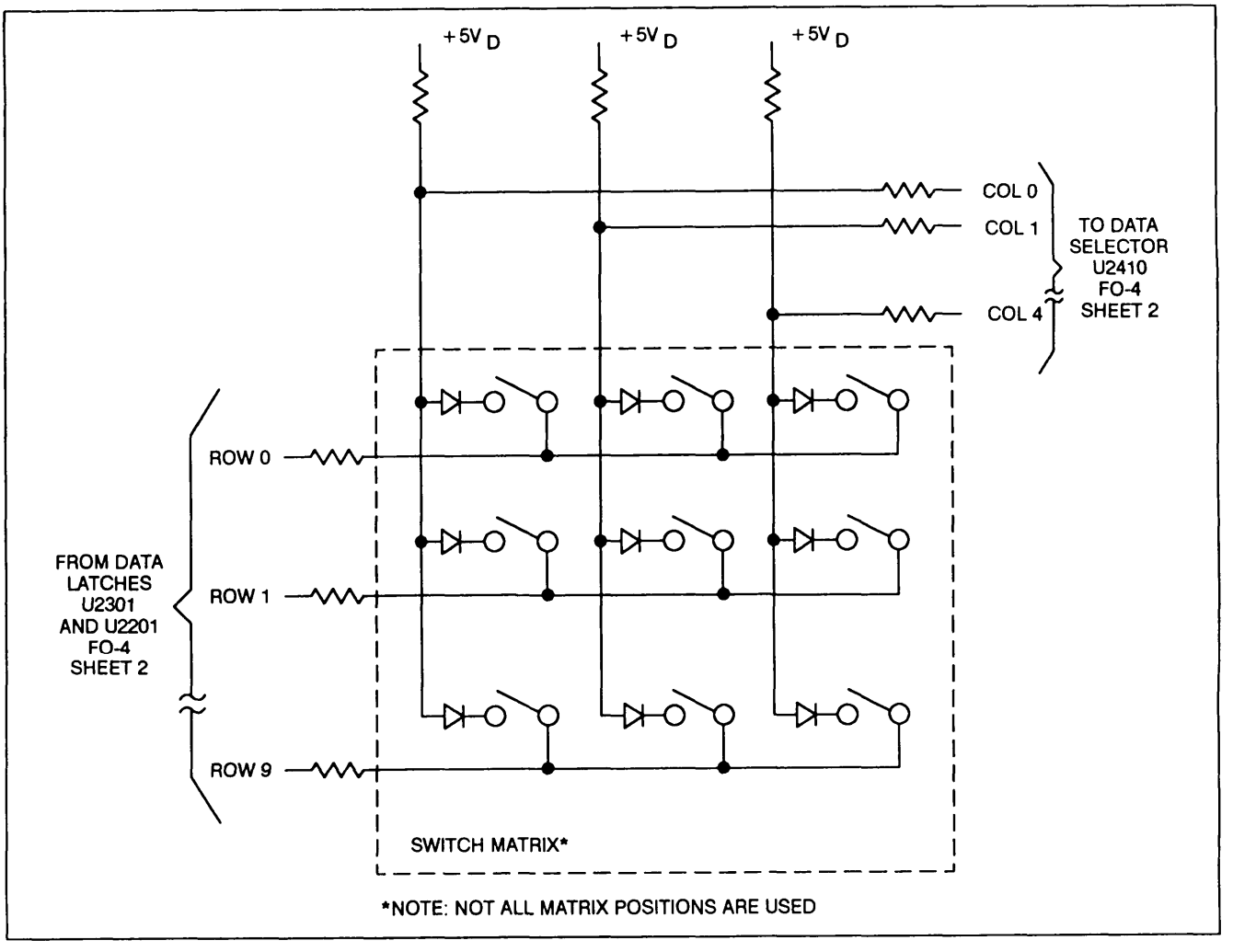


Figure 3-2. Front-panel switch matrix.

With all thirteen Front-Panel Potentiometers, READ-OUT INTENSITY, and INTENSITY controls, the processor reads the magnitude and direction of pot rotation and produces variable-resolution control voltages. if a pot's direction of rotation changes, the magnitude of the change from the last-set position remains small, or if it was not the last pot moved, a fine-resolution control voltage results. in the fine-resolution range, a given rotation displacement will cause a small control voltage change. The same displacement farther away from the last-set reference will cause a proportionally larger control voltage change, producing a coarse-resolution effect. if the changing pot is the last one moved and the direction of rotation remains the same, the algorithm continues from where it left off during the preceding scan; producing control voltage changes with the same increment as it was last using.

The delta reference controls (Δ REF OR DLY POS and Δ) are continuous-rotation potentiometers. They each consist of two pots ganged together with their wiper arms electrically oriented at 180° apart. As the wiper of one pot is leaving its resistive element, the wiper of the other pot comes onto its element. The Microprocessor has the ability to watch the output voltage from each wiper and when it detects that the controlling wiper is nearing the end of its range, it will switch control over to the other wiper. The routine the processor uses to watch these pots sets the associated control voltage on the basis of relative voltage changes (Δ V) that occur. Switching between the pots to change control to the opposite wiper arm is based on specific voltage levels being sensed.

Sensing specific voltage levels is also used when reading the VOLTS/DIV VAR, SEC/DIV VAR, and HOLD-OFF controls. These pots have both a mechanical detent and a processor-generated electrical detent. As one of these controls is moved out of the mechanical detent position, the processor watches the analog voltage changes that occur; but the associated control voltage will

not change until a specific voltage level (the electrical detent level) is reached. Once the electrical detent value is exceeded, the processor begins to vary the associated control voltage in response to further pot rotation. When returning to the mechanical position, the electrical detent level is reached first, and the variable voltage action is stopped before the mechanical detent is entered.

Front-Panel Status LEDs

Light-emitting diodes (LEDs) are used to provide visual feedback to the operator about the oscilloscope status and operating mode by backlighting front-panel nomenclature. A 48-bit status word, defining the diodes to be illuminated, is generated by the processor and then serially clocked into the six LED-Status Registers (U3001, U3002, U3003, U3004, U3005, and U3006). The registers hold the selected diodes on until the next update. Whenever the processor detects that a front-panel control has changed (and a new status display is required), a new status word is generated and applied to pin 1 of U3002. As each of the bits is clocked into the Q_A position of U3002, the preceding bit is shifted to the next register position. After 48 bits have been clocked into (and 40 bits through) U3002, all six LED-Status registers are full and contain the LED illumination pattern to be displayed to the user. ALO at any Q output of the registers illuminates the corresponding front-panel LED.

The TRIG'D LED is not driven by the LED-Status Register. It is driven by the Analog Control circuitry and illuminated whenever a triggered sweep is in progress.

ATTENUATORS AND PREAMPS

The Attenuators and Preamps circuitry (fig. FO-9, sheets 1 and 2) allows the operator to select the vertical deflection factors. The Microprocessor reads the Channel VOLTS/DIV switches and VOLTS/DIV VAR controls and then digitally switches the attenuator and sets the preamplifier gains accordingly.

Channel 1 and Channel 2 Attenuators

The Channel 1 and Channel 2 Attenuators are identical in operation, with corresponding circuitry in each channel performing the same function. Therefore, only the Channel 1 circuitry is described.

Input signals from the Channel 1 input connector are routed through an attenuator network by four pairs of magnetic-latch relay contacts. The position of the relays is set by Microprocessor data placed into Auxiliary Control Register U140. Relay buffer U110 provides the necessary drive current to the relays.

Four input coupling modes (1M Ω AC, GND, 1M Ω DC, and 50 Ω DC) and three attenuation factors (1X, ÷ 10, and ÷100) may deselected by closing different combinations or relay contacts. The three attenuation factors, along with the variable gain factors of the Vertical Preamplifier, are used together to obtain the CRT deflection factors. The relays are magnetically latched and once set, remain in position until new attenuator-relay-setting data and strobes are generated. (See the "Auxiliary Control Register" description for a discussion of the relay-latching procedure.)

The 50 Ω termination resistor has a thermal sensor associated with it that produces a DC voltage (CH 1 OVL) proportional to the input power. Should the input power exceed the normal safe-operating level for the 50 Ω DC input, the termination resistor temperature will exceed the normal operating limit and change the output voltage of the thermal sensor. The amplitude of this DC level is periodically checked via comparator U2510 and DAC U2101 (fig. FO-4, sheets 1 and 2) and allows the MicroProcessor to detect when an overload condition is present. When an overload occurs, the processor switches the input coupling to the 1 M Ω position to prevent damage to the attenuator and displays 50 Ω OVERLOAD on the CRT.

Compensating capacitor C105 is adjusted at the time of calibration to normalize input capacitance of the preamplifier to the attenuator.

A probe-coding ring around the BNC input connector passes probe coding information (a resistance to ground) to the Analog Control circuitry for detection of probe attenuation factors. The readout scale factors are set to reflect the detected attenuation factor of the attached probe.

Auxiliary Control Register

The Auxiliary Control Register allows the Microproces--sor to control various mode and range dependent functions of the instrument. Included in these functions are: attenuation factors, input coupling, Channel 3 and Channel 4 gains, vertical-bandwidth limiting, the X-Y display mode, and the state of the measurement PAL.

When the Microprocessor sets the input coupling mode and attenuation factors for Channel 1 and Channel 2, a series of eight, 16-bit control words are serially clocked into shift registers U140 and U150 (eight bits in each register). Each control word is used to set the position of one of the eight attenuator and coupling relays (four relays are in each attenuator assembly). Each control word will have one HI bit. This bit will correspond to the specific relay contact to be closed. Relay buffers U110 and U130A (for Channel 1) and U120 and U130B (for Channel 2) are Darlington configurations that invert the polarities of all bits. This results in a LO being applied to only the coil lead associated with the contact to be closed; all other coil leads are held HI.

To set a relay once the control word is loaded, the Microprocessor generates a ATTN STRB (attenuator strobe) to U130G pin 7 via R129 and C130. The strobe pulses the output of U130G LO for a short time. This output pulse attempts to turn on both Q130 and Q131 (relay drivers) via their identical base-bias networks. Due to the lower level from the turned on Darlington relay buffer (coupled through the associated coil diode and either CR130 or CR131 to one of the bias networks), one transistor will turn on harder as the ATTN STRB pulse begins to forward bias the transistors. The more positive collector voltage of the transistor turning on harder is fed through the bias diode (again either CR130 or CR131) to further turn off the opposite transistor. This action results in one transistor being fully on and the other one being fully off. The saturated transistor sources current through the two stacked relay coils to the LO output of either U140 or U150 (current sink) to close the selected contacts. Once set, the magnetic-latch feature will hold the relay set to this position until opposing data is clocked into the Auxiliary Control Register and strobed into the relay. All coil leads for the remaining relays are set HI, and only the selected relay will be set.

To set the seven remaining Attenuator and coupling relays, the sequence just described is repeated seven more times. Whenever the Microprocessor determines that the attenuation factor or input coupling has changed, the entire relay-setting procedure is repeated for all eight relays.

After the coupling and attenuator relays have been latched into position, the Auxiliary Control Register is free to be used for further circuit-controlling tasks. Eight more bits of control data are then clocked into U140 either to enable or disable the following functions: vertical bandwidth limiting (BWL), triggered X-Y mode (TXY), the A and B Sweep Delay Comparators (BDCA and BDCA), and slow-speed intensity limit (SIL); or to alter the Channel 3 and Channel 4 gain factors (GA3 and GA4). Four other bits are clocked into register U150: one to produce the CTC signal, one to control the scale illumination circuit during SGL SEQ display mode, and two (CNTL1 and CNTL2) to control the state of the measurement PAL, U975. The CTC control bit is used to enable a sweep-start linearity circuit in the A Sweep circuitry (fig. FO-10, sheets 1 and 2) on the 2 ns and 20 ns per division sweeps.

Analog Control Demultiplexer

When enabled by the Address Decode circuitry, Analog Control Demultiplexer U170 directs the analog levels applied to pin 3 from DACU2101 (fig. FO-4, sheet 2) to one of six sample-and-hold circuits. In the Preamplifier circuitry, the sample-and-hold circuits maintain the VAR gain and DC Bal control-voltage levels applied to both the Channel 1 and Channel 2 Preamplifiers U100 and U200 between updates. Two of the Demultiplexers outputs direct analog levels to the Holdoff and Channel 2 Delay offset sample-and-hold circuits (fig. FO-4, sheets 1 and 2). Routing is determined by the three-bit address from register U2301 (fig. FO-4, sheet 2) applied to Demultiplexer U170 on pins 9,10, and 11.

Channel 1 Preamplifier

Channel 1 Preamplifier U100 converts the single-ended input signal from the Channel 1 Attenuator to a differential output signal used to drive the Vertical Channel Switch. The device produces either amplification or attenuation in predefine increments, depending on the control data written to it from the Microprocessor. The preamp also has provisions for VAR gain, vertical positioning, and a trigger signal pickoff.

The Channel 1 vertical input signal is applied to pin A of Channel 1 Preamplifier U100. Control data from the processor is clocked into the internal control register via pin 22 (CD) by the clock signal applied to pin 23 ($\overline{CC}$). The data sets the device to have an input-to-output gain ratio of 2,4, or 10, depending on the VOLTS/DIV control setting.

Two analog control voltages set by DACS modify the differential output signal at pins 9 and 10. The front-panel Channel 1 POSITION control supplies a position signal to U100 pin 17 (via MUX U2530 and sample-and-hold U2430 and C2432) that vertically positions the Channel 1 display on the CRT. ADC Bal signal is applied to pin 2 of U100 from MUX U170 via the sample-and-hold circuit composed of U160A and C177. This DC BAL signal is a DC offset-null level that is determined during the automatic DC Bat procedure. The offset value is stored as a calibration constant in RAM and is recalled at regular intervals to set the DC Bal level, holding the Preamplifier in a DC balanced condition.

The Channel 1 VOLTS/DIV VAR control is monitored by the Microprocessor during the front-panel scanning routine. When the processor has determined where the VOLTS/DIV VAR control is positioned, it causes DAC U2101 (fig. FO-4, sheet 2) to produce a corresponding control level and routes it to the VAR gain sample-and-hold circuit composed of U160D, C179, and associated components. The control voltage at the output of U160D (pin 14) sets the variable gain of the Preamplifier.

A pickoff amplifier internal to U100 conditions the trigger signal and provides the proper signal level at pin 15 to drive the A/B Trigger Generator U500 (fig. FO-10, sheets 1 and 2). The pickoff point for the trigger signal is prior to the addition of the vertical position offset, so the position of the signal on the CRT has no effect on the trigger operation. However, the pickoff point is after the DC Bal and Variable gain signals have been added to the signal so both of these functions will affect trigger operation.

Common-mode signals are rejected from the trigger signal by the circuitry composed of operation amplifier

U450B and associated components. The inverting input of U450B (pin 6) is connected to the common-mode point between APO + (pin 12) and TPO- (pin 15) of U100. Any common-mode signals present are inverted and applied to a common-mode point between R451 and R453 to cancel the signals from the differential output. A filter network composed of LR 180 and the built-in circuit board capacitor (5.6 pF) reduces trigger noise susceptibility.

The Channel 1 input signal used to provide the horizontal deflection for the X-Y displays is obtained from U100 pin 11. The components between pin 11 and the Horizontal Output Amplifier provide phase compensation of the signal. During instrument calibration, the delay produced by C115, C116, L115, R115, and variable capacitor Cl 18 is matched to the 78-ns delay of the vertical delay line DL100 (fig. FO-11, sheet 1).

Channel 2 Preamplifier

Operation of Channel 2 Preamplifier U200 is nearly identical to that of the Channel 1 Preamplifier just described. The exceptions are that the output polarity of the Channel 2 signal may be either normal or inverted and that the signal obtained from the BPO + output (pin 11) is conditioned differently for a different purpose than in the Channel 1 Preamplifier circuitry.

Inverting the Channel 2 signal for the CH 2 INVERT feature is accomplished by biasing on different amplifiers. The control data clocked into the internal control register from pin 22 sets up the necessary switching.

The Channel 2 BPO + signal at U200 pin 11 provides an accurate representation of the Channel 2 signal at the rear-panel CH 2 OUT connector.

Channel 3 and Channel 4 Preamplifier

The functions provided by the Channel 3 and Channel 4 Preamplifier are similar to those provided by the Channel 1 and Channel 2 Preamplifiers. The single-ended CH 3 and CH 4 input signals are converted to differential signals, and vertical gain and vertical positioning are added to the output signals. Trigger pickoff signals are generated for both channels and are routed to the Trigger hybrid.

Channel 3 and Channel 4 gains may be either 0.1 V per division or 0.5V per division. The logic levels of control bits applied to U300 pin 30 (GA3) and pin 31 (GA4) from Auxiliary Control Register U140 sets the gain of the Channel 3 and Channel 4 preamplifiers respectively. Vertical positioning of the Channel 3 and Channel 4 signals on the CRT is controlled by the voltage levels applied to pin 29 (POS3) and pin 32 (POS4) from the front-panel CH 3 and CH 4 POSITION potentiometers (via MUX U2530 and sample-and-hold amplifiers U2430C and C2333 and U2430D and C2332).

DC offsets in the output signal due to any tracking differences between the + 5 V and the -5 V supply to U300 are reduced by the tracking regulator circuit composed of U165A, Q190, and associated components. Operational amplifier U165A and Q190 is configured so that the output of voltage at the emitter of Q190 follows the -5 V supply applied to R198. This tracking arrangement ensures that the supply voltages are of equal magnitudes to minimize DC offsets in the output signals.

Scale Illumination

The Scale Illumination circuit consists of U130C, U130D, U130E, U130F, and associated components. The circuit enables the operator to adjust the illumination level of the graticule marks on the CRT face plate using the SCALE ILLUM control.

Components U130C through U130F, depicted on diagram 4 as inverters, are actually Darlington transistor pairs. Figure 3-3 is a simplified illustration of the Scale Illumination circuitry, redrawn to show U130C through 130F as Darlington transistor pairs for the purpose of the following description.

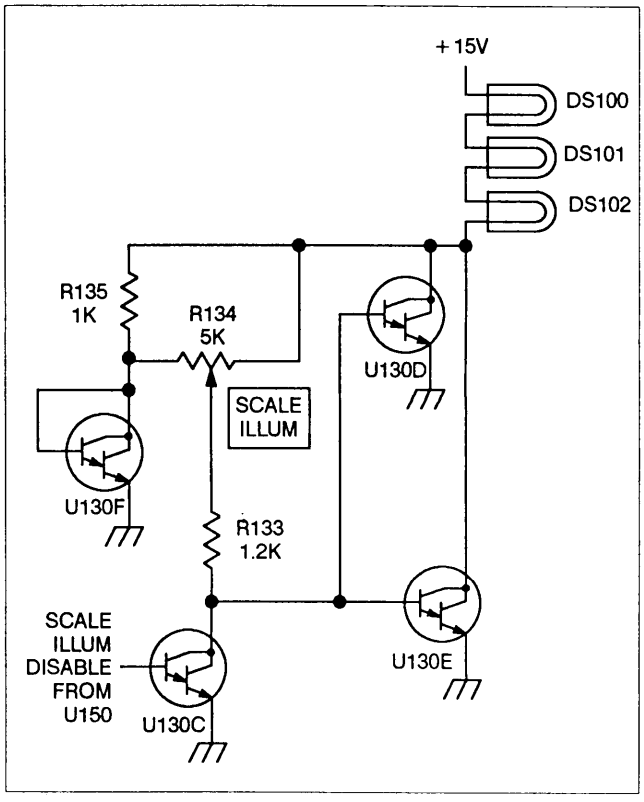


Figure 3-3. Scale illumination circuit.

Darlington transistors U130D and U130E control the current flow to scale-illumination lamps DS100, DS101, and DS102. Base drive current for U130D and U130E via R133 is set by the front-panel SCALE ILLUM pot R134. Voltage at the more negative end of the pot is set by the self-biasing configuration of U130F and R135. The voltage level established by these two components is two diode drops above ground (- 1.2 V) so that, at full counterclockwise rotation, the wiper voltage of the SCALE ILLUM pot will just match the turn-off point of U130D and U130E. The voltage at the other end of the pot is set by the collectors of U130D and U130E. As the SCALE ILLUM pot is advanced, the base drive to U130D and U130E increases, and the voltage on their collectors moves closer to ground potential. This increases the current through the scale-illumination lamps to make them brighter and produces some negative feedback to the base circuit through the SCALE ILLUM pot. Negative feedback stabilizes the base drive to U130D and U130E to hold the illumination level constant at the selected setting of the SCALE ILLUM control.

During SGL SEQ display mode, the graticule is illuminated only once during the sequence for photographic purposes. In this mode, a HI is initially written to Auxiliary Control Register U150 (bit Q_H). This turns on U130C and shunts the base drive current of U130D and U130E to ground. At the point in the sequence when the graticule should be illuminated, the processor writes a LO to bit Q_H, and Q130C is turned off. This enables U130D and U130E to turn on the lamps to the illumination level set by the SCALE ILLUM pot.

DISPLAY SEQUENCER, TRIGGERS, AND SWEEPS

The Display Sequencer circuitry (fig. FO-10, sheets 1 and 2) controls and sequences the "analog-type" oscilloscope functions in real time, dependent on control data it receives from the Microprocessor. The A/B Trigger circuitry, under control of the Display Sequencer, detects when triggering requirements are met and initiates the appropriate sweep. The A Sweep and B Sweep circuits generate sweep ramps under control of the Display Sequencer when triggered by the A/B Trigger circuitry.

Display Sequencer

The Display Sequencer consists primarily of integrated circuit U650. This IC accepts analog and digital control signals from various parts of the instrument and, depending on the control data string clocked into its internal control register from the Microprocessor, will change control signals that it sends to other, signal-handling circuits.

In the course of developing waveform displays, the Display Sequencer selects one or more vertical channels, sets the trigger source, and selects the horizontal display mode. In most cases, the trigger selection does not change after it has been set unless a front-panel trigger control is changed. An exception is that in VERT TRIGGER MODE, the trigger source tracks the sequencing of the vertical channels (unless AUTO LVL MODE, or CHOP VERTICAL MODE is also selected). Trigger source selection lines are changed only during trigger holdoff time between sweeps.

Fifty-five bits of serial data from the processor defining the instrument's operating sequence are applied to the Display Sequencer data input, pin 25. The data string is clocked into U650 to the internal control register by the processor-generated control clock applied to pin 24. The data string is organized in several fields, with each field defining the operating mode of one specific instrument function.

Display Sequencer U650 controls the various functions defined by the data fields by setting the levels of the associated control lines. The functions and controlling signal lines for each function areas follows:

VERTICAL DISPLAY SELECTION. CH 1, CH 2, CH 3, CH 4, ADD, and Readout Y signals are selected by the $\overline{VS1}$, $\overline{VS2}$, $\overline{VS3}$, and $\overline{VS4}$ control signals. See the Vertical Channel Switch description for further information.

HORIZONTAL DISPLAY SELECTION. A Sweep, B Sweep, CH 1 (for X-Y displays) and Readout X are selected by the $\overline{HSA}$ and $\overline{HSB}$ control signals. See the Horizontal Output Amplifier description for further information.

TRIGGER SOURCE SELECTION. CH 1, CH 2, CH 3, CH 4, ADD, Line, and a sample of the vertical output signal (for calibration purposes only) are selectable as the Trigger SOURCE by the $\overline{SR0A}$, $\overline{SR1A}$, $\overline{SR2A}$, $\overline{SR0B}$, $\overline{SR1B}$, and $\overline{SR2B}$ control lines (pins 28, 27, 29, 32, 31, and 30 respectively). See the A/B Trigger description for further information.

TRIGGER HOLD OFF. Sweep recovery time and the circuit initialization time required when front-panel controls are changed are controlled by the THO (trigger holdoff) signal.

DELTA TIME (Δt) DELAY SELECTION. DLY REF 0 or DLY REF 1 is selected by the $\overline{DS}$ (delay select) signal.

TRIGGER and SWEEP ACTIVITY (STATUS). The activity of the Trigger and Sweep circuits, as indicated by the $\overline{SGA}$, $\overline{SGB}$, $\overline{TSA}$, and $\overline{TSB}$ lines, is reported to the Microprocessor via the TSO (trigger status output) line when clocked by the $\overline{TSS}$ (trigger status strobe) signal.

INTENSITY CONTROL. The readout intensity, display intensity, and display intensity compensation are controlled by the BRIGHT output level.

DISPLAY BLANKING. Display blanking for CHOP VERTICAL MODE, Readout transitions, and front-panel control changes is controlled by the BLANK output.

READOUT CONTROL. The vertical selection, horizontal selection, and intensity controls are all set to their readout modes either at the end of an A Sweep ($\overline{SGA}$ goes HI) or in response to a readout request (ROR) from the Readout circuitry (fig. FO-13, sheet 2). While in the readout mode, the BLANK control signal is driven by the readout blank (ROB) input signal on pin 5 (also from the Readout circuitry). The readout active line (ROA, pin 6), when set LO, tells the Readout circuitry that readout dots may be displayed if necessary. The $\overline{ROA}$ signal is always set LO at the start of the trigger holdoff time following sweeps, and it is held there until the holdoff time is almost over. This allows the majority of hold off time to be used for displaying readout dots. The Display Sequencer will switch the ROA signal back to HI before the end of holdoff so that the readout display does not interfere with display of the vertical signal at the triggering event.

TRACE SEPARATION. Vertical separation between the A Sweep trace and the B Sweep traces (for alternate horizontal sweep displays), and between the reference B Sweep trace and the delta B Sweep trace (when delta time is selected in B Sweep only mode), is enabled by the TS1 + TS2 output.

X10 HORIZONTAL MAGNIFICATION. Horizontal X10 magnification is controlled by the MAG output.

CALIBRATOR TIMING. The 5-Hz to 5-MHz drive signal to the Calibrator circuitry is provided by the CT output.

DELAY GATE OPERATION. Analog Switches U850B and U850C select the delay references for each sweep. Depending on the display mode and point in the display sequence, the DS control signal (U650 pin 40) routes one of the two analog delay references through U850B and U850C to the two sweep hybrids. The selected reference level is compared against the changing sweep ramp voltages to generate the delay gates that control each sweep's functions.

After an A Sweep has been initiated by a trigger, a delay gate circuit within U700 compares the A Sweep ramp voltage to the selected delay reference. When the sweep ramp reaches the delay reference level, the DG (delay gate) output goes LO, enabling the B trigger portion of U500 and B Sweep hybrid U900. Then, when B triggering occurs (for TRIG AFT DLY mode), the A/B Trigger hybrid sets the TGB (trigger gate B) signal LO, initiating the B Sweep. In RUN AFT DLY mode, however, the TGB signal to U900 is held LO, and the B Sweep is initiated at the end of the A Sweep delay time when the A Sweep delay gate goes LO.

STATUS MONITORING. As the Display Sequencer controls the display system in real time, it continually monitors the trigger and sweep operations and updates the internal trigger status register accordingly. The Microprocessor checks the contents of this register every 3.3 ms to determine the current status of the trigger and sweep circuitry. The Microprocessor reads the trigger status register by generating a series of trigger status strobe (TSS) pulses (U650 pin 19) to serially clock the contents of the register out to the TSO (trigger status output) line and onto the Data Bus (via Status Buffer U2220) (fig. FO-4, sheet 1). The system status information obtained by this check is used for AUTO LVL triggering, AUTO free-run triggering, detecting the completion of all sweeps in a SGL SEQ display, automatic measurement functions, and during instrument calibration.

INTENSITY CONTROL. The Display Sequencer controls the Intensity for both sweep and readout displays. The analog levels at pins 22 and 23 determine the basic intensity level of the displays. Two internally generated DAC currents (developed by multiplying the IREF current at pin 20 by two processor- generated numbers stored internally) are added to the basic intensity level currents to produce the display intensity seen on the CRT (see table 3-1). The two DAC currents added to the INTENSITY current are dependent on sweep speed, number of channels being displayed, and whether or not the X10 MAG feature is in use. These added currents increase CRT beam current and hold the display intensity somewhat constant under the varying display conditions. The resulting current is applied to Z-Axis Amplifier U950 (fig. FO-11, sheet 2) from the BRIGHT output of the Display Sequencer (pin 21).

To produce the intensified zone on the A Sweep trace for A intensified by B Sweep displays, an additional current is added to the CRT drive signal by the Z-Axis Amplifier during the concurrence of the SGAZ and SGBZ (sweep gate A and B z-axis) signals.

Table 3-1

Intensity Control

Type of Display	Horizontal Selects		Resulting Current at BRIGHT Output
	HSA	HSB	
X/Y	LO	LO	DI (Display intensity only)
A Sweep	LO	HI	DI + A SWP DAC current
B Sweep	HI	LO	DI + B SWP DAC current
Readout	HI	HI	ROI (readout intensity) only

The readout intensity (ROI) level, controlled from the front-panel READOUT INTENSITY pot (via MUX U2530 and sample-and-hold U2630A and C2732). The Microprocessor increases readout intensity when the pot is rotated either direction from center. Minimum readout intensity current occurs at the midpoint of the READOUT INTENSITY pot rotation. The Microprocessor also detects to which side of center the READOUT INTENSITY control is set. Depending on the status received, the processor sets up the Readout circuitry (fig. FO-13, sheets 1 and 2) to display

either all of the readout information or just the "delta type" readouts.

Blanking of the CRT display during CHOP VERTICAL MODE displays or when switching between dot positions in the readout displays is controlled by the Display Sequencer's BLANK output (pin 3). When the signal is LO, the CRT z-axis is turned onto the selected intensity level; when HI, the CRT display is blanked.

READOUT CONTROL. The readout request signal (ROR), the readout active signal (ROA), and the readout blank signal (ROB) control readout displays. During the first part of the holdoff time, up until one or two holdoff ramps before holdoff time ends (dependent on the sweep rate), the Display Sequencer sets the ROA signal line LO. While the ROA line is LO, the Readout circuitry may display readout character dots if necessary. During readout displays, the horizontal and vertical select signals ($\overline{HSA}$, $\overline{HSB}$, $\overline{VS1}$, $\overline{VS2}$, $\overline{VS3}$, and $\overline{VS4}$) are all set HI. This deselects the waveform-related sweep and deflection signals and gives display control to the Readout circuitry. While readout information or cursors are being displayed, the BLANK output signal (pin 3) is controlled by the readout blank ($\overline{ROB}$) signal from the Readout circuitry, and the readout intensity (ROI) signal pin (pin 23) controls the BRIGHT output level.

During holdoff, the Display Sequencer always sets the readout active ($\overline{ROA}$) line LO. As previously described, setting the $\overline{ROA}$ signal LO allows the Readout circuitry to display readout dots. In some settings of the SEC/DIV switch, with adequate trigger rates, holdoff time is provided for the Readout circuitry to display all the readout information without causing noticeable display flicker.

In those cases where the holdoff time is insufficient to prevent flicker, a portion of the Readout circuitry will request display control by setting the readout request ($\overline{ROR}$) signal LO. The Display Sequencer recognizes all readout requests immediately and switches the horizontal and vertical select lines to the readout display mode. The Readout circuitry displays one readout dot and then resets the readout request HI to switch back to the display of waveforms. Readout requests occur as required during sweep times, keeping the readout display up to date. (See "Readout" description for further information).

TRACE SEPARATION. The TRACE SEP feature is used to position the alternate B Delayed Sweep trace downward from the A Sweep when Alternate Horizontal Display Mode (TURN-ALT) is active. It is also used when either the Δ t or 1/ Δ t measurement function is used with B Sweep only displays. In the latter case, the TRACE SEP control vertically positions the trace(s) associated with the Δ control.

When the Display Sequencer determines that trace separation should be active, the LO TSIN level at pin 7 is routed to pins 9 and 8, the TS1 and TS2 outputs (connected together). This LO output turns off transistor Q600 (fig. FO-11, sheet 1), thereby enabling the trace separation voltage from the front-panel TRACE SEP pot (via MUX U2530 and sample-and-hold U2630C and C2631) to be applied to pin 42 of Vertical Output Amplifier U600. To disable the trace separation function, the Display Sequencer sets the TS1 + TS2 control line HI, turning on Q600 and shunting the trace separation signal to ground.

X10 MAG SELECT. The MAG (sweep magnifier) output (pin 39) drives the magnifier control input (pin 14) of Horizontal Output hybrid U800 and the select input (pin 9) of analog switch U860C (fig. FO-11, sheet 2). Analog switch U860C routes a magnifier gain-control voltage to the Horizontal Amplifier to set the horizontal gain for the X10 magnified displays.

CH 2 DELAY OFFSET. The $\overline{VS2}$ (vertical select, channel 2) output applied to analog switch U860B at pin 10 routes a calibrated offset voltage from sample-and-hold buffer U165D to both sweep hybrids when the Channel 2 vertical signal is being displayed. The offset voltage is used to eliminate the apparent propagation delay between the Channel 2 and the Channel 1 (or CH 2 and either one of the other channels). A step in the calibration procedure allows use of the front-panel Channel 2 Delay Offset feature to be either enabled or disabled, When enabled, the Channel 2 offset may be adjusted up to ±500 ps (with respect to Channel 1) using the Δ control.

CALIBRATOR TIMING. The Calibrator timing signal (CT) from the Display Sequencer is generated by an internal counter. The counter divides the 5-MHz clock input at pin TC (timing clock) by a value that is a function of sweep speed, The resulting square-wave output signal drives the Calibrator circuit. For ease of sweep rate verification, the Calibrator signal provides a display of five complete cycles on the CRT at sweep speeds from 100 ms per division to 0.1 µs per division. Below 100 ms per division, the Calibrator output frequency remains at 5 Hz; and above 0.1 µs per division, the Calibrator frequency remains at 5 MHz.

When chopping between vertical channels, the Display Sequencer adds a 200-ns skew at the end of some sweeps to desynchronize the chop frequency from the sweep speed (to prevent the sweep from locking onto the chop frequency). Due to this, the Calibrator signal has an irregular pulse repetition characteristic between sweeps. This will not be apparent when observing the Calibrator signal on the instrument CRT since the skew is synchronized to the sweep, but may be observed when the Calibrator output signal is used with other instrumentation. The skew can be eliminated by setting the instrument to SGL SEQ Mode (to shut off the sweeps).

Holdoff Circuitry

The holdoff circuit, used to delay the start of a sweep until all circuits have recovered from the previous sweep,

is made up of U165C, Q154, Q155, and associated components. Operational Amplifier U165C and capacitor C180 form a sample-and-hold buffer used to set the charging current for holdoff-ramp integrating capacitor C171. A control voltage from digital-to-analog converter (DAC) U2201 (fig. FO-4, sheet 2) via multiplexer U170 (fig. FO-9, sheet 1) is stored on C180. The stored voltage level sets the base voltage for both Q154 and Q155 via amplifier U165C. Transistors Q154 and Q155 form a current-mirror with nearly equal collector currents. Transistor Q154 is a current-to-voltage converter that provides negative feedback to U165C, setting loop gain. Transistor Q155 acts as a constant-current source that charges integrating capacitor C171, producing a linear holdoff ramp.

A comparator circuit in U650 detects when the ramp crosses a predefine threshold voltage (approximately + 3 V). When the threshold is reached, pin 10 of U650 (HRR) goes LO and the integrating capacitor is discharged. At that same time, an internal counter that keeps track of the hold off ramp cycles is incremented. The ramps continue to be generated and reset until the holdoff ramp counter has counted the number of ramp cycles defined by the sweep-rate-dependent holdoff data field stored in the Display Sequencer control register. At all sweep speeds except 5 ns per division, the count is at least two holdoff ramp cycles. The front-panel variable HOLDOFF control affects holdoff time by varying the HOLDOFF control voltage to U165C (from the DAC), changing the charging rate of integrating capacitor C171.

When holdoff time requirements are met (determined by the number of ramps counted), the Display Sequencer sets the THO (trigger holdoff) signal LO. This enables both the A Sweep hybrid (U700) and the A Trigger circuitry in U500. The Trigger circuit begins monitoring the selected trigger source line and, when a triggering event is detected that meets the triggering requirements defined by the stored control data, initiates the A Sweep and sets the TSA (trigger status, A Sweep) line to Display Sequencer U650 LO (indicating that the A Sweep has been triggered).

As the A Sweep circuit (U700) responds to the trigger, it sets the $\overline{\text{SGA}}$ (sweep gate A) line LO (via U980A) indicating that an A Sweep is in progress. After the sweep has run to completion, U700 sets the $\overline{\text{SGA}}$ line HI signaling the end of sweep. The Display Sequencer then sets the THO line HI, resetting A/B Trigger hybrid U500 and A Sweep hybrid U700 in preparation for the next sweep.

Triggers

The A/B Trigger hybrid (U500) and associated circuitry select the triggering signal source for each horizontal sweep as directed by the Display Sequencer. When the proper triggering criteria to initiate a sweep are detected, a triggering gate signal is produced to start the selected sweep.

Control data from the processor defining trigger mode, coupling, and slope parameters for each trigger is clocked into two storage registers internal to U500 by the A TRIG CLK signal on pin 23 ($\overline{\text{CCA}}$) and the B TRIG CLK signal on pin 47 ($\overline{\text{CCB}}$). The Display Sequencer selects the A trigger source with the $\overline{\text{SR0A}}$, $\overline{\text{SR1A}}$, and $\overline{\text{SR2A}}$ signal lines; the B trigger source is selected using the $\overline{\text{SR0B}}$, $\overline{\text{SR1B}}$, and $\overline{\text{SR2B}}$ signal lines. Table 3-2 illustrates trigger source selection.

Table 3-2
Trigger Source Selection

Select Inputs			Trigger
SR2A(B)	SR1A(B)	SR0A(B)	Source
H	H	L	CH 1
H	L	H	CH 2
H	L	L	ADD
L	H	L	CH 3
L	L	H	CH 4
H	H	H	LINE (or BWLB)[1]

[1]During calibration routines from the Diagnostic Monitor.

To initiate the A Sweep, the trigger hybrid compares the selected signal to the analog trigger level input at pin 13, the TLA (trigger level A). B trigger signals are compared to the TLB (trigger level B) signal at pin 37 when trigger B Sweeps are required. When the proper trigger signal is detected, U500 outputs a trigger gate ($\overline{\text{TGA}}$ or $\overline{\text{TGB}}$) to the appropriate sweep circuit to initiate that sweep.

When an A Sweep is initiated, the trigger-status line ($\overline{\text{TSA}}$) (trigger status A, U500 pin 20) goes LO to signal the Display sequencer that a trigger has occurred. Until the sweep is completed, the $\overline{\text{TGA}}$ signal on pin 18 (or $\overline{\text{TGB}}$ signal on pin 42 for B Sweeps) remains LO. After the A Sweep is completed, the A Sweep Gate ($\overline{\text{SGA}}$) from A Sweep hybrid U700 (via U980A) will go HI, causing the Display Sequencer to set its THO (trigger holdoff) line (pin 13) HI. This resets the sweep hybrid and the trigger hybrid in preparation for the next trigger event.

The B Trigger Holdoff input (THOB, U500 pin 39) is held HI (keeping the B Trigger reset) until the A Sweep Delay Gate (DG, U700 pin 41) goes LO (see the following A Sweep description). When DG goes LO, the B Trigger portion of U500 is enabled. The B Sweep Trigger functions in a manner similar to that of the A Sweep Trigger just described. During a parametric measurement, the THOB line may be driven by either A Sweep Delay Gate, or BHO from the measurement PAL, U975. If CNTL1 is LO, THOB is driven by A Sweep Delay Gate through the buffer transistor Q741. If CNTL1 is HI, Q741 is held off by Q742 and THOB is driven by BHO.

A Sweep

When properly triggered, the A Sweep circuit generates linear sweep ramps of selectable slopes. When amplified, these ramp signals horizontally sweep the CRT beam across the face of the CRT. The A Sweep circuitry consists of U700, Q709, Q710, Q741, U910B, U980A, and associated components.

The A Sweep ramp signal is derived by charging one of several selectable capacitors from a programmable constant-current source. Capacitor selection depends on the sweep-rate-dependent control data (CD) on pin 29 that is clocked into A Sweep hybrid U700 by the ASWP CLK on pin 28 ($\overline{CC}$). This sweep-rate data causes some internal logic to select either hybrid-mounted capacitors CT0 or CT1 or capacitor C708 at the CT2 (timing capacitor two) pin. An additional capacitor, C709, maybe selected (via Q709 and Q710) if the control data asserts the TCS (timing capacitor select) signal on pin 9. TCS will be HI for A Sweep speeds slower than 1 ms per division. Capacitor C707 and associated circuitry forma linearity compensation circuit.

The constant current to charge the selected capacitor is derived from the DAC-controlled voltage, A TIM REF (A timing reference), generated on the Control Board. The ITREF input (U700 pin 24) is held at zero volts by an internal programmable current-mirror circuit at that input (see fig. 3-4). The A TIM REF voltage is applied to the current mirror via series resistors R723 and R724 to establish the input reference current (ITREF). The output of this current mirror is related to the input reference current by a multiple "M" that is set by a control data field stored in the internal control register of U700. The derived output current (M X ITREF) is connected to another programmable current-mirror circuit, U910B, external to the hybrid. The output of U910B provides the actual charging current and is a control-data-selected multiple of the M X ITREF current.

At the time of calibration, the processor will vary the ITREF input current until the slope of the output ramp for specific current-mirror/timing capacitor combinations is precisely set. The values of A TIM REF at these settings allow the processor to precisely calculate the characteristics of the current-mirror circuits at their various multiplication factors and the charging characteristics of the timing capacitors. These values are stored as calibration constants in nonvolatile memory RAM U2460 (fig. FO-3, sheet 2).

Once the calibration constants are set, any setting of the SEC/DIV switch causes the Microprocessor to recall the associated calibration constants from RAM. The processor then calculates the proper value of A TIM REF based on the selected timing capacitor and the current-mirror multiplication factors.

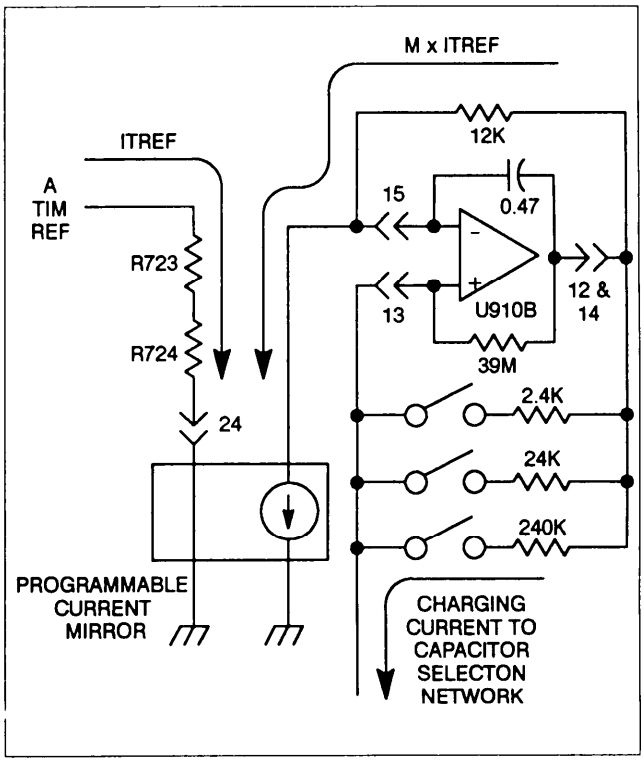


Figure 3-4. Sweep generator.

If the SEC/DIV VAR control is out of the calibrated detent position, the processor will decrease the A TIM REF voltage from the maximum, in-detent value by an amount proportional to the position setting of the VAR control. At the maximum, fully counterclockwise setting of the VAR control, the ITREF current is one-third that of the normal, in-detent current.

For A Sweep hybrid U700 to initiate a sweep at the selected rate, the $\overline{AUXTRIG}$ (auxiliary trigger) input (pin 3), the THO (trigger holdoff) line from the Display Sequencer (on pin 1), and the $\overline{TRIG}$ (trigger) line from the trigger hybrid (on pin 2) must all be LO. With these three inputs LO, the A SWEEP ramp begins, and the sweep gate (SG) output (pin 45) goes LO. The buffered sweep gate signal ($\overline{SGA}$) at the output of U975 returns to the Display Sequencer through R981 to indicate that the A Sweep is active. The sweep gate signal is used by various other circuits for their timing activities and is held LO until the A SWEEP ramp ends. The buffered (negative) sweep gate is inverted and routed to the rear-panel A GATE output connector via U975.

Diodes CR752 and CR753 and associated components form a charging network that permits delaying the timing of the end-of-A-Sweep gate signal ($\overline{SGAZ}$) for B Sweep displays. For normal A Sweep operation with the $\overline{SGBZ}$ signal HI, the SGAZ signal will end quickly, since the capacitance associated with Z-Axis hybrid U950 input

(diagram 6) will be charged positively through both R753 and R754. For B Sweep operation ($\overline{SGBZ}$ is LO), the end of the SGAZ gate signal will be delayed slightly (with respect to the normal sweep gate) since charging of the Z-Axis input capacitance will be at a slower rate through R754 only. This allows more of the B Sweep to be displayed than would otherwise be possible.

The A Sweep Delay Gate (DG) signal acts as the trigger holdoff (THO) signal for the B Sweep and the B Trigger circuitry. It is generated by comparing the A SWEEP ramp voltage to the selected delay reference (DR) level from analog switch U850C. As the ramp voltage crosses the delay reference level, the delay gate (DG) output signal goes LO, removing the HI THO level to the B Sweep. This enables the B Sweep to run immediately in RUN AFT DLYB Trigger Mode or, when in TRIG AFT DLY B Trigger Mode, enables the B Sweep to run when a B triggering event occurs.

The BDCA (A Sweep bypass-delay comparator) input (U700 pin 39) is a data bit from Auxiliary Control Register U140 (fig. FO-9, sheet 1) that, when HI, sets the A Sweep DG output LO at the beginning of the A Sweep. This enables the B Sweep to run immediately at the start of the A Sweep and is used for calibration purposes.

The capacitive load (part of the etched-circuit board) at the RDA (retrace delay adjust) input (U700 pin 4) is used to delay the retrace of the sweep until the Z-Axis drive is fully turned off in response to the SGAZ gate going HI. This delay prevents any part of the retrace from being seen.

B Sweep

Operation of B Sweep hybrid U900 is similar to that just described for the A Sweep with the following exceptions: the THO input (and thus sweep enabling) is controlled by the A Sweep hybrid or the measurement PAL and not the Display Sequencer (see the preceding A Sweep description). The timing capacitor select output, TCS, is not used, and only three timing capacitors are selectable (two on the B Sweep hybrid at CT0 and CT1 and one externally at CT2).

Calibrator

The Calibrator circuit, composed of Q550, U165B, U550A, B, C, and D, and associated components, generates a square wave output of precise amplitude and frequency characteristics. The CALIBRATOR signal provided at the front-panel output connector is useful for adjusting probe compensation and verifying VOLTS/DIV, SEC/D IV, and Δt (delta time) calibration. Output frequency is controlled by the Display Sequencer and is set to display five cycles across the ten CRT graticule divisions at sweep speed settings from 100 ns per division to 100 ms per division. This feature allows quick and easy verification of the sweep rates. The Calibrator circuitry is essentially a voltage regulator that is alternately switched on and off, producing the square-wave output signal.

When the timing signal (CT) from the Display Sequencer to the base of U550D is LO, U550C (configured as a diode) is forward biased, shunting bias current away from Q550, keeping it turned off. When transistor Q550 is off,the front-panel CAL OUT connector is pulled to ground potential through R558, setting the lower limit of the CALIBRATOR output signal.

As the CAL signal goes from LO to HI, the emitter of U550D is pulled HI to reverse bias U550C. Bias current for Q550 is established, and the transistor is turned on. The voltage at the emitter of Q550 rises to a level of + 2.4 V, determined by the voltage regulator composed of U165B, U550A, U550B, and associated components. This regulated level is applied to the front-panel CALIBRATOR connector through a voltage-divider network composed of R557 and R558. This produces an output voltage of 400 mV with an effective output impedance of 50 Ω.

Since the frequency of the CALIBRATOR signal is controlled by the same divider chain that controls operation of the vertical chopping rate, the intentional 200-ns shift added to the chop signal at the end of some sweeps (to desynchronize the chopping rate from the sweep rate) shows upon the CALIBRATOR signal as an irregular-width pulse. This shift is not apparent when viewing the Calibrator signal on the instrument providing the signal (since the skew occurs during sweep-retrace time), but it should be taken into account when using the CALIBRATOR signal with other instrumentation. The skew can be eliminated from the signal by setting the instrument TRIGGER MODE to SGLSEQ (to shut off the sweeps).

PARAMETRIC MEASUREMENTS

The VOLTS Parametric Measurement is made using the same methods and circuitry that is used in the Auto Level trigger mode to find the peak voltages. The accuracy of the VOLTS measurement is based on the accuracy of the trigger level and the DC balance of the instrument.

All of the time-based Parametric Measurements use the A and B Sweep gates and delay gates as the basis for the measurements. The measurement PAL, U975, controls the signal flow while in the Parametric mode. The measure ment flip-flop, U980B, reports the state of a variety of conditions to the SLIC through the $\overline{SGB}$ line. The SLIC data is read by the processor system and used to compute the desired measurement.

VERTICAL CHANNEL SWITCH AND OUTPUT AMPLIFIERS

The Vertical Channel Switch (fig. FO-11, sheets 1 and 2) selects the signal source for vertical deflection of the CRT beam. The Vertical, Horizontal, and Z-Axis output amplifiers provide the signal amplification necessary to drive the CRT.

Vertical Channel Switch

The Vertical Channel Switch consists of hybrid Channel Switch U400, that selects one of the vertical signals for application to the Vertical Output Amplifier, and a combined switch/amplifier circuit that converts the single-ended readout vertical signal into a differential signal for application to the Channel Switch.

Channel selection is controlled by the Display Sequencer $\overline{VS1}$ through $\overline{VS4}$ signals applied to the vertical channel selection pins (pin 24, pin 25, pin 13, and pin 14 respectively). (See table 3-3 for the Vertical Display Selection.) When a vertical select line is LO, the associated input signal pins are connected to the differential output (+ OUT, pin 11 and -OUT, pin 3). The CH 5 input signal (Readout Vertical) is added to the output whenever both the $\overline{VS3}$ and $\overline{VS4}$ select signals are HI but will only contain readout information when the readout select logic (U975A and U975C) detects that the Display Sequencer has set both the Horizontal Select signals ($\overline{HSA}$ and $\overline{HSB}$) HI (readout selected).

Table 3-3
Vertical Display Selection

Select Inputs				Vertical
VS1	VS2	VS3	VS4	Display
L	H	H	H	CH 1
H	L	H	H	CH 2
L	L	H	H	ADD
H	H	L	L	CH 3
H	H	H	L	CH 4
H	H	H	H	Readout (Y)

READOUT SWITCH/AMPLIFIER. Transistors U485A, U485B, U485C, U485D, and U475C, along with their associated components, make up ananalog switch circuit that routes either the readout vertical signal at the base of U485A or the ground reference at the base of U485C to the output at the emitter of U475C. The signal selected depends on the complementary voltages applied to the emitter junctions of the two emitter-coupled transistor pairs, U485A and B and U485C and D. The selection voltages are developed by voltage-divider networks on the complementary logic outputs of U975A and U975C.

When readout information is to be displayed, the horizontal select inputs to U980B and U980C go HI and the output of NAND-gate U975C goes LO. The LO applied to the divider network of R498, R484, and R471 pulls the anode of CR484 low enough to reverse bias it. This forward biases the emitter-coupled pair U485A and B via R483. NAND-gate U975A inverts the LO and applies a HI to the junction of R497 and R485. The HI forward biases CR485, and the emitters of U485C and D are pulled to a level in excess of + 2 V, reverse biasing the transistor pair. With U485C and D reverse biased, the ground reference level at the base of U485C is isolated from the output, while the readout vertical information is allowed to pass through the forward-biased transistor pair.

When readout information is not being displayed, a HI is present at the output of NAND-gate U975C. The HI forward biases CR484 and, when inverted by U975A, reverse biases CR485. With the biasing conditions reversed, the transistor pair of U485C and D becomes forward biased and U485A and B becomes reversed biased. The ground reference level present at the base of U485C is coupled to the output, while the readout vertical signal is isolated.

The output signal (either the readout vertical signal or the ground reference level) is applied to the CH5 + input of Channel Switch U400 via R495 and R412. The inverting amplifier circuit composed of U475A, U475B, U475D, and associated components inverts thereabout vertical signal for application to the CH5- input. The amplifier is an inverting unity-gain configuration with transistors U475A and U475B connected as an emitter-coupled pair. The base of U475A is referenced to ground through R482. The base of U475B is pulled to the same level by the negative feedback from emitter-follower U475D through R478. The noninverted signal is applied to the base of U475B through R492 and will attempt to increase or decrease the current to the base of U475B, depending on the amplitude and polarity of the signal. However, the negative feedback from the collector of U475B (via U475D and R478) will hold the base of U475B at the ground reference level. The feedback current through R478 develops a voltage drop across R478 that is equal in amplitude but opposite in polarity to the non inverted vertical readout signal. The inverted readout signal is applied to the Channel Switch on pin 2 (CH5-) via R476 and R402.

The HF ADJ (high-frequency adjust) potentiometer R417 and resistor R416 (connected to pin 16) adjust the high-frequency response of the Channel Switch hybrid.

Vertical Amplifier

Vertical Amplifier U600 is a hybrid device that provides the final amplification of the selected vertical signal, raising it to the level required to drive the CRT deflection plates. Vertical deflection signals from the Vertical Chan-

nel Switch are delayed approximately 78 ns by Delay Line DL100. This delay allows the Sweep and Z-Axis circuits to turn on before the triggering event begins vertical deflection of the CRT beam, thereby permitting the operator to view the triggering event. The bridged-T network, composed of inductors and capacitors built into the circuit board, corrects phase-distortion introduced by the delay line. The RLC networks connected between the output pins of U400 are adjusted during calibration to obtain the correct overall high-frequency response of the vertical deflection system. The vertical signal from the Delay Line is applied to pins 10 and 3 of U600. The RL network connected between pins 8 and 5 (COMPA and COMPB) of U600 compensates the signal for the skin-effect losses associated with the delay line.

Amplifier gain and vertical centering are adjusted by R638 and R639 respectively, primarily to match the amplifier hybrid to the CRT installed in the instrument. The Dynamic Centering circuit sinks an intensity-dependent correction current away from the vertical centering input at pin 39. The correction signal holds the vertical centering stable over a wide range of varying display intensities. Readout jitter adjustment pot R618 is used to minimize thermal distortion in the output amplifier to reduce jitter in the display readout.

The vertical output signal at pins 28 and 33 of U600 (OUT A and OUT B) is applied to the vertical deflection plates of the CRT (fig. FO-15, sheets 1 and 2) via L628 and L633. The deflection plates form a distributed-deflection structure that is terminated by a hybrid resistor network. One element of the terminating network is an adjustment potentiometer used to match the network impedance to that of the CRT.

BANDWIDTH LIMITING. Bandwidth limiting coils L644 and L619, along with capacitors built into U600, form a three-pole filter used to roll off high-frequency response of the Vertical Output amplifier above 20 MHz. To limit the vertical bandwidth, the $\overline{\text{BWL}}$ (bandwidth limit) input to U600 (pin 16) is pulled LO. It may be set LO either by the BWL control data bit from Auxiliary Control Register U140 (fig. FO-9, sheet 1) when the operator selects the Bandwidth Limit feature or automatically by the output of NAN D-gate U975A in the Vertical Channel Switch circuitry (via CR616) when the readout is being displayed.

TRACE SEPARATION. The voltage applied to the TS (trace separation) input of U600 (pin 42) is used to offset the output levels to vertically shift the position of the trace on the CRT. During normal sweep displays, TS1 + TS2 signal applied to the base of Q600 by the Display Sequencer (fig. FO-10, sheet 1) is HI, and the transistor is turned on. The TRACESEP level at the junction of R642 and CR600 is shunted to ground, and no offsetting at the output signal will occur. For those displays in which trace separation should occur, the Display Sequencer switches the base of Q600 to ground level to turn off the transistor. The trace separation level set by front-panel TRACE SEP control R3190 (via MUX U2530 and sample-and-hold circuit U2630C and C2631) is applied to the TS input of U600, and a corresponding offset of the displayed trace will occur.

BEAM FIND. As an aid in locating off-screen or overscanned displays, the instrument is provided with a beam-finding feature. When the front-panel BEAM FIND button is pushed, the beam-find input pin (BF, pin 15) of U600 will be pulled HI. While BF is HI, the dynamic range of Vertical Output Amplifier U600 is reduced, and all deflected traces will be held to within the vertical limits of the CRT graticule.

Also, the activation of the BEAM FIND switch is detected by the microprocessor during its normal Front-Panel Switch Scanning.

OUTPUT PROTECTION CIRCUIT. A current-limit circuit composed of transistors Q623 and Q624 protects the Vertical Output Amplifier from a short-circuited output or a bias-loss condition. Either of these fault conditions will cause excessive current to flow into pins 30 and 31 of U600. Current in FET Q624 is limited to the IDSS current, so the voltage at pins 24, 30 and 31 will drop. This decreases the forward bias on pass-transistor Q623 and lowers the voltage at pin 23 of U600 enough to provide some degree of protection for the device.

Horizontal Amplifier

The Horizontal Amplifier circuitry consists of a Horizontal Output Amplifier U800, a unity-gain buffer amplifier made up of the five transistors in U735, and associated components.

UNITY-GAIN BUFFER AMPLIFIER. The amplifier circuit composed of U735A, B, C, D, and E along with their associated components, form a unity-gain amplifier that buffers the ramp signal from A Sweep Generator U700 to the Horizontal Output Amplifier. Transistors U735C and D form a differential pair with the negative excursion of their emitters limited to -5 V (clamped by U735E). Negative feedback from the collector of U735C to its base is via emitter-followers U735A and B (in parallel) which drive the A Sweep input (pin 18, A+) of Horizontal Output Amplifier U800.

HORIZONTAL OUTPUT AMPLIFIER. Integrated circuit U800 provides the final amplification of the selected horizontal-deflection signal required to drive the CRT. One of the single-ended input signals applied to the four input pins is converted to a differential-output signal at the output pins of the amplifier. The four deflection signals to U800 are: the A sweep (pin 18, A+), the B Sweep (pin 16, B+), the Readout Horizontal signal (pin 17, RO) and the Channel 1 signal (used for horizontal deflection of the X-Y displays) at pin 20, the X+ input pin. Signal selection is done by an internal channel switch and is controlled by the HSA (horizontal select A) and HSB (horizontal select B) signals from the Display Sequencer (see table 3-4).

Table 3-4
Horizontal Display Selection

Control Level		Selected
HSA	HSB	Signal
H	H	Readout (X)
H	L	B Sweep Ramp
L	H	A Sweep Ramp
L	L	X Input (from CH 1)

Switching between unmagnified (X1) gain and magnified (X10 gain) is also controlled by signals from the Display Sequencer. For normal horizontal deflection, the $\overline{MAG}$ signal on pin 14 of U800 is HI, and the gain of the output amplifier produces normal sweep deflection. Precise X1 deflection gain is set by adjusting X1 Gain pot R860. When the X10 MAG feature is selected, amplifier gain for the magnified sweeps is increased by a factor of 10. The $\overline{MAG}$ signal from the Display Sequencer goes LO when magnified sweep is to be displayed. This switches the amplifier gain and switches analog switch U860C from the X1 position to the X10 position. Amplifier gain in the magnified mode is adjusted by adding or subtracting a small bias current using X10 Gain control R850. DC offsets in the amplifier and CRT are compensated for, using Horiz Centering pot R801 to precisely center the display. An intensity-dependent position correction signal, used to hold the horizontal centering stable over a wide range of varying display intensities, is also added at this point by the Dynamic Centering circuitry.

Timing and linearity of the sweep is affected by the amplifier transient response; and Trans Resp pot R802, connected to pin 2, is adjusted during calibration for optimum accuracy of the high-speed sweeps.

As with the Vertical Output Amplifier, the Beam Find feature reduces the dynamic range of the Horizontal Output Amplifier. While the front-panel BEAM FIND button is pressed in, a HI is placed on U800 pin 15 via pull-up resistor R615, and the horizontal deflection is reduced, moving horizontally off-screen displays to within the graticule viewing area.

Z-Axis Amplifier

Z-Axis Amplifier U950 turns the CRT beam off and on at the desired intensity levels as the oscilloscope goes through its display sequence. The BRIGHT (brightness) signal applied to U950 pin 44 from the Display Sequencer U650 (fig. FO-10, sheet 2) is amplified to the level required to drive the CRT control grid (via the DC Restorer circuitry) and sets the CRT beam intensity. The BLANK input signal applied to U950 pin 5, also from the Display Sequencer, blanks the trace during sweep retrace, chop switching, and readout blanking by

reducing the VZ OUT signal to a blanked level. Sweep gate z-axis signals ($\overline{SGAZ}$ and $\overline{SGBZ}$) from the A Sweep and B Sweep hybrids (U700 and U900) respectively, (fig. FO-10, sheets 1 and 2) are applied to the Z-Axis Amplifier on pins 4 and 3. These signals turn the beam current on and off for the related displays and, when used in conjunction with the BLANK signal on pin 5, enable the sweeps to be blanked while still allowing the Readout circuit to blank and unblank the CRT for the readout displays.

Control signals applied to U950 pin 48, pin 2, and pin 1 ($\overline{HSA}$, $\overline{HSB}$, and $\overline{TXY}$ respectively) switch some internal logic circuitry to enable or disable different input signals for the various types of displays. Table 3-5 illustrates the effects of the various input signals on the output signal for different combinations of $\overline{HSA}$, $\overline{HSB}$, and $\overline{TXY}$.

The Z-Axis hybrid has an internal limiter circuit that prevents the CRT from being damaged during high-intensity, high-repetition-rate displays. A signal representative of the intensity setting and the sweep repetition rate is integrated on C957 and results in a control level at pin 7 of U950 used to limit intensity of the CRT beam. Maximum Grid drive is controlled by R949 on U950 pin 9.

Table 3-5
Blanking and Intensity Control Selection

Control Inputs			Intensity	Blanking	
TXY	HSA	HSB	Affected By	Affected By	Typical Display
X[1]	H	H	BRIGHT (RO level)	BLANK	Readout
X	H	L	BRIGHT, Z EXT	BLANK, SGAZ, SGBZ	Delayed Sweep
X	L	H	BRIGHT, SGBZ,Z EXT	BLANK, SGAZ	Main Sweep
L	L	L	BRIGHT, SGBZ,Z EXT	BLANK	X-Y
H	L	L	BRIGHT, SGBZ,Z EXT	BLANK, SGAZ	X-Y

[1]X = State doesn't matter.

Focus tracking for intensity (VZ OUT) level changes is provided by the VQ OUT (quadrapole output voltage) signal at pin 22 of U950. The VQ OUT signal varies the focusing voltages (and thus the focusing strength) of two quadrapole lenses in the CRT (fig. FO-15, sheet 2). The VQ OUT signal is related to the VQ OUT level exponentially and provides the greatest auto-focus control at high intensity levels. Gain of the VQ OUT signal is set by the High-Drive Focus adjustment, R1842. The VQ OUT signal also drives the Dynamic Centering circuit and holds the display position stable during wide-range intensity level changes.

Dynamic Centering

The circuit composed of U3401, U3402, and associated components generates compensating signals to offset positioning effects that occur in the CRT when the intensity is varied over a wide range. The VQ OUT signal from Z-Axis Amplifier U950 is exponentially proportional to the display intensity and dynamically controls the intensity-dependent offsets.

Dynamic Centering adjustment pots R3401 and R3407 set the gain and polarity of the signals at their related outputs by varying the current in the emitter circuit of one of two emitter-coupled pairs of transistors. Adjusting the bias level, at either pin 4, above ≈ -10.6V (determined by R3410 and R3411 at the complementary inputs, pins 1) will generate an inverted signal, while adjusting the bias levels below -10.6V will cause a noninverted signal. Amplitude of the resulting signal is dependent on how far from the -10.6V reference the bias is set. The output signal is added or subtracted from the position voltage applied to the Vertical and Horizontal Output Amplifiers. Both pots are adjusted so that position shifts due to display intensity variations are minimized.

READOUT

The Readout circuitry (fig. FO-13, sheets 1 and 2) is responsible for displaying the alphanumeric readout characters in the CRT. An eight-bit character code specifying each character (or cursor segment) to be displayed is written from the Microprocessor to a corresponding location in the Character RAM U2920 (a 2K by 8-bit, random access memory integrated circuit). Each of the following 128 locations in the RAM, address locations 0 through 63 for the first and fourth readout lines and 128 through 191 for the second and third readout lines, corresponds to one of the 128 possible character locations in the CRT readout display (see fig.3-5). The next 128 RAM locations, address locations 64 through 127 for the first and fourth readout lines and 192 through 255 for the second and third readout lines, are used to store cursor segment information for the display of the Δ V and Δ t measurement cursors. The eight-bit character code written to each location in RAM points to a block of addresses in Character ROM U2930. This block in the ROM contains the dot-position information for the specific character to be displayed at the associated CRT position.

Each character is made up of zero (for a space character) or more dots displayed in an eight-wide by sixteen-high dot matrix. Specific blocks of ROM addresses contain all the X-Y offset coordinates for the dots in a particular character in the readout. The coordinates are referenced to the lower-left corner of the character dot matrix. Each individual data byte in the block of ROM addresses contains both the X and the Y coordinates for one dot of the associated character.

To display a character, a combination of the character position on the CRT (the RAM address) and the byte of X-Y position data from Character ROM U2930 (relative to that character position) is applied to Horizontal and Vertical DAC (digital-to-analog converters) circuits, U2910 and U2905 respectively. In these circuits, the X-Y position data is converted to analog deflection signals used to position each dot in the CRT readout display. Each of the position bytes are read from the block of ROM defining the character under control of the readout timing and sequencing circuitry. The resulting dots, when displayed in sequence, form the character at the proper location on the CRT.

Readout I/O

The Readout I/O circuitry, composed of U2860, U2865, U2960, and associated components, provides the interface between the Microprocessor and the Readout board. Two types of data, Readout mode data and character data, are written to the Readout board serially via data bus line BD0.

STORING A CHARACTER. Displaying a character starts with serially clocking 16 character data bits into a 16-bit shift register formed by registers U2960 and U2860. The $\overline{\text{ROS1}}$ strobe (readout strobe one) from the Address Decode circuitry (fig. FO-3, sheet 1) is the clocking signal. The first eight bits of the loaded data indicate the character to be displayed, while the last eight select the location on the CRT that the character is to be displayed.

On positive-going transitions of the $\overline{\text{ROS1}}$ strobe, the data bit present on the BD0 data line is shifted into the first latch of character address register U2960. The following negative-going edges of the $\overline{\text{ROS1}}$ strobe are inverted by U2965A to produce a positive transition that shifts the data bit present at U2960 pin 9 (Q_{SH}) into U2860. After 15 $\overline{\text{ROS1}}$ strobes have occurred, seven bits of character data are latched into U2860, and the eighth character bit and seven of the character address bits are latched into character address register U2960 (though they have not been shifted into their correct positions for addressing the RAM).

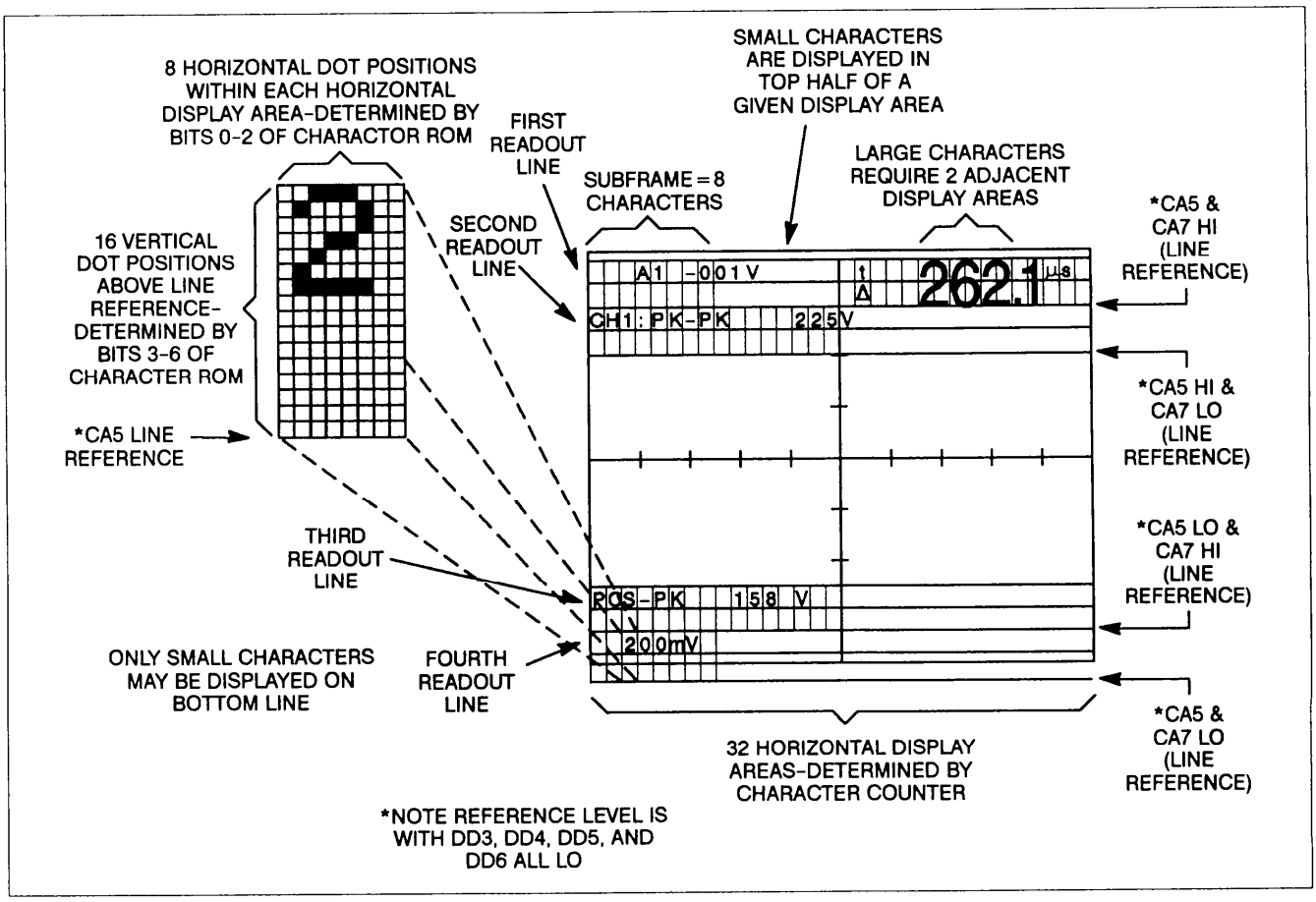


Figure 3-5. Developing the readout display.

At this point, the last character bit remains to be shifted into the registers, but the operating mode must be setup first to ensure correct operation upon shifting in the final bit. The eight bits of mode data are shifted into the mode control register U2865 by the $\overline{ROS2}$ strobe. Bit Q_4 ($\overline{WRITE}$), along with the ROS2 and the R/W DLYD signal are applied to the RAM enabling circuitry and determine when new character information will be written into the Character RAM. With U2865 loaded with the mode data, a final $\overline{ROS1}$ strobe clocks the eighth bit of character data from U2960 to U2860 on the negative edge, and the positive edge of the strobe clocks the eighth character address bit into U2960.

With control bit Q_4 from U2865 LO, the outputs of U2860 are enabled and the eight bits of character data (CD0 through CD7) are written in parallel into the Character RAM at the location selected by the eight-bit address from U2960. Register U2960 is enabled only when the Readout is not displaying characters (the REST signal at pin 15 of U2960 is HI).

The character data register U2860 also provides a means for the Microprocessor to read data from the Character RAM for partial verification of Readout circuit operation (during the power-up tests). The eight bits of parallel data from the Character RAM location selected by character address' register U2960 are loaded into U2860 by setting bit QS of mode control register U2865 LO. inverter U2965C converts the LO to a HI and applies it to character-register U2860 at pin 1. The HI on pin 1, in combination with the fixed HI on pin 19 of U2860, switches the character register to the Parallel Load mode. The next positive transition of the $\overline{ROS1}$ strobe loads the eight data bits placed on the CDO through CD7 bus lines into the register in parallel. Bit Q_3 is then returned HI, and the next positive transition of the $\overline{ROS1}$ strobe shifts the Q_A bit to pin 8 (Q_A'), the RO DO (readout data out) line. Seven more $\overline{ROS1}$ strobes shift the remaining seven bits of character data out onto the RO DO line to Status Buffer U2220 (fig. FO-4, sheet 1) to be read, one at a time, by the processor.

Character RAM

Character RAM U2920 provides temporary storage of the readout character selection data. This character data is organized as 256 eight-bit words that define the character that should be displayed at any given readout

position on the CRT. Cursor information is also stored in U2920 when cursors are to be displayed.

RAM locations may be addressed either from the Readout I/O stage by character address register U2960, as previously described, or by the Character Counter stage. Each of the following 128 address locations corresponds to a specific readout location on the CRT. Address locations 0 through 63 correspond to the first and fourth readout lines and 128 through 191 to the second and third readout lines. Thenext 128 address locations store cursor information. Address locations 64 through 127 correspond to the first and fourth readout line storage and 192 through 255 to the second and third readout line storage. The eight bits of data written to one of these locations from the Readout I/O stage is a code that identifies the specific character (or cursor segment) that should be displayed at the associated CRT location. After the display data is written into the RAM, the Character Counter is allowed to address the RAM, incrementing through the RAM address field. The eight-bit character codes for each display location are output to Character ROM U2930 in sequence.

Character Counter

The Character Counter stage consists of two four-bit counters (both within U2940) cascaded together to form an eight-bit counter and tristate buffer U2935 which drives the RAM address lines.

As the Character Counter addresses each RAM location (the counter also determines the character screen location), a sequence of "dot display cycles" is performed in which the individual dots that make up the character are positioned on the CRT and turned on. The $\overline{\text{EOCH}}$ (end of character) signal applied to U2855A prevents the counter from incrementing until all dots of the character have been displayed. As the last dot of a character is addressed, the $\overline{\text{EOCH}}$ bit at pin 2 of U2855A goes LO. The next $\overline{\text{GETDOT}}$ pulse increments U2940 (via U2855A), and the next RAM location is addressed to start the display of the next character. Space characters have the $\overline{\text{EOCH}}$ bit set LO for the first "dot" of the character and merely advance the Counter to the next character address without displaying any dots. See the Character ROM description for further explanation of the $\overline{\text{EOCH}}$ bit.

Character ROM

Character ROM U2930 contains the horizontal and vertical dot-position information for all of the possible characters (or cursor segments) that may be displayed. The eight bits of character data from the Character RAM are applied to the eight most-significant address inputs (A4 through A11) of the Character ROM and select a block of dot-positioning data unique to the character to be displayed. The Dot Counter increments the four least-significant address lines (A0 through A3), causing the ROM to output a sequence of eight-bit words, each defining a dot position for the selected character.

The three least-significant bits of a ROM dot-data word (DD0 through DD2) select one of eight horizontal positions for the dot within an eight-by-sixteen character matrix (see fig. 3-5). The next four bits (DD3 through DD6) define the vertical position of the dot within the matrix. These dot-data bits are applied to the Horizontal and Vertical Character DACS, where they are converted to the analog voltages used to position the dot on the CRT.

The last dot-data bit DD7 is the $\overline{\text{EOCH}}$ (end of character) bit and, when LO, indicates that the last clot of the character is addressed. It is used to reset the Dot Counter (via U2855B) and enables the Character Counter to be incremented (via U2855A) after the last dot of a character has been displayed.

Two servicing jumpers, J401 and J402, have been provided to disable the Character ROM and force the DD7 bit ($\overline{\text{EOCH}}$) LO. In certain instances, these two conditions maybe useful when troubleshooting the Readout circuitry. To prevent damage to the ROM output circuitry, J402 should only be installed after J401 is installed (to disable the ROM).

Dot Counter

The Dot Counter consists of two four-bit counters (both within U2870), OR-gate U2835A, inverter U2980D, and inverting input AND-gate U2855B. It sequences through a block of addresses containing dot-position data for a selected character. The Dot Counter is incremented when a dot is finished (via Inverter U2980D) by the GETDOT signal from the Dot Cycle Generator.

The counter increments through the block of dot-position data until the last byte of the block is encountered (last dot). This last data byte has the $\overline{\text{EOCH}}$ (end of character) bit (DD7) set LO. The dot is positioned and displayed in the normal manner, but when the $\overline{\text{GETDOT}}$ signal occurs for the next dot display cycle, the $\overline{\text{EOCH}}$ bit is latched into U2905 and generates the $\overline{\text{EOCH1}}$ (end of character, delayed one dot) signal at U2905 pin 18. With $\overline{\text{EOCH}}$ and $\overline{\text{EOCH1}}$ both LO, the HI reset pulse produced at pin 4 of NOR-gate U2855B resets the counter and, except for space characters, the $\overline{\text{EOCH}}$ bit returns HI. As the reset is removed from the Dot Counter, it is reenabled for display of the next character. For space characters, the $\overline{\text{EOCH}}$ bit will be detected as a LO when the first dot is read from the Character ROM, and the Character Counter will advance to the next character on the next rising edge of $\overline{\text{GETDOT}}$.

Counter U2870 and OR-gate U2835A enable characters of more than 16 dots to be displayed. Since most of the readout characters are small, using 16 dots or less, efficient data storage is achieved by storing the dot-position data as 16 consecutive bytes. For displaying these smaller characters, the least significant four bits from

U2870 are sufficient to address the 16 possible dot-position bytes.

When larger characters (up to 32 dots) are to be displayed, an additional bit of counter data must be used to address the ROM. This fifth bit comes from U2870 pin 3 and is ORed by U2835A with bit CD0 from the Character RAM. The block address for these larger characters always has bit CD0 set LO, so the counter bit from U2870 pin 3 is in control of the ROM address line at pin 4 of U2930. When displaying these larger characters, the dot count goes beyond 16 dots before the $\overline{EOCH}$ bit is set LO. On the seventeenth character, the fifth counter bit (pin 3 of U2870) will go HI to address the next 16-byte block of character data in ROM U2930. The lower four bits of the DOT Counter then sequence through this additional block in the normal manner until the $\overline{EOCH}$ bit is encountered, resetting the counter.

Horizontal DAC

The Horizontal DAC generates the voltages used to horizontally position dots of the readout display on the CRT. Five data bits (CA0 through CA4) from the Character Counter stage position a character to the correct column in the display (32 possible columns across the CRT), while three data bits from Character ROM U2930 (DD0 through DD2) horizontally position the dots within the eight-by-sixteen character matrix (see fig. 3-5).

The eight bits of position data are written to the permanently enabled DAC each time a new dot is requested by the Dot Cycle Generator. The $\overline{GETDOT}$ signal applied to pin 11 (Chip Select) enables the $\overline{DAC}$ to be written into, and the falling edge of the 5-MHz clock applied to pin 12 (Write) writes the data at the eight DAC input pins into an internal latch. The voltage at the DAC output pin changes to reflect the data present in the latch.

Vertical Character DAC

The function of Vertical Character DAC U2905 is similar to that of the Horizontal DAC just described. It is responsible for vertically positioning each character dot on the CRT. The Vertical DAC circuit is made up of seven, D-type flip-flops (contained within U2905) and an accompanying resistor weighting network. The outputs of the flip-flops source different amounts of current to a summing node through a resistor weighting network.

The seven data bits are latched into U2905 on the rising edge of the $\overline{GETDOT}$ signal. Two bits of character address data (CA5 and CA7) from the Character Counter switches the vertical display position between the four readout display lines. When the display is to be in the bottom line, bit CA5 is set LO. With CA5 LO, zener diode VR2925 is biased off and a small current is sourced to the summing node via R2925. Vertical position above this reference is determined by dot data bits DD3 through DD6. When the top line is to be displayed, the CA5 bit is set HI, biasing VR2925 on. A larger current is now sourced into the summing node via R2925 and enough voltage is developed across R2926 to move the display to the top row of the CRT. The CA7 bit is used to offset the top and bottom readout display lines to form the center two readout display lines. As before, the individual dots are then positioned above this reference level by dot data bits DD3 through DD6.

Mode Select Logic and Analog Channel Switch

The Mode Select Logic circuitry is composed of analog switches U2800 and U2805, buffers U2820A and B, gates U2810A, B, C, and D, U2900B and C, and part of U2905. It controls the readout display mode by selecting which defection signals should drive the Horizontal and Vertical Deflection Amplifiers during a readout display. Five display modes are decoded by the Mode Select Logic: character display, vertical cursor 0, vertical cursor 1, horizontal cursor 0, and horizontal cursor 1.

Table 3-6
Readout Display Mode Selection

Control Bits				Mode Selected	Horizontal Signal	Vertical Signal
CA6 (Cursor Select)	DD5	DD4	DD3			
L	X[1]	X	X	Character Display	Horiz DAC	Vert DAC
H	L	H	L	Vert Cursor 1	Horiz DAC	DLY REF 1
H	L	H	H	Horiz Cursor 1	DLY REF 1	Horiz DAC
H	H	L	L	Vert Cursor 0	Horiz DAC	CURSOR 0
H	H	L	H	Horiz Cursor 0	CURSOR 0	Horiz DAC
H	L	L	X	Return to character display Mode		

[1]X = State doesn't matter.

For normal character displays, cursor select bit CA6 on U2800 pin 1 is LO. This LO signal passes through analog switch U2800 and is latched into U2905 when the $\overline{\text{GETDOT}}$ request from the Dot Cycle Generator goes HI. This latched LO selects the character display mode by forcing the outputs of U2900B and C and U2810A and B HI. The HI outputs of U2900B and C applied to the select input pins of analog switch U2805 cause the Horizontal DAC output signal applied to U2805 pin 11 to be routed to the Horizontal Amplifier (fig. FO-11, sheets 1 and 2) via buffer U2820B. The same HI logic levels cause NOR-gates U2810C and D to produce a LO at their outputs. This causes analog switch U2800 to route the Vertical DAC output signal applied to pin 12 to the Vertical Output Amplifier (also fig. FO-11, sheet 1) via buffer U2820A.

For cursor displays, cursor select bit CA6 goes HI. This HI is routed through analog switch U2800 and latched into U2905 when $\overline{\text{GETDOT}}$ next goes HI. This produces a HI at U2905 pin 16, enabling the Mode Select Logic to decode output bits DD3, DD4, and DD5 (from U2905) to determine which of the four possible cursor modes is selected (see table 3-6). Once one of the cursor modes is entered, analog switch U2800 routes a fixed HI from pin 5, pin 2, or pin 4 to U2905 to keep the Mode Select Logic enabled. Character display mode is reentered only when return-to-character-mode data is decoded (DD4 and DD5 both LO). When that occurs, U2800 routes the CA6 bit to U2905 and, if the bit is LO, the cursor display mode is halted.

CURSOR DEVELOPMENT. Cursors are displayed in short sections, alternating between both vertical positions (for the delta voltage cursors) or both horizontal positions (for the delta time cursors). When displaying delta voltage cursors, the CURSOR O level is routed to the Vertical Amplifier by analog switch U2800. This level determines the vertical position of one of the voltage cursors. Horizontal-positioning voltages for one segment of the cursor are routed from Horizontal DAC through analog switch U2805 and buffer U2820B to horizontally position each of the dots making up the cursor segment. DLY REF 1 is then used to vertically position the second cursor, and the Horizontal DAC positions each of the dots for that cursor segment. The cycle is repeated until all segments of both cursors are displayed.

Delta time cursor displays are similar in that the CURSOR 0 and DLYREF 1 signals are used to position the cursors. In this case, however, analog switch U2805 selects the CURSOR 0 and DLYREF 1 signals alternately to position the cursors horizontally, and the Horizontal DAC output is routed via analog switch U2800 and buffer U2820A to vertically position the dots within each cursor segment.

Refresh Prioritize

The Refresh Prioritizer circuitry consists of U2850A and B, U2950A, U2990A, and U2985. It keeps track of how well the Readout circuitry is doing in displaying all the required readout information and maintains the overall refresh rate. Since the readout display must remain flicker-free and at a constant intensity over the entire sweep rate range, various modes of displaying readout information are provided. The Refresh Prioritizer keeps track of the display status and enables the various readout-display modes as required to produce minimal interference with the displayed waveform trace(s).

Ideally, readout information should be displayed only when the oscilloscope is not trying to display waveform traces. These times occur before a trace commences, after a trace is completed, or between consecutive traces. Displaying in this mode corresponds to “priority one” in Figure 3-6 and causes no interference with the displayed waveforms. If the Readout circuitry is able to display all the required readout dots during the holdoff time between sweeps, the prioritize U2985 will turn off the Dot Start Governor until the next subframe of readout information is to redisplayed. When the sweep times are either too fast to finish a readout display during holdoff (at 5 ns per division no identifiable holdoff time exists) or too slow to allow flicker-free readout, readout display modes other than priority one are initiated.

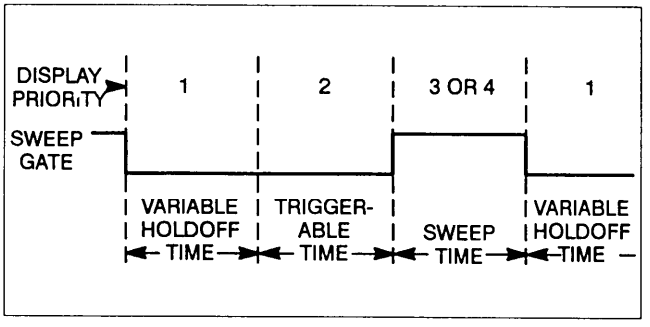


Figure 3-6. Readout display priorities.

The next most desirable time for dots to be displayed is during "triggerable" time: that time between sweeps when the oscilloscope is waiting for a sweep trigger event to occur. This is designated priority two and may cause slight interference on the leading edge of the displayed trace if a dot is being displayed when the actual trigger occurs.

Finally, the least desirable dot display time is during a waveform trace display. This display time is designated either priority three or priority four. (Priority four indicates a higher demand of display time.) In priorities three and four, dot displays occur during the main portion of the waveform display. However, the waveform blanking associated with these displays is relatively random in nature and is usually not noticeable.

To start a readout display, the ROSFRAME (readout subframe) request from the Timing Logic (fig. FO-3, sheet

1) clocks the Q output of flip-flop U2850A HI. ROSFRAME is a periodic clocking signal used to hold the overall refresh rate constant and occurs at regular intervals, regardless of the state of the display.

As the Dot Cycle Generator runs, it resets half of U2830 in the Dot Timer at somewhat irregular intervals with the STARTDOT signal (via inverter U2890A). The Dot Timer then starts a timing sequence, and the rising edge of the REFRESH signal from U2830 pin 4 clocks the latched ROSFRAME request from U2850A pin 5 to the Q output (pin 9) of flip-flop U2850B. This HI, applied to the S1 input (pin 10) of prioritizer U2985, sets it up to increment with the next REFRESH clock applied to its clock input (pin 11). The LO Q output of U2850B (pin 8) applied to the reset input of U2850A resets the latched ROSFRAME request. See Figure 3-7 for an illustration of the timing sequence involved.

The next REFRESH clock increments the display priority to one by clocking a HI to the Q_D output (pin 12) of prioritize shift register U2985 (table 3-7 illustrates the operation of U2985). The same clock latches the now LO ROSFRAME request at U2850B pin 12 to the Q output (pin 9), where it is applied to the S1 input (pin 10) of prioritize U2985. The LO on the S1 input of the prioritizer will remain until another ROSFRAME request from the Timing Logic occurs, and the encoded priority at the output pins of U2985 will remain as it is presently set.

Table 3-7
Operation of Prioritizer Shift Register

Select Inputs		Mode
S0	S1	
H	H	Parallel Load
H	L	L - Q_A (decrease priority)
L	H	H - Q_D (increase priority)
L	L	Hold Data

As each of the consecutive dots of the readout frame are displayed, the Dot and Character Counters increment until all dots of the subframe have been displayed (eight characters). As the Character Counter increments to address the next character of the display (first character of the next frame), the fourth bit of counter U2940 goes HI and sets the S0 input (pin 9) of prioritize U2985 HI via exclusive-OR-gate U2990A. The Dot Timer then clocks the prioritize with a REFRESH clock on pin 11 of U2985, and the priority is decremented back to zero (indicating that the subframe is completed). The next ROSFRAME request starts the process over again to display the next subframe of readout display. The sequence just described is the priority one display mode and is used when holdoff time between sweeps allows all dots of the subframe to be displayed before the next ROSFRAME request occurs.

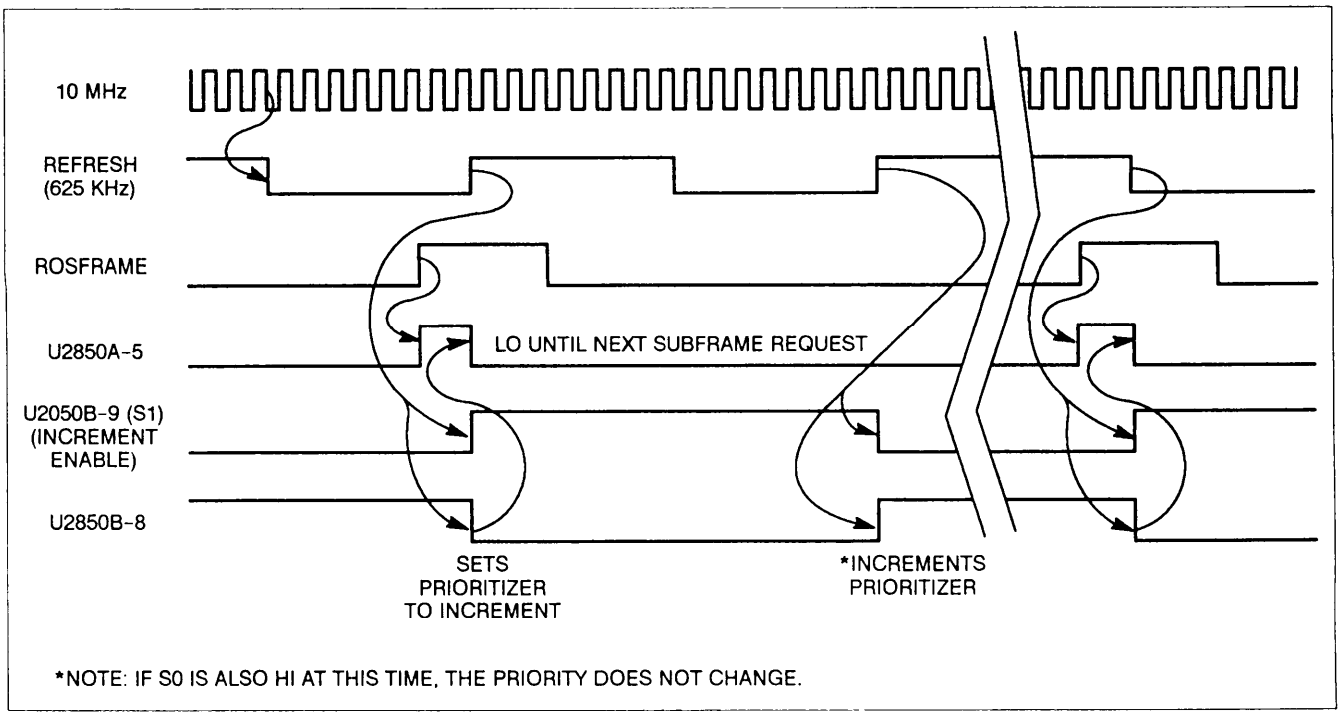


Figure 3-7. Timing of Refresh Prioritizer.

If a second ROSFRAME request occurs before the Character Counter indicates the end of the subframe (to decrement the prioritize back to zero), input S1 of U2985 will be set HI (while the SO input pin remains LO) and the Prioritizer will increment to priority two (outputs Q_C and Q_D go HI) on the next STARTDOT cycle. If this display priority still is inadequate to complete the subframe display before the next ROSFRAME request occurs, priority two will be incremented up to priority three, or even to priority four should the condition persist. Priority four is operationally the same as priority three, but it is used to keep thereabout circuitry continuously displaying readout data on through the next subframe, thus allowing the display to catch up. If priority four is in effect, the next decrement that occurs at the end of a subframe only returns the prioritizer to priority three, not to priority two.

The circuit composed of flip-flop U2950A and exclusive-OR-gate U2990A enables either edge of the CA3 bit to decrement the priority of the display when a subframe is completed. Either a negative or positive transition on pin 2 of U2990A will cause the output at pin 3 go HI since the Q output of U2950A is still at the opposite level. The HI from U2990A indicates that the end of the present subframe has occurred, and it sets up the prioritize to decrement with the next REFRESH clock. At the same time that the prioritize decrements, the changed level of the CA3 bit is clocked through U2950A and causes the output of exclusive-OR-gate U2990A to return LO until the next subframe is completed.

If the subframe is completed (SO on U2985 goes HI) when a ROSFRAME request is also pending (S1 is also HI), U2985 does a parallel load, reloading the present priority back into the prioritize. Since, in this case, the subframe display was completed at the same rate as the ROSFRAME request occurred, the readout display priority is not changed.

Dot Start Governor

The Dot Start Governor detects the display priority from the Refresh Prioritize and initiates dot-display cycles as the appropriate conditions are met. The conditions tested include display priority, sweep gate completion, dot completion, readout control status, and the readout active enable from the Display Sequencer.

When the readout board status line (ACTIVE/$\overline{\text{ADDRESSABLE}}$) is HI (signifying display) and the REST line goes HI to indicate that the dot cycle is complete, AND-gate U2970C generates a HI at pin 8 (DOTOK) to signal that a new dot display is allowed, The HI from U2970C enables most of the gating in the Dot Start Governor. If the Refresh Prioritize has encoded a display priority of either one or two, the output of exclusive-OR-gate U2990B is HI. When DOTOK from U2970C goes HI to enable a dot display, the LO reset from pin 6 of U2970B to pin 1 of flip-flop U2880A is removed. Now, when the A Sweep gate ($\overline{\text{SGA}}$) goes HI (beginning of Holdoff), the HI at the D input of U2880A is clocked to the Q output and the Q output at pin 6 will go LO, requesting display of a priority one or two dot. This LO dot request is propagated through U2885B, U2890D, U2890B, and U2890C and sets the STARTDOT signal LO. START-DOT going LO resets Dot Cycle Generator shift register U2995 and counter U2830B of the Dot Timer. Resetting the Dot Cycle Generator shift register causes the REST signal from U2995 pin 13 to go to a LO, removing the HI DOTOK signal at U2970C pin 8. As DOTOK goes LO, STARTDOTat pin 8 of U2890C goes HI to start the DOT Cycle Generator. At the same time the reset to U2880A is asserted via U2970B and the dot request is removed. Both the Dot Timer and the Dot Cycle Generator are now enabled and start the first dot-display cycle during holdoff time.

After the Display Sequencer U650 (fig. FO-10, sheets 1 and 2) has time to respond to the end of the sweep gate, it sets the readout active signal ($\overline{\text{ROA}}$) to pin 10 of U2880A LO. This sets pin 6 of U2880A LO, and the signal is propagated through U2885B, U2890D, U2890B, and U2890C, as before, resetting the Dot Timer and the Dot Cycle Generator. REST then goes LO as before and starts the Dot Cycle Generator and Dot Timer. This cycle continues, displaying one dot per cycle (except for the first nondisplayed dot of a character which is automatically initiated by $\overline{\text{EOCH2}}$, until the Display Sequencer determines that the readout time is over (sets $\overline{\text{ROA}}$ HI) or until the display priority is decremented to zero.

When a display priority of three or four exists, the output of U2990B will be LO, and U2970B, U2880A, and the associated logic gates following it will not be able to initiate a dot cycle. In either of these display priorities, U2970D, U2835C, U2980A, U2965B, and flip-flop U2950B detect the higher priority and generate a readout request signal (ROR) to the Display Sequencer. The LO from U2950B pin 8 propagates through U2890B and U2890C to initiate a STARTDOT cycle. When the Display Sequencer recognizes that the readout request signal is LO, it will perform the mode-dependent setup functions necessary to give display control to the Readout Board and will then set the $\overline{\text{ROA}}$ (readout active) line LO. The LO will be clocked into U2880B, and the Dot Cycle Generator will generate a $\overline{\text{GETDOT}}$ signal, resetting the readout request from flip-flop U2950B. Only one dot is displayed for each readout request.

A similar readout display request will be generated when priority-two-or-higher displays are required when sweep gates are not present (dot display during triggerable time after holdoff). This condition is detected by NAND-gate U2885A. AND-gate U2970D allows a readout request to be generated when in the interfere mode. This mode is invoked only during a single-sequence waveform display and ensures that all of the selected sweep combinations are displayed once, followed by a complete readout frame (for the purpose of CRT photography).

Dot Cycle Generator

The Dot Cycle Generator, composed of shift register U2995, flip-flop U2880B, and associated gating circuitry, generates time-related signals for the following purposes: unblinking the CRT to display a dot; requesting the next byte of dot data in preparation for displaying the next dot; and reenabling itself to repeat the tasks, via the Dot Start Governor (dependent on the display priority).

The timing relationships of the Dot Cycle Generator output signals are controlled by shift register U2995. When the Dot Start Governor initiates a STARTDOT cycle as previously described, the STARTDOT signal initially goes LO, resetting all the Q outputs of U2995 LO and setting the Q output of flip-flop U2880B to a HI. The STARTDOT signal is then returned HI, and the Dot Timer counter U2830A and shift register U2995 are enabled. The shift register begins to consecutively shift HI logic levels to its Q output pins with each 5-MHz clock from the Dot Timer. After approximately 400 ns, pin 5 (Q_C) of the shift register will go HI. The HI at Q_C propagates through exclusive-OR-gate U2990D and AND-gate U2970A to unblank the CRT by setting the readout blanking signal ($\overline{ROB}$) HI.

When the Q_F output of U2995 goes HI (1 µs after STARTDOT), the output of U2990D goes LO and the output of U2990C goes HI. The LO from U2990D propagates through U2970A to blank the CRT ($\overline{ROB}$ goes LO) and to clock flip-flop U2880B via NAND-gate U2980C. The $\overline{ROA}$ (readout active) level from the Display Sequencer (fig. FO-10, sheet 2) is clocked from the D input (pin 12) of U2880B to the Q output; and, if LO (indicating that the readout circuitry had control of the CRT when unblinking occurred; thus the dot was displayed), the output of U2980B is set HI. With three HI levels applied to NAND-gate U2885C, a $\overline{GETDOT}$ request is generated to get the next byte of dot-position data for display. The next 5-MHz clock sets the Q_G output of U2995 HI, and the output of U2990C goes LO, removing the LO $\overline{GETDOT}$ signal.

At 1.4 µs after STARTDOT goes HI, U2995 pin 13 (Q_H) goes HI to produce the REST signal, indicating that the current dot cycle is complete and the Dot Cycle Generator is at REST. If the readout ACTIVE/ADDRESSABLE mode bit at U2970C pin 10 is still HI, the REST signal going HI produces a HI DOTOK signal (next dot is allowed) at pin 8. This HI applied to pin 10 of U2890C, along with any of the possible dot requests from the Dot Start Governor, will initiate another STARTDOT cycle for the next dot of the display. As long as the Display Sequencer holds the readout active line (ROA) LO, U2885B, U2890D, and U2890B of the Dot Start Governor will automatically initiate dot cycles as soon as the previous one ends (REST goes Hi), until the Refresh Prioritize is decremented to zero.

When the last dot of the character is called from the Character ROM, the EOCH bit (DD7) applied to latch U2905 at pin 18 (in the Vertical Character DAC circuitry) is LO. At the end of that dot display cycle, the $\overline{GETDOT}$ signal (going HI) clocks the LO $\overline{EOCH}$ bit into latch U2905 and increments character counter U2940. The latched bit becomes the $\overline{EOCH1}$ signal (end of character, delayed one dot request) and is applied to U2855B, along with the already LO $\overline{EOCH}$ bit, to reset Dot Counter U2870. The least-significant bits to the Character ROM address pins (A0 through A4) are then zeros, and the first dot of the next character is addressed. The Horizontal and Vertical DACS don't write this first dot position data into their registers until the end of the next $\overline{GETDOT}$ signal. That same $\overline{GETDOT}$ signal also clocks $\overline{EOCH1}$ into U2905 which becomes $\overline{EOCH2}$ at pin 17 (end of character, delayed by two dot requests). $\overline{EOCH2}$ is applied to AND-gate U2970A and disables the gate prior to the time the Dot Cycle Generator attempts to unblank the CRT for the first dot display; thus the first dot of a character is never displayed.

Disabling the unblinking path for the first dot of each character in the manner just described allows the more radical voltage changes between characters to settle before the actual display of the next character begins. When the dot data for one of these undisplayed dots also has the $\overline{EOCH}$ bit set LO, it is a space character, and the display is advanced to the next character.

Dot Timer

The Dot Timer, composed of U2890A and U2830, generates three, time-related signals used to synchronize the display and maintain the proper sequencing of the individual character dots.

The two least-significant bits of the Dot Timer, from U2830 pins 11 and 10, are reset at the beginning of a dot cycle by a LO STARTDOT signal applied to the reset input of the counter via U2890A. As the dot-display cycle begins, the STARTDOT signal returns HI and the Dot Timer begins counting in a binary fashion. The 10-MHz clock applied to pin 13 is divided by two to produce the 5-MHz clocking signal at output pin 11. The 5-MHz clock sequences the Dot Cycle Generator through the various phases of the dot-display cycle. The REFRESH output signal from U2830 pin 4 updates the Refresh Prioritize as each subframe is displayed.

A third clock, from U2830 pin 6, occurs at approximately 8-µs intervals and allows any pending dot requests to generate a $\overline{ROR}$ signal to the Display Sequencer via flip-flop U2950B. (Readout request generation is described in the Dot Start Governor discussion.)

HIGH VOLTAGE POWER SUPPLY AND CRT

The High-Voltage Power Supply and CRT circuit (fig. FO-15, sheets 1 and 2) provides the voltage levels and

control circuitry for operation of the cathode-ray tube (CRT). The circuitry consists of the High Voltage Oscillator, the High Voltage Regulator, the Cathode Supply, the Anode Multiplier, the DC Restorer, Focus Amplifiers, the CRT and the various CRT Control circuits.

High-Voltage Oscillator

The High-Voltage Oscillator transforms power obtained from the-15 V unregulated supply to the various AC levels necessary for the operation of the CRT circuitry. The circuit consists of transformer T1970, switching transistor Q1981, and associated circuitry. The low-voltage oscillations set up in the primary winding of T1970 are raised by transformer action to high-voltage levels in the secondary windings. These AC secondary voltages are applied to the DC Restorer, the Cathode Supply, and the a node multiplier circuits.

Oscillation occurs due to the positive feedback from the primary winding (pin 4 to pin 5) to the smaller base-drive winding (pin 3 to pin 6) for transistor Q1981. The frequency of oscillation is about 50kHz, and is determined primarily by the resonant frequency of the transformer.

When power is first applied, the High-Voltage Regulator circuit detects that the negative CRT cathode voltage is too positive and pulls pin 2 of transformer T1970 negative. The negative level forward biases transistor Q1981 via the base-drive winding of the transformer. Current begins to flow in the primary winding through transistor Q1981, inducing a magnetic field around the transformer primary winding. The increasing magnetic field induces a current in the base-drive winding that further increases the base drive to the transistor. This in-phase feedback causes current in Q1981 to increase until the primary winding current reaches its maximum value. As the rate of change of the primary current peaks and then reverses, the induced magnetic field begins to decay. This decreases the base-drive current and begins turning Q1981 off.

As Q1981 is beginning to turn off, the magnetic field around the primary winding continues to collapse at the resonant frequency rate of the transformer. This induces into the base-drive winding a voltage that completely turns off the transistor. The collapsing magnetic field goes to zero, then builds in the opposite direction to a maximum before collapsing again (resonant flywheel effect). This sequence of events occurs repetitively as the circuit continues to oscillate.

The oscillating magnetic field in the primary winding couples power into the secondary windings of the transformer. The amplitude of the voltages induced in the secondary windings is a function of the turns ratios of the transformer windings.

High-Voltage Regulator

The High-Voltage Regulator consists of U1956A and B and associated components. It monitors the CRT Cathode Supply voltage and varies the bias point of the switching transistor in the High Voltage Oscillator to hold the Cathode Supply voltage at the nominal level. Since the output voltages at the other secondary winding taps are related by turns ratios to the Cathode Supply voltage, all voltages are held in regulation.

When the Cathode Supply voltage is at the proper level (-1900 V), the current through R1945 and the 19-M Ω resistor internal to High Voltage Module U1830 holds the voltage developed across C1932 at zero volts. This is the balanced condition and sets base drive in Q1981 via integrator U1956A and voltage-follower U1956B. Varying base drive to Q1981 holds the secondary voltages in regulation.

If the Cathode Supply voltage level tends too positive, a slightly positive voltage will develop across C1932. This voltage causes the outputs of integrator U1956A and voltage-follower U1956B to move negative. The negative shift charges capacitor C1951 to a different level, around which the induced feedback voltage at the base-drive winding will swing. The added negative bias causes Q1981 to turn on earlier in the oscillation cycle, and a stronger current pulse is induced in the secondary windings. The increased power in the secondary windings increases the secondary voltages until the Cathode Supply voltage returns to the balanced condition (zero volts across C1932). Opposite action occurs should the Cathode Supply voltage tend too negative.

Cathode Supply

The Cathode Supply circuit is composed of a voltage-doubler and an RC filter network contained within High-Voltage Module U1830. This supply produces the -1900 V accelerating potential applied to the CRT cathode and the -900 V slot lens voltage. The -1900 V supply is monitored by the High Voltage Regulator to maintain the regulation of all voltages from the High Voltage Oscillator.

The alternating voltage (950 V peak) from pin 10 of transformer T1970 is applied to a conventional voltage-doubler circuit at pin 7 of the High Voltage Module. On the positive half cycle, the input capacitor of the voltage doubler (0.006 µf) is charged to -950 V through the forward-biased diode connected to ground at pin 9 of the module (charging path is through the diode, so stored charge is negative). The following negative half cycle adds its AC component (-950 V peak) to this stored DC value and produces a total peak voltage of -1900 V across the capacitor. This charges the 0.006-µf storage capacitor (connected across the two doubler diodes) through the second diode (now the forward-biased diode) to -1900 V. Two RC filters follow the voltage doubler to smooth out the

AC ripple. A resistive voltage divider across the output of the filter network provides the -900-V slot lens potential.

Anode Multiplier

The Anode Multiplier circuit (also contained in High Voltage Module U1830) uses voltage multiplication to produce the +14 kV CRT anode potential. Circuit operation is similar to that of the voltage-doubler circuit of the Cathode Supply.

The first negative half-cycle charges the 0.001 -µf input capacitor (connected to pin 8 of the High Voltage Module) to a positive peak value of + 2.33 kV. The following positive half cycle adds its positive peak amplitude to the voltage stored on the input capacitor and boosts the charge on the second capacitor of the multiplier (and those following) to + 4.66 kV. Following cycles continue to boost up succeeding capacitors to values 2.33 kV higher than the preceding capacitor until all six capacitors are fully charged. This places the output of the last capacitor in the multiplier at + 14 kV above ground potential. Once the multiplier reaches operating potential, succeeding cycles replenish current drawn from the Anode Multiplier by the CRT beam. The 1-M Ω resistor in series with the output protects the multiplier by limiting the anode current to a safe value.

Focus Amplifier

The Focus Amplifier, in conjunction with the auto-focus circuitry of Z-Axis hybrid U950 (fig. FO-11, sheet 2), provides optimum focus of the CRT beam for all settings of the front-panel INTENSITY control. The Focus Amplifier itself consists of two shunt-feedback amplifiers composed of Q1851, Q1852, and associated components. The outputs of the amplifiers set the operating points of a horizontally converging quadrapole lens and a vertically converging quadrapole lens within the CRT. The convergence strength of each lens is dependent on the electric field set up between the lens elements.

Since the bases of Q1851 and Q1852 are held at constant voltages (set by their emitter potentials), changing the position of the wiper arms of the ASTIG and FOCUS pots changes the amount of current sourced to the base junctions through R1856 and R1857 respectively. This changes the base-drive currents and produces different output levels from the Focus Amplifiers; that, in turn, changes the convergence characteristics of the quadrapole lenses.

Initially, at the time of adjustment, the FOCUS and ASTIG potentiometers are set for optimum focus of the CRT beam at low intensity. After that initial adjustment, the ASTIG pot normally remains asset, and the FOCUS control is positioned by the user as required when viewing the displays. When using the FOCUS control, transistor Q1852 is controlled as described above; however, an additional current is also supplied to the base node of Q1851 from the FOCUS pot through R1855. This additional current varies the base-drive current to Q1851 and provides tracking between the two lenses as the FOCUS control is adjusted during use of the instrument.

The convergence strengths of the quadrapole lenses also dynamically track changes in the display intensity. The VQ OUT signal, applied to the CRT at pins 5 and 6, is exponentially related to the VZ OUT (intensity) signal driving the CRT control grid and increases the strength of the lenses more at higher CRT beam currents. (A higher beam current requires a stronger lens to cause an equal convergence of the beam.)

DC Restorer

The DC Restorer provides CRT control-grid bias and couples both the DC and the low-frequency components of the Z-Axis drive signal to the CRT control grid. This circuit allows the Z-Axis Amplifier to control the display intensity by coupling the low-voltage Z-Axis drive signal (VZ OUT) to the elevated CRT control-grid potential (about -1.9kV).

The DC Restorer circuit (fig. 3-8) operates by impressing the CRT grid bias setting and the Z-Axis drive signal on an AC voltage waveform. The shaped AC waveform is then coupled to the CRT control grid through a coupling capacitor that restores the DC components of the signal.

GRID BIAS LEVEL. An AC drive voltage of approximately 300 V peak-to-peak is applied to the DC Restorer circuit from pin 7 of transformer T1970. The negative half cycle of the sinusoidal waveform is clipped by CR1953, and the positive half cycle (150 V peak) is applied to the junction of CR1930, CR1950, and R1941 via R1950 and R1953. Transistor Q1980, operational amplifier U1890A, and associated components form a voltage clamp circuit that limits the positive swing of the AC waveform at the junction.

Transistor Q1980 is configured as a shunt-feedback amplifier, with C1991 and R1994 as the feedback elements. The feedback current through R1994 develops a voltage across the resistor that is positive with respect to the + 42.6 V on the base of the transistor. The value of this additive voltage plus the diode drop across CR1950 sets the upper clamping threshold. Grid Bias potentiometer R1878 sinks varying amounts of current away from the base node of the transistor and thus sets the feedback current through R1994. The adjustment range of the pot can set the nominal clamping level between +71 V and +133V.

When the amplitude of the AC waveform is below the clamping threshold, series diode CR1950 will be reverse biased and the AC waveform is not clamped. During the time the diode is reverse biased, transistor Q1980 is kept biased in the active region by the charge retained on C1971 from the previous cycle. As the amplitude of the AC

waveform at the junction of CR1930 and CR1950 exceeds the voltage at the collector of Q1980, diode CR1950 becomes forward biased, and the AC waveform is clamped at that level. Any current greater than that requited to maintain the clamp voltage will be shunted to the +42 V supply by transistor Q1980.

Operational amplifier U1890A sinks a time-dependent variable current away from the base node of Q1 980 that modifies the CRT control-grid bias during the first few minutes of instrument operation. The circuit compensates for the changing drive characteristics of the CRT as it warms up.

At power-up, capacitor C1990 begins charging through R1991 toward the + 15 V supply. The output of U1890A follows the rising voltage on pin 3; and after about ten minutes (for all practical purposes), it reaches + 15 V. As the output voltage slowly increases, the charging current through R1992 causes the Grid Bias voltage to gradually lower about ten volts from its power-on level. The charge on Cl 990 dissipates slowly; therefore, if instrument power is turned off and then immediately back on again, the output of U1890A will still be near the + 15 V limit rather than starting at zero volts as when the CRT was cold.

Z-AXIS DRIVE LEVEL. The variable-level Z-Axis signal (VZ OUT) establishes the lower clamping level of the AC waveform applied to the High Voltage Module. When the amplitude of the waveform drops below the Z-Axis signal, CR1930 becomes forward biased, and the AC waveform is clamped to the Z-Axis signal level. The VZ OUT level may vary between + 8 V and +75 V, depending on the setting of the front-panel INTENSITY and READOUT INTENSITY controls.

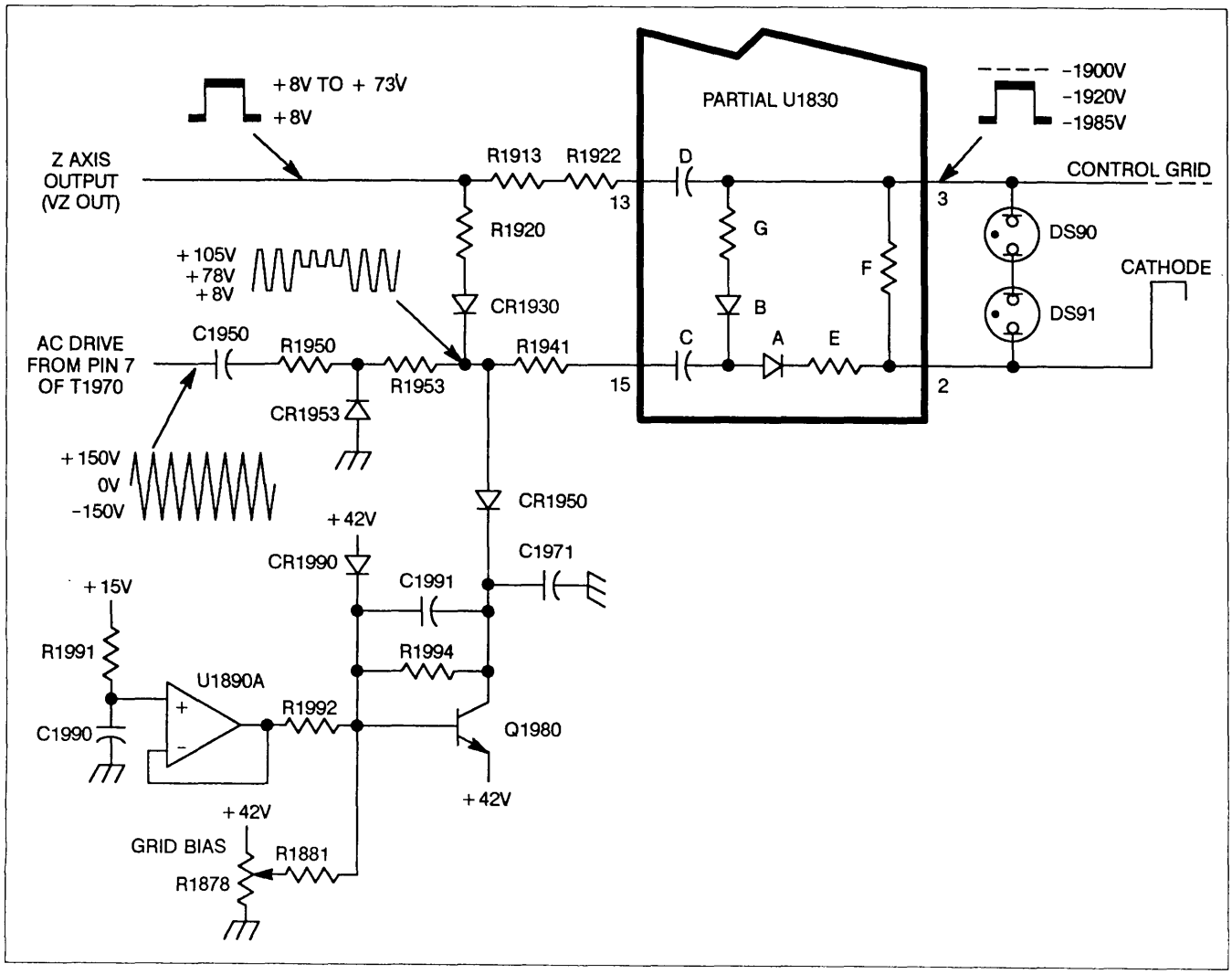


Figure 3-8. DC restorer circuit.

The AC waveform, now carrying both the grid-bias information and the Z-Axis drive information, is applied to a DC Restorer circuit in the High Voltage Module where it is raised to the high-voltage levels of the CRT control grid.

DC RESTORATION. The DC Restorer circuit in the High Voltage Module is referenced to the CRT cathode voltage via a connection within U1830. Capacitor C (in fig. 3-8), connected to pin 15 of U1830, initially charges to a level determined by the difference between the Z-Axis signal level and the CRT cathode potential. The Z-Axis signal sets the level on the positive plate of capacitor C through R1920, CR1930, and R1941; the level on the negative plate is set by the CRT cathode voltage through resistor E and diode A. Capacitor D is charged to a similar DC level through resistors F, R1922, and R1913.

When the AC waveform applied to pin 15 begins its transition from the lower clamped level (set by the Z-Axis signal) towards the upper clamped level (set by the Grid Bias potentiometer), the charge on capacitor C increases. The additional charge is proportional to the voltage difference between the two clamped voltage levels.

When the AC waveform begins its transition from the upper clamped level back to the lower clamped level, diode A becomes reverse biased. Diode B becomes forward biased, and an additional charge proportional to the negative excursion of the AC waveform (difference between the upper clamped level and the lower clamped level) is added to capacitor D through diode Band resistor G. The amount of change added to capacitor D depends on the setting of the front-panel lNTENSITY control, as it sets the lower clamping level of the AC waveform. This added charge determines the potential of the control grid with respect to the CRT cathode.

The potential difference between the control grid and the cathode controls the beam current and thus the display intensity. With no Z-Axis signal applied (INTENSITY control off), capacitor D will be charged to its maximum negative value, since the difference between the two clamped voltage levels is at its maximum value. This is the minimum intensity condition and reflects the setting of the Grid Bias potentiometer. During calibration, the Grid Bias pot is adjusted so that the difference between the upper clamping level (set by the Grid Bias pot) and the “no signal” level of the Z-Axis drive signal (VZOUT) produces a control grid bias that barely shuts off the CRT electron beam.

As the lNTENSITY control is advanced, the amplitude of the square-wave Z-Axis signal increases accordingly. This increased signal amplitude decreases the difference between the upper and lower clamped levels of the AC waveform, and less charge is added to capacitor D. The decreased voltage across capacitor D decreases the potential difference between the control grid and the cathode, and more CRT beam current is allowed to flow. Increased beam current increases the CRT display intensity.

During the periods that capacitor C is charging and discharging, the control-grid voltage is held stable by the long-time-constant discharge path of capacitor D through resistor F. Any charge removed from capacitor D during the positive transitions of the AC waveform will be replaced on the negative transitions.

The fast-rise and fast-f all transitions of the Z-Axis signal are coupled to the CRT control grid through capacitor D. This at-coupled fast-path signal quickly sends the CRT electron beam to the new intensity level, then the slower DC Restorer path “catches up” to handle the DC and low-frequency components of the Z-Axis drive signal.

Neon lamps DS90 and DS91 prevent arcing inside the CRT should the control grid potential or cathode potential be lost for any reason.

CRT Control Circuits

The CRT Control circuits provide the various potentials and signal attenuation factors that set up the electrical elements of the CRT. The control circuitry is divided into two separate categories: (1) level setting and (2) signal handling. The level setting circuitry produces voltages and current level necessary for the CRT to operate, while the signal-handling portion is associated with changing CRT signal levels.

LEVEL-SETTING CIRCUITRY. Operational amplifier U1890B, transistor Q1980, and associated components form an edge-focus circuit that sets the voltages on the elements of the third quadrapole lens. The positive lens element is set to its operating potential by Edge Focus adjustment pot R1864 (via R1897). This voltage is also divided by R1893 and R1982 and applied to the non-inverting input of U1890B to control the voltage on the other element of the lens.

The operational amplifier and transistor are configured as a feedback amplifier, with R1891 and R1990 setting the stage gain. Gain of the amplifier is equal to the attenuation factor of divider network R1893 and R1892, so total overall gain of the stage from the wiper of R1864 to the collector of Q1890 is unity. The offset voltage between lens elements is set by the ratio of R1891 and R1990 and the + 10 V reference applied to R1990. This configuration causes the two voltages applied to the third quadrapole lens to track each other over the entire range of Edge Focus adjustment pot R1864.

Other adjustable level-setting circuits include Y-Axis Alignment pot R1848, used to rotate the beam alignment after vertical deflection. This adjustment controls the amount of current through the Y-Axis Alignment coil around the neck of the CRT and is set to produce precise perpendicular alignment between x- and y-axis def!ec-

tions. The TRACE ROTATION adjustment R975 is a front-panel screwdriver-adjustable control. The effect of the adjustment is similar to the Y-Axis Alignment pot, but when adjusted, it rotates both the X-axis and the y-axis deflections of the trace on the face of the CRT. A final adjustable level-setting control is the Geometry pot R1870, adjusted to optimize display geometry. The potential at pin 8 for the vertical shield internal to the CRT is produced by zener diode VR1891 and associated components.

SIGNAL-HANDLING CIRCUITRY. The CRT termination adjustment R1501 is set to match the loading characteristics of the CRT's vertical deflection structure to the Vertical Output Amplifier.

LOW VOLTAGE POWER SUPPLY

The low voltages required by the instrument are produced by a high-efficiency, switching power supply (fig. FO-18, sheets 1 and 2). This type of supply directly rectifies and stores charge from the AC line supply; then the stored charge is switched through a special transformer at a high rate, generating the various supply voltages.

Line Rectifier

AC line voltages of either 115V or 230 V may provide the primary power for the instrument, depending on the setting of LINE VOLTAGE SELECTOR switch S90 (located on the instrument rear panel). Power Switch S350 applies the selected line voltage to power supply rectifier CR1011.

With the selector switch in the 115 V position, the rectifier and storage capacitors C1021 and C1022 operate as a full-wave voltage doubler. When operating in this configuration, each capacitor is charged on opposite half cycles of the AC input, and the voltages across the two capacitors in series will approximate the peak-to-peak value of the source voltage. For 230 V operation, switch S90 connects the rectifier as a conventional bridge rectifier. Both capacitors charge on both input half cycles, and the voltage across C1021 and C1022 in series will approximate the peak value of the rectified source voltage. For either configuration, the DC voltage supplied to the power supply inverter is the same.

Thermistors RT1010 and RT1016 limit the surge current when the power supply is first turned on. As current flow warms the thermistors, their resistances decrease and have little effect on circuit operation. Spark-gap electrodes E1001 and E1002 are surge-voltage protectors. If excessive source voltage is applied to the instrument, the spark-gaps conduct, and the extra current flow quickly exceeds the rating of fuse F90. The fuse then opens to protect the instrument's power supply. The EMI (electromagnetic interference) filter, inductors L1011 and L1012, capacitors C1016 and C1018, and resistors R1011, R1012, R1016 and R1018 form a line-filter circuit. This filter, along with common mode rejection transformer T1020, prevents power-line interference from entering the instrument and prevents power supply switching signals from entering the supply line.

Preregulator Control

The Preregulator Control circuit monitors the drive voltage applied to inverter output transformer T1060 and holds it at the level that produces proper supply voltages at the secondary windings.

The Preregulator Control circuit consists primarily of control IC U1030, its switching buffers, and its power supply components. The control IC senses voltage on the primary winding of T2060 and varies the "on time" of a series-switching transistor, depending on whether the sensed voltage was too high or too low. The switching transistor Q1050, rectifier CR1050, choke T1050, and capacitor C1050 form a buck-switching regulator circuit. The output voltage at W1060 is proportional to the product of the rectified line voltage on C1020-C1022 and the duty cycle of Q1050. In normal operation, Q1050 is on about one-half the time. When Q1050 is off, current flows to W1060 and T1060 through CR1050.

PREREGULATOR CONTROL POWER SUPPLY. Since the Preregulator Control network controls supply startup and preregulates the secondary supplies, an independent power source must be established for it before any of the other power supplies will operate. The independent power supply for the control circuitry is composed of Q1021, Q1022, and associated components.

Initially, when instrument power is applied, the positive plate of capacitor C1025 is charged toward the positive rectified line voltage through R1020. The voltage at the base of Q1022 follows at a level determined by the voltage divider composed of R1022, R1024, CR1023, and the load within U1030. When the voltage across C1025 reaches about +21 V, the base voltage of Q1022 reaches + 6.8 V and Q1022 turns on, saturating Q1021. The +21 V on the emitter of Q1021 appears at its collector and establishes the positive voltage supply for the Preregulator IC. With Q1021 on, R1024 is placed in parallel with R1022, and both Q1022 and Q1021 remain saturated.

The +21 V level begins to drain down as the control IC draws current from C1025. If the Preregulator Control IC doesn't start the switching supply (and thus recharge C1025 and C1023 via CR1022) by the time the voltage across C1025 reaches about + 8 V, Q1021 will turn off. Resistor R1024 pulls the base of Q1022 low and turns that transistor off also. (Capacitor C1025 would only discharge low enough to turn off the transistors under a fault condition.) In this event, C1025 would then charge again to +21 V, and the start sequence would repeat. Normally, the control IC will start Inverter action before the + 8V level is reached, and current is drawn through T1050 via Q1050.

This induces a current in the secondary winding of T1050 via Q1050. This induces a current in the secondary winding of T1050 and charges C1025 positive via diode CR1022. The turns ratio of T1050 sets the secondary voltage at approximately + 15V; and, as long as the supply is being properly regulated, C1025 will be charged up to that level and held there.

PREREGULATOR START-UP. As the supply for the Preregulator Control IC is established, an internal switching oscillator begins to run. The oscillator generates a repetitive triangular wave (as shown in fig. 3-9) at a frequency determined primarily by R1032 and C1032. The simplified schematic of Figure 3-10 illustrates the voltage control functions of U1030.

As the Preregulator power supply turns on, capacitor C1034 charges from the + 5 V reference level toward ground potential through R1034 and R1037. As it does, the voltage-at pin 4 (one input of Dead-Time Comparator U1) will pass through the positive-peak value of the triangular waveform on the otherinput of the Dead-Time Comparator. The comparator will then begin outputting narrow pulses that become progressively wider as the voltage on pin 4 settles to zero volts. These pulses drive switching transistor Q1050, and their slow progression from narrow to wide causes the various secondary supplies to gradually build up to their final operating levels. The slow buildup prevents a turn-on current surge that would cause the current-limit circuitry to shut down the supply.

During startup, capacitor C1072 acts as a substantial load, and a relatively large current flows in the windings of T1050 for the first few cycles of Preregulator switching. These strong current pulses ensure that storage capacitor C1066 becomes charged sufficiently to start the Inverter Drive circuit. Once the Inverter Drive stage is operating, the normal switching current through T1050 maintains the required charge on C1066. (The Inverter Drive power supply is discussed later in this description.)

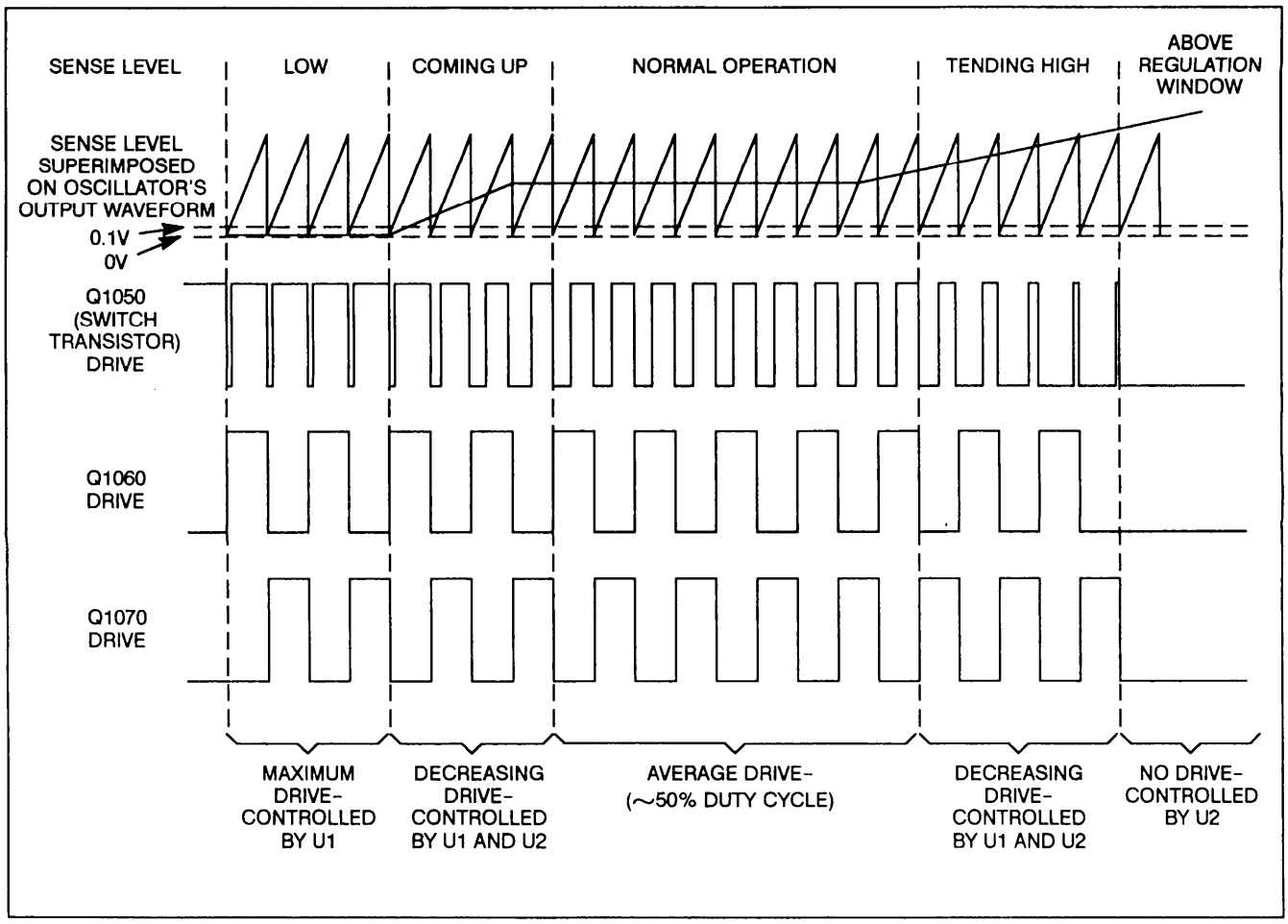


Figure 3-9. Timing relationships of the Inverter Drive signals.

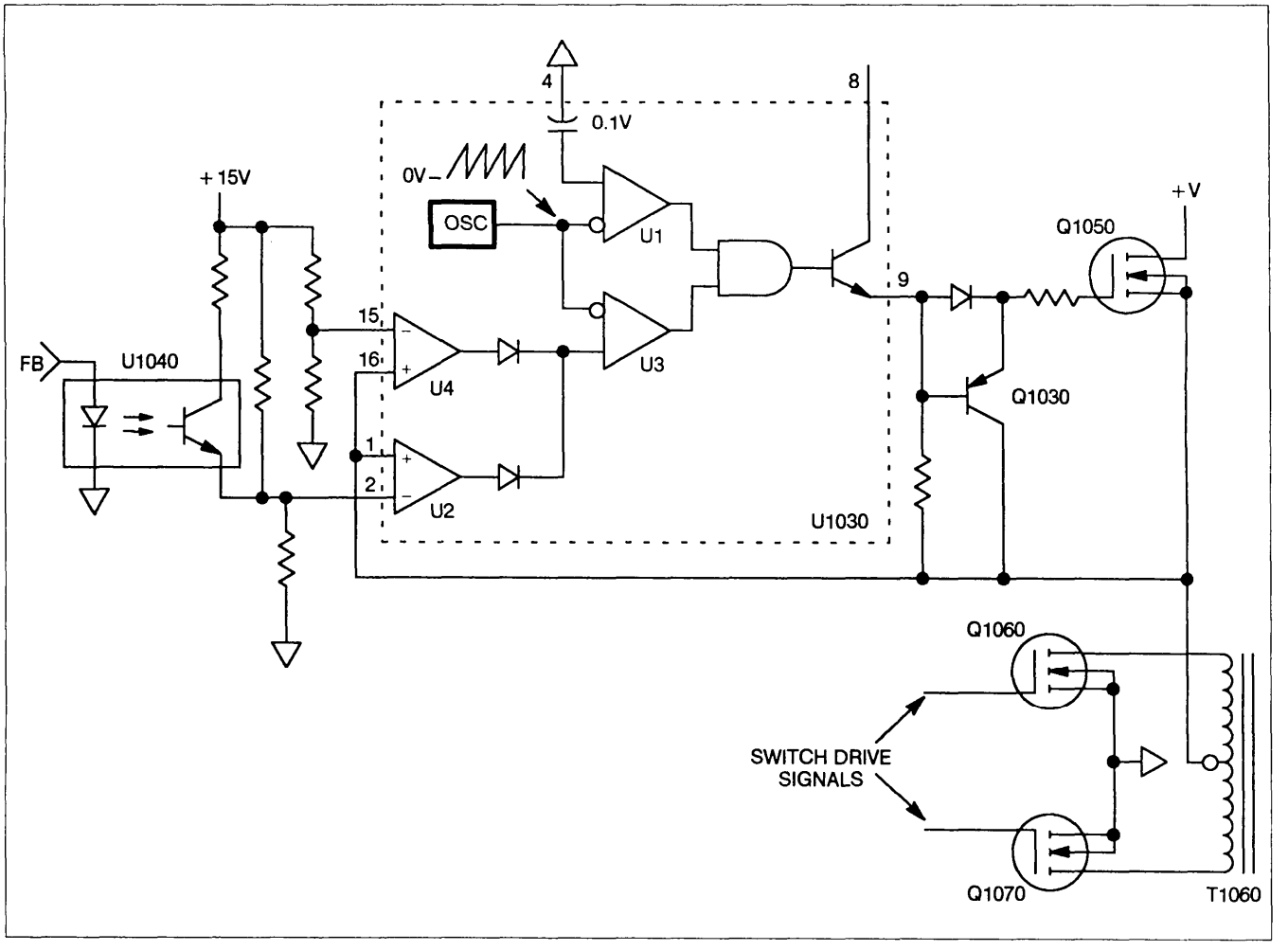


Figure 3-10. Simplified schematic of control network.

Dead-Time Comparator U1 is referenced at approximately 0.1 V above the ground level at pin 4 (established when C1034 becomes fully charged) and outputs a narrow, negative-going pulse that turns off switching transistor Q1050 for a portion of each switching cycle. This off time ensures that flip-flop U1064B in the Inverter Drive circuit toggles every cycle (thereby maintaining the proper duty cycle), independent of the voltage conditions being sensed by the remainder of the voltage control circuitry.

PREREGULATION. Once the initial charging at power-up is accomplished, as just described, the voltage-sensing circuitry begins controlling the Inverter switching action. The actual voltage sensing is done by error amplifier U2. The level at the center tap of output transformer T1060 is applied to pin 1 and is compared to the reference established by R1045 and R1046 at pin 2. If the sensed level at pin 1 is lower than the reference level (as it will always be for the first few switching cycles), the of error-amplifier U2 will be LO. The LO, applied to the inverting input of U3, results in a long-duty-cycle drive signal to transistor Q1050 (via CR1030). Since the Inverter Drive stage will alternately turn either Q1060 or Q1070 on, relatively large current pulses will result in the primary winding of inverter output transformer T1060.

These large current pulses, over the period of a few cycles, will increase the charge on the storage capacitors on the secondary side of the transformer and will reduce the current demand on the inverter output transformer. As the demand increases, the voltage across the primary winding will increase until it reaches the point where the two inputs of U2 are at the same potential, At this point, the output of U2 (to U3) will settle to a level approximately equal to the midpoint of the triangular waveform applied to the other input of U3. The resulting drive signal has an approximate 50% duty cycle and will respond to changes in either the AC line voltage or supply load conditions. Depending on the output levels sensed, the duty cycle of the drive signal will change (sensed level rises or falls with

respect to the triangular waveform) to hold the secondary supplies at their proper levels.

Opto-isolator U1040 and resistor R1044 form a control network that allows a voltage sensed at the feedback input (FB) to slightly alter the voltage-sense reference applied to pin 2 of U2. The FB signal is generated by the + 5V Inverter Feedback amplifier U 1371 (fig. FO-19, sheet 1) and is directly related to the level of the + 5 V_D supply line. Base drive to the shunt transistor (in opto-isolator U1040) is increased should the FB signal go below its nominal value. Additional current is shunted around R1045 (via R1044) and raises the voltage-sense reference level to error-amplifier U2. This increases the voltage applied to the primary winding of the output transformer, since U2 sensing depends on a balanced condition. Higher currents are induced in the secondary windings, and the secondary voltages begin to return to their nominal values. As the + 5 V_D line returns to its nominal level, base drive to the shunt transistor will be reduced and the voltage in the primary winding will follow. Should the FB signal level tend too high, opposite control responses occur. Further information about the FB signal is given in the + 5 V Inverter Feedback description.

Error amplifier U4 and the voltage divider composed of R1035 and R1031 provide a backup sensing circuit. Its operation is similar to that of error amplifier U2, just described, but it senses at a slightly higher level. As long as U2 is operating properly, U4 will be inactive. However, should a failure occur in the U2 sensing circuitry, the voltage on the primary winding of T1060 will rise to the sensing level at pin 15 of U4. Sense amplifier U4 will then takeover, preventing a damaging over-voltage condition.

Inverter Drive

The Inverter Drive circuit performs the necessary switching to drive the inverter output transformer. Like the Preregulator Control IC, the Inverter Drive circuit requires an independent power supply, since it must be operational before any of the secondary supply voltages can be generated.

INVERTER DRIVE POWER SUPPLY. This power supply consists of Q1062, VR1062, and their associated components. As power is first applied, the initial charging current through T1050 induces a current in the transformer secondary winding (pins 8 and 9). The alternating current is rectified by the diode bridge composed of CR1062, CR1063, CR1064, and CR1065 and stored in C1066, providing power for the lnverter Drive circuitry.

When the Preregulator Control IC turns switching transistor Q1050 on for the first time, the charge stored on C1066 during the initial charging period is sufficient to properly turn on one of the current-switching transistors (either Q1060 or Q1070) for the first cycle. After that, the alternating drive signals continue to induce current into the secondary winding of T1050 to provide operating power as long as the instrument is turned on.

The current rectified by the diode bridge and stored on capacitor C1066 is regulated down to the required voltage level by R1061, VR1062, and Q1062. Zener diode VR1062 references emitter-follower Q1062 and holds the supply output at approximately + 11.4 V.

INVERTER DRIVE GENERATOR. The Inverter Drive generator consists of U 1062, U1064, U1066, switching transistors Q1060, Q1070 and their associated components. The circuitry alternately switches current through each leg of the output transformer (T1060) primary winding and produces the AC current required for transformer action.

Out-of-phase input signals to comparator U1062C come from two resistive voltage dividers placed in either leg of one secondary winding of T1050. The comparator detects the phase changes (crossover points) of the secondary current caused as Q1050 switches on and off. Every complete on-off cycle of Q1050 produces a positive clock at pin 14 of U1062C that toggles flip-flop U1064B. The toggling alternately turns switching transistors Q1060 and Q1070 on, each with an approximate 50% duty cycle.

Comparators U1062A and U1062B, at the Q and $\overline{Q}$ output of the flip-flop, detect the precise crossing point of the toggling drive signals and ensure that only one switching transistor will be on at any one time. These mutually-exclusive drive signals are buffered by inverters U1066A and U1066B and applied to switching transistors Q1060 and Q1070 to alternately turn them on and off at one-half the switching rate of Q1050. By alternately switching opposite ends of the primary winding to ground, the current flowing through switching transistor Q1050 will flow alternately in each half of the primary winding. This produces AC voltages at the secondary windings that are then rectified, providing the various unregulated DC supply voltages.

Current Limit

The Current Limit circuit, composed of transistor Q1040 and the associated components, limits the maximum current flow in the output transformer to about 1 ampere. Resistor R1040 (connected to the Preregulator Control IC + 15 V supply) forward biases germanium diode CR1040 and applies approximately + 0.3 V across the base-to-emitter junction of Q1040. Current flowing to the output transformer develops a voltage drop across R1050 that adds to the bias developed by CR1040. As the current to the transformer increases, the voltage drop across R1050 also increases until, at around 1 A, the combined voltage drop across R1050 and CR1040 forward biases transistor Q1040. The base of Q1022 is pulled negative through R1042, and the + 15V supply for the Preregulator IC turns off (see Preregulator Control description). The power supply will try to restart itself; but, as long as the

excessive-current condition persists, the current-limit circuit will keep shutting the supply down, protecting the instrument.

Rectifiers

The rectifiers convert the alternating current from the secondary windings of inverter output transformer T1060 to the various DC supply voltages required by the instrument. Rectification is done by conventional diode rectifier circuits, and filtering is done by conventional LC networks.

The +87 V unregulated supply is produced by a voltage-doubler circuit. The positive plate of Cl 130 at the anode of CR1132 is referenced at approximately +45 V through diode CR1131 (to the +42 V unregulated supply). As the positive half cycle from the 42V secondary winding (actually about +45 V peak) is applied to the negative plate of C1130, the positive plate is elevated to a peak value of approximately +90 V. Diode CR1132 becomes forward biased and storage capacitor C1132 is charged to about +90 V. Following cycles replenish the charge drawn off by the loads on the +87 V supply line.

Line Signal

A sample of the AC line voltage is coupled tothe Trigger circuit by transformer T1229 and provides the LINE TRIG signal to the Trigger hybrid. Transformer current is limited to a safe value by resistors R1014 and R1015 placed in series with the primary winding leads. The transformer's output characteristics are matched to the input of the Trigger circuit hybrid by R1208 and C1208.

Line Up Signal

The circuit composed of Q1029, opto-isolator U1029, and their associated components, detects when power has been applied to the instrument and the Preregulator Control power supply is functioning properly. When the rectified line voltage reaches proper operating voltage, the voltage divider composed of R1027 and R1028 forward biases Q1029. As soon as the Preregulator Control power supply turns on, current flows through R1029, Q1029, and the opto-isolator LED. The illuminated LED saturates transistor U1029 and the LINEUP signal to the Power-Up Delay circuit (fig. FO-19, sheet 2) is pulled Hl, indicating that the Preregulator Control circuit should now be functioning properly.

POWER DOWN. When instrument power is turned off, the voltage across the primary storage capacitors (Cl 021 and C1022) begins to fall as the capacitors discharge. As the voltage drops, the bias current through R1027 to the base of Q1029 also drops until the bias voltage across R1028 reaches a point about 2 V above the average transformer drive level at pin 2 of U1029. At this point, Q1029 turns off, and the LINEUP signal to the Power-Up Delay circuit goes LO. This LO signals the Microprocessor that it should start its power down routine.

The Line Up circuit tells the Microprocessor that the primary capacitors have started discharging while there is still a stored charge (set by R1027 and R1028) about 40% in excess of that required to keep the power supply voltages in regulation. This allows the Microprocessor to complete the power-down sequence before the supplies drop below their normal operating level. Further information about the power-down sequence is given in the Microprocessor Reset Control description.

Fan Circuit

Fan motor B10 is driven by adjustable three terminal regulator U1110. The fan's speed is determined by the voltage supplied by U1110 and varies with ambient temperature.

As the ambient temperature in the cabinet increases, the resistance of thermistor RT1110 decreases causing more current to flow in R1112. This causes the voltage at pin 2 and therefore the voltage at pin 3 of U1110 to increase, and the fan motor speed increases to provide more cooling capacity.

LOW-VOLTAGE REGULATORS

The Low-Voltage Regulators remove AC noise and ripple from the various unregulated DC supply voltages (fig. FO-19, sheets 1 and 2). Each regulator output is automatically current limited if the output current exceeds the requirements of a normally functioning instrument. This limiting prevents any further component damage.

+10 Volt Reference

Each of the power-supply regulators control their respective outputs by comparing their output voltages to a known reference level. In order to maintain stable supply voltages, the reference voltage must itself be highly stable. The circuit composed of U1290, U1300C and associated components establish this reference.

Resistor R1400 and capacitor C1400 form an RC filter network that smooths the unregulated + 15 V supply before it is applied to voltage-reference IC U1290. The +2.5 V output from pin 2 of U1290 is applied to the noninverting input of operational amplifier U1300C. The output of U1300C is the source of the +10V reference level used by the various regulators. The output level is set by the voltage divider formed by R1291, R1293, and potentiometer R1292. The Volt Ref Adjust pot in the divider allows the reference level to be precisely set. Zener diode VR1292 prevents the reference from exceeding +11V should a failure in the reference circuitry occur.

+87 V Regulator

The +87 V Regulator is composed of Q1220, Q1221, Q1222, Q1223, U1281A, and their associated compo-

nents. The circuit regulates and limits both the voltage and current of the supply output.

initially, as power is applied, the voltage applied to pin 2 of U1281A from the voltage divider formed by R1227 and R1228 is lower than the +10 V reference level applied to pin 3. The output of U1281A is forced high, reverse biasing the base-emitter junction of Q1222 and turning it completely off. With Q1222 off, all the current through R1212 is supplied as base current to Darlington transistor pair Q1221 and Q1220, and maximum current flows in series-pass transistor Q1220. This charges up the various loads on the supply line, and the output level charges positive.

As the regulator output charges toward +87 V, the voltage divider applies a positive-going voltage to the inverting input of U1281A. When the output level reaches +87 V, the inverting input reaches the + 10 V reference at the noninverting input. The output voltage at pin 1 of U1281A will go negative and the base-emitter junction of Q1222 will be biased into the active region. As Q1222 turns on, base drive for the Darlington pair (Q1221 and pass transistor Q1220) is reduced. The output will beheld at the level required (+87 V) for voltage at the two inputs of amplifier U1281A to be in balance.

Current limiting is a foldback design and is performed by Q1223 and its associated components. Under normal current demand conditions, Q1223 is off. If the regulator output current exceeds approximately 100 mA (as it might if a component fails), the voltage drop across R1221 and CR1220 reaches a point that forward biases Q1223 via the bias divider formed by R1222 and R1223. As Q1223 turns on, a portion of the base-drive current to Q1221 is shunted away by Q1223. This reduces the base-drive current (and thus the output current) of series-pass transistor Q1220.

+42 V Regulator

The circuit configuration and operation of the +42 V Regulator is identical to that of the +82 V Regulator. Current limiting of the +42 V supply occurs at approximately 400 mA. Base drive to Darlington pair Q1241 and Q1240 is via R1244 and is dependent on proper operation of the +87 V Regulator. This dependency ensures that the relative polarities of the two supplies are never reversed (preventing semiconductor-junction damage in the associated load circuitry).

+15 V Regulator

The + 15 V Regulator uses three-terminal regulator U1260 and operational amplifiers U1371A and U1371B, arranged as voltage sensors, to achieve regulation of the + 15 V supply. The three-terminal regulator holds its output voltage at pin 2 at 1.25 V more positive than the reference input level at pin 1. The voltage at the reference pin is established by current flow in either diode CR1262 or CR1263.

Resistors R1261 and R1262 at the regulator output divide the + 15 V level down for comparison with the + 10V reference applied to pin 5 of operational amplifier U1371 B. When the input voltage at pin 6 (supplied by the voltage divider) is lower than the +10 V reference, the output of amplifier U1371B is high and the output voltage of U1260 is allowed to rise. As the regulator output reaches + 15 V, the voltage on pin 6 of U1371B approaches the level on pin 5, and the amplifier begins sinking current away from the reference pin of the three-terminal regulator via diode CR1263. This lowers the voltage on the reference pin and holds the output at + 15 V.

The other voltage-sensing amplifier (U1371A) ensures that the relative polarity between the + 15 V supply and the +42 V supply is maintained, preventing component damage in the load circuitry. Should the +42 V supply be pulled below + 15V (excessive loading or supply failure), the voltage at pin 3 of U1371A falls below the voltage at pin 2 and the amplifier output voltage goes low. This forward biases CR1262 and lowers the reference voltage for U1260, reducing the output voltage.

Current limiting for the + 15 V supply is provided by the internal circuitry of the three-terminal regulator.

+5 V Regulator

Regulation of the + 5 V supply is provided by a circuit similar to those of the + 87 V and the +42V Regulators. As long as the relative polarity between the + 15V and the + 5 V supplies is maintained, base drive to Q1281 is supplied through R1283. The current through Q1281 provides base drive for series-pass transistor Q1280.

When voltage-sense amplifier U1300B detects that the output voltage has reached + 5 V, it begins shunting base-drive current away from Q1281 via CR1281 and holds the output voltage constant.

Current limiting for the + 5 V supply is done by U1300A and associated components. Under normal current-demand conditions, the output of U1300A is high and diode CR1282 is reverse biased. However, should the current through the current-sense resistor R1281 reach approximately 2A, the voltage developed across R1281 will raise the voltage at pin 2 of U1300A (via divider R1282 and R1286) to a level equal to that at pin 3. This causes the output of U1300A to go low, forward biasing CR1282. This sinks base drive current away from Q1281 and lowers the output current in series-pass transistor Q1280.

-15 V Regulator

Operation of the -15 V Regulator, composed of three-terminal regulator U1330, operational amplifier U1270C, and their associated components, is similar to

that of the +15 V Regulator with the following major changes. The control voltage at the three-terminal regulator's reference pin (pin 1) is established by the current through series-resistors RI 333 and R1334. The reference pin is clamped by CR1332 at about -5.6 V should a failure in the sensing network occur. (Clamping also prevents latchup of the operational amplifier during start-up of the power supply.) Finally, the sensing divider formed by R1331 and R1332 is referenced to the + 10 V reference instead of ground to enable sensing of negative voltage.

-8 V Regulator

Operation of the -8 V Regulator is similar to that of the +87 V and +42 V Regulators. Due to the lower operating voltages of the -8V Regulator the common-base transistor present in both the +87 V and the +42 V is not required. Current limiting in the -8 V supply occurs at about 480 mA.

-5 V Regulator

Operation of the -5 V Regulator is similar to that of the + 5 V Regulator. Current limiting in the -5 V supply occurs at about 2 A.

+ 5 V Inverter Feedback

Operational amplifier U1371C and associated components are configured as a frequency-compensated voltage-sensing network. The circuit monitors the + 5V digital power supply line from the rectifiers and provides feedback to the Preregulator Control IC (U1030) via opto-isolator U1040 (both on fig. FO-18, sheet 1). The feedback is used to slightly vary the voltage-sensing characteristics of the Preregulator Control circuitry. The feedback (FB) signal slightly varies the voltage to the inverter output transformer and holds the output of the 5 V secondary windings at an optimum level. Output levels of the other secondary windings are related to the + 5 V_D level and are also held at their optimum values. This technique minimizes power losses in the series-pass transistors and increases regulator reliability.

Power-Up Delay

The Power-Up Delay circuit, composed of Q1370, Q1376, U1371D, and the associated components, ensures that the various regulated power supplies have time to reach their proper operating voltages before signaling the Microprocessor that the power supplies are up.

When power is first applied, a LINE UP signal from the Prereguiator Control circuit goes Hl, indicating that the power switch has been closed and that ample supply voltage is available for driving the Inverter transformer. The HI is applied to the base of Q1370, but since the collector is not properly biased yet, no transistor current will flow. As the Inverter begins to run, the various voltages from the secondary rectifiers begin coming up to their proper levels. A +2.5 V reference voltage is applied to operational amplifier U1371 D pin 12 and forces the output high, biasing Q1376 on.

Before any of the Low-Voltage Regulators may function properly, the + 10 V reference voltage must be established as previously described. When the + 15 V Regulator turns on, current flows through Q1370, and pin 13 of U1371 D is pulled above the +2.5 V reference through divider R1370 and R1372. The output of U1371D goes low, turning off Q1376.

When power to the instrument is turned off, the LINEUP signal goes LO (as explained in the Line Up Signal description). The falling LINE UP signal turns Q1370 off and drives the output of U1371D high. The output level from U1371D turns on Q1376 and pulls the PWR UP signal to the Microprocessor LO. This LO initiates the power-down sequence used to shutdown the instrument in an orderly fashion. The delay between the time that the PWR UP signal goes LO and when the regulated power supplies fall below their normal operating levels provides ample time for the Microprocessor to complete the power-down sequence.

Power Supply Shutdown

Phosphor damage can occur to the CRT if certain regulated power supply voltages are overloaded due to excessive current draw by their loads. U1300C and its associated circuitry monitor the + 15 V and the + 5 V Regulator supplies. The +87 V and the +42 V Regulator supplies are monitored via R1294 and R1295 respectively. If any of these regulated supplies exceed their limit, current is sourced to U1300D (pin 13). When this happens, the + 10 Preference begins to drop which in turn lowers all the regulated supplies. This causes the high voltage oscillator to shutdown preventing damage to the CRT. Q1290 and its associated circuitry allows the +10 V Reference to come up and stabilize before the shutdown circuitry is enabled. Jumper J208 is used to disconnect the shutdown circuitry for troubleshooting purposes.

POWER DISTRIBUTION

Figures FO-20, sheets 1 and 2, and FO-21, sheets 1 and 2, illustrate the power distribution of the instrument. The connections to the labeled boxes (representing the hybrids and ICS) show the power connections to each device, while connections to non-power lines are shown by the component and schematic number. Power supply decoupling is done with traditional LRC networks as shown on the diagrams.

Several intermediate supply voltages are generated by devices shown on figures FO-20, sheets 1 and 2, and FO-21, sheets 1 and 2. An approximate +32 V supply for the A and B Sweeps is developed by emitter-follower Q700

and its associated components. Zener diodes VR125 and VR225 develop approximate + 6.2 V supplies for the CH 1 and CH 2 Preamps respectively, and zener diode VR2805 establishes an approximate -6.8 V supply for U2800 and U2805.

INTERCONNECTIONS

Figure FO-22, sheets 1 and 2, illustrates the circuit board interconnections of the instrument. Connector numbers and cabling types are shown.

Section 4
PERFORMANCE CHECK AND FUNCTIONAL VERIFICATION PROCEDURE

INTRODUCTION

This procedure is used to verify proper operation of instrument controls and to check the instrument's performance against the requirements listed in the "Specification" (Section 1). This procedure verifies instrument function and maybe used to determine need for readjustment. These checks may also be used as an acceptance test and as a preliminary troubleshooting aid.

Removing the wrap-around cabinet is not necessary to perform this procedure. All checks are made using the operator accessible front- and rear-panel controls and connectors.

Within the procedure, steps to verify proper operation of an instrument control or function that are not specified in the "Specification" section begin with the word "VERIFY. " These functions ARE NOT specifications and should not be interpreted as such. Steps to check performance specifications begin with the word "CHECK."

PREPARATION

Test equipment items 1 through 27 listed in Table 4-1 are required to perform this procedure. The specific pieces of equipment required to perform the checks within each section are listed at the beginning of that section. The item numbers in parentheses next to each piece of equipment refer to the numbered equipment list of Table 4-1.

Before performing this procedure, ensure that the LINE VOLTAGE SELECTOR switch is set for the AC power source being used (see "Preparation for Use" in Section 2). Connect the instrument to be checked and the test equipment to an appropriate power source. Turn the instrument on and ensure that no error message is displayed on the CRT. If an error message is present, have the instrument repaired or calibrated by a qualified service technician before performing this procedure.

The procedure is divided into sections to permit functional and performance verifications of individual sections of the instrument without performing the entire procedure. Perform all steps within a section, both in the sequence presented and in their entirety to ensure that control settings are correct for the following step.

When performing partial procedures, the Initial Control Settings at the start of the section should be set up first; then make any changes noted at the start of the subsection to be performed. When performing the procedures in sequence, merely change those controls that have changed from the previous step.

NOTE

In order to see a channel's VOLTS/DIV setting, the channel must be selected using the VERTICAL MODE switches.

Table 4-1
Cross Reference for Test Equipment

Description	Suggested	U.S. Army Equivalent
1. Variable Power Supply	TEKTRONIX PS 503A	MIS-30526
2. Primary Leveled Sine-Wave Generator	TEKTRONIX SG 503	Bal. 6126M
3. Calibration Generator	TEKTRONIX PG 506	Bal. 6126M
4. Secondary Leveled Sine-Wave Generator	TEKTRONIX SG 504 with Leveling head	Bal. 6126M (Coverage to 250 MHz, not full requirement)
5. Function Generator	TEKTRONIX FG 501A	MIS - 30526
6. Time-Mark Generator	TEKTRONIX TG 501	Bal. 6126M
7. Test Oscilloscope with 10X Probe	TEKTRONIX 2465B wutg P6137 10X Probe	OS-288/G MIS - 30526
8. T-Connector (2 required)	TEKTRONIX Part Number 103-0030-00	103-0030-00
9. Precision BNC Cable	TEKTRONIX Part Number 012-0482-00	Bal. 6126M
10. BNC Cable (4 required)	TEKTRONIX Part Number 012-0057-01	012-0057-01
11. Dual-Input Coupler	TEKTRONIX Part Number 067-0525-02	067-0525-02
12. Termination (2 required)	TEKTRONIX Part Number 011-0049-01	011-0049-01
13. Subminiature Probe Tip to BNC Adapter	TEKTRONIX Part Number 013-0195-00	013-0195-00
14. BNC Female to BNC Female Adapter	TEKTRONIX Part Number 103-0028-00	UG 914/U
15. BNC Female to Dual Banana Adapter	TEKTRONIX Part Number 103-0090-00	7907592
16. 2X Attenuator	TEKTRONIX Part Number 011-0069-02	011-0059-02
17. 5X Attenuator	TEKTRONIX Part Number 011-0060-02	011-0060-02
18. 10X Attenuator	TEKTRONIX Part Number 011-0059-02	011-0069-02
19. Digitial Multimeter (DMM)	TEKTRONIX DM 502A	MIS 30526
20. Low-Capacitance Alignment Tool	TEKTRONIX Part Number 003-0675-00	003-0489-00
21. 1X Probe	TEKTRONIX P6101-01	P6028
22. Normalizer	TEKTRONIX Part Number 067-0537-00	MIS 7916146
23. Tunnel Diode Pulser	TEKTRONIX Part Number 067-0681-01	Bal. 6126M
24. Pulse Generator (2 required)	TEKTRONIX PG 502 Pulse Generator	HP 214B, WAVETEK 145
25. Adapter (2 required)	TEKTRONIX Part Number 103-0035-00	7909401
26. BNC to Probe Tip Adapter	TEKTRONIX Part Number 013-0227-00	013-0227-00
27. 2.5X Attenuator	TEKTRONIX Part Number 011-0076-02	011-0076-02

VERTICAL

Equipment Required (see table 4-1)

- Variable Power Supply (Item 1)
- Primary Leveled Sine-Wave Generator (Item 2)
- Calibration Generator (Item 3)
- Secondary Leveled Sine-Wave Generator (Item 4)
- 10X Probe (supplied with Test Oscilloscope, Item 7)
- Precision BNC Cable (Item 9)
- BNC Cable (Item 10)
- Dual-Input Coupler (Item 11)
- Termination (Item 12)
- Subminiature Probe Tip to BNC Adapter (Item 13)
- BNC Female to BNC Female Adapter (Item 14)
- BNC Female to Dual Banana Adapter (Item 15)
- 2X Attenuator (Item 16)
- 5X Attenuator (Item 17)
- 10X Attenuator (Item 18)
- 1X Probe (Item 21)
- BNC to probe tip Adapter (Item 26)

Initial Control Settings.

Control settings not listed do not affect the procedure.

Set:

NOTE

Select channels to set VOLTS/DIV.

VOLTS/DIV

CH 1 and CH 2	1V
CH 1 and CH 2 VAR	In detent
CH 3 and CH 4	0.1 v

VERTICAL MODE

CH 1	On
CH 2, CH 3, CH 4, ADD, and INVERT	off
CHOP/ALT	ALT
20 MHZ BW LIMIT	off

INPUT COUPLING

CH 1 and CH 2	1 MΩ GND

HORIZONTAL

A SEC/DIV	10 ms (knob in)
SEC/DIV VAR	In detent
X10 MAG	off
TRACE SEP	Fully CW

DELTA

Δ t and Δ V	Off (press and release until associated readout is off)
TRACKING	Off

TRIGGER

HOLDOFF	Fully CCW
LEVEL	Midrange
SLOPE	+ (plus)
A/B TRIG SELECT	A
MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC

1. Verify CH 1 and CH 2, 50 W OVERLOAD Protection.

a. Connect the Power Supply to the CH 1 OR X input connector via a BNC cable and a BNC female to dual banana adapter,

b. Using the CH 1 VERTICAL POSITION control, position the trace on the bottom horizontal graticule line.

c. Change CH 1 Input Coupling to 1 M Ω DC.

d. Turn the Power Supply on.

e. Adjust the Power Supply output level until the CH 1 trace rises to 1 division above the center graticule line (+5V).

f. Change CH 1 Input Coupling to 50 Ω DC.

g. VERIFY– For a period of one minute, the readout display does not indicate any overload condition (50 Ω OVERLOAD).

h. Change the CH 1 VOLTS/DIV control to 5 V and the CH 1 Input Coupling to 1 M Ω DC.

i. Increase the Power Supply output level until the CH 1 trace rises to the center graticule line (+20 V).

CAUTION

To prevent damage to the input circuitry when in 50 DC, the 20 V source must not be applied to the CH 1 OR X or CH 2 input connectors for longer than 20 seconds. If the automatic OVERLOAD switching does not occur within 20 seconds, turn the Power Supply off immediately.

j. Set the CH 1 Input Coupling to 50 Ω DC.

k. VERIFY –Within 20 seconds after CH 1 input coupling is set to 50 Ω DC, the readout display indicates "50 Ω OVERLOAD," the CH 1 Input Coupling changes to 1 M Ω GND automatically, and the trace returns to the bottom horizontal graticule line.

l. Turn the Power Supply Off.

m. Disconnect the Power Supply from CH 1 input.

n. Clear the OVERLOAD condition by pressing the upper CH 1 Input Coupling button.

o. VERIFY–The CH 1, 1 M Ω DC indicator is lit and the readout display no longer indicates "50 Ω OVERLOAD. "

p. Set the VERTICAL MODE buttons to display CH 2 and repeat parts a through o to verify 50 Ω OVERLOAD protection for CH 2.

2. Check CH 1 and CH 2 Low-Frequency AC Coupling.

a. Set:

NOTE

Select channels to set VOLTS/DIV

CH 1, CH 2 VOLTS/DIV	100 mV
CH 1 VERTICAL MODE	On
CH 2 VERTICAL MODE	Off
A SEC/DIV	10 ms (knob in)
CH 1 and CH 2 Input Coupling	1 M Ω GND

b. Connect the CALIBRATOR output signal to the CH 1 OR X input connector using a 1X probe.

c. Position the ground-reference trace 2 divisions below the center horizontal graticule line.

d. Set the CH 1 Input Coupling to 1 M Ω DC.

e. CHECK– Displayed signal is vertically centered and has an amplitude of 3.88 to 4.12 divisions.

f. Set the CH 1 Input Coupling to the upper 1 M Ω GND position.

g. Using the CH 1 POSITION control, align the trace with the center horizontal graticule line.

h. Set the CH 1 Input Coupling to 1 M Ω AC.

i. CHECK– Displayed signal is a tilted square wave, 4.36 to 5.37 divisions in amplitude, vertically centered on the graticule.

j. Move the probe to the CH 2 input connector.

k. Set the VERTICAL MODE buttons to deselect CH 1 and display CH 2.

l. Repeat parts c through i for CH 2.

m. Disconnect the test setup.

3. Check CH 1 and CH 2 VOLTS/DIV, CH 2 INVERT, Δ V and TRIGGER LEVEL Readout Accuracies, Variable VOLTS/DIV, Vertical Linearity, and ADD.

a. Set:

CH 1 Input Coupling	1 M Ω DC
CH 2 Input Coupling	1 M Ω DC

NOTE

Select channels to set VOLTS/DIV

CH 1 VOLTS/DIV	2 mV
CH 2 VOLTS/DIV	2 mV
BW LIMIT	On
CH 1	On
CH 2	Off
Δ V	On (press and release for a Δ V readout)
A SEC/DIV	1 ms (knob in)
TRIGGER MODE	AUTO

NOTE

The instrument must have had at least 20 minutes warmup prior to performing the following steps.

b. Momentarily press and hold both the CH 1 and CH 2 upper input Coupling buttons until a moving dot display replaces the normal signal. This performs a DC Balance of CH 1 and CH 2 and the readout indicates "DC BALANCE IN PROGRESS. "

c. When the signal and readout displays automatically return to normal, set the CH 1 and CH 2 Input Coupling to 1 M W DC.

d. Connect the Calibration Generator to the CH 1 OR X input connector via a BNC cable. Do not use a termination.

e. CHECK– CH 1 and CH 2 VOLTS/DIV, Δ V, and TRIGGER LEVEL readout accuracies as follows:

1. Set VOLTS/D IV control to the first position listed in Table 4-2.

2. Set the Calibration Generator STD AMPLITUDE output level to the corresponding Standard Amplitude Input Level in Table 4-2.

NOTE

To properly verify TRIGGER LEVEL Readout Accuracy, the Calibration Generator's STD AMPLITUDE output must have rising and falling transition times (10% to 90%) > 20 ns. No overshoot should appear on the waveform.

3. Verify that the generator output meets the requirements noted above.

4. Use the VERTICAL POSITION control to set the bottom of the signal 2 divisions below graticule center.

5. Rotate the Δ REF OR DLY POS control to align the reference cursor with the bottom of the waveform.

6. Rotate the Δ control to align the delta cursor with the top of the signal display.

7. CHECK–Vertical Deflection Accuracy (measured against the graticule) and Δ V Readout Accuracy are within the limits listed in Table 4-2.

8. Set the TRIGGER LEVEL control at the most positive voltage that produces a barely triggered, jittering display for each position (+ and -) of SLOPE.

9. CHECK–The A Trigger Level readings are within the limits given in the + Peak column of Table 4-2.

10. Set the TRIGGER LEVEL control at the most negative voltage that produces a barely triggered, jittering display for each position (+ and -) of SLOPE.

11. CHECK –The A Trigger Level readings are within the limits given in the -Peak column of Table 4-2.

12. Set the TRIGGER LEVEL for a stable display.

13. Pull the SEC/DIV knob out.

14. Set:

A/B TRIG	B
B TRIGGER MODE	TRIG AFT DLY
SOURCE	VERT
COUPLING	DC
SLOPE	+

15. Adjust Δ REF OR DLY POS control for a delay reading of 0.000 ms.

16. Set the TRIGGER LEVEL control to the most positive voltage that produces an intensified point on the waveform display for each position (+ and -) of SLOPE.

17. CHECK–The B Trigger Level readings are within the limits given in the + Peak column of Table 4-2.

18. Set the TRIGGER LEVEL control to the most negative voltage that produces an intensified point on the waveform display for each position (+ and -) of SLOPE.

19. CHECK–The B Trigger Level readings are within the limits given in the -Peak column of Table 4-2.

20. Push the SEC/DIV knob in.

21. Change the VOLTS/DIV to the next position listed in Table 4-2.

22. Set the Calibration Generator to the corresponding signal amplitude setting.

23. Press and release the Δ V pushbutton to obtain the Δ V readout display.

24. Repeat subparts 4 through 23 of part e for each VOLTS/DIV setting listed in Table 4-2.

25. Set the TRIGGER Coupling to NOISE REJ.

26. Set the CH 1 VOLTS/DIV to 50 mV.

27. Set the Calibration Generator STD AMPLITUDE output level to 0.2 V.

28. CHECK –Trigger Level Readout is within the limits given in Table 4-2 for NOISE REJ Coupling.

Table 4-2
Accuracy Limits
CH 1, CH 2 INVERT, and DELTA Volts Readouts

VOLTS/ DIV Switch Setting CH 1 and CH 2	Standard Amplitude Input Level	Vertical Deflection Accuracy (± 2% in divisions)	Delta Volts Readout Accuracy (limits) 1.25% + 0.03 div	Limits of Trigger LEVEL Readout			
				DC Coupling		NOISE REJ Coupling	
				+ Peak	-Peak	+ Peak	-Peak
2 mV	10 mV	4.90 to 5.10	9.81 mV to 10.20 mV	8.0 mV to 12.0 mV	+ 1.7 mV to -1.7 mV		
5 mV	20 mV	3.92 to 4.08	19.5 mV to 20.4 mV	16.8 mV to 23.2 mV	+ 2.6 mV to -2.6 mV		
10 mV	50 mV	4.90 to 5.10	49.0 mV to 50.9 mV	44 mV to 56 mV	+ 4.5 mV to -4.5 mV		
20 mV	0.1 V	4.90 to 5.10	98.1 mV to 102.0 mV	89 mV to 111 mV	+ 8.0 mV to -8.0 mV		
50 mV	0.2 V	3.92 to 4.08	196 mV to 204 mV	178 mV to 222 mV	+ 16 mV to -16 mV	148 mV to 252 mV	+ 46 mV to -46 mV
100 mV	0.5 V	4.90 to 5.10	490 mV to 409 mV	0.450 V to 0.550 V	+ 0.035 V to -0.035 V		
200 mV	1.0 V	4.90 to 5.10	0.981 V to 1.020 V	0.90 V to 1.10 V	+ 0.07 V to -0.07 V		
500 mV	2.0 V	3.92 to 4.08	1.96 V to 2.04 V	1.78 V to 2.22 V	0.16 V to -0.16 V		
1.0 V	5.0 V	4.90 to 5.10	4.90 V to 5.09 V	4.50 V to 5.50 V	+ 0.35 V to -0.35 V		
2.0 V	10.0 V	4.90 to 5.10	9.81 V to 10.2 V	9.0 V to 11.0 V	+ 0.7 V to -0.7 V		
5.0 V	20.0 V	3.92 to 4.08	19.6 V to 20.4 V	17.8 V to 22.2 V	+ 1.6 V to -1.6 V		

f. Return the TRIGGER COUPLING to DC.

g. Set the CH 1 VOLTS/DIV and the Calibration Generator output level to produce a vertical signal display 5 divisions in amplitude.

h. CHECK – Display amplitude reduces to 2 divisions or less when the VOLTS/DIV VAR control (of the channel undertest) is rotated fully CCW. Return the VOLTS/DIV VAR control to its maximum CW (detent) position.

i. Set the Calibration Generator output level and VERTICAL POSITION controls for a 2-division display vertically centered on the graticule. Use the CH 1 VAR control if necessary to obtain the correct display amplitude.

j. Set the VERTICAL POSITION control to align the top edge of the display with the top graticule line.

k. CHECK–Signal display amplitude is 1.9 to 2.1 divisions.

l. Set the VERTICAL POSITION control to align the bottom edge of the signal display with the bottom graticule line.

m. CHECK–Signal display amplitude is 1.9 to 2.1 divisions.

n. Set:

CH 1 and CH 2
Input Coupling 50 Ω DC

o. Connect the Calibration Generator to the CH 1 OR X input connector via a BNC cable. Do not use a termination.

p. Check CH 1 and CH 2 VOLTS/DIV 50 Ω Coupling accuracy as follows:

1. Set VOLTS/DIV control to the first position listed in Table 4-3.

2. Set the Calibration Generator STD AMPLITUDE output level to the corresponding Standard Amplitude Input Level in Table 4-3.

3. Use the VERTICAL POSITION control to set the bottom of the signal 2 divisions below graticule center.

4. CHECK –Vertical Deflection Accuracy (measured against the graticule) is within the limits listed in Table 4-3.

5. Change the VOLTS/DIV to the next position listed in Table 4-3.

6. Set the Calibration Generator to the corresponding signal amplitude setting.

7. Repeat subparts 3 through 6 of part p for each VOLTS/DIV setting listed in Table 4-3.

8. Set CH 1 and CH 2 Input Coupling to 1 M Ω DC.

Table 4-3

CH 1 and CH 2 VOLTS/DIV 50 Ω Coupling

VOLTS/DIV Setting CH 1 and CH 2	Standard Amplitude Input Level	Vertical Deflection Accuracy (± 3% in divisions)
2 mV	20 mV	4.85 to 5.15
5 mV	50 mV	4.85 to 5.15
10 mV	0.1 V	4.85 to 5.15
20 mV	0.2 V	4.85 to 5.15
50 mV	0.5 V	4.85 to 5.15
100 mV	1.0 V	4.85 to 5.15
200 mV	2.0 V	4.85 to 5.15
500 mV	5.0 V	4.85 to 5.15
1.0 V	10.0 V	4.85 to 5.15

q. Move the test signal to CH 2 and set the VERTICAL MODE controls to display CH 2.

r. Return the CH 1 VOLTS/DIV VAR control to the calibrated detent position.

s. Repeat parts e through p for CH 2.

t. Return the CH 2 VOLTS/DIV VAR control to the calibrated detent position.

u. Rotate the Δ REF OR DLY POS control CCW until the cursor stops moving.

v. CHECK–Cursor is aligned with the bottom graticule line within ± 0.2 division.

w. Rotate the Δ control CW until the cursor stops moving.

x. CHECK–Cursor is aligned with the top graticule line within ± 0.2 division. Push Δ V to turn off cursors.

y. Turn the INVERT function on, and obtain a 5-division signal as explained in part g.

z. VERIFY–A down-arrow symbol appears to the left of the CH 2 VOLTS/DIV readout.

aa. CHECK– Display amplitude is between 4.9 divisions and 5.1 divisions in amplitude (5 divisions ± 2%). Turn the INVERT function off when finished.

ab. Connect a 5 V standard-amplitude signal from the Calibration Generator to the CH 1 OR X and CH 2 input connectors via a BNC cable and a dual-input coupler.

ac. Set:

VOLTS/DIV

CH 1 and CH 2	2 V

VERTICAL **MODE**

CH 1 and CH 2	Off
ADD	On
VAR	In Detent

ad. CHECK–Vertical deflection amplitude is 4.9 to 5.1 divisions.

ae. VERIFY–A + (plus) symbol appears to the left of the CH 2 VOLTS/DIV readout.

af. CHECK–Signal amplitude reduces to 0.2 division or less when CH 2 INVERT is on.

ag. Set:

VERTICAL MODE

CH 3	On
CH1, CH2, CH4 ADD, and INVERT	Off

Table 4-4
CH 3 and CH 4 Accuracy Limits

VOLTS/DIV Switch Setting CH 3 and CH 4	Standard Amplitude Signal Input Level	Vertical Deflection Accuracy (± 10% in divisions)	Trigger LEVEL Readout When Barely Triggered at the Indicated Peak	
			+ Peak	-Peak
0.1 V	0.5 V	4.50 to 5.50	0.455 V to 0.545 V	±0.03 V
0.5 V	2.0 V	3.60 to 4.40	1.82 V to 2.18 V	±0.12 V

ah. Move the dual-input coupler to the CH3 and CH4 input connectors.

ai. CHECK – VOLTS/DIV and TRIGGER LEVEL Readout accuracies for both setting-input level combinations listed in Table 4-4 as in subparts 4 through 23 of part e.

aj. Set the Calibration Generator output level and VERTICAL POSITION controls for a 2-division display vertically centered on the graticule.

ak. Set the VERTICAL POSITION control to align the top edge of the display with the top graticule line.

al. CHECK–Signal display amplitude is 1.9 to 2.1 divisions.

am. Set the VERTICAL POSITION control to align the bottom edge of the signal display with the bottom graticule line.

an. CHECK–Signal display amplitude is 1.9 to 2.1 divisions.

ao. Set the VERTICAL MODE buttons to disable CH 3 and display CH 4.

ap. Repeat parts aj through ao for CH 4.

aq. Disconnect the test setup.

4. Check Channel 2 Delay.

a. Set:

CH 1,2	
VERTICAL MODE	On
CH 3 and CH 4	
VERTICAL MODE	Off
20 MHZ BWLIMIT	Off
CH 1 and CH 2 Input Coupling	50 Ω DC
CH 1 and CH 2 VOLTS/DIV	10mV
A SEC/DIV	1 µs (knob in)
TRIGGER SOURCE	CH 1

b. Connect a 100 kHz, fast-rise, positive-going signal from the Calibration Generator to the CH 1 OR X and the CH 2 input connectors via a BNC cable, a 5X attenuator and a dual-input coupler.

c. Set the output level of the Calibration Generator for an approximate 5-division, vertically-centered display for both channels.

d. Use either the CH 1 or CH 2 VAR control to match signal amplitude between both channels.

e. Set:

A SEC/DIV	5 ns (knob in)
X10 MAG	On

f. Use the Horizontal POSITION control to move the rising edges of the CH 1 and CH2 displays to graticule center.

g. Pull the SEC/DIV knob out to activate the CH 2 DLY feature.

NOTE

If the readout displays "CH 2 DLY DISABLED" instead of "CH 2 DLY-TURN " the delay matching feature has been disabled and the remainder of this subsection cannot be performed. In this case, proceed to subsection 5 below.

h. CHECK– Δ control will position the CH 2 display one division or more (500 ps) to either side of the CH 1 display.

i. Superimpose the rising edges of the pulses using the Δ control.

j. Turn X10 MAG off and push in the SEC/DIV knob.

k. Disconnect the test setup.

5. Check Vertical Bandwidth–All Channels.

a. Set:

A SEC/DIV	50 µs (knob in)
TRIGGER SOURCE	VERT

NOTE

Select channels to set VOLTS/DIV

CH 1, CH 2 VOLTS/DIV	20 mV
CH 3, CH 4 VOLTS/DIV	0.1 V
CH 1 and CH 2 VAR	Calibrated (in detent)
CH 1 VERTICAL MODE	On
CH 2, CH 3, CH 4 VERTICAL MODE	Off
CH 1 and CH 2 Input Coupling	50 Ω DC

b. Connect the output of the Secondary Leveled Sine-Wave Generator to the CH 1 OR X input connector via a precision BNC cable and any combination of the 10X, 5X, or 2X Attenuators needed to reduce the signal amplitude to the level called out in the next step.

c. Set the generator output level for a 6-division display at the reference frequency (.05 or 6 MHz on the SG 504), then change the generator output to 350 MHz.

d. CHECK–Signal display amplitude is 4.25 divisions or greater while sweeping the generator frequency from 350 MHz to 420 MHz.

e. Set the VOLTS/DIV to 0.5 V and repeat parts c and d.

f. Set the VOLTS/DIV to 1 V and the generator output level for a 4-division display at the reference frequency, then change the generator frequency to 350 MHz.

g. CHECK–Signal display amplitude is 2.82 divisions or greater while sweeping the generator frequency from 350 MHz to 420 MHz.

h. Move the signal to CH 2 input connector and set the VERTICAL MODE to disable CH 1 and display CH 2.

i. CHECK–Repeat parts c through g for CH 2.

j. Set the VERTICAL MODE to display CH 3 only.

k. Attach the 10X probe (supplied with the Test Oscilloscope or the OS-288) to the CH 3 input connector and the probe tip to the CALIBRATOR terminal,

l. Set the SEC/DIV (knob in) to 1 ms.

m. Adjust probe compensation for the best flat top on the square-wave signal display.

n. Disconnect the probe tip from the CALIBRATOR terminal. Remove the grabber tip from the probe, unscrew and remove the plastic barrel, and connect the probe to the output of the Secondary Leveled Sine-Wave Generator (with the leveling head) via a BNC to probe tip adapter.

o. Set the SEC/DIV to 50 µs (knob in).

p. Set the generator output for a 4-division display at the reference frequency, then change the generator frequency to 350 MHz.

q. CHECK–Signal display amplitude is 2.82 divisions or greater while sweeping the generator frequency from 350 MHz to 420 MHz.

r. Move the signal to CH 4 and set the VERTICAL MODE to display CH 4 only.

s. CHECK– Repeat parts k through q for CH 4.

t. Disconnect the test setup.

6. Check Common Mode Rejection Ratio (CMRR).

a. Set:

NOTE

Select channels to set VOLTS/DIV

CH 1, CH 2 VOLTS/DIV	10mV
CH 1 and CH 2 VAR	In detent
CH 1, ADD, and INVERT	On
CH 2, CH 3, and CH 4	Off
CH 1 and CH 2 Input Coupling	50 Ω DC
A SEC/DIV	50 µs (knob in)
TRIGGER MODE	AUTO LVL
TRIGGER SOURCE	CH 1

b. Connect a reference frequency signal from the Primary Leveled Sine-Wave Generator to the CH 1 OR X and CH 2 input connectors via a BNC cable, a 5X attenuator, and a dual-input coupler.

c. Set the generator output level for an 8-division display of the reference signal on CH 1.

d. Adjust either the CH 1 VAR control or the CH 2 VAR control for a minimum ADD display amplitude while leaving the other control in the calibrated detent (whichever provides the best CMRR).

e. Set the generator frequency to 50 MHz.

f. Set the A SEC/DIV to 20 ns.

g. CHECK–ADD display amplitude is 0.4 division or less (discount trace width).

h. Set ADD and INVERT Off and rotate the CH 1 and CH 2 VAR controls CW to their calibrated detent positions.

i. Disconnect the test setup.

7. Check Channel Isolation.

a. Set:

CH1, 2, 3 and 4	
VERTICAL MODE	On
CHOP/ALT	ALT
CH 1 and CH 2 Input Coupling	50 Ω DC
CH 1, CH 2 VOLTS/DIV	0.1 v
CH 3, CH 4 VOLTS/DIV	0.1 v
TRIGGER SOURCE	CH 1
A SEC/DIV	20 ns (knob in)

b. Connect the Primary Leveled Sine-Wave Generator to the CH 1 OR X input connector via a BNC cable.

c. Set the generator frequency to 100 MHz and adjust the output level for an 8-division display.

d. CHECK–Amplitude of each trace other than CH 1 is 0.08 division or less (discount trace width).

e. Move the signal to the CH 2 input connector and change the TRIGGER SOURCE to CH 2.

f. CHECK–Amplitude of each trace other than CH 2 is 0.08 division or less (discount trace width).

g. Add a termination to the BNC cable and move the signal to CH 3.

h. Set the TRIGGER SOURCE to CH 3 and adjust the generator output for a signal display amplitude of 8 divisions.

i. CHECK–Amplitude of each trace other than CH 3 is 0.16 division or less (discount trace width).

j. Move the signal to CH 4 input connector and set TRIGGER SOURCE to CH 4.

k. CHECK –Amplitude of each trace other than CH 4 is 0.16 division or less (discount trace width).

l. Replace the Primary Leveled Sine-Wave Generator with the Secondary Leveled Sine-Wave Generator (with the leveling head) and connect the generator to the CH 1 OR X input connector.

m. Set the TRIGGER SOURCE to CH 1.

n. Set the generator output frequency to 400 MHz and the output level for an 8-division display.

o. CHECK –Amplitude of each trace other than CH 1 is 0.16 division or less (discount trace width).

p. Move the signal to the CH 2 input connector and set the TRIGGER SOURCE to CH 2.

q. CHECK–Amplitude of each trace other than CH 2 is 0.16 division or less (discount trace width).

r. Disconnect the test setup.

8. Set CH 1 and CH 2 DC Balance.

NOTE

For an accurate DC Balance setting, the instrument MUST be allowed to warm up for 20 minutes before performing the following steps.

a. Press both the CH 1 and CH 2 upper Input Coupling buttons for approximately 1 second, then release them.

b. VERIFY–DC BALANCE IN PROGRESS in top line of readout. A flashing dot is also displayed. The display returns to normal in approximately 15 seconds.

c. VERIFY–There is less than 0.2 division + 0.5 mV vertical trace shift between adjacent settings of the CH 1 and CH 2 VOLTS/DIV as they are rotated through each of their positions.

d. VERIFY–There is less than 0.2 division vertical trace shift between the CH 3 and CH 4 VOLTS/DIV settings.

e. VERIFY–There is less than 1.0 division vertical trace shift as the CH 1 and CH 2 VOLTS/DIV VAR controls are rotated fully CCW.

f. VERIFY–There is less than 0.5 division vertical trace shift when the INVERT button is pressed.

g. Return the VERTICAL VAR controls to their detent positions and turn the CH 2 lNVERT function off.

9. Check CH 2 SIGNAL OUT and Cascaded Operation.

a. Set:

CH 1 VERTICAL MODE	On
CH 2, CH 3, CH 4	
VERTICAL MODE	Off
20 MHZ BW LIMIT	On

NOTE

Temporarily select CH2 to set CH 2 VOLTS/DIV

CH 1, CH 2 VOLTS/DIV	2 mV
CH 1 and CH 2 Input Coupling	1 M Ω DC
A SEC/DIV	200 µs (knob in)
TRIGGER MODE	AUTO LVL
SOURCE	VERT
COUPLING	HF REJ

b. Connect a 1 kHz, 1 mV standard-amplitude signal from the Calibration Generator to the CH 2 input connector via a BNC cable.

c. Connect the CH 2 signal from the rear-panel CH 2 SIGNAL OUT connector to the CH 1 OR X input connector via a precision BNC cable.

d. CHECK–Display amplitude is 4.5 to 5.5 divisions (discount trace width).

e. Set CH 2 Input Coupling to GND and align the trace with the center graticule line.

f. CHECK–Trace noise is 1.2 divisions peak-to-peak or less.

g. Set CH 1 Input Coupling to GND and align the trace with the center graticule line.

h. Return CH 1 Input Coupling to 1 M Ω DC.

i. Set the CH 1 VOLTS/DIV to 10 mV.

j. CHECK–The baseline of the display is within 2 divisions of the ground reference set above (discount trace width).

10. Check BW Limit Operation.

a. Set:

CH 1 VERTICAL MODE	Off
CH 2 VERTICAL MODE	On
20 MHZ BW LIMIT	On
A SEC/DIV	50 µs (knob in)
CH 2 VOLTS/DIV	10 mV
CH 2 Input Coupling	1 M Ω DC

b. Connect the Primary Leveled Sine-Wave Generator output to the CH 2 input connector via a precision BNC cable.

c. Set the generator frequency to 50 kHz and adjust the output level for a 6-division display on the CRT.

d. Gradually increase the generator output frequency until the display amplitude decreases to 4.24 divisions.

e. CHECK – Generator frequency is between 13 MHz to 24 MHz.

f. Turn BW LIMIT off.

g. Disconnect the test setup.

TRIGGERING

Equipment Required (see table 4-1)

Primary Leveled Sine-Wave Generator (Item 2)	BNC Cable (4 required) (Item 10)
Secondary Leveled Sine-Wave Generator (Item 4)	Dual-Input Coupler (Item 11)
Function Generator (Item 5)	Termination (2 required) (Item 12)
10X Probe (supplied with Test Oscilloscope, Item 7)	Subminitiare Probe Tip to BNC Adapter (Item 13)
T-Connector (2 required) (Item 8)	10X Attenuator (Item 18)
Precision BNC Cable (Item 9)	Adapter (2 Required) (Item 25)

Initial Control Settings.

Control settings not listed do not affect the procedure.

a. Set:

NOTE

Select channels to set VOLTS/DIV.

VOLTS/DIV

CH 1	100 mV
CH 2	500 mV
CH 1 and CH 2 VAR	In detent
CH 3 and CH 4	0.5 v

VERTICAL MODE

CH 1	On
CH 2, CH 3, CH 4, ADD and INVERT	Off
CHOP/ALT	ALT
20 MHZ BWLIMIT	Off

INPUT COUPLING

CH 1 and CH 2	1 M Ω DC

HORIZONTAL

A SEC/DIV	2 µs (knob in)
SEC/DIV VAR	In detent
X10 MAG	Off
TRACE SEP	Fully CW

DELTA

Δ t and Δ V	Off (press and release until associated readout is off)
TRACKING	Off

TRIGGER

HOLDOFF	B ENDS A (fully CW)
LEVEL	Midrange
SLOPE	+ (plus)
MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC

1. Check A and B Triggers.

NOTE

The Trigger Level Readout Accuracies are checked in the Vertical Performance Checks.

a. Refer to Table 4-5 to determine what the A Trigger requirements are and at what frequencies various checks are made.

b. Using a BNC cable, connect one of the following test generators to the CH 1 input connector. Select the generator that produces the proper frequency range for the conditions being tested as called out in Tables 4-5 and 4-6. When using the leveled sine-wave generators (items 2 and 3 below), the output must be terminated into 50 Ω (either the input coupling or a termination may be used).

1. Function Generator (60 Hz, 30 kHz and 80 kHz)

2. Primary Leveled Sine-Wave Generator (50 MHz)

3. Secondary Leveled Sine-Wave Generator (500 MHz)

NOTE

To obtain signal amplitudes less than 1 division, first set the signal for either 4, 5, or 10 times the specified amplitude, then reduce the amplitude by a factor of 4, 5, or 70 by increasing the VOLTS/DIV settings as necessary.

c. For each combination listed in the table, set the generator Test Frequency and the oscilloscope TRIGGER COUPLING as indicated, performing the following steps to verify the Triggering levels in each setup.

d. Set the VOLTS/DIV and the generator output level to obtain the test signal amplitude indicated for the particular combination being tested. When checking Channel 1 and Channel 2500 MHz triggering, also adjust the VOLTS/DIV VAR for the correct input level.

e. Set the A SEC/DIV and the X10 MAG to obtain a well-defined display of the test signal.

NOTE

Normally, unless trigger sensitivity is very close to the specified limits, it is sufficient to check each of the indicated frequency-coupling combinations listed in the table in Channel 1 only; checks for Channels 2, 3 and 4 need only be done in DC COUPLING (to verify signal path).

f. CHECK– For a stable triggered display (unless otherwise indicated) for each of the Test Frequency-TRIGGER COUPLING combinations listed in Table *4-5.* When testing the 300 MHz triggering, check that trigger jitter is <100 ps (0.2 division at 5 ns/div with X10 MAG), with 5 divisions of signal and TRIGGER LEVEL adjusted for minimum jitter.

g. Press the ADD button to select the function and press the CH 1 button to turn off the CH 1 display.

h. Repeat the DC TRIGGER COUPLING tests of Table4-5 while in the ADD mode, adding 0.5 DIV to the 300 and 500 MHz amplitudes.

i. Move the signal to the CH 2 input connector and repeat step h for CH 2.

j. Press the CH 2 button to select the channel and press the ADD button to turn off the ADD display.

k. Repeat the DC TRIGGER COUPLING tests of Table 4-5 while in CH 2 mode.

l. If trigger sensitivity is close to the specified limits given in steps c through k above, test all of the frequency-coupling combinations given in Table 4-5 for CH 2.

Table 4-5
CH 1 or CH 2 Triggering Conditions

Test Frequency	Minimum Vertical Display Levels at Which Triggering Should Occur				
	TRIGGER COUPLING				
	DC	NOISE REJ	HF REJ	LF REJ	AC
60 Hz	[1]	[1]	[1]	No Trigger, Freeruns	0.35 div
30 kHz	[1]	[1]	0.35 div	[1]	[1]
80 kHz	[1]	[1]	[1]	0.35 div	[1]
50 MHz	0.35 div	1.2 div	No Trigger, Freeruns at 1.2 div	0.35 div	0.35 div
300 MHz	1.0 div	3.0 div	No Trigger, Freeruns at 3.0 div	1.0 div	1.0 div
500 MHz	1.5 div	4.5 div	[1]	1.5 div	1.5 div

[1] **Not necessary to check.**

Table 4-6
CH 3 or CH 4 Triggering Conditions

Test Frequency	Minimum Vertical Display Levels at Which Triggering Should Occur				
	TRIGGER COUPLING				
	DC	NOISE REJ	HF REJ	LF REJ	AC
60 Hz	[1]	[1]	[1]	No Trigger, Freeruns	0.18 div
30 kHz	[1]	[1]	0.25 div	[1]	[1]
80 kHz	[1]	[1]	[1]	0.25 div	[1]
50 MHz	0.18 div	0.6 div	No Trigger, Freeruns at 0.6 div	0.18 div	0.18 div
300 MHz	0.5 div	1.5 div	No Trigger, Freeruns at 1.5 div	0.5 div	0.5 div
500 MHz	0.75 div	2.25 div	[1]	0.75 div	0.75 div

[1] **Not necessary to check.**

m. Move the test signal to CH 3 and CH 4 in turn and repeat parts c through f using Table 4-6.

n. Set:

TRIGGER MODE	AUTO
TRIGGER LEVEL	Fully clockwise

o. Pull the SEC/DIV knob out and set the B SEC/DIV one setting (CW) faster than the A SEC/DIV setting, then push the SEC/DIV knob back in.

p. Verify that the CRT readout displays DLY and not At. If At is displayed, press the At button in and release it to select the DLY function. When DLY is displayed, rotate the A REF OR DLY POS control CCW until the readout display indicates zero delay. (The display will indicate DLY?, which is normal.)

q. Press the A/B TRIG button to select the BTRIGGER.

r. Set B TRIGGER MODE to TRIG AFT DLY and adjust TRIGGER LEVEL for a stable signal display.

s. Repeat parts a through m for B TRIGGER, changing the SEC/DIV and X10 MAG as required to maintain a well-defined display.

t. Disconnect the test setup.

2. Check Composite Triggering.

a. Set:

CH1, CH2, CH3, CH4 VERTICAL MODE	On
ADD	off
CHOP/ALT	ALT
CH1 and CH2 input Coupling	1 M Ω DC
A/B TRIG TRIGGER	A
TRIGGER MODE	NORM
TRIGGER SOURCE	CH1
TRIGGER COUPLING	DC
A SEC/DIV	10 µs (knob in)

b. Connect the Function Generator to the CH1 and CH2 inputs via a BNC cable and a dual-input coupler.

c. Set the Function Generator for a 50 kHz, 1.35-division display for CH1 and CH2.

d. Connect the Primary Leveled Sine-Wave Generator to the CH3 input connector using a BNC cable and a termination.

e. Set TRIGGER SOURCE to CH3.

f. Set the generator output level for a 0.7-division display at the reference frequency (50 kHz).

g. Connect the Secondary Leveled Sine-Wave Generator to the CH4 input using a BNC cable and a termination.

h. Set TRIGGER SOURCE to CH4.

i. Set the generator output level for a 0.7-division display at the reference frequency.

j. Set TRIGGER SOURCE to VERT.

k. CHECK – Display will trigger as the TRIGGER LEVEL control is rotated through its range.

l. Pull the SEC/DIV knob out, rotate it to 5 µs, and push it back in.

m. Press the A/B TRIG button and set the B TRIGGER MODE to TRIG AFT DLY.

n. Set B TRIGGER SOURCE to VERT.

o. Rotate the Δ REF OR DLY POS control CCW until the delay readout indicates DLY? 0.00 µs.

p. CHECK – Display will trigger as the TRIGGER LEVEL control is rotated through its range.

q. Rotate the SEC/DIV knob back to 10 µs (knob in).

r. Disconnect the test setup.

3. Check Trigger Noise Rejection–All Channels.

a. Set:

NOTE

Select channels to set VOLTS/DIV

CH1 VOLTS/DIV	5 mV
CH2 VOLTS/DIV	50 mV
CH3, CH4 VOLTS/DIV	0.1 v
CH1 VERTICAL MODE	On
CH2, CH3, CH4 VERTICAL MODE	Off
CH1 and CH2 Input Coupling	1 M Ω DC
A SEC/DIV	10 µs (knob in)
TRIGGER MODE	AUTO LVL
TRIGGER SOURCE	VERT

b. Connect the Function Generator to the CH1 input via a BNC cable and a 10X attenuator.

c. Set the Function Generator output frequency and level for a 50-kHz, 4-division display.

d. Set the CH1 VOLTS/DIV to 50 mV.

e. Set the TRIGGER COUPLING to NOISE REJ.

f. CHECK– Display will not trigger (freeruns).

g. Pull the SEC/DIV knob out, rotate it to 5 µs and push it back in.

h. Press the A/B TRIG button to select the B TRIGGER.

i. Set the TRIGGER MODE to B TRIG AFT DLY.

j. Set TRIGGER COUPLING to NOISE REJ.

k. CHECK– Display will not trigger for any setting of the LEVEL control.

l. Rotate the SEC/DIV back to 10 µs (knob in).

m. Move the input signal to CH2, CH3, and CH4 in turn, selecting each channel as the display source. Repeat parts f through k for each channel.

4. Check Slope Selection and Verify Line Trigger.

a. Set:

CH1 VERTICAL MODE	On
CH2, CH3, CH4 VERTICAL MODE	Off
A SEC/DIV	2 ms (knob in)
X10 MAG	Off
TRIGGER MODE	AUTO
TRIGGER SOURCE	LINE
TRIGGER COUPLING	AC
CH1 VOLTS/DIV	
CH1 Input Coupling	1 M Ω DC

CAUTION

In the next part, DO NOT connect the probe ground lead to the ac power source.

b. Attach the 10X probe to the CH1 OR X input connector and connect the probe tip to the ac power source.

c. CHECK– Display can be triggered in both the + (plus) and - (minus) positions of the SLOPE switch using the TRIGGER LEVEL control and that the displayed slope agrees with the selected slope.

d. CHECK–Display phase shifts slightly as the TRIGGER COUPLING is changed from AC to DC.

e. Disconnect the test setup.

HORIZONTAL

Equipment Required (see table 4-1)

Primary Leveled Sine-Wave Generator (item 2)	T-Connector (item 8)
Calibration Generator (item 3)	Precision BNC Cable (2 required) (Item 10)
Time-Mark Generator (Item 6)	

Initial Control Settings.

Control settings not listed do not affect the procedure.

Set:

NOTE

Select channels to set VOLTS/DIV

VOLTS/DIV

CH 1 and CH 2	0.5 V
CH 1 VAR	In detent
CH 3 and CH 4	0.1 v

VERTICAL MODE

CH 1	On
CH 2, CH 3, CH 4, ADD, and INVERT	Off
CHOP/ALT	ALT
20 MHz BW LIMIT	Off

INPUT COUPLING

CH 1 and CH 2	50 Ω DC

HORIZONTAL

A SEC/DiV	200 ns (knob in)
SEC/DIV VAR	in detent
X10 MAG	Off
TRACE SEP	Fully CW

DELTA

ΔV and Δt	Off (press and release until associated readout is off)
TRACKING	Off

TRIGGER

HOLDOFF	B ENDS A
LEVEL	Midrange
SLOPE	+ (plus)
MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC

1. Check Horizontal Display Modes (A, A INTEN, ALT, and B).

a. Use a precision BNC cable to connect 200 ns time markers from the Time-Mark Generator to the CH 1 OR X input connector.

b. Adjust the TRIGGER LEVEL control as necessary for a stable signal display.

c. Pull the SEC/DIV knob out and set the B TRIGGER MODE to RUN AFT DLY.

d. Set the Δ REF OR DLY POS control for a DLY readout of approximately 1000 ns.

e. VERIFY – An intensified zone appears on the displayed signal near graticule center. The INTENSITY control may need adjustment.

f. Rotate the Δ REF OR DLY POS control to center the intensified zone on one of the time markers near graticule center.

g. Set the B SEC/DIV to 50 ns (knob out).

h. Rotate the TRACE SEP control CCW to separate the A and B sweep displays.

i. CHECK–The B sweep is displayed with the A sweep.

j. Push the SEC/DIV knob in.

k. CHECK – Only the B sweep is displayed.

2. Check A and B Timing, A Cursor Accuracies, and A Cursor Range.

a. Set:

A SEC/DIV	5 ns (knob in)
TRACE SEP	Fully CW
Δt	On (press and release for Δt display)

b. Select 5 ns time markers from the Time-Mark Generator and adjust the TRIGGER LEVEL control for a stable display.

c. Use the Horizontal POSITION control to align the 2nd time marker with the 2nd vertical graticule line (2nd from the left edge of the display).

NOTE

The 2 ns and the 5 ns time markers are sinusoidal. Use either the rising or falling zero-crossings as alignment points.

d. Align the Δ REF OR DLY POS cursor with the 2nd time marker and align the Δ cursor with the 10th time marker.

e. CHECK–The A Sweep timing and cursor readout accuracies are within the limits given in Tables 4-7 and 4-8.

NOTE

If the 2nd and 10th time markers are within 0.06 division of the 2nd and 10th vertical graticule lines for unmagnified sweeps and within 0.1 division for magnified sweeps, the sweep timing accuracy is conservatively within limits. When the timing accuracy is checked at each sweep speed, note any SEC/DIV setting at which the timing error exceeds the 0.06-division limit. Check these sweep speeds against the major-division time-interval limits given in Table 4-8.

For SEC/DIV settings of 5 ns and 10 ns, the time-marker period is greater than 1 division when the sweep is magnified. At 500 ps per division (SEC/DIV setting of 5 ns with X10 MAG), input the signal through a dual input coupler to CH 1 and CH 2. Select CH 1, CH 2, and CH 2 INVERT. Set the CH 1 and CH 2 VOLTS/DIV settings for a 6 division signal. Center the waveforms. Check for 2 eye/es between the 2nd and 10th vertical graticule lines (within 0.1 division) at the intersections of the waveforms. For 1 ns per division, check for 4 cycles between the 2nd and 10th vertical graticule lines (0.1 division).

f. Repeat parts c, d, and e for each A SEC/DIV-time marker combination given in Table 4-7 for both unmagnified and magnified sweeps.

Table 4-7

Settings for A and B Timing Accuracy Checks and A Cursor Accuracy Limits

SEC/DIV Setting	Unmagnified		X10	
	Time Markers	Limits of Δt Cursor Readout	Time Markers	Limits of Δt Cursor Readout
5 ns	5 ns	39.65 ns to 40.35 ns	2 ns 4 Div/cycle	3.94 ns to 4.06 ns (2 cycles)
10 ns	10 ns	79.30 ns to 80.70 ns	2 ns 2 Div/cycle	7.89 ns to 8.11 ns (4 cycles)
20 ns	20 ns	158.60 ns to 161.40 ns	2 ns	15.78 ns to 16.22 ns
50 ns	50 ns	396.5 ns to 403.5 ns	5 ns	39.45 ns to 40.55 ns
100 ns	0.1 μs	793.0 ns to 807.0 ns	10 ns	78.90 ns to 81.10 ns
200 ns	0.2 μs	1485.0 ns to 1614.0 ns	20 ns	157.80 ns to 162.20 ns
500 ns	0.5 μs	3965 ns to 4035 ns	50 ns	394.5 ns to 405.5 ns
1 μs	1 μs	7.930 μs to 8.070 μs	0.1 μs	789.0 ns to 811.0 ns
2 μs	2 μs	15.860 μs to 16.140 μs	0.2 μs	1578.0 ns to 1622.0 ns
5 μs	5 μs	39.65 μs to 40.35 μs	0.5 μs	3945 ns to 4055 ns
10 μs	10 μs	79.30 μs to 80.70 μs	1 μs	7.890 μs to 8.110 μs
20 μs	20 μs	158.60 μs to 161.40 μs	2 μs	15.780 μs to 16.220 μs
50 μs	50 μs	396.5 μs to 403.5 μs	5 μs	39.45 μs to 40.55 μs
100 μs	100 μs	793.0 μs to 807.0 μs	10 μs	78.90 μs to 81.10 μs
200 μs	200 μs	1586.0 μs to 1614.0 μs	20 μs	157.80 μs to 162.20 μs
500 μs	500 μs	3965 μs to 4035 μs	50 μs	394.5 μs to 405.5 μs
1 ms	1 ms	7.930 ms to 8.070 ms	100 μs	789.0 μs to 811.0 μs
2 ms	2 ms	15.860 ms to 16.140 ms	200 μs	1578.0 μs to 1622.0 μs
5 ms	5 ms	39.65 ms to 40.35 ms	500 μs	3945 μs to 4055 μs
10 ms	10 ms	79.30 ms to 80.70 ms	1 ms	7.890 ms to 8.110 ms
20 ms	20 ms	158.60 ms to 161.40 ms	2 ms	15.780 ms to 16.220 ms
50 ms	50 ms	396.5 ms to 403.5 ms	5 ms	39.45 ms to 40.55 ms
A SEC/DIV ONLY	(B Sweep does not have these sweep speeds)			
100 ms	0.1 s	793.0 ms to 807.0 ms	10 ms	78.90 ms to 81.10 ms
200 ms	0.2 s	1578.0 ms to 1622.0 ms	20 ms	157.00 ms to 163.00 ms
500 ms	0.5 s	3945 ms to 4055 ms	50 ms	392.5 ms to 407.5 ms

Table 4-8
Horizontal Timing Accuracy Checked Against the Graticule

	Over Any									
	1 Div	2 Div	3 Div	4 Div	5 Div	6 Div	7 Div	8 Div	9 Div	10 Div
Time-Marker Accuracy (X10 MAG off)	± 0.07 Div	± 0.07 Div	± 0.08 Div	± 0.09 Div	± 0.10 Div	± 0.10 Div	± 0.11 Div	± 0.12 Div	± 0.12 Div	± 0.13 Div
Time-Marker Accuracy (X10 MAG on). Exclude first 0.5 division of sweep rate.	± 0.07 Div	± 0.08 Div	± 0.1 Div	± 0.11 Div	± 0.12 Div	± 0.13 Div	± 0.14 Div	± 0.16 Div	± 0.17 Div	± 0.18 Div
As Measured Against These Time-Marker Pairs (X10 MAG off only)	1-2	1-3	1-4	1-5	1-6	1-7	1-8	1-9	1-10	1-11
	2-3	2-4	2-5	2-6	2-7	2-8	2-9	2-10	2-11	
	3-4	3-5	3-6	3-7	3-8	3-9	3-10	3-11		
	4-5	4-6	4-7	4-8	4-9	4-10	4-11			
	5-6	5-7	5-8	5-9	5-10	5-11				
	6-7	6-8	6-9	6-10	6-11					
	7-8	7-9	7-10	7-11						
	8-9	8-10	8-11							
	9-10	9-11								
	10-11									

g. Rotate the Δ REF OR DLY POS control CCW until the cursor stops moving.

h. CHECK– Δ REF OR DLY POS cursor aligns with the 1st graticule line within 0.2 division.

i. Rotate the Δ control CW until the cursor stops moving.

j. CHECK– Δ cursor aligns with the 11th graticule line within 0.2 division.

k. Set the ASEC/DIV to 10 ns.

l. Rotate the Δ REF OR DLY POS and the Δ controls to precisely superimpose the cursors near the 2nd graticule line.

m. CHECK– Δ t readout indicates a difference of 0.30 ns or less.

n. Rotate the Δ REF OR DLY POS and the A controls to precisely superimpose the cursors near the 10th graticule line.

o. CHECK– Δ t readout indicates difference of 0.30 ns or less

p. Set:

B SEC/DIV	5 ns (knob in)
B TRIGGER MODE	RUN AFT DLY
X10 MAG	Off
Δ t	Off (DLY)
Δ REF OR DLY POS	Set for zero delay

q. CHECK–The B sweep timing accuracy as in parts b through f, making sure that the A SEC/DIV is set slower than the B SEC/DIV.

3. Check Delta Time Accuracy using the Delayed Sweep.

a. Set:

A SEC/DIV	10 ns
B SEC/DIV	5 ns (knob out)
X10 MAG	On
Δ t	Off (DLY readout)
TRIGGER MODE	AUTO LVL
TRIGGER SOURCE	VERT
TRIGGER COUPLING	DC
TRIGGER SLOPE	+ (plus)
TRIGGER LEVEL	As required for a stable display
B TRIG MODE	RUN AFT DLY

NOTE

Certain time marks from the TG 501 (and other Time-Mark Generators) will vary in width and may be displaced in time. This will happen in a repeatable sequence and is caused by the loading and interaction of the 2, 5, and 10 dividers. This is most noticeable with 10 ns, 20 ns, and 50 ns markers. The following procedure will use the above markers to set up the proper references but the 5 ns markers will be used to make the actual measurement. Close inspection of apparent jitter or mistrigger of the time marks will show the trigger point to be stable with the apparent jitter to be variable with unique combinations of trigger holdoff and sweep speed. This is normal behavior with this type of signal and is not an instrument defect.

It is not necessary to count the number of marks given in the tables. Switching to 10 ns, 20 ns, or 50 ns markers as required and then to 5 ns will show the proper 5 ns mark to be used.

b. Set the Time-Mark Generator for 10 ns markers. Adjust the Vertical VOLTS/DIV as required for a display of 3 to 6 divisions.

c. Adjust the Δ REF OR DLY POS control for a readout display of DLY 10.64 ns.

d. Adjust the Horizontal POSITION control CW until the trace stops moving, then CCW to display the leading edge of the 2nd time marker near the graticule center. This becomes the reference point for the following procedure. Set the Time-Mark Generator to 5 ns and adjust the Vertical VOLTS/DIV and Trigger LEVEL as required.

e. Press and release the Δ t button to obtain the Δ t display. Push in the SEC/DIV knob for B SWP only. Rotate the Δ control for a readout display of Δ t -10.64 ns. If the time marks are not superimposed, adjust the Δ control to do so.

f. CHECK– Δ t readout is within the limits listed in Table 4-9 for the lst 5 ns time marker; then check that the 3rd through 19th time markers are within the given limits as the Δ control is rotated CW to superimpose every second time marker on the reference time marker.

NOTE

Correct time marks to superimpose on the reference marker can be easily found by noting the Delta Time Readout.

Table 4-9

Delta Time Display Accuracy

Time-Marker Period and A SEC/DIV Switch Setting	B SEC/DIV Switch Setting	Marker Superimposed using the Δ (Delta) Control	Delta Time Readout Accuracy Limits
10 ns	500 ps[1]	1st	-9.86 ns to -10.14 ns
		3rd	-0.10 ns to 0.10 ns
		5th	9.86 ns to 10.14 ns
		7th	19.84 ns to 20.16 ns
		9th	29.80 ns to 30.20 ns
		11th	39.78 ns to 40.22 ns
		13th	49.74 ns to 50.26 ns
		15th	59.72 ns to 60.28 ns
		17th	69.68 ns to 70.32 ns
		19th	79.66 ns to 80.34 ns
20 ns	500 ps[1]	1st	-19.75 ns to -20.25 ns
		9th	19.75 ns to 20.25 ns
		37th	159.3 ns to 160.70 ns
50 ns	500 ps[1]	1st	-49.3 ns to -50.7 ns
		21st	49.3 ns to 50.7 ns
		91st	398.3 ns to 401.7 ns

[1]5 ns with X10 MAG on.

g. Set:

A SEC/DIV	20 ns
B SEC/DIV	5 ns (knob out)
X10 MAG	ON
Δ t	Off (DLY readout)

h. Set the Time-Mark Generator for 20 ns time markers and adjust the Δ REF OR DLY POS control for a readout display of DLY 21.25 ns.

i. Position the leading edge of the 2nd time marker near graticule center using the Horizontal POSITION control. Set the Time-Mark Generator to 5 ns and adjust the Vertical VOLTS/DIV and Trigger LEVEL as required.

j. Press and release the Δ t button to obtain a Δ t display. Push in the SEC/DIV knob for B sweep only. Adjust the Δ control for a readout display of Δ t -20.00 ns. if the time markers are not superimposed, adjust the Δ control to do so.

k. CHECK– Δ t readout is within the limits listed in Table 4-9 for the first 5 ns time marker; then check that the 9th and 37th time markers are within the given limits as the Δ control is rotated CW to superimpose each time marker on the reference time marker.

l. Set:

A SEC/DIV	50 ns
B SEC/DIV	5 ns (knob out)
X10 MAG	ON
Δt	Off (DLY readout)

m. Set the Time-Mark Generator for 50 ns time markers and adjust the Δ REF OR DLY POS control for a readout display of DLY 53.2 ns.

n. Position the leading edge of the 2nd time marker near graticule center using the Horizontal POSITION control. Set the Time-Mark Generator to 5 ns and adjust the Vertical VOLTS/DIV and Trigger LEVEL as required.

o. Press and release the Δ t button to obtain a Δ t display. Push in the SEC/DIV knob for B sweep only. Adjust the Δ control for a readout display of Δ t -50.00 ns. If the time markers are not superimposed, adjust the Δ control to do so.

p. CHECK– Δ t readout is within the limits listed in Table 4-9 for the first 5 ns time marker; then check that the 21st and 91st time markers are within the given limits as the Δ control is rotated CW to superimpose each time marker on the reference time marker.

q. Set:

TRACKING/INDEP	TRACKING
A SEC/DIV	100 ns
B SEC/DIV	10 ns (knob out)
X10 MAG	On

r. Select 0.1 μs time markers from the Time-Mark Generator.

s. Adjust the Δ and Δ REF OR DLY POS controls for a Δ t readout display of 800.0 ns.

t. Adjust the Horizontal POSITION control to align the leading edge of the 2nd time marker on the A sweep with the 2nd vertical graticule line.

u. Rotate the TRACE SEP control CCW to separate the traces.

v. Adjust the Δ REF OR DLY POS control to intensify the 2nd and 10th time markers (of the A sweep) and display the leading edges of the displayed B sweep time markers in the center area of the graticule.

w. VERIFY –The horizontal distance between the leading edges of the B sweep time markers is within the conservative guideline listed in Table 4-10. If this guideline is met, accuracy between each marker is ensured, and the following CHECK step need not be performed.

Table 4-10

Delayed Sweep Delta Time Accuracy

A SEC/DIV and Time Markers	B SEC/DIV as Displayed on Readout	Displayed Separation of Delayed Time Markers (for 2nd and 10th markers)	
		Conservative Guideline (divisions)	Specified Limit: (± 0.3% time) Interval + 0.1% of full scale-division
0.1 μs	1 ns[1]	2.4	3.4
0.2 μs	2 ns[1]	2.4	3.4
0.5 μs	5 ns[2]	2.4	3.4
1 μs	10 ns	2.4	3.4
2 μs	20 ns	2.4	3.4
5 μs	50 ns	2.4	3.4
10 μs	100 ns	2.4	3.4
20 μs	200 ns	2.4	3.4
50 μs	500 ns	2.4	3.4
0.1 ms	1 μs	2.4	3.4
0.2 ms	2 μs	2.4	3.4
0.5 ms	5 μs	2.4	3.4
1 ms	10 μs	2.4	3.4
2 ms	20 μs	2.4	3.4
5 ms	50 μs	2.4	3.4
10 ms	100 μs	2.4	3.4
20 ms	200 μs	2.4	3.4
50 ms	500 μs	2.4	3.4
0.1 s	1 ms	2.4	3.4
0.2 s	2 ms	6.4	7.4
0.5 s	5 ms	6.4	7.4

[1] X10 MAG On.
[2] For remainder of Table, turn X10 MAG off.

x. CHECK –The horizontal distance between the leading edges of the B sweep time markers is within the specified limits given in Table 4-10. The limit given is for separation between the 2nd and 10th marker; however, separation between the 2nd marker and each succeeding marker should also be checked, calculating the limits from the specification as listed at the top of the table.

NOTE

To easily maintain the A SWP and B SWP difference while testing Delta Time, use the following method:

1. Starting with the 0.5 µs test in Table 4-9 (X10 MAG off), turn TRACKING off.
2. Press and hold the TRACKING button, then push the SEC/DIV knob in. This will lock the sweeps together at that difference.
3. Pull the SEC/DIV knob out.

The fastest sweep speed at which the X100 difference is maintained is with an A SEC/DIV of 500 ns and a B SEC/DIV of 5 ns, after which only the A sweep speed will change with the SEC/DIV knob. Push TRACKING to unlock this setup.

y. Repeat part w (and x if necessary) for each combination of A SEC/D IV, B SEC/DIV, and X10 MAG settings listed in Table 4-9. The Δ t readout should be set to indicate eight times the A SEC/DIV setting. At the slowest sweep speeds, the B SEC/DIV knob can be pushed in (in B Sweep only) to increase the display repetition rate.

4. Check Delay Jitter.

a. Set:

TRACKING	Off
A SEC/DIV	1 ms
B SEC/DIV	500 ns (knob out)
B TRIG	RUN AFT DLY

b. Select 1 ms time markers from the Time-Mark Generator.

c. Align the intensified zones with the 10th time marker using the Δ REF OR DLY POS and Δ controls. Superimpose the zones to obtain a Δ t readout display of 0.000 ms.

d. Push in the SEC/DIV knob and adjust TRACE SEP to separate the traces.

e. CHECK–For 0.8 divisions or less of horizontal jitter on the rising edge of both time markers.

5. Check SEC/DIV VAR Range and Accuracy.

a. Set:

A SEC/DIV	10 ms (knob in)
SEC/DIV VAR	In detent
Δ t	Off (press and release to eliminate Δ t readout)
HOLDOFF	B ends A

b. Select 10 ms time markers from the Time-Mark Generator and adjust the Time-Mark Generator variable timing control for exactly 1 time marker per division. Note the variable timing % error on the Time-Mark Generator.

c. Adjust the SEC/DIV VAR control for a sweep-speed readout (on bottom line of readout) of 20 ms and adjust the Time-Mark Generator variable timing control for exactly 2 time markers per division.

d. CHECK–The Time-Mark Generator variable timing % of error has changed 2% or less from the reading noted in part b.

e. Adjust the SEC/DIV VAR control fully CCW.

f. CHECK–Sweep speed readout displays 30.0 ms.

g. Set the Time-Mark Generator variable timing control for exactly 3 time markers per division.

h. CHECK–The Time-Mark Generator variable timing % of error has changed 2% or less from the reading noted in part b.

i. Set:

A SEC/DIV	50 ms
B SEC/DIV	10 ms (knob in)
SEC/DIV VAR	CW (in detent)
Δ t	Off (DLY readout)
B TRIGGER MODE	RUN AFT DLY
Δ REF OR DLY POS	Zero delay

j. Repeat parts b through h for the B Sweep.

k. Rotate the SEC/DIV VAR control CW to the detent position and disconnect the test setup.

6. Check X-Axis Gain.

a. Set:

NOTE

Select channels to set VOLTS/DIV

VOLTS/DIV

CH 1 and CH 2	10 mV

VERTICAL MODE

CH *2*	On
CH 1, CH 3, CH 4, ADD, and BW LIMIT	Off

HORIZONTAL

SEC/DIV	X-Y (knob in)

INPUT COUPLING

CH 1	1 M Ω DC
CH 2	1 M Ω GND

b. Connect a 50 mV standard-amplitude signal from the Calibration Generator to the CH 1 OR X input connector via a precision BNC cable.

c. CHECK–Signal display amplitude is 4.9 to 5.1 horizontal divisions.

d. Disconnect the test setup.

7. Check X-Axis Bandwidth.

a. Set the CH 1 Input Coupling to 50 Ω DC.

b. Connect a 50 kHz signal from the Primary Leveled Sine-Wave Generator to the CH 1 OR X input connector via a precision BNC cable.

c. Set the generator output for a 6-division horizontal display.

d. Change the generator frequency to 3 MHz.

e. CHECK – Signal display is greater than 4.2 horizontal divisions.

8. Check X-Y Phase Differential.

a. Set the Primary Leveled Sine-Wave Generator for a 1 MHz, 6-division horizontal display.

b. Set the CH 2 VERTICAL MODE off. CH 1 displays automatically.

c. Use the CH 1 VERTICAL POSITION control to vertically center the display on the graticule.

d. CHECK–Ellipse opening is 0.1 division or less, measured horizontally.

e. Set the CH 2 VERTICAL MODE on.

f. Set the generator for a 2 MHz, 6-division horizontal display.

g. Set the CH 2 VERTICAL MODE off.

h. CHECK–Ellipse opening is 0.3 division or less, measured horizontally.

i. Set the CH 2 VERTICAL MODE on.

9. Check X-Axis Low-Frequency Linearity.

a. Set the Primary Leveled Sine-Wave Generator and the CH 1 POSITION control for a 50 kHz, 2-division horizontal display centered on the graticule.

b. Use the CH 1 POSITION control to align the left edge of the signal with the left side vertical graticule line.

c. CHECK–Signal display is 1.8 to 2.2 divisions, measured horizontally.

d. Use the CH 1 POSITION control to position the right edge of the signal on the right side vertical graticule line.

e. CHECK–Signal display is 1.8 to 2.2 divisions, measured horizontally.

f. Disconnect the test setup.

PARAMETRIC MEASUREMENTS CHECK

Initial Control Settings.

Control settings not listed do not affect the procedure.

VERTICAL MODE

CH 1	On
CH 2,3,4	Off

INPUT COUPLING

CH 1	50 Ω DC

1. Check Timing Accuracy

NOTE

All Parametric timing measurements are derived from the same timing ramps as the period measurements. Verification of the period measurements provides verification of all timing measurements.

a. Connect Time-Mark Generator to CH 1 OR X input of the oscilloscope under test.

b. For each entry in Table 4-11:

1. Set Time-Mark Generator as indicated.
2. Press MEASURE.
3. Select FREQ from menu.
4. Verify resulting period measurement is within limits shown in Table 4-11.

NOTE

If the 50 ns period is out of limits shown on Table 4-11, perform steps d through h (50 ns Timing Accuracy Verification) below.

c. Disconnect Time-Mark Generator.

d. Connect Primary Leveled Sine-Wave Generator to CH 1 OR X input of the oscilloscope under test and the test oscilloscope using a T-connector.

e. Set frequency for 20 MHz.

f. Using the counter in the test oscilloscope, measure period of signal.

g. Press MEASURE then select FREQ on the oscilloscope under test.

h. Verify that the oscilloscope under test reads a period that is within 0.5% + 0.5 ns of the value measured by the counter on the test oscilloscope. The Time-Mark Generator cannot be used at this frequency because of jitter which distorts the reading.

Table 4-11

Parametric Measurement Period Checks

Time Mark Setting	Minimum Period	Maximum Period
2 ns	1.49 ns	2.51 ns
5 ns	4.48 ns	2.52 ns
10 ns	9.45 ns	10.55 ns
20 ns	19.4 ns	20.4 ns
50 ns	49.25 ns	50.75 ns[1]
100 ns	99.0 ns	101.0 ns
200 ns	198.5 ns	201.5 ns
500 ns	497.0 ns	503.0 ns
1 µs	994.5 µs	1.005 µs
2 µs	1.989 µs	2.011 µs
5 µs	4.975 µs	5.025 µs
10 µs	9.950 µs	10.05 µs
20 µs	19.90 µs	20.10 µs
50 µs	49.75 µs	50.25 µs
100 µs	99.50 µs	100.5 µs
200 µs	199.0 µs	201.5 µs
500 µs	497.5 µs	502.5 µs
1 ms	995.0 µs	1.005 µs
2 ms	1.990 ms	2.010 ms
5 ms	4.975 ms	5.025 ms
10 ms	9.950 ms	10.05 ms
20 ms	19.90 ms	20.10 ms
50 ms	49.75 ms	50.25 ms
100 ms	99.50 ms	100.5 ms[1]

[1]For this setting, change MINFREQ to 10 Hz.

2. Verify Volts Measurement

a. Connect Calibration Generator to CH 1 OR X input of the oscilloscope under test.

b. Set CH 1 OR X input coupling to 1 M Ω.

c. For each entry in Table 4-12:

1. Measure VOLTS by pressing MEASURE and then selecting VOLTS.

2. Verify reading is within limits specified.

d. Disconnect generator from CH 1 or X input and connect to CH 2 OR Y input.

e. Select only CH 2 for display.

f. Repeat step c for CH 2.

g. Disconnect test setup.

Table 4-12
Parametric Measurement Volts Checks

Calibration Generator Setting	Max +pk	Min +pk	Max -pk	Min -pk	Max Avg	Min Avg	Max P-P	Min P-P
20 mV	26 mV	14 mV	5 mV	-5 mV	15 mV	5 mV	26 mV	14 mV
50 mV	57 mV	43 mV	5 mV	-5 mV	32 mV	18 mV	57 mV	43 mV
100 mV	110 mV	90 mV	5 mV	-5 mV	57 mV	43 mV	110 mV	90 mV
200 mV	215 mV	185 mV	5 mV	-5 mV	110 mV	90 mV	215 mV	185 mV
500 mV	530 mV	470 mV	5 mV	-5 mV	267 mV	233 mV	530 mV	470 mV
1 V	1.055 mV	0.945 V	5 mV	-5 mV	530 mV	470 mV	1.055 V	0.945 V
2 V	2.105 V	1.895 V	5 mV	-5 mV	1.055 V	0.945 V	2.105 V	1.895 V
5 V	5.255 V	4.745 V	5 mV	-5 mV	2.630 V	1.870 V	5.255 V	4.745 V
10 V	10.50 V	9.495 V	5 mV	-5 mV	5.255 V	4.745 V	10.50 V	9.495 V
20 V	21.00 V	19.00 V	5 mV	-5 mV	10.50 V	9.495 V	21.00 V	19.00 V
50 V	52.50 V	47.50 V	5 mV	-5 mV	26.25 V	24.75 V	52.50 V	47.50 V

CALIBRATOR, EXTERNAL Z-AXIS AND GATE OUTPUTS

Equipment Required (see table 4-1)

- Calibration Generator (Item 3)
- Time-Mark Generator (Item 6)
- Test Oscilloscope with 10X Probe (Item 7)
- T-Connector (Item 8)
- BNC Cables (2 required) (Item 10)

Initial Control Settings.

Control settings not listed do not affect the procedure.

Set:

VERTICAL MODE

CH 1 and CH 2	On
CH 3, CH 4, ADD, and INVERT	Off
CHOP/ALT	CHOP
20 MHZ BW LIMIT	Off

VOLTS/DIV

CH 1	10 mV
CH 2	500 mV
CH 1 and CH 2 VAR	In detent

INPUT COUPLING

CH 1	1 MΩ DC
CH *2*	50 Ω DC

HORIZONTAL

A SEC/DIV	1 ms (knob in)
SEC/DIV VAR	In detent
X10 MAG	Off
Delta Δ V and Δ t	Off (press and release until associated readout is off)

TRIGGER

HOLDOFF	B ENDS A (fully CW)
LEVEL	INIT@50%
SLOPE	+ (plus)
MODE	AUTO LVL
SOURCE	CH 1
COUPLING	DC

1. Check CALIBRATOR Repetition Rate.

NOTE

Refer to the Adjustment Procedure to check the accuracy of the CALIBRATOR output levels.

a. Connect a 10X probe from the CALIBRATOR terminal to the CH 1 OR X input connector.

b. Connect 1 ms time markers from the Time-Mark Generator to the CH 2 input connector via a BNC cable.

c. Adjust the CH 2 VOLTS/DIV for several divisions of marker display.

d. CHECK– Horizontal drift for any time marker is 1 division or less per second (10 seconds or more for 1 marker to drift 10 horizontal divisions).

e. Set the CH 2 VERTICAL MODE off.

f. CHECK– 1 cycle is displayed per 2 horizontal divisions for each A SEC/DIV setting from 0.1 s to 0.1 µs.

g. Disconnect the test setup.

2. Check External Z-Axis Operation.

a. Set:

INTENSITY	Fully clockwise
A SEC/DIV	1 ms
CH 1 VOLTS/DIV	500 mV

b. Connect a 1 kHz, 2 V standard-amplitude signal from the Calibration Generator to the CH 1 OR X input connector and the rear-panel EXT Z-AXIS input connector using a T-Connector and two BNC cables.

c. CHECK – The positive portion of the 4-division signal display is blanked out.

d. Disconnect the test setup and adjust the CRT INTENSITY as desired.

3. Check A and B GATE Outputs and Verify TRIGGER HOLDOFF.

a. Set:

Δ SEC/DIV	100 µs
B SEC/DIV	50 µs (knob in)
Δ t	Off (DLY readout)
TRIGGER MODE	AUTO
HOLDOFF	Minimum (CCW)
Δ REF OR DLY POS	Zero DLY readout

b. Connect the Test Oscilloscope to the A GATE OUT connector (located on the instrument rear panel) via a BNC cable.

c. CHECK–Test Oscilloscope displays a signal with a high level between 2.4 V and 5 V and a low level between 0 V and 0.4 V.

d. VERIFY– Duration of the high level is between 1 ms and 1.2 ms.

e. VERIFY– Duration of the low level is between 80 us and 150 µs.

f. VERIFY– Duration of the low level increases to at least 10 times the time measured in part e when the HOLDOFF control is rotated to the maximum CW position but not in the detent.

g. Move the BNC cable from the AGATE OUT connector to the B GATE OUT connector.

h. CHECK–Test Oscilloscope displays a signal with a high level between 2.4 V and 5 V and a low level between 0 V and 0.4 V.

i. VERIFY– Duration of the high portion of the signal is between 500 µs and 600 µs.

j. Disconnect the test setup.

ADDITIONAL FUNCTIONAL VERIFICATION

Equipment Required (see table 4-1)

10X Probe (supplied with Test Oscilloscope, item 7)

Initial Control Settings.

Control settings not listed do not affect the procedure.

Set:

NOTE

Select channels to set VOLTS/DIV

VOLTS/DIV

CH 1 and CH 2	0.1 v
CH 1 and CH 2 VAR	in detent
CH 1, CH 2, CH 3, CH 4, ADD, and INVERT	Off
CHOP/ALT	ALT
20 MHz BW LIMIT	Off

INPUT COUPLING

CH 1 and CH 2	1 MΩ DC

HORIZONTAL

A SEC/DIV	1 ms (knob in)
SEC/DIV VAR	In detent
X10 MAG	Off
TRACE SEP	Fully CW

DELTA

ΔV and Δt	Off (press and release until associated readout is off)
TRACKING	Off

TRIGGER

HOLDOFF	B ENDS A (fully CW)
LEVEL	Midrange
SLOPE	+ (plus)
A/B TRIG Select	A
MODE	AUTO
SOURCE	VERT
COUPLING	DC

1. Verify ALT, CHOP, and ADD Modes and TRACE SEP.

a. VERIFY– CH 1 trace is visible with no VERTICAL MODE buttons selected.

b. Press the CH 2 VERTICAL MODE button.

c. VERIFY – CH 1 trace is not displayed and the CH 2 trace is displayed.

d. Press the CH 1 VERTICAL MODE button.

NOTE

Separate the traces by approximately 1 division using the VERTICAL POSITION controls. Do not position either trace precise/y at graticule center.

e. VERIFY – Both the CH 1 and the CH 2 traces are displayed.

f. Press the ADD button.

g. VERIFY– A third trace (ADD) is displayed.

h. Press the CH 3 VERTICAL MODE button.

i. VERIFY–The CH 3 trace is added to the display.

j. Press the CH 4 VERTICAL MODE button.

k. VERIFY – The CH 4 trace is added to the display.

l. Set the SEC/DIV controls to 50 ms (knob in).

m. VERIFY – 5 traces are alternately displayed in the following sequence: CH 1, CH 2, ADD, CH 3, CH 4.

n. Set the TRIGGER MODE to SGL SEQ.

o. VERIFY – After the current sequence of traces is complete, no further traces are displayed.

p. Set the TRIGGER SOURCE to LINE.

q. Press and release the lower TRIGGER MODE button.

r. VERIFY– Each time the lower TRIGGER MODE button is pressed and released, the 5 signal traces appear once (in sequence), the readout display flashes once and the scale illumination flashes on and off.

s. Set the TRIGGER MODE to AUTO LVL and press the CHOP button.

t. VERIFY – The 5 traces appear to be displayed simultaneously.

u. Set:

TRIGGER SOURCE	CH 4
A SEC/DIV	20 µs
B SEC/DIV	10µs (knob out)
CHOP/ALT	ALT
TRACE SEP	CCW until traces are separated

v. VERIFY – An alternate B sweep trace appears for each A sweep trace (10 traces total).

2. Verify BEAM FIND Operation.

a. Set:

A SEC/DIV	1 ms (knob in)
CH 1 VERTICAL MODE	On
CH 2, CH 3, CH 4 and ADD	Off
X10 MAG	On
Horizontal POSITION	Midrange
Vertical POSITION	Midrange

b. Press and hold the BEAM FIND button.

c. VERIFY – The trace is less than 10 divisions long and remains in the graticule area as the CH 1 POSITION control and the Horizontal POSITION controls are rotated through their complete ranges.

d. Release the BEAM FIND button and set the VERTICAL POSITION and Horizontal POSITION controls to midrange.

3. Check Probe Encoding.

NOTE

Refer to instrument "Operators Manual" for the positioning of the readout display information.

a. Set:

CH 1, CH 2, CH 3, CH 4 VERTICAL MODE	On
CH 1 and CH 2 VOLTS/DIV	100 mV
CH 3 and CH 4 VOLTS/DIV	0.1 V

b. Connect the 10X probe (with readout encoding capability) to the CH 1 input connector.

c. CHECK – CH 1 readout changes from 100 mV to 1 V.

d. Move the probe to CH 2 and repeat part c for that channel.

e. Move the probe to CH 3.

f. CHECK– Readout changes from 0.1 V to 1 V.

g. Move the probe to CH 4 and repeat part f for that channel.

h. Short probe code ring to ground.

NOTE

If using a P6137 probe, press probe ID button.

i. Check R/O changes to ID for that channel and the trace jumps up approximately 0.5 Div.

j. Repeat for each vertical channel.

k. Disconnect test setup.

Section 5
ADJUSTMENT PROCEDURE

INTRODUCTION

IMPORTANT–PLEASE READ BEFORE USING THIS PROCEDURE

The Adjustment Procedure is used to restore optimum performance or return the instrument to conformance with its Performance Requirements as listed in the Specification (Section 1). As a general rule, these adjustments should be performed every 2000 hours of operation or once a year if used infrequently.

PARTIAL PROCEDURES

This procedure is divided into subsections to permit calibration of individual sections of the instrument whenever complete instrument calibration is not required. To perform a partial procedure, first set the instrument as directed in the Initial Setup Conditions at the beginning of the section, then make any changes tailed for within the procedure. Perform all steps within a subsection, both in the sequence presented and in their entirety to ensure that control settings will be correct for the following steps.

The adjustments in CAL 01, 02,03,06, 07 and 09 should be performed in numerical sequence; i.e., CAL 01 should be done before CAL 02, CAL02 should be done before CAL 03, etc. CAL 04, 05, and 08 are independent of adjustments made in the other calibration routines. Performing partial procedures when setting the automatic calibration constants (i.e., only one or two of the CAL steps) is not recommended and should only be done if the calibration constants set in the preceding steps are known to be correct.

PREPARATION FOR ADJUSTMENT

It is necessary to remove the cabinet to do the Adjustment Procedure. See the cabinet removal instructions in the Maintenance section of this manual, Section 6.

All test equipment items required to do the complete Adjustment Procedure are described in Table 4-1 at the beginning of Section 4, Performance Check Procedure. The specific items of equipment needed to do each subsection in this procedure are listed at the beginning of that subsection.

BEFORE YOU BEGIN:

NOTE

When performing any of the automatic calibration routines (CAL 01 through CAL 08), the CAL/NO CAL jumper P501 must be moved to its CAL position (between pins 2 and 3) before turning the power on. When the desired calibration has been performed, return the jumper to its NO CAL position.

a. Turn instrument Power on.

NOTE

The instrument MUST have a 20-minute warmup *period before making any adjustments. Performing the adjustment procedure while the temperature is drifting may cause erroneous calibration settings.*

POWER SUPPLIES AND DAC REF ADJUSTMENT

Equipment Required (see table 4-1)

Test Oscilloscope (With 10X Probe, Item 7)	Low-Capacitance Alignment Tool (item 20)
Digital Multimeter (DMM) (item 19)	1X Probe (item 21)

See **ADJUSTMENT LOCATIONS 1** *and* **4 (fig. FO-23)** *at the back of this manual for test point and adjustment locations.*

NOTE

If the instrument displays "DIAGNSTIC. PUSH A/B TRIG TO EXIT" at power on, one of the power-up tests has failed. If the error message on the bottom line of the display is "TEST 04 FAIL xx" where "xx" is 01, 10 or 11, stored calibration data is in error, and the instrument should be recalibrated. If this is the case, pressing the A/B *TRIG button will force entry to the normal operating mode; however, the accuracy of any measurement taken could be in error.*

if any other error message occurs, the failure is probably not related to calibration. in this case, the instrument should be repaired before attempting calibration.

Initial Control Settings.

Control settings not listed will not affect the procedure.

VERTICAL VOLTS/DIV

CH 2	100 mV
CH 3 and CH 4	100 mV
CH 1 and CH 2VAR	In detent

VERTICAL MODE

CH 1	On
CH 2, CH 3, CH 4	Off
ADD, INVERT, and BW LIMIT	Off
ALT/CHOP	ALT

VERTICAL POSITION

CH 1	Midrange

INPUT COUPLING

CH 1 and CH 2	1 M Ω DC

HORIZONTAL

SEC/DIV	X-Y (knob in)
SEC/DIV VAR	in detent
POSITION	Midrange

TRIGGER

MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC
SLOPE	+ (plus)
LEVEL	Midrange
HOLDOFF	In detent

DELTA

Δ V and Δ t	Off (press and release until readout display disappears)
INTENSITY	Visible display
READOUT INTENSITY	Visible display (CW from OFF)
SCALE ILLUM	Fully CCW
FOCUS	Defocused dot

1. Check/Adjust Power Supply DC Levels, Regulation, and Ripple (R1292).

a. Connect the Digital Multimeter (DMM) negative lead to chassis ground. Connect the positive lead to the first test point listed in Table 5-1 (all test points are on the Main Board).

b. CHECK–That the reading is within the limits given in Table 5-1.

c. ADJUST – Volt Ref Adj (R1292) for a DMM reading of precisely 10.00 V. The adjustment is accessible through a hole in the top cover plate.

Table 5-1
Power Supply Voltage and Ripple Tolerances

Power Supply	Test Point (+ Lead)	Reading	Total p-p Ripple	p-p Ripple at Two Times Line Frequency
+10 V	J119-4	+9.99 to +10.01	100 mV	1 mV
+87 V	J119-8	+85.26 to +88.74	80 mV	5 mV
+42.4 V	J119-9	+41.55 to +43.25	80 mV	2 mV
+15 V	J119-6	+14.775 to +15.225	15 mV	11 mV
Digital +5 V	J119-2	+4.85 to +5.15	150 mV	30 mV
Analog +5 V	J119-12	+4.925 to +5.075	15 mV	1 mV
-5 V	J119-5	-4.965 to -5.035	15 mV	1 mV
-8 V	J119-11	-7.88 to -8.12	100 mV	1 mV
-15 V	J119-1	-14.775 to -15.225	10 mV	2 mV

d. Repeat parts a and b for the other test points listed in Table 5-1.

e. Disconnect the DMM.

f. Set the Test Oscilloscope as follows:

Sweep Speed	5 ms/div
CH 1 Input Coupling	1 MΩ AC
Vertical controls	To display CH 1
Trigger controls	Line source, triggered display
Volts/Division	2 mV
BW Limit	20 MHz

g. Using a 1X probe, connect the Test Oscilloscope probe ground lead to chassis ground. Connect the probe tip to the first test point listed in Table 5-1.

h. CHECK– Ripple at two times the line frequency and the total peak-to-peak ripple do not exceed the values given in Table 5-1.

i. Repeat part h for each test point in Table 5-1.

j. Disconnect the Test Oscilloscope.

2. Adjust DAC Ref (R2010)

a. Set:

A SEC/DIV	100 µs
Δt	On (Δ t readout)

NOTE

The objective of this step is to make the total range of the DAC output voltage (sum of the CCW and CW readings) equal to 2.5 *V.*

b. Connect the Digital Multi meter (DMM) negative lead to the chassis ground. Connect the positive lead to pin 13 of J119 (on the Main Board).

c. Set the DMM to measure approximately 1.5 V DC.

d. Rotate the Δ control CCW until the DMM reading remains at a constant value (approximately -1 .250 V). Note the reading.

e. Rotate the Δ control CW until the DMM reading remains at a constant value (approximately + 1.250 V). Note the reading.

f. Add the absolute values of the readings noted in parts d and e together (approximately 2.500 V).

g. Subtract the total in part f from 2.500 V, then divide the difference by two.

h. ADJUST– DAC Ref (R2010 on the Control Board) to add the (signed) number obtained in part g to the reading obtained in part e.

i. Repeat parts d through h as necessary to obtain a total DAC range of 2.500 V.

CRT ADJUSTMENTS

Equipment Required (see table 4-1)

Primary Leveled Sine-Wave Generator (Item 2)
BNC Cable (Item 10)
Low-Capacitance Alignment Tool (Item 20)

See **ADJUSTMENT LOCATIONS 1,2,** *and* **4 (fig. FO-23)**
at the back of this manual for test point and adjustment locations.

NOTE

When performing the following automatic cal steps, initial setting of the front-panel controls is not required.

1. Adjust GRID BIAS (R1878).

a. Simultaneously press in and hold the Δ t and the Δ V push buttons, then press and hold the SLOPE button. Hold all three buttons in for approximately one second, then release them.

b. CHECK–Top line of the readout display says: “Diagnostic. PUSH A/B TRIG TO EXIT.”

NOTE

The "menu" of calibration, test, and exercise routines are in a loop that may be scrolled through in single steps, either forward or backward. Pressing the upper or lower TRIGGER MODE push buttons respectively increments or decrements the menu position by one. As each routine is selected, its name appears in the lower left corner of the readout display.

c. Scroll to CAL 08.

NOTE

In this procedure, pressing the upper TRIGGER COUPLING button increments the routine to the next step. Pressing the lower TRIGGER COUPLING button will return to the previous step.

d. Press and release the upper TRIGGER COUPLING button to initiate the routine.

e. Set SCALE illumination control (front panel) full CCW (off).

f. ADJUST– Grid Bias (R1878) if necessary to obtain an X-Y dot near center screen.

g. Position the X-Y dot adjacent to a dot in the lower row of readout dots using CH 1 and CH 2 position controls.

h. ADJUST–Grid Bias (R1878) to match the intensity of the X-Y dot to the readout dots. (Defocusing the display may give better resolution.)

i. Press and release the upper TRIGGER COUPLING button to advance to the next step.

2. Check Grid Bias Adjustment.

a. Set SCALE illumination control (front panel) full CCW (off).

b. CHECK–A dim X-Y dot is visible near graticule center.

c. Set INTENSITY control (front panel) full CCW (Off).

d. CHECK – The dot is no longer visible with the INTENSITY Off.

NOTE

If the dot is not present in the first part of the check or does not fully disappear during the second part of the check; the Grid Bias adjustment step should be repeated. To repeat the Grid Bias Adjust step, press the lower TRIGGER COUPLING button once to return to the Grid Bias Adjustment step and repeat step 1 above.

e. Press and release the upper TRIGGER COUPLING button to advance to the next step.

3. Adjust TRACE ROTATION (Front Panel), Y-AXIS (R1848), EDGE FOCUS (R1864), ASTIG (Front Panel) and GEOMETRY (R1870)

a. Using the CH 1 Vertical POSITION control, align the trace with the center horizontal graticule line.

b. Position one of the Δ t cursors to the center vertical graticule line using either the Δ or the Δ REF OR DLY POS control.

c. ADJUST– INTENSITY control for a comfortable display.

d. ADJUST –TRACE ROTATION control (front panel) to align the trace with the center horizontal graticule line.

e. ADJUST–Y-Axis Alignment (R1848) to align the Δ t cursor with the center vertical graticule line.

f. Repeat parts d and e as necessary for the best aligned display.

NOTE

Y-Axis and TRACE ROTATION will remain adjusted and are not interactive of the following adjustments.

g. ADJUST – ASTIG control (front panel), in conjunction with the FOCUS control (front panel) for the sharpest possible display near the center graticule area.

h. Position the Δ t cursors on (or within 0.2 division of) the first and eleventh vertical graticule lines using the Δ REF OR DLY POS and Δ controls.

NOTE

Adjust Xl Horizontal Gain (R860) if necessary to position the Δ t cursors as described instep h above. If the Horizontal *Gain (R860)* is *adjusted, it will be necessary to perform CAL 01 to restore optimum adjustment.*

i. ADJUST– Geometry (R1870) for minimum curvature of both Δ t cursors.

j. ADJUST– READOUT INTENSITY control (front panel) to the OFF position.

k. Using the CH 2 Vertical POSITION control, set the CH 2 trace off screen.

l. Connect a 50 kHz, 8-division signal from the Primary Leveled Sine-Wave Generator to the CH 1 input connector via a 50 Ω BNC cable.

m. Center the display on the graticule. Set INTENSITY control as necessary for a well defined display.

n. ADJUST– Edge Focus (R1864), FOCUS control (front panel), and ASTIG control (front panel) for the most uniform focus over the entire display.

NOTE

Slight interaction between Geometry, Edge Focus, and Focus, and Astigmatism is normal, To achieve optimum edge focus it may be necessary to slightly compromise the Geometry adjustment.

o. Disconnect the generator from the CH 1 input.

p. ADJUST– READOUT INTENSITY control to display Δ t cursors and readout information.

q. CHECK – Readout characters remain focused.

r. REPEAT– Parts i through q as necessary to obtain optimum focus.

s. Press and release the upper TRIGGER COUPLING button to advance to the next step.

4. Adjust HIGH DRIVE FOCUS (R1842).

a. Connect a 10 MHz, 6-division signal from the Primary Leveled Sine-Wave Generator to the CH 1 input connector via a BNC cable.

b. Center the display on the graticule.

c. ADJUST– Horizontal POSITION control to view the sweep start.

d. ADJUST– High Drive Focus (R1842) for the best overall focus of the trace.

NOTE

Do not disconnect the Sine-Wave Generator from the CH 1 input.

e. Press and release the upper TRIGGER COUPLING button to advance to the next step.

5. Adjust HORIZONTAL DYNAMIC CENTERING (R3401).

a. Center the display on the graticule.

b. ADJUST– Horizontal Dynamic Centering (R3401) for minimum horizontal display shift as the INTENSITY control (front panel) is repeatedly changed from minimum to maximum trace intensity.

NOTE

Disregard any vertical shift of the waveform during the adjustment.

c. Disconnect the generator from the CH 1 input.

d. Press and release the upper TRIGGER COUPLING button to advance to the next step.

6. Adjust VERTICAL DYNAMIC CENTERING (R3407).

a. ADJUST–Vertical Dynamic Centering (R3407) for minimum vertical deflection of the intensified zone with respect to the trace.

NOTE

Correct adjustment will align the intensified zone with the trace such that a single horizontal trace results with no vertical deflection difference between the trace and the intensified zone.

b. Press and release the upper TRIGGER COUPLING button to conclude CAL 08.

CH 1 AND CH 2 INPUT CAPACITANCE, AND VERTICAL READOUT JITTER ADJUSTMENTS

Equipment Required (see table 4-1)

Calibration Generator (Item 3)
BNC Cable (Item 10)
Termination (Item 12)
Low-Capacitance Alignment Tool (Item 20)
Normalizer (item 22)

See **ADJUSTMENT LOCATIONS 3** *and* **4 (fig. FO-23)**
at the back of this manual for test point and adjustment locations.

Initial Control Settings.

Control settings not listed do not affect the procedure.

VERTICAL VOLTS/DIV

CH 1 and CH 2	100 mV
CH 1 and CH 2 VAR	In detent

INPUT COUPLING

CH 1 and CH 2	1 MΩ DC

VERTICAL MODE

CH 1	On
CH 2, CH 3, CH 4	Off
ADD, INVERT, and BW LIMIT	Off
ALT/CHOP	ALT

VERTICAL POSITION

CH 1	Midrange

HORIZONTAL

A SEC/DIV	100 µs (knob in)
SEC/DIV VAR	In detent
Horizontal POSITION	Midrange

TRIGGER

MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC
SLOPE	+ (plus)
LEVEL	Midrange
HOLDOFF	In detent

DELTA

Δ V and Δ t	Off (press and release until readout display disappears)
INTENSITY	Left of center
READOUT INTENSITY	As required for a visible display
SCALE ILLUM	Fully CCW
FOCUS	Best focused display

1. Adjust CH 1 and CH 2 Input Capacitance (C105 and C205).

NOTE

The objective of this adjustment is to match the input capacitance of the 50 mV per division position of the VOLTS/DIV switches to the 0.1 mV per division position. The front corner of an input square-wave signal is used to indicate when the capacitances are matched.

a. Connects 1 kHz square-wave signal from the Calibration Generator high-amplitude output to the CH 1 OR X input connector via a BNC cable, a termination, and a normalizer. Adjust the generator output level for a 6-division signal vertically centered on the graticule.

b. Set the normalizer for a square front corner over approximately the first 40 µs (0.4 division) of the positive portion of the waveform.

c. Change the CH 1 VOLTS/DIV switch to the 50 mV position and adjust the generator for a 6-division signal display.

d. ADJUST–The CH 1 50 mV C Adj (C105 on the Main Board) for the same waveform front corner noted in part b.

e. Repeat parts b through d until no change is observed in the waveform front corner when the CH 1 VOLTS/DIV switch is alternated between the 50 mV and 0.1 V positions. When switching between positions, re-establish the reference display amplitude at each position, and observe the square-wave front corner to make the comparison.

f. Move the input signal to CH 2 and change the VERTICAL MODE to display CH 2 only. Adjust the generator amplitude for a 6-division signal amplitude.

g. Set the normalizer for a square front corner over approximately the first 40 µs (0.4 division) of the positive portion of the waveform.

h. Change the CH 2 VOLTS/DIV switch to the 50 mV position and adjust the generator for a 6-division display.

i. ADJUST–The CH 250 mV C Adj (C205 on the Main Board) for the same waveform front corner noted in part g.

j. Repeat parts g through i until no change is observed in the waveform front corner when the CH 2 VOLTS/DIV switch is alternated between the 50 mV and 0.1 V positions. When switching between positions, re-establish the reference signal amplitude at each position, and observe the square-wave front corner to make the comparison.

k. Disconnect the test setup.

2. Adjust Vertical Readout Jitter (R618).

NOTE

If the previous step was not performed, first set up the Initial Control Settings before, then proceed as follows.

a. Set:

VERTICAL

CH 1 Input Coupling	50 Ω DC
CH 1 VERTICAL MODE	On
CH 2, CH 3, and CH 4 VERTICAL MODE	Off

HORIZONTAL

A SEC/DIV	500 µs (knob in)

b. Press and release the Δ V button to obtain a Δ V display.

c. Use the Δ REF OR DLY POS control to position one cursor 3 divisions above graticule center. Use the Δ control to position the other cursor 3 divisions below graticule center.

d. Connect a 1 kHz, fast-rise signal from the Calibration Generator to the CH 1 OR X input connector via a BNC cable.

e. Set the generator output level for an 8-division display.

f. Use the CH 1 Vertical and Horizontal POSITION controls to center the CH 1 display on the graticule.

g. ADJUST – Vertical Readout Jitter (R618) for minimum vertical jitter of the readout characters and cursors.

h. Disconnect the test setup.

AUTOMATIC CALIBRATION CONSTANTS, HORIZONTAL AND VERTICAL GAIN, CENTERING, AND TRANSIENT RESPONSE ADJUSTMENTS

Equipment Required (see table 4-1)

- Calibration Generator (Item 3)
- Time-Mark Generator (Item 6)
- Test Oscilloscope with 10X Probe (Item 7)
- BNC Cable (Item 10)
- Dual-Input Coupler (Item 11)
- 5X Attenuator (Item 17)
- Digital Multi meter (DMM) (Item 19)
- Low-Capacitance Alignment Tool (Item 20)
- Tunnel Diode Pulser (Item 23)
- 2.5X Attenuator (Item 27)

NOTE

Within the following procedures, the calibration constants for timing, vertical gain, trigger level, transient response, and parametric measurements are generated by the system microprocessor and are stored in nonvolatile memory. The adjustments in CAL 01,02,03,06,07, and 09 should be performed in sequence; i.e., CAL 01 should be done before CAL 02, CAL 02 should be done before CAL 03, etc. Performing partial procedures (i. e., only one or two of the CAL steps) is not recommended and should only be done if the calibration constants that would have been set in the preceding steps are known to be correct. The CAL functions are available only if the CAL/NO CAL jumper (P501 on the Control Board) is in the CAL position (between pins 2 and 3) when power is turned on. When the automatic calibration procedures are completed, return the jumper to the NO CAL position to prevent entry into the calibration routines. When performing the automatic CAL steps, initial setting of the front-panel controls is not required.

See **ADJUSTMENT LOCATIONS 4 (fig. FO-23)**

at the back of this manual for test point and adjustment locations.

CAL 01 – HORIZONTAL

1. Check/Adjust Horizontal Timing, X1 Gain (R860), X10 Gain (R850), Hrz Ctr (R801), and Trans Resp (R802).

a. Simultaneously press in and hold the Δ t and the Δ V push buttons, then press and hold the SLOPE switch. Hold all three switches in for approximately one second, then release them.

b. CHECK–Top line of the readout display says: “DIAG-NOSTIC. PUSH A/B TRIG TO EXIT”.

NOTE

The “menu” of calibration, test, and exercise routines are in a loop that may be scrolled through in single steps, either forward or backward. Pressing the upper or lower TRIGGER MODE switch respectively increments or decrements the menu position by one. As each routine is selected, its name appears in the lower left corner of the readout display.

When performing a calibration step, touch only the specific control or controls called out in the procedure. Movement of other controls may cause erroneous calibration results.

c. Scroll to CAL 01.

CAUTION

Upon entering CAL 01, the Input Coupling is automatically set to 50 Ω DC and the 50 Ω OVERLOAD protection is disabled. Before starting the procedure, make sure any 50 OVERLOAD condition has been cleared.

NOTE

In this procedure, pressing the upper TRIGGER COUPLING switch stores the current calibration parameter being set and increments the routine to the next step (except where otherwise noted).

d. Connect the DMM, set to measure approximately 500 mV, to the CALIBRATOR output.

e. Press and release the upper TRIGGER COUPLING switch.

NOTE

The CALIBRATOR output will go to its LO level on odd CAL steps and to its HI level on even steps.

f. CHECK– Readout indicates ADJUST Δ, (step) 0, CH 1 PROBE TO TP800 ON MAIN BD.

g. Connect a 10X probe from CH 1 to TP800, at rear of main board near readout connector.

h. ADJUST– Δ REF to center signal on displayed cursors, and ADJUST– Δ control to join traces.

i. Press and release the upper TRIGGER COUPLING switch.

j. CHECK–CALIBRATOR output voltage is 0 mV ±1 mV.

k. Disconnect the 10X probe from TP800 and from the CH 1 Input.

l. CHECK– Readout indicates ADJUST Δ (step) 1, 100 µs (for A Sweep), and 1 µs (for B Sweep).

NOTE

The readout prompts the operator by showing the control to be moved (upper left corner), the autocal step number (upper right corner), the A-Sweep speed (bottom right center), and the B-Sweep speed (bottom right corner) as setup by the routine. An example (from step I above) is:

ADJ Δ *1*
100 µs 1 µs

m. Connect the Time-Mark Generator, set for 0.1 ms time markers, to the CH 1 OR X input connector via a BNC cable.

n. Set:

VOLTS DIV	As needed for a convenient signal display amplitude
TRACE SEP	As needed to separate the A and B Sweeps
CH 1 POSITION	As needed to view both A and B Sweeps
Horizontal POSITION	Position start of trace at the left graticule line

NOTE

In the following calibration routine some sequential pairs of steps are iterative, i.e., the earlier step is recalled if an adjustment is made in the later step. Occasionally, on the earlier of some of these pairs, the readout may indicate "LIMIT" before the correct control setting is reached. If this occurs, proceed to the next AUTOMATIC CAL step. After the adjustment at the next step in performed, the previous step will automatically be recalled, and the adjustment may be performed in the normal manner.

o. ADJUST– Δ REF OR DLY POS and Δ controls to align both the intensified zones with the 6th time marker (near graticule center) and to superimpose the delayed B-Sweeptime markers. Press and release the upper TRIGGER COUPLING switch.

p. CHECK – CALIBRATOR output voltage is between 398 mV and 402 mV of the reading noted in part j. Disconnect the DMM when through.

q. CHECK– Readout indicates ADJ Δ (step) 2, 100 µs (for A Sweep), and 1 µs (for B Sweep).

r. ADJUST– Δ REF OR DLY POS control to intensify the 2nd time marker, and ADJUST– Δ control to intensify the 10th time marker. Superimpose the delayed B Sweep time markers within 0.2 division.

s. Press and release the upper TRIGGER COUPLING switch.

t. CHECK – Readout indicates ADJ Δ (step) 3, 300 µs (for A Sweep), and 1 µs (for B Sweep).

u. ADJUST– Δ REF OR DLY POS control to intensify the 4th time marker, and ADJUST– Δ control to intensify the 28th time marker. Superimpose the delayed B Sweep time markers within 1 division.

v. Press and release the upper TRIGGER COUPLING switch. If the adjustment in step 3 was changed, step 2 will be recalled; otherwise step 4 will be initiated.

w, CHECK – Readout indicates ADJ Δ (step) 4, 100 µs (for A Sweep), and 1 µs (for B Sweep). Set the Time-Mark Generator for 5 µs time markers.

x. ADJUST– Δ control CCW until no further movement of the B Sweep display occurs. Note the position of the 1st time marker, then adjust the Δ control CW until the 2nd time marker moves to the left and aligns with the position just noted.

NOTE

Movement of the Δ REF control at this point will adversely affect the calibration.

y. Press and release the upper TRIGGER COUPLING switch. Set the Time-Mark Generator for 10 µs time markers.

z. CHECK– Readout indicates X1, X10, HRZ CTR, (step) 5, and 10 µs (for A Sweep) and two vertical cursors appear on the display.

aa. ADJUST–Xl Gain (R860) and Hrz Ctr (R801) to align the two cursors with the 2nd and 10th vertical graticule lines, then adjust X10 Gain (R850) for 1 time marker per division.

ab. Press and release the upper TRIGGER COUPLING switch. Set the Time-Mark Generator for 10 ms time markers.

ac. CHECK– Readout indicates ADJ, (step) 6,10 ms (for A Sweep), and 100 µs (for B Sweep).

ad. ADJUST– Δ REF OR DLY POS control to intensify the 2nd time marker, and ADJUST– Δ control to intensify the 10th time marker. Superimpose the delayed B Sweep time markers within 0.2 division.

ae. Press and release the upper TRIGGER COUPLING switch. Set the Time-Mark Generator for 1 µs time markers.

af. For each step in Table 5-2, do the following:

1. Adjust the Δ REF OR DLY POS and Δ controls, as necessary, to intensify the indicated time marks on the A Sweep and superimpose the displayed B Sweep markers within the listed limits.

2. Press and release the upper TRIGGER COUPLING switch.

NOTE

If the Δ control is adjusted at step 9, 12 or 14, the previous step will be repeated.

ag. Set the TRACE SEP fully CW.

ah. Connect the Time Mark Generator output to CH 1 of both the instrument under test and the Test Oscilloscope via a T-Connector and two BNC cables. Connect B GATE OUT of the instrument under test to CH 2 of the Test Oscilloscope via a BNC cable.

ai. Set the Test Oscilloscope to view CH 1, with TRIGGER SOURCE CH 2. CH 1 and CH 2 coupling 50 Ω.

Table 5-2

Horizontal Timing
(Steps 7 through 16)

Step Number	Time-Marker Period	Δ REF Marker	Δ Marker	Super-imposition Tolerance In Divisions
7	1 µs	2	10	0.2
8	2 µs	2	10	0.2
9	2 µs	4	28	1.2
10	10 µs	2	10	0.2
11	50 µs	2	10	0.2
12	50 µs	4	28	1.2
13	0.5 µs	2	10	0.2
14	0.5 µs	4	28	1.2
15	50 ns	3	19	0.2
16[1]	20 ns	2	10	0.1

[1]Use the Δ control to adjust for approximately 1 time marker per division. Set Time-Mark Generator for 2 ns markers. Adjust volts/div for display amplitude of > 3 divisions. Adjust the Δ control to superimpose the displayed B Sweep markers. Return volts/div to original amplitude after making the adjustment.

aj. For each step in Table 5-3 (except step 28), adjust the Δ control for roughly the listed number of markers over the center 8 divisions, then superimpose markers on the Test Oscilloscope screen. Manually set SEC/DIV setting of bench scope to keep a usable time mark as listed in Table 5-3. Use DELAY POS on the instrument under test to bring markers on screen. Some sweep speeds might require adjusting holdoff to see both markers. When markers are superimposed, press and release the upper TRIGGER COUPLING switch. If the Δ control is adjusted at step 18, 20,23, or 25, the previous step will be repeated. At step 28, adjust Trans Resp (R802 on the Main board) as indicated.

ak. Disconnect the test setup.

NOTE

Change the CH 1 VOLTS/DIV switch setting as necessary to maintain adequate signal display amplitude. Step 28 requires the 2 ns time marks to be input through a dual input coupler to CH 1 and CH 2. Center the two waveforms.

If the remainder of the Adjustment Procedure will not be performed (in totality), readjustment of Horizontal Readout Jitter (R805) may be necessary if the X1 Gain (R860) or the X10 Gain (R850) was changed. See subsection 1 on page 5-20 for that procedure.

Table 5-3
Horizontal Timing (Steps 17 through 34)

Step No.	Bench Scope Time/Div	Time-Marker Period	Markers Over 8 Divisions	Test Oscilloscope Superimposition Tolerance In Divisions
17	200 ns and X10 (20 ns)	1 μs	8	0.2
18	200 ns and X10 (20 ns)	1 μs	24	1.2
19	500 ns and X10 (50 ns)	2 μs	8	0.2
20	500 ns and X10 (50 ns)	2 μs	24	1.2
21	2 μs and X10 (200 ns)	10 μs	8	0.2
22	10 μs and X10 (1 μs)	50 μs	8	0.2
23	10 μs and X10 (1 μs)	50 μs	24	1.2
24	100 ns and X10 (10 μs)	500 ns	8	0.2
25	100 ns and X10 (10 μs)	500 ns	24	1.2
26	20 ns and X10 (2 ns)	100 ns	8	0.2
27	20 ns and X10 (2 ns)[1]	20 ns	8	0.2
28	na	2 ns	2[2]	na
29	200 μs and X10 (20 μs)	1 ms	8	0.2
30[3]	na	5 ns	8	na
31[3]	na	10 ns	8	na
32[3] [5]	na	10 ns	8	na
33[4] [5]	na	2 ns	4	na
34[4] [5]	na	2 ns	4	na

[1]Use the Δ control to adjust for approximately 1 time marker per division. Set Time-Mark Generator for 5 ns markers. Adjust the Δ control to superimpose the displayed test oscilloscope display. The bench scope holdoff may require adjustment.
[2]Adjust Trans Resp (R802) for precisely 2 cycles between the 2nd and 10th graticule lines at the INTERSECTIONS on the two waveforms.
[3]Adjust volt/div for > 3 division amplitude. Adjust Δ for 1 time marker per division over the center 8 divisions.
[4]Adjust volt/div for 1 to 4 division amplitude. Adjust Δ for 1 time marker per 2 divisions over the center 8 divisions. To do this, set Horizontal Position control CCW and note end of sweep timing over the center 8 divisions. Return Horizontal Position control CW to locate beginning of sweep. Some compromise of the Δ adjustment may be necessary to obtain best timing accuracy over the center 8 divisions at the start and end of sweep.
[5]Steps 32, 33, and 34 are for instruments with serial number B012946 and above.

CAL 02 - VERTICAL

2. Check/Adjust Vertical Preamplifier Gain, Gain (R638), and Vertical Centering (R639).

NOTE

If the previous step (CAL 01) was not performed, the adjustments in this subsection should only be performed if those constants that would have been set in CAL 01 are known to be correct.

a. Set the front-panel INTENSITY control at midrange.

b. Scroll to CAL 02.

c. Press and release the upper TRIGGER COUPLING switch. The instrument will automatically increment through steps 100 to 110.

d. CHECK–Readout indicates CH 1 VAR, CH2 POS, (step) 111,500 mV.

NOTE

The readout prompts the operator by showing the controls to be moved (upper left corner and upper center), the autocal step number (upper right corner), the amplitude of signal to be applied to either the CH 1 or CH 2 connectors (lower left corner), and any other scope function that is enabled, An example (from step d above) is:

CH1 VAR CH2 POS 111
500 mV

e. Connect a 0.5 V, standard-amplitude signal from the Calibration Generator to the CH 1 OR X input connector via a BNC cable.

f. Use the CH 2 POSITION control to vertically position the trace to within 1 division of the center graticule line.

g. ADJUST– CH 1 POSITION and VOLTS/DIV VAR controls to obtain a 10-division horizontal signal. Press and release the upper TRIGGER COUPLING switch.

NOTE

When step 111 is performed, step 112 is also automatically done. No indication of step 112 will be shown unless a LIMIT error is indicated.

In the following steps, if the "LIMIT" message appears, it probably indicates that the TRIGGER COUPLING (step) switch was moved before the *required signal was applied. Press and release the lower TRIGGER COUPLING switch, verify that the correct signal is applied, then press and release the upper TRIGGER COUPLING switch.*

h. CHECK – First step number listed in Table 5-4 appears in the readout.

i. Apply the corresponding standard-amplitude signal from the Calibration Generator, then press and release the upper TRIGGER COUPLING switch.

j. Repeat steps h and i for each step-signal combination listed in Table 5-4.

k. Move the signal to the CH 2 input connector.

l. CHECK– Readout indicates CONNECT SIGNAL TO CH 2, (step) 121, 500 mV, 500 mV, and BWL.

m. Set the Calibration Generator for a 500 mV standard-amplitude signal, then press and release the upper TRIGGER COUPLING switch.

Table 5-4
Vertical Calibration Signals
(Steps 113 through 120)

Autocal Step Readout Display	Standard-Amplitude Signal to Apply
113[1]	0.5 V
115	0.2 V
116	0.1 V
117	50 mV
118	20 mV
119	1 V
120	10 V

[1]When step 113 is performed, step 114 is also automatically done. No indication of step 114 will be shown unless a LIMIT error is encountered.

NOTE

When step 121 is performed, step 122 is also automatically done. No indication of step 122 will be shown unless a LIMIT error is indicated.

n. CHECK–First step number listed in Table 5-5 appears in the readout.

o. Apply the corresponding standard-amplitude signal, then press and release the upper TRIGGER COUPLING switch.

p. Repeat steps n and o for each step-signal combination listed in Table 5-5.

Table 5-5
Vertical Calibration Signals
(Steps 123 through 130)

Autocal Step Readout Display	Standard-Amplitude Signal to Apply
123[1]	0.5 V
125	0.2 V
126	0.1 V
127	50 mV
128	20 mV
129	1 V
130[2]	10 V

[1]When step 123 is performed, step 124 is automatically done. No indication of step 124 will be shown unless a LIMIT error is encountered.
[2]When step 130 is performed, step 131 is automatically done. No indication of step 131 will be shown unless a LIMIT error is encountered.

q. CHECK– Procedure automatically steps through steps 132-141 (DC balance).

r. CHECK– Readout indicates CONNECT SIGNAL TO CH 1, 50mV, and BWL.

s. Move the signal to the CH 1 OR X input connector and set the Calibration Generator for a 50 mV standard-amplitude signal, then press and release the upper TRIGGER COUPLING switch. Wait approximately 10 seconds for automatic calibration of the Δ V cursors.

t. CHECK– Readout indicates VERT CENTER GAIN.

u. ADJUST–Gain (R638) for precisely 5 divisions between the two horizontal cursors.

v. ADJUST–Vertical Centering (R639) to center the cursors on the graticule (align the cursors with the dotted 0% and 100% graticule lines).

w. Press and release the upper TRIGGER COUPLING switch. The microprocessor continues calibrating the vertical. Remove signal from CH 1 input.

CAL 03 - TRIGGERING

3. Check/Adjust Triggering.

NOTE

If the previous steps (CAL 01 and CAL 02) were not performed, the adjustments in this subsection should only be performed if those constants that would have been set in CAL 01 and CAL 02 are known to be correct and if a DC Balance has been performed after a 20-minute warmup period.

a. Scroll to CAL 03.

b. Press and release the upper TRIGGER COUPLING switch.

c. CHECK – Procedure automatically steps from 200 through 214 and stops at 215.

d. CHECK – Readout indicates CH 1, 500 mV, and (step) 215.

NOTE

The readout prompts the operator by showing which connector the input signal should be applied to (upper left corner), the amplitude of that signal (upper center), and the autocal step number (upper right corner). An example (from step d above) is:

CH1 500 mV 215

e. Connect a 0.5 V standard-amplitude signal from the Calibration Generator to the CH 1 OR X input connector via a BNC cable.

f. Press and release the upper TRIGGER COUPLING switch.

g. CHECK – Readout indicates CH 1, 500 mV, and (step) 216.

h. Press and release the upper TRIGGER COUPLING switch.

i. CHECK– Readout indicates CH 2, 500 mV, and (step) 217.

j. Move the signal to the CH2 input connector. Press and release the upper TRIGGER COUPLING switch.

k. CHECK – Readout indicates CH 3, 500 mV, and (step) 218.

l. Move the signal to the CH3 input connector. Press and release the upper TRIGGER COUPLING switch.

m. CHECK– Readout indicates CH3, 2V, and (step) 219.

n. Change the generator output level to 2 V, then press and release the upper TRIGGER COUPLING switch.

o. CHECK– Readout indicates CH 4, 500 mV, and (step) 220.

p. Move the signal to the CH 4 input connector and change the generator output level to 0.5 V. Press and release the upper TRIGGER COUPLING switch.

q. CHECK– Readout indicates CH4, 2V, and (step) 221.

r. Change the generator output level to 2 V, then press and release the upper TRIGGER COUPLING switch.

s. Disconnect the test setup.

CAL 04 - CH 2 DELAY ENABLE/DISABLE

4. Check/Adjust CH 2 Delay Enable/Disable.

a. Scroll to CAL 04.

b. Press and release the upper TRIGGER COUPLING switch to initiate the routine.

c. CHECK– Readout alternately indicates “ENABLED” and “DISABLED” each time the upper TRIGGER COUPLING switch is pressed and released.

d. Leave the readout display indicating “ENABLED”. Press and release the A/B TRIG button to exit the routine.

e. Connect a 100 kHz, positive-going signal from the Calibration Generator fast-rise output to the CH 10RX and CH 2 input connectors via a BNC cable, a 5X attenuator, and a dual-input coupler.

f. Set:

VERTICAL MODE

CH 1 and CH 2	On

VOLTS/DIV

CH 1 and CH 2	10 mV

INPUT COUPLING

CH 1 and CH 2	50 Ω DC

HORIZONTAL

A SEC/DIV	5 ns (knob in)

TRIGGER

SOURCE	CH 1
MODE	AUTO LVL
COUPLING	DC
SLOPE	+ (plus)

g. Set the generator amplitude for a 3- to 5-division display amplitude. Use the CH 1 and CH 2 POSITION controls to vertically overlay the traces near the center of the graticule area.

h. Set the Horizontal POSITION control to set the rising edge of the signal near the center vertical graticule line.

i. Press the X10 MAG button to obtain a magnified display.

j. Pull out the SEC/DIV knob.

k. CHECK– Readout indicates "CH 2 DLY–TURN Ω " and that the Δ control will move the leading edge of the CH 2 trace at least 1 division to either side of the CH 1 trace.

l. ADJUST– Δ control to superimpose the leading edges.

m. Push in the SEC/DIV knob.

NOTE

If the CH 2 Delay Adjust feature is to be disabled for normal instrument use, perform the following steps; otherwise, proceed to CAL 05.

n. Re-enter the Diagnostic Monitor by pressing the Δ V and Δ t buttons simultaneously (hold them in), then press and hold the TRIGGER SLOPE button. Release the buttons after about 1 second.

o. Scroll to CAL 04.

p. Press and release the upper TRIGGER COUPLING switch until the readout indicates “DISABLED. ”

q. Press and release the A/B TRIG button to return to normal operating mode.

CAL 05 – Set HRS ON and PWR ON/OFF cycles.

5. Check/Adjust Hours On and Power On/Off cycles.

a. Scroll to CAL 05.

b. Press and release the upper TRIGGER COUPLING switch to initiate the routine.

c. CHECK –Readout indicates HRS ON xxx PWR ON/OFF XXX Δ REF HRS Δ PWR PUSH MAG 10/1.

d. Press and release the lower TRIGGER SOURCE and then press and release the lower TRIGGER MODE to reset HRS ON and PWR ON/OFF to zero.

NOTE

HRS ON and PWR ON/OFF can be set to any value from 0-99999 with the Δ REF and Δ controls. The X10 MAG Switch can be used to select increment by 10 or increment by 1 mode.

e. Press and release the lower TRIGGER COUPLING switch to exit the routine.

CAL 06 - VERTICAL TRANSIENT RESPONSE

6. Check/Adjust Vertical Transient Response.

NOTE

If CAL 02 was not performed, the adjustments in this subsection should only be performed if those constants that would have been set in CAL 02 are known to be correct.

a. Scroll to CAL 06.

b. Press and release the upper TRIGGER COUPLING button to initiate the routine.

c. CHECK– Readout indicates ADJ Δ (step) 1, 10 mV, 100 ns.

d. Connect the high-amplitude output of the Calibration Generator to the CH 1 OR X input connector via a BNC cable, a Tunnel Diode Pulser, and a 5X attenuator.

e. Set the generator Period switch to 100 kHz, and set the generator amplitude control to maximum.

f. Rotate the pulser Trigger control CW (from a fully CCW position) until a stable pulse first appears on the graticule. Over adjustment of the pulser Trigger control will lead to erroneous transient response adjustment. Display amplitude will be approximately 5 divisions. The oscilloscope TRIGGER LEVEL control may need to be adjusted to obtain a stable trigger.

NOTE

As a guide when performing the following adjustments, optimum performance is achieved when the CH 1 and CH 2 step response aberrations are ≤ 4% over the first 10 ns of the pulse when using 10 mV/division deflection factors (≤ 0.2 division on a 5-division signal).

g. Press and release the upper TRIGGER COUPLING button twice to advance to step 3.

h. CHECK– Readout indicates ADJ Δ (step) 3, 10 mV, 10 ns.

i. ADJUST – Trans Resp Adjustments C403, R411, L403, R417, and Δ for flattest corner over first 5ns. The total system will tune best if the indicator cursor is in the 7th or 8th horizontal division.

NOTE

Inductor L403 is a selectable component chosen to match transient response characteristics of the Vertical system. If spreading the coil turns will not correct the front corner overshoot, a smaller value coil should be installed. Likewise, a larger coil can be installed to raise the front corner. The proper coils to use are:

90 nH-5 turn inductor Part No. 108-0620-00
80 nH-4 turn inductor Part No. 108-0552-00
60 nH-3 turn inductor Part No. 108-0420-00
45 nH-2 turn inductor Part No. 108-0578-00

j. Turn A SEC/DIV VAR control CCW and ADJUST CRT termination (R1501) for flattest waveform over the first 0.2 division.

k. Set SEC/DIV VAR to detent.

l. Press and release the upper TRIGGER COUPLING button.

m. CHECK– Readout indicates ADJ Δ (step) 4, 10 mV, 100 ns.

n. Connect the Calibration Generator, Tunnel Diode Pulser, 5X attenuator combination to CH 2 input via a BNC cable.

NOTE

Pressing the lower TRIGGER COUPLING button at any step of CAL 06 will return to step 1. By then pressing the upper TRIGGER COUPLING button repeatedly, the routine can be advanced to the desired step. This is useful for cal steps 1,2,3, and 4 which may require some compromise of adjustments.

o. ADJUST– Δ for the flattest waveform.

NOTE

Some compromise may be necessary between step 3 and 4 for the flattest corner over first 5 ns.

p. Press and release the lower TRIGGER COUPLING button to return to step 1.

q. Disconnect the Tunnel Diode Pulser and connect the fast rise output of the Calibration Generator to CH 1 OR X via a 5X attenuator and a BNC cable. Adjust generator amplitude for a 5 division display.

r. ADJUST– Trans Resp adjustments (R605, R403, C404, C601 ,and R1501) for the flattest response in the first 100 ns.

s. Press and release the upper TRIGGER COUPLING button.

t. CHECK – Readout indicates ADJ Δ (step) 2, 10 mV, 100 ns.

u. Connect the generator and 5X attenuator combination to CH 2 input via a BNC cable.

NOTE

Some compromise may be necessary between step 1 and 2 for the flattest response in the first 100 ns.

v. Press and release the lower TRIGGER COUPLING button to return to step 1.

w. Disconnect the Calibration Generator and connect the Secondary Leveled Sine-Wave Generator head to the CH 1 input via a 10X attenuator.

x. Set the generator for a 6-division display at the reference frequency.

y. Change the generator output frequency to 350 MHz.

z. CHECK– Display amplitude is between 4.4 divisions and 6 divisions while the generator frequency is changed from 350 MHz to 420 MHz. This bandwidth provides optimum performance of the Vertical system.

aa. Press and release the upper TRIGGER COUPLING switch.

ab. Check – Readout indicates ADJ Δ (step) 2, 10 mV, 10 ns.

ac. Connect the Secondary Leveled Sine-Wave Generator head to the CH 2 input via a 10X attenuator. Repeat steps x through aa for CH 2.

ad. Connect the Calibration Generator, Tunnel Diode Pulser, 5X attenuator combination to CH 1 OR X input via a BNC cable.

NOTE

Check pulser Trigger control is adjusted correctly as described in step f above.

ae. Check – Readout indicates ADJ Δ (step) 3, 10 mV, 10 ns.

af. ADJUST – Trans Resp adjustments (R411, C403, L403, R417 and the Δ control) for best response if necessary.

ag. Disconnect the Tunnel Diode Pulser and connect the fast rise output of the Calibration Generator to CH 1 OR X via a 5X attenuator and a BNC cable. Adjust generator amplitude for a 5 division display. Note the amount of roll up or roll down in the first 3 ns. This difference represents the error between the Tunnel Diode Pulser (reference) and the fast rise generator output.

ah. Press and release the upper TRIGGER COUPLING switch (step 4). Move the test signal to CH 2 and ADJUST amplitude for 5 division signal.

ai. ADJUST– Δ until CH 2 waveform best matches that noted in step ff above.

aj. Press and release the upper TRIGGER COUPLING switch (step 5). Connect the test signal to CH 1 through 2X, 2.5X, and 5X attenuators. ADJUST Δ for best front corner.

ak. Press and release the upper TRIGGER COUPLING switch (step 6). Remove 2.5X attenuator. ADJUST Δ for best corner.

NOTE

The 5 mV response should have a 4-5% front corner spike to maintain correct bandwidth.

al. Press and release the upper TRIGGER COUPLING switch (step 7). Remove 5X attenuator. ADJUST generator for a 5 division signal. ADJUST Δ for best corner.

am. Press and release the upper TRIGGER COUPLING switch (step 8). Adjust generator for 5 division signal. ADJUST Δ for best corner.

an. Press and release the upper TRIGGER COUPLING switch (step 9). Adjust high amplitude generator for 5 division signal. ADJUST Δ for a front corner spike of 6 to 7%. This is necessary to have the 10X bandwidth (0.1V - 0.5V) be similar to the 10 mV bandwidth.

NOTE

Generator amplitude for the 500 *mV step will be approximately 2 divisions and the amplitude for the 1 V step will be approximately 1 division.*

ao. Press and release the upper TRIGGER COUPLING switch (step 10). Remove 2X attenuator. ADJUST Δ for best corner. Continue through cal step 12 as above.

ap. Press and release the upper TRIGGER COUPLING switch. Steps 13 and 14 are automatically calibrated. Connect test signal to CH 2 via 2X, 2.5X, and 5X attenuators and adjust for 5 division signal. ADJUST Δ for best corner.

aq. Repeat steps ak through ao for CH 2 (steps 16-22).

ar. Steps 23 and 24 are automatically calibrated after step 22.

as. Disconnect the generator from the CH 2 input.

at. CHECK– Readout indicates VERT CENTER GAIN.

au. ADJUST–Gain (R638) and Vertical Centering (R639) to align the cursors with the dotted 0% and 100% graticule markings.

av. Press and release the upper TRIGGER COUPLING switch to conclude the calibration routine.

CAL 07 - READOUT CENTERING AND GAIN

7. Check/Adjust Readout Centering and Gain (R2918, R2931).

a. Scroll to CAL 07.

b. Press and release the upper TRIGGER COUPLING switch to initiate the routine.

c. CHECK– Readout displays large 8 characters in the top line and BWL characters in the bottom line.

d. ADJUST– Readout Centering (R2918) and Gain (R2931) so characters remain just inside the graticule area.

e. Press and release the lower TRIGGER COUPLING switch.

CAL 09 - PARAMETRIC MEASUREMENTS

NOTE

At the end of this calibration procedure, move the Cal/No-Cal jumper (P501) to the No-Cal position (between pins 1 and 2).

8. Adjust Parametric Measurements.

NOTE

If CAL 01, 02, and 03 were not performed, the adjustments in this subsection should only be performed if those constants that would have been set in CAL 01, 02 and 03 are known to be correct. "Limit" messages that appear during this calibration are generally due to A or B Sweeps, A or B Gates, or the measurement PAL, U975.

a. Scroll to CAL 09.

b. Press and release the upper TRIGGER COUPLING button to initiate the routine.

c. CHECK– Readout indicates (step) 1, CAL 09, 100 ns.

NOTE

The readout prompts the operator by showing the autocal step number (upper right corner) and Time-Marker Generator setting (lower right corner).

d. Connect the Time-Mark Generator, set for 0.1 µs time markers, to the CH 1 OR X input connector via a BNC cable.

e. Press and release the upper TRIGGER COUPLING button to calibrate the step.

f. CHECK– Readout indicates (step) 2, CAL 09, 100 ns.

g. For the remaining steps in Table 5-6, do the following:

1. Set the Time-Marker Generator output for markers corresponding to the Step Number.

2. Press and release the upper TRIGGER COUPLING button to calibrate the step.

h. Steps 18 through 28 are automatically calibrated by the system processor.

i. CHECK– Calibration is concluded and the instrument returns to the Diagnostic menu.

j. Disconnect the Time-Mark Generator.

Table 5-6

Parametric Measurement Calibration

Autocal Step Readout Display	Time Markers to Apply	Autocal Step Readout Display	Time Markers to Apply
2	0.1 µs	10	50 µs
3	0.2 µs	11	0.1 ms
4	0.5 µs	12	0.2 ms
5	1 µs	13	0.5 ms
6	2 µs	14	1 ms
7	5 µs	15	2 ms
8	10 µs	16	5 ms
9	20 µs	17[1]	0.2 ms

[1]At the conclusion of step 17 calibration, the instrument returns to the Diagnostic readout display. Disconnect the Time-Mark Generator at this time.

9. Adjust Bandwidth Limit.

a. Set:

VERTICAL

CH 1 POSITION	Midrange
CH 1 MODE	On
CH 2, CH 3, and CH 4 MODE	Off
20 MHz BW LIMIT	On
CH 1 VOLTS/DIV	10 mV
CH 1 VAR	In detent

INPUT COUPLING

CH 1	1 MΩ DC

HORIZONTAL

POSITION	Midrange
X10 MAG	Off
A SEC/DIV	100 ns (knob in)
SEC/DIV VAR	In detent

TRIGGER

HOLDOFF	MIN (Fully CCW)
LEVEL	Midrange
A/B TRIG	A
SLOPE	+
MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC

b. Connect a fast-rise, positive-going square-wave output via a precision BNC cable, a 10X attenuator, and a termination to the CH 1 input connector.

c. Set the generator to produce a 100-kHz, 5-division display.

d. ADJUST – Coil L644 for as flat a response as possible.

e. Disconnect the test equipment from the instrument.

DC BALANCE, AND X-Y PHASE DIFFERENTIAL ADJUSTMENTS

Equipment Required (see table 4-1)

Primary Leveled-Sine wave Generator (Item 2)
Calibration Generator (Item 3)
BNC Cable (Item 10)
5X Attenuator (Item 17)
Low-Capacitance Alignment Tool (Item 20)

See ADJUSTMENT LOCATIONS 1 *and* **4 (fig. FO-23)**
at the back of this manual for test point and adjustment locations.

Initial Control Settings.

Control settings not listed do not affect the procedure.

VERTICAL VOLTS/DIV

CH 1 and CH 2	10mV
CH 1 VAR	CCW (out of detent)
CH 2 VAR	In detent

INPUT COUPLING

CH 1 and CH 2	50 Ω DC

VERTICAL MODE

CH 1	On
CH 2, CH 3, CH 4	Off
ADD, INVERT, and	
BW LIMIT	Off
ALT/CHOP	ALT

VERTICAL POSITION

CH 1	Midrange

HORIZONTAL

A SEC/DIV	1 ms
SEC/DIV VAR	In detent
POSITION	Midrange

TRIGGER

MODE	AUTO LVL
SOURCE	VERT
COUPLING	DC
SLOPE	+ (plus)
LEVEL	Midrange
HOLDOFF	Minimum

DELTA

ΔV	On (RATIO readout)
TRACKING/INDEP	INDEP
Δ REF OR DLY POS and Δ	Cursors near the 3rd line above and 3rd line below graticule center (6 division spacing)
INTENSITY	Left of center
READOUT INTENSITY	Right of center
SCALE ILLUM	Fully CCW
FOCUS	Best focused display

1. **Check/Adjust Readout Jitter (R805 and R618).**

a. Rotate the Δ REF OR DLY POS control CCW until the RATIO readout is constant.

b. Rotate the Δ control until the readout display indicates 30.0%.

c. CHECK– One cursor is near the bottom horizontal graticule line and the other is near dotted graticule line marked 100(%).

d. Rotate the Δ REF OR DLY POS control until the readout displays exactly 100.0%. The cursors should now be on or near the dotted graticule lines marked 0% and 100(%).

e. Set the CH 1 VOLTS/DIV VAR to the detent position.

NOTE

Care must be taken not to disturb the position of the controls adjusted in parts b through e during the balance of this procedure. If they are accidentally moved, repeat the procedure from the beginning.

f. Connect a 1 kHz, fast-rise signal from the Calibration Generator to the CH 1 OR X input connector via a BNC cable and 5X attenuator.

g. Set the generator output level for an 8-division display.

h. Use the CH 1 Vertical and the Horizontal POSITION controls to center the CH 1 display on the graticule.

i. ADJUST – Vertical Readout Jitter (R618) for minimum vertical jitter of the readout characters and cursors.

j. ADJUST–Gain (R638) and Centering (R639) to align cursors with the 0 and 100% graticule markings.

k. Disconnect the 1 kHz signal.

l. Press the At button to obtain a At cursor display.

m. Using the ARE FOR DLY POS and A controls, position the cursors to the 2nd and 10th graticule lines.

n. Set X10 MAG on.

o. ADJUST– Horizontal Readout Jitter (R805) for minimum horizontal jitter of the readout characters and cursors.

p. Set X10 MAG off.

2. Set CH 1 and CH 2 DC Balance.

NOTE

The instrument must have had a 20-minute warmup prior to performing the next step to ensure accuracy.

a. Press and hold momentarily and release the CH 1 and CH 2 upper Input Coupling switches simultaneously.

b. CHECK–The display reads DC BALANCE IN PROGRESS for approximately 10 seconds, then the display returns to normal.

c. CHECK – For less than 0.2-division + 0.5 mV vertical trace shift when the CH 1 VOLTS/DIV switch is rotated through all of its settings.

d. Set the VERTICAL MODE switches to disable CH 1 and display CH 2.

e. CHECK – For less than 0.2-division + 0.5 mV vertical trace shift when the CH 2 VOLTS/DIV switch is rotated through all of its settings.

3. Adjust X-Y Phasing (C118).

a. Set:

CH 1 VOLTS/DIV	50 mV
Input Coupling	50 Ω DC
A SEC/DIV	x-Y
CH 1 VERTICAL MODE	On
CH 2, CH 3, CH 4 VERTICAL MODE	Off

b. Connect the Primary Leveled Sine-Wave Generator to the CH 1 OR X input connector via a BNC cable.

c. Set the generator frequency to 1 MHz and adjust the amplitude for a 6-division vertical signal display.

d. Use the CH 1 POSITION control to vertically center the display on the graticule.

e. ADJUST– X-Y Phasing (Cl 18) for no opening in the ellipse.

f. Set the generator frequency to 2 MHz and adjust the amplitude for a 6-division vertical signal display.

g. CHECK – Horizontal opening in the ellipse is 0.3 division or less, measured at the center horizontal graticule line.

h. Disconnect the test setup.

Section 6
MAINTENANCE

This section of the manual contains information for conducting preventive maintenance, troubleshooting, and corrective maintenance on the instruments.

STATIC-SENSITIVE COMPONENTS

The following precautions are applicable when performing any maintenance involving internal access to the instrument. Also refer to page C at the beginning of this manual.

CAUTION

Static discharge can damage any semiconductor component in this instrument.

This instrument contains electrical components that are susceptible to damage from static discharge. Table 6-1 lists the relative susceptibility of various classes of semiconductors. Static voltages of 1 kV to 30 kV are common in unprotected environments.

When performing maintenance, observe the following precautions to avoid component damage:

1. Minimize handling of static-sensitive components.
2. Transport and store static-sensitive components or assemblies in their original containers or on a metal rail. Label any package that contains static-sensitive components or assemblies.
3. Discharge the static voltage from your body by wearing a grounded antistatic wrist strap while handling these components. Servicing static-sensitive components or assemblies should be performed only at a static-freework station by qualified service personnel.
4. Nothing capable of generating or holding a static charge should be allowed on the work station surface.
5. Keep the component leads shorted together whenever possible.
6. Pick up components by their bodies, never by their leads.

Table 6-1
Susceptibility to Static Discharge Damage

Semiconductor Classes	Relative Susceptibility Levels[1]
MOS or CMOS microcircuits or discretes, or linear microcircuits with MOS inputs. (Most Sensitive)	1
ECL	2
Schottky signal diodes	3
Schottky TTL	4
High-frequency bipolar transistors	5
JFETs	6
Linear microcircuits	7
Low-power Schottky TTL	8
TTL (Least Sensitive)	9

[1]Voltage equivalent for levels: (Voltage discharged from a 100 pF capacitor through a resistance of 100 Ω).

1 = 100 to 500 V
2 = 200 to 500 V
3 = 250 V
4 = 500 V
5 = 400 to 600 V
6 = 600 to 800 V
7 = 400 to 1000 V (est.)
8 = 900 V
9 = 1200 V

7. Do not slide the components over any surface.
8. Avoid handling components in areas that have a floor or work-surface covering capable of generating a static charge.
9. Use a soldering iron that is connected to earth ground.
10. Use only approved antistatic, vacuum-type resoldering tools for component removal.

PREVENTIVE MAINTENANCE

INTRODUCTION

Preventive maintenance consists of cleaning, visual inspection, and checking instrument performance. When accomplished regularly, it may prevent instrument malfunction and enhance instrument reliability. The severity of the environment in which the instrument is used determines the required frequency of maintenance. An appropriate time to accomplish preventive maintenance is just before instrument adjustment.

GENERAL CARE

The cabinet minimizes accumulation of dust inside the instrument and should normally be in place when operating the instrument. The front cover supplied with the instrument provides both dust and damage protection for the front panel and CRT, and it should be on whenever the instrument is stored or is being transported.

INSPECTION AND CLEANING

The instrument should be visually inspected and cleaned as often as operating conditions require. Accumulation of dirt in the instrument can cause overheating and component breakdown. Dirt on components acts as an insulating blanket, preventing efficient heat dissipation. It also provides an electrical conduction path that could result in instrument failure, especially under high-humidity conditions.

CAUTION

Avoid the use of chemical cleaning agents which might damage the plastics used in this instrument. Use a nonresidue-type cleaner, preferably isopropyl alcohol or a solution of 1% general purpose detergent with 99% water. Before using any other type of cleaner, consult your Tektronix Service Center or representative.

Exterior

INSPECTION. Inspect the external portions of the instrument for damage, wear, and missing parts; use Table 6-2 as a guide. Instruments that appear to have been dropped or otherwise abused should be checked thoroughly to verify correct operation and performance. Deficiencies found that could cause personal injury or could lead to further damage to the instrument should be repaired immediately.

Table 6-2
External Inspection Check List

Item	Inspect For	Repair Action
Cabinet, Lid, Front Panel	Cracks, scratches, deformations, damaged hardware or gaskets.	Repair or replace defective components.
Front Panel Controls	Missing, damaged, or loose knobs, buttons, and controls.	Repair or replace missing or defective items.
Connectors	Broken shells, cracked insulation, and deformed contacts. Dirt in connectors.	Replace defective parts. Clear or wash out dirt.
Carrying Handle	Correct operation.	Replace defective parts.
Accessories	Missing items or parts of items, bent pins, broken or frayed cables, and damaged connectors.	Replace damaged or missing items, frayed cables, and defective parts.

CAUTION

To prevent getting moisture inside the instrument during external cleaning, use only enough liquid to dampen the cloth or applicator.

CLEANING. Loose dust on the outside of the instrument can be removed with a lint-free cloth. Dirt that remains can be removed with a lint-free cloth dampened in a general purpose detergent and water solution. Do not use abrasive cleaners.

Two plastic light filters, one blue and one clear, are provided with the oscilloscope. Clean the light filters and

the CRT face with a lint-free cloth dampened with either isopropyl alcohol or a general purpose detergent and water solution.

Interior

To gain access to internal portions of the instrument for inspection and cleaning, refer to the "Removal and Replacement Instructions" in the "Corrective Maintenance" part of this section.

INSPECTION. Inspect the internal portions of the instrument for damage and wear, using Table 6-3 as a guide. Deficiencies found should be repaired immediately. The corrective procedure for most visible defects is obvious; however, particular care must be taken if heat-damaged components are found. Overheating usually indicates other trouble in the instrument; therefore, it is important that the cause of overheating be corrected to prevent recurrence of the damage.

If any electrical component is replaced, conduct a Performance Check for the affected circuit and for other closely related circuits (see Section 4). If repair or replacement work is done on any of the power supplies, conduct a complete Performance Check and, if so indicated, an instrument readjustment (see Sections 4 and 5).

Table 6-3

Internal Inspection Check List

Item	Inspect For	Repair Action
Circuit Boards	Loose, broken, or corroded solder connectors. Burned circuit boards. Burned, broken, or cracked circuit-run plating.	Clean solder corrosion with isopropyl alcohol. Resolder defective connections. Determine cause of burned items and repair. Repair defective circuit runs.
Resistors	Burned, cracked, broken, blistered.	Replace defective resistors. Check for cause of burned component and repair as necessary.
Solder Connections	Cold Solder or rosin joints.	Resolder joint and clean with isopropyl alcohol.
Capacitors	Damaged or leaking cases. Corroded solder on leads or terminals.	Replace defective capacitors. Clean solder connections and flush with isopropyl alcohol.
Semiconductors	Loosely inserted in sockets. Distorted pins.	Firmly seated loose semicondcutors. Remove devices having distorted pins. Carefully straighten pins (as required to fit the socket), using long-nose pliers, and reinsert firmly. Ensure that straightening action does not crack pins, causing them to break off.
Wiring and Cables	Loose plugs or connectors. Burned, broken, or frayed wiring.	Firmly seat connectors. Repair or replace defective wires or cables.
Chassis	Dents, deformations, and damaged hardware.	Straighten, repair, or replace defective hardware.

CAUTION

To prevent damage from electrical arcing, ensure that circuit boards and components are dry before applying power to the instrument.

CLEANING. To clean the interior, blowoff dust with dry, low-pressure air (approximately 9 psi). Remove any remaining dust with a lint-free cloth dampened with a solution of general purpose detergent and water. A cotton-tipped applicator is useful for cleaning in narrow spaces and on circuit boards.

If these methods do not remove all the dust or dirt, the instrument may be spray washed using a solution of 5% general purpose detergent and 95% water as follows:

CAUTION

Exceptions to the following procedure are the Attenuator assemblies. Clean these assemblies only with isopropyl alcohol as described in step 4.

1. Gain access to the parts to be cleaned by removing easily accessible shields and panels.

2. Spray wash dirty parts with the detergent-and-water solution; then use clean water to thoroughly rinse them.

3. Dry all parts with low-pressure air.

NOTE

Most of the switches used in the instrument are sealed and the contacts are inaccessible. If cleaning is deemed necessary, use only isopropyl alcohol.

4. Clean switches with isopropyl alcohol and wait 60 seconds for the majority of the alcohol to evaporate. Then complete drying with low-pressure air.

5. Dry all components and assemblies in an oven or drying compartment using low-temperature (125°F to 150°F) circulating air.

LUBRICATION

There is no periodic lubrication required for this instrument.

SEMICONDUCTOR CHECKS

Periodic checks of the transistors and other semiconductors in the oscilloscope are not recommended. The best check of semiconductor performance is actual operation in the instrument.

PERIODIC READJUSTMENT

To ensure accurate measurements, check the performance of this instrument every 2000 hours of operation, or if used infrequently, once each year. “In addition, replacement of components may necessitate readjustment of the affected circuits.

Complete Performance Check and Adjustment instructions are given in Sections 4 and 5. The Performance Check Procedure can also be helpful in localizing certain troubles in the instrument.

TROUBLESHOOTING

INTRODUCTION

Preventive maintenance performed on a regular basis should reveal most potential problems before an instrument malfunctions. However, should troubleshooting be required, the following information is provided to facilitate location of a fault. In addition, the material presented in the "Theory of Operation" section and on foldout pages of this manual may be helpful while troubleshooting.

TROUBLESHOOTING AIDS

Diagnostic Firmware

The operating firmware in this instrument contains diagnostic routines that aid in locating malfunctions. When instrument power is applied, power-up tests are performed to verify proper operation of much of the instrument's circuitry. If a failure is detected, this information is passed on to the operator in the form of either a CRT readout or illuminated LED indicators. The failure information directs the operator to the failing block of circuitry. If the failure is such that the processor can still execute the diagnostic routines, the user can call up specific tests to further check the failing circuitry. The specific diagnostic routines are explained later in this section.

Schematic Diagrams

Complete schematic diagrams are located on foldout pages at the rear of this manual. Portions of circuitry mounted on each circuit board are enclosed by heavy black lines. The assembly number and name of the circuit are shown near either the top or the bottom edge of the diagram.

Functional blocks on schematic diagrams are also outlined with a wide black line. Components within the outlined area perform the function designated by the block label. The "Theory of Operation" uses these functional block names when describing circuit operation as an aid in cross-referencing between the theory and the schematic diagrams.

Component numbers and electrical values of components in this instrument are shown on the schematic diagrams. Important voltages and waveform reference numbers (enclosed in hexagonal-shaped boxes) are also shown on each diagram. Waveform illustrations are located adjacent to or on a sheet following their respective schematic diagram.

Circuit Board Illustrations

Circuit board component locator illustrations showing the physical location of each component are provided for use in conjunction with each schematic diagram. Each board illustration is found in the foldout section at the rear of this manual.

The locations of waveform test points are marked on the component locator illustrations with hexagonal outlined numbers corresponding to the waveform numbers on both the schematic diagram and the waveform illustrations.

Circuit Board Locations

The placement in the instrument of each circuit board is shown in a board locator illustration. This illustration is located on the foldout page along with the circuit board illustration.

Power Distribution Diagrams

Power Distribution diagrams (fig. FO-20 and FO-21, sheets 1 and 2) are provided to aid in troubleshooting power-supply problems.

Circuit Board Interconnection Diagram

A circuit board interconnection diagram (fig. FO-22, sheets 1 and 2) is provided at the rear of this manual, following the Power Distribution diagrams.

Grid Coordinate System

Each schematic diagram and circuit board illustration has a grid border along its left and top edges. A table located adjacent to each diagram lists the grid coordinates of each component shown on that diagram. To aid in physically locating components on the circuit board, this table also lists the grid coordinates of each component on the component locator illustration.

Near each component locator illustration is an alphanumeric listing of all components mounted on that board. The second column in each listing identifies the foldout figure number in which each component can be found. These component-locator tables are especially useful when more than one schematic diagram is associated with a particular circuit board.

Troubleshooting Flowcharts

The troubleshooting flowcharts contained in the foldout section at the rear of this manual are to be used as an aid in locating malfunctioning circuitry. To use the flowcharts, begin with the Preliminary Troubleshooting flowchart

(fig. FO-24). This chart will help identify problem areas and will direct you to other appropriate charts for further troubleshooting.

Some malfunctions, especially those involving multiple simultaneous failures, may require more elaborate troubleshooting approaches with references to circuit descriptions in the "Theory of Operation" section of this manual.

RESISTOR COLOR CODE. Resistors used in this instrument are carbon-film, composition, or precision metal-film types. They are usually color coded with the EIA color code; however, some metal-film type resistors may have the value printed on the body. The color code is interpreted starting with the stripe nearest to one end of the resistor. Composition resistors have four stripes; these represent two significant digits, a multiplier, and a tolerance value. Metal-film resistors have five stripes representing three significant digits, a multiplier, and a tolerance value.

CAPACITOR MARKINGS. Capacitance values of common disc capacitors and small electrolytic are marked on the side of the capacitor body. White ceramic capacitors are color coded in picofarads, using a modified EIA code.

Dipped tantalum capacitors are color coded in microfarads. The color dot indicates both the positive lead and the voltage rating. Since these capacitors are easily destroyed by reversed or excessive voltage, be careful to observe the polarity and voltage rating when replacing them.

DIODE COLOR CODE. The cathode end of each glass-encased diode is indicated by either a stripe, a series of stripes or a dot. For most diodes marked with a series of stripes, the color combination of the stripes identifies three digits of the Tektronix Part Number, using the resistor color-code system. The cathode and anode ends of a metal-encased diode may be identified by the diode symbol marked on its body.

Multipin Connectors

Multipin connector orientation is indexed by a triangle on the cable connector and a 1 or triangle on the circuit board. Slot numbers may be molded into the connector. When a connection is made to circuit board pins or header, ensure that the index on the connector is aligned with the index on the circuit board (see fig. 6-1). Cable connectors can be removed by inserting a screwdriver into the center slot of its header.

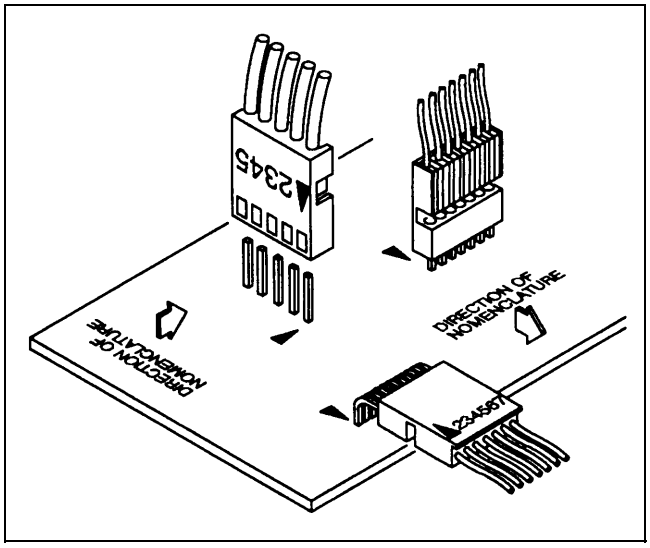


Figure 6-1. Multipin connector orientation.

TROUBLESHOOTING EQUIPMENT

The equipment listed in Table 4-1 of this manual, or equivalent equipment, may be useful when troubleshooting this instrument.

TROUBLESHOOTING TECHNIQUES

The following procedure is arranged in an order that enables checking simple trouble possibilities before requiring more extensive troubleshooting. The first two steps use diagnostic aids inherent in the instrument's operating firmware and will locate many circuit faults. The next four procedures are check steps that ensure proper control settings, connections, operation, and adjustment. If the trouble is not located by these checks, the remaining steps will aid in locating the defective component. When the defective component is located, replace it using the appropriate replacement procedure given under "Corrective Maintenance" in this section.

CAUTION

Before using any test equipment to make measurements on static-sensitive, current-sensitive, or voltage-sensitive components or assemblies, ensure that any voltage or current supplied by the test equipment does not exceed the limits of the component to be tested.

1. Power-up Tests

The instrument performs automatic verification of much of the instrument's circuitry when power is first applied.

The Kernel tests verify proper operation of the Microprocessor, the ROM, and the RAM. If all Kernel tests pass, a second level of checks, the Confidence tests, are performed. The Confidence tests, when passed, give the user a high degree of assurance that the instrument is functioning properly.

If a Kernel test or Confidence test fails, the area of failure is identified either by a message on the CRT (if the instrument is able to produce a display) or by an error code displayed on the front-panel LED indicators. If a failure occurs, refer to the "Diagnostic Routines" discussion later in this section for definitions of error messages and LED error codes.

Once a problem area has been identified, the associated troubleshooting procedure should be performed to further isolate the problem. The troubleshooting procedures are shown as flowcharts on foldout pages at the rear of this manual.

2. Diagnostic Test and Exerciser Routines

Each of the tests automatically performed at power-up, along with several other circuit exercising routines, may be individually selected by the user to further clarify the nature of a suspected failure, The desired test or exerciser is selected by scrolling through a menu of the available routines when under control of the Diagnostic Monitor. Entry into the Diagnostic Monitor and its uses are explained in the "Diagnostic Routines" discussion later in this section.

3. Check Control Settings

Incorrect control settings can give a false indication of instrument malfunction. If there is any question about the correct function or operation of any control, refer to either the "Operating Information" in Section 2 of this manual and to the Operators Manual.

4. Check Associated Equipment

Before proceeding, ensure that any equipment used with the instrument is operating correctly. Verify that input signals are properly connected and that the interconnecting cables are not defective. Check that the AC-power-source voltage to all equipment is correct.

5. Visual Check

Perform a visual inspection. This check may reveal broken connections or wires, damaged components, semiconductors not firmly mounted, damaged circuit boards, or other clues to the cause of an instrument malfunction.

6. Check Instrument Performance and Adjustment

Check the performance of either those circuits where trouble appears to exist or the entire instrument. The apparent trouble may be the result of misadjustment. Complete performance check and adjustment instructions are given in Sections 4 and 5 of this manual.

7. Isolate Trouble to a Circuit

To isolate problems to a particular area, use any symptoms noticed to help locate the trouble. Refer to the troubleshooting flowcharts at the rear of this manual as an aid in locating a faulty circuit.

When trouble symptoms appear in more than one circuit, first check the power supplies; then check the affected circuits by taking voltage and waveform readings. Check first for the correct output voltage of each individual supply. These voltages are measured between the power supply test points and ground (see fig. FO-15, sheets 2 and 3, FO-18, sheets 1 and 2, FO-19, sheets 1 and 2, and associated circuit board illustrations). If the power-supply voltages and ripple are within the listed ranges, the supply can be assumed to be working correctly. If they are outside the range, the supply may be either misadjusted or operating incorrectly.

The Low Voltage Power Supply levels are interdependent. All the low voltage supplies use the + 10 Preference for their reference levels. If more than one of the low voltage supplies appears defective, repair them in the following order: +10 VREF, +5 VDigital, +87V, +42V, +15 V, +5V Analog, -15 V, -8 V, and -5V.

A defective component elsewhere in the instrument can create the appearance of a power-supply problem and may also affect the operation of other circuits. Use the power supply troubleshooting charts to aid in locating the problem.

8. Check Circuit Board Interconnections

After the trouble has been isolated to a particular circuit, again check for loose or broken connections, improperly seated semiconductors, and heat-damaged components.

9. Check Voltages and Waveforms

Often the defective component can be located by checking circuit voltages or waveforms. Typical voltages are listed on the schematic diagrams. Waveforms indicated on the schematic diagrams by hexagonal-outlined numbers are shown adjacent to or following the diagrams. Waveform test points are shown on the component locator illustrations,

NOTE

Voltages and waveforms indicated on the schematic diagrams are nonabsolute and may vary slightly between instruments. To establish operating conditions similar to those used to obtain these readings, see the voltage and waveform setup conditions preceding the waveform illustrations.

Note the recommended test equipment, front-panel control settings, voltage and waveform conditions, and cable-connection instructions. Any special control settings required to obtain a given waveform are noted under the waveform illustration. Changes to the control settings from the initial setup, other than those noted, are not required.

10. Check Individual Components

The following procedures describe methods of checking individual components. Two-lead components that are soldered in place are most accurately checked by first disconnecting one end from the circuit board. This isolates the measurement from the effects of the surrounding circuitry.

WARNING

To avoid electric shock, always disconnect the instrument from the AC power source before removing or replacing components.

CAUTION

When checking semiconductors, observe the static-sensitivity precautions located at the beginning of this section.

TRANSISTORS. A good check of a transistor is actual performance under operating conditions. A transistor can most effectively be checked by substituting a known-good component. However, be sure that circuit conditions are not such that a replacement transistor might also be damaged. If substitute transistors are not available, use a dynamic-type transistor checker for testing. Static-type transistor checkers are not recommended, since they do not check operation under simulated operating conditions.

When troubleshooting transistors in the circuit with a voltmeter, measure both the emitter-to-base and emitter-to-collector voltages to determine whether they are consistent with normal circuit voltages. Voltages across a transistor may vary with the type of device and its circuit function.

Some of these voltages are predictable. The emitter-to-base voltage for a conducting silicon transistor will normally range from 0.6 V to 0.8 V. The emitter-to-collector voltage for a saturated transistor is about 0.2 V. Because these values are small, the best way to check them is by connecting a sensitive voltmeter across the junction rather than comparing two voltages taken with respect to ground. If the former method is used, both leads of the voltmeter must be isolated from ground.

If voltage values measured are less that those just given, either the device is shorted or no current is flowing in the external circuit. If values exceed the emitter-to-base values given, either the junction is reverse biased or the device is defective. Voltages exceeding those given for typical emitter-to-collector values could indicate either a nonsaturated device operating normally or a defective (open-circuited) transistor. If the device is conducting, voltage will be developed across the resistors in series with it; if open, no voltage will be developed across the resistors unless current is being supplied by a parallel path.

CAUTION

When checking emitter-to-base junctions, do not use an ohmmeter range that has a high internal current. High current may damage the transistor. Reverse biasing the emitter-to-base junction with a high current may degrade the current-transfer ratio (Beta) of the transistor.

A transistor emitter-to-base junction also can be checked for an open or shorted condition by measuring the resistance between terminals with an ohmmeter set to a range having a low internal source current, such as the R x 1 k Ω range. The junction resistance should be very high in one direction and much Iower when the meter leads are reversed.

When troubleshooting a field-effect transistor (FET), the voltage across its elements can rechecked in the same manner as previously described for other transistors. However, remember that in the normal depletion mode of operation, the gate-to-source junction is reverse biased; in the enhanced mode, the junction is forward biased.

INTEGRATED CIRCUITS. An integrated circuit (IC) can be checked with a voltmeter, test oscilloscope, or by direct substitution. A good understanding of circuit operation is essential when troubleshooting a circuit having IC components. Use care when checking voltages and waveforms around the IC so that adjacent leads are not

shorted together. An lC test clip provides a convenient means of clipping a test probe to an IC.

HYBRIDS. Hybrid components can best be checked by observing voltages and waveforms on the circuit board. Measurements should not be made on any hybrid component while out of the circuit as they may easily be damaged. Direct substitution is the best troubleshooting method when a hybrid failure is suspected. The CH 1 and CH 2 hybrids are matched, and should be replaced as a matched pair.

CAUTION

When checking a diode, do not use an ohmmeter scale that has a high internal current. High current may damage a diode. Checks on diodes can be performed in much the same manner as those on transistor emitter-to-base junctions. Do not check tunnel diodes or back diodes with an ohmmeter; use a dynamic tester, such as the TEKTRONIX 576 Curve Tracer.

DIODES. A diode can be checked for either an open or a shorted condition by measuring the resistance between terminals with an ohmmeter set to a range having a low internal source current, such as the R x 1 k Ω range. The diode resistance should be very high in one direction and much lower when the meter leads are reversed.

Silicon diodes should have 0.6 to 0.8 V across their junctions when conducting. Higher readings indicate that they are either reverse biased or defective, depending on polarity.

Light Emitting Diodes (LEDs) should have 1.5 to 2.2 V, depending on their current and color, across their junctions when conducting. Higher readings usually indicate the diodes are open, especially if they are not illuminated (ON).

RESISTORS. Check resistors with an ohmmeter. Refer to the “Replaceable Electrical Parts” list for the tolerances of resistors used in this instrument. A resistor normally does not require replacement unless its measured value varies widely from its specified value and tolerance.

INDUCTORS. Check for open inductors by checking continuity with an ohmmeter. Shorted or partially shorted inductors can usually be found by checking the waveform response when high-frequency signals are passed through the circuit.

CAPACITORS. A leaky or shorted capacitor can best be detected by checking resistance with an ohmmeter set to one of the highest ranges. Do not exceed the voltage rating of the capacitor. The resistance reading should be high after the capacitor is charged to the output voltage of the ohmmeter. An open capacitor can be detected with a capacitance meter or by checking whether the capacitor passes AC signals.

ATTENUATORS. The Attenuators are built as complete assemblies and should not be taken apart. If an Attenuator is suspected as having failed, direct substitution is the recommended troubleshooting method.

11. Repair and Adjust the Circuit

If any defective parts are located, follow the replacement procedures given under “Corrective Maintenance” in this section. After any electrical component has been replaced, the performance of that circuit and any other closely related circuit should rechecked. Since the power supplies affect all circuits, performance of the entire instrument should be checked if work has been done on the power supplies or if the power transformer has been replaced. Readjustment of the affected circuitry may be necessary. Refer to the “Performance Check” and “Adjustment Procedure, ” Sections 4 and 5 of this manual.

DIAGNOSTIC ROUTINES

The diagnostic routines contained in the instrument operating firmware consist of the various power-up tests that are automatically performed when power is first applied and several circuit exerciser routines. The test or exerciser routines are selected by scrolling through a menu of available routines when the firmware is under control of the Diagnostic Monitor. Monitor control is indicated by the message “DIAGNSTIC. PUSH A/B TRIG TO EXIT” displayed in the top CRT graticule division.

Entry into the monitor is automatic if a power-up test fails. The user may also force entry into the Diagnostic Monitor from the normal operating mode by holding in the front-panel Δ V and Δ t push buttons and then pressing the front-panel SLOPE push button. Exiting the monitor is accompli shed by pressing in the A/B TRIG push button, as instructed by the CRT readout display.

Depending on how the Diagnostic Monitor was entered (from normal mode or as a result of a power-up test failure), the first menu item displayed may vary; entry into the monitor from the normal mode begins at ALL TESTS while entry from power-up starts at the first failed test. Since, in a failure mode, the CRT readout may not be able to display the selected menu item, the VERT TRIGGER SOURCE indicator illuminates as a reference when ALL TESTS is selected. With the VERT TRIGGER SOURCE indicator illuminated, the user may scroll to the desired test or exerciser routine using the test order called out in Table 6-4 or Table 6-5 respectively. Whether the menu is displayed or not, scrolling is accomplished by pressing either the front-panel upper TRIGGER MODE switch to increment or the lower TRIGGER MODE switch to decrement the menu position by one.

Table 6-4
Sequence of Diagnostic Tests

Routine Type	Type Number	Lit LED	Routine Name	Error Code	Error Code Meaning
All Tests[1]	00	VERT	All	ZZ	The test number of the first failing test of the last ALL TESTS run. When looping, it shows the last failing test.
Test	00		Kernel Test	ZZ	The device number. See Table 6-6 for kernel test failure codes.[4]
Test	01	CH 1	Interrupt Request	01	Interrupt request is missing or has wrong period.
Test	02	CH 2	Switch Stuck	01 02 03 04 05 14 12 13 14 15 25 31 32 33 34 35 41 42 43 44 45 51 52 53 54 55 61 62 63 64 65[2]	Trigger COUPLING lower Trigger COUPLING upper MEASURE/HELP CH 1 Coupling lower CH 1 Coupling upper CH 4 VOLTS/DIV CH 3 VOLTS/DIV INIT @ 50% CH 2 Coupling lower CH 2 Coupling upper CH 2 INVERT CH 1 VERTICAL MODE CH 2 VERTICAL MODE ADD VERTICAL MODE CH 3 VERTICAL MODE CH 4 VERTICAL MODE STEP/AUTO SAVE HELP RECALL HELP CHOP/ALT VERTICAL MODE 20 MHz BW LIMIT X10 MAG TRACK/INDEP Δt (delta time) ΔV (delta volts) Trigger SLOPE Trigger SOURCE lower Trigger SOURCE upper Trigger MODE lower Trigger MODE upper A/B TRIG select
Test	03	CH 3	Readout Board	01 02	Shift register failure.[3] (-Trigger LED). Readout RAM failure.[3] (+Trigger LED).
Test	04	CH 4	Calibration Data	X1 X2 1X	Parity error on read (bit 0 set). Out of limits (bit 1 set). Bad checksum (bit 4 set).
Test	05	ADD	Main Board	01 X2 X4 2X 4X	AUTO LVL failed to trigger. Negative level not negative enough. Negative level too negative. Positive level not positive enough. Positive level too positive.
Test	06	INVERT	RAM Battery	01 02	Battery voltage too low. Battery voltage too high.

[1]VERT TRIG SOURCE indicator lights when in ALL TESTS as a visual reference in the event a CRT display can not be produced.
[2]If the A/B TRIG switch is stuck during power-up, the oscilloscope will branch to "normal" operation after a short delay. The associated error message will only be visible momentarily if the CRT is warmed-up.
[3]Readout Board error codes are also displayed on the + and - Trigger SLOPE LEDs.
[4]This test is not user-selectable but is run automatically during cycle mode.

Table 6-5

Sequence of Exerciser Routines

Routine Type	Type Number	ON LED	Routine Function
Exerciser	01	CH 1	Display Potentiometers and Switches.
Exerciser	02	CH 2	Examine Calibration Data in RAM.
Exerciser	03	CH 3	Clears Cycle Errors.
Exerciser	04	CH 4	Display ROM Headers.
Exerciser	05	ADD	Display Operating Time and Power Cycle Count.
Exerciser	06	INVERT	Select Setup to Use at Power-Up.
Exerciser	07	CHOP	Enable/Disable Setup SAVE and Sequence Definition.
Exerciser	08	BW LIMIT	Initialize Setups.

Routine Control

When the desired Test or Exerciser has been selected, the operator has two types of control that maybe exercised over the routine: START/STOP and LOOP.

Starting or stopping the execution of the selected routine is controlled by the front-panel TRIGGER COUPLING switches. Pressing the upper switch starts the routine; pressing the lower switch stops it.

All of the test routines may be set to LOOP mode (continuously repeated) by pressing the front-panel upper TRIGGER SOURCE switch while the routine is selected but not executing. The LOOP feature will cause the routine to be continuously repeated once started until stopped when the operator presses the lower TRIGGER Coupling switch. Once the routine is stopped, the LOOP feature may be disabled by pressing the lower TRIGGER SOURCE switch.

While a Test or Exerciser routine is executing, the Diagnostic Monitor Control message on the top line of the CRT display will be cleared as an indication that a routine is running. When test routines are looping, the message “LOOP” is displayed in the bottom division of the CRT graticule.

Display Format

The Tests and Exercisers routines display information about the routine type and number, as well as any test results, at the bottom of the CRT display. Thereabout line is formatted as follows:

TYPE XY STATUS ZZ LOOP <ABCC>

The information is defined as follows:

“TYPE” refers to routine type: All Tests (ALL), Test (TEST), Exerciser (EXER), or Calibration (CAL).

“X” is zero.

“Y” is the TYPE number of the routine (see the ‘Type Number” column of Table 6-4).

“STATUS” shows the results of the Last time a selected test routine ran: either PASS or FAIL. This space is blank for exerciser and calibration routines. When the diagnostics are called up from normal operating mode, the space will be blank until the selected test is executed.

"ZZ" is a two-digit error code identifying the nature of the failure in a failed test (see the “Error Code” column of Table 6-4).

“LOOP” indicates when a selected test is set to the LOOP mode.

“<ABCC>” is the CYCLE mode failure indicator. CYCLE mode, when entered by removing the NO CAL/CAL jumper (P501) before turning the instrument on, causes the instrument to continuously LOOP through the Power Up Diagnostic Tests. if a failure occurs, the cycle-failure data, identifying the first failure encountered, is written to RAM. Thereafter, at each power-up, the Diagnostic Monitor is automatically entered, and the failure data is displayed. The failure data must be cleared from the RAM location to eliminate the CYCLE mode failure display (see CYCLE ERROR CLEAR Exerciser 03). The information displayed is an abbreviated version of the previous items:

"A" is the same code as for “X”.

“B” is the test Type Number where the failure occurred (the same codes as for “Y”).

“CC” is the error code for the test (the same codes as for “ZZ”).

Kernel Tests

The Kernel tests are those tests which, when failed, are considered “fatal” to the operation of the microprocessor. Failure of a Kernel test will cause the front-panel TRIG’D indicator to flash, and certain of the other front-panel indicators will be illuminated with an error code. The code points to the area of failure as indicated in Table 6-6. Tables 6-7 and 6-8 are used to determine the device numbers used in Table 6-6.

Table 6-6
Kernel Test Failure Codes

Failure Codes		Failing Device
Option	Device	
0	0	Control Board RAM
0	1	ROM U2160
0	2	ROM U2260
0	3	Reset Control Circuitry

Table 6-7
Front Panel LED Option Code

Option Code					Option Name
CH 1 LED (bit 3)	CH 2 LED (bit 2)	CH 3 LED (bit 1)	CH 4 LED (bit 0)	Option Number (in Hex)	
OFF	OFF	OFF	OFF	0	Basic instrument

Table 6-8
Front Panel LED Device Codes

READY LED (bit 2)	Device Code		Device Number
	+ LED (bit 1)	- LED (bit 0)	
OFF	OFF	OFF	0
OFF	OFF	ON	1
OFF	ON	OFF	2
OFF	ON	ON	3

Even if a Kernel test fails, the operator may try to go to normal oscilloscope operation by pressing the A/B TRIG select push button. Depending on the exact nature of the failure, the instrument may or may not be functional.

Kernel tests are automatically executed at power-up. The Kernel tests are divided into RAM tests and ROM tests as follows:

RAM TEST. This test is done with a complementary data pattern starting at the highest RAM address available and continuing to the lowest. The process reads and saves the original data, and then writes a pattern of 01010101's (55 Hex) at the highest RAM memory address. The data is then read back to see if it is still 55 (Hex). Next a complementary pattern of 10101010 (AA Hex) is written to the same address. Then the address content is read back and tested to see if it is still AA (Hex). After the memory is checked, the original data is written back into the memory address. RAM TEST then checks the next lower address. The testing continues until all of RAM is checked.

Test checks: RAM address decoding, RAM address lines, RAM data lines, RAM memory, and Data Bus Buffers.

ROM TEST. The ROM test performs three checks on each of the system read-only memories.

Data Bus Drive – Two locations containing complementary data patterns are read.

Test checks: Data bus lines and the Data Bus Driver.

Correct Part-A byte in the ROM being checked is compared to the most-significant byte of the addressed ROM block (starting address of where the ROM should be installed).

Test checks: ROM address decoding and proper installation of ROM components.

Checksum–A sixteen bit, spiral-add checksum is calculated and compared to a two-byte value stored in ROM being checked.

Test checks: ROM contents, ROM addressing, ROM data lines, and the Data Bus Driver.

Confidence Tests

The Confidence tests provide checks for much of the remaining circuitry to ensure that instrument operation is correct. Confidence tests are performed automatically at power-up after the Kernel is determined to be functional or initiated by the operator from the Diagnostic Monitor.

A failure of any Confidence test during power-up will pass control to the Diagnostic Monitor; this permits the test results to be examined. Descriptions of the Confidence tests follow.

KERNEL TEST (Test 00). This test is not user selectable, but runs automatically when cycle mode is entered at power up. During cycle mode the microprocessor forces a self-reset by setting the PWR DOWN bit (bit #5) of U2310. If this does not force a reset condition, an error is recorded. Any kernel failures detected during cycle mode are also recorded.

INTERRUPT REQUEST (Test 01). Ten consecutive interrupt cycles are checked to ensure that succeeding interrupts occur not more than 4.5 ms apart (5600 "E" cycles).

Test checks: Interrupt Timer circuitry.

SWITCH STUCK (Test 02). The front-panel, momentary-contact switches are scanned, checking for a closed switch. At power-up, the test runs immediately.

By holding one of the momentary switches in a closed position when power is first applied, this test will fail, and

the Diagnostic Monitor will be entered. When the test is started from the Diagnostic Monitor, a one-half second delay is incorporated to allow the COUPLING (test start) switch to return to its normal (open) position. Table 6-4, above, defines the error codes that may be encountered when a switch is detected as closed.

NOTE

When the user presses the lower TRIGGER COUPLING switch to stop this test, an error code may be generated. This is normal and does not indicate an actual failure.

Test checks: Momentary switches, row scanning circuitry, and column scanning circuitry.

READOUT BOARD (Test 03). This two-part test checks the interface to the Readout board from the microprocessor and the character RAM circuits.

Processor Interface Test–The microprocessor loads the three, eight-bit shift registers with an alternating bit pattern that is then shifted back to the processor for comparison.

Test checks: Data Registers, data strobes (clocks), and the data input and output lines.

RAM Test - A “1” is rotated through each byte of the Readout RAM, one bit at a time. Each time an additional bit is rotated into the byte, the byte is loaded into the processor interface and clocked back to the processor for comparison. The byte is then restored to its original content, and each successive byte is tested in the same manner.

Test checks: Readout RAM addressing, Readout RAM data lines, and RAM read/write capability.

CALIBRATION DATA (Test 04). Three checks are performed on the RAM to verify its contents.

Checksum Test – The contents of Iocations containing calibration constants are checksummed using a spiral -add technique. The result is compared to the stored checksum generated at the time of calibration.

Test checks: RAM addressing and RAM contents.

Parity Test – As each of the calibration constants is read for the Checksum test above, the parity of each 14-bitword is checked.

Test checks: CALIBRATION DATA integrity and RAM CALIBRATION DATA retention.

Limit Test – Checks for valid calibration data.

Test checks: The contents of locations containing calibration data are compared to their stored limits.

MAIN BOARD (Test 05). The AUTO LVL triggering feature (a routine stored in firmware) is operated to detect the peaks of a Line Trigger signal. Detected peaks are compared to expected values to verify operation (and calibration) of interrelated signal processing circuits.

Test checks: Line Trigger source, the A Trigger generation circuitry, and Control DAC U2101 (located on the Control board, diagram 2).

BATTERY VOLTS (Test 06). The battery voltage is read and compared to stored constants. If the voltage is above or below the stored limits the appropriate error code is displayed.

Test checks: Battery voltage, voltage follower operational amplifier U2620C, and CR2770.

Exerciser Routines

The Exerciser routines (see Table 6-5, above) allow the operator to set and examine various bytes of control data used in determining instrument function.

POTS AND SWITCHES (Exerciser 01). This routine displays the values that the microprocessor detects as the various digitized pots and switches are activated. The left half of the top line of the display appears after turning a pot. The right half of the top line of the CRT display appears after pressing a switch. The top line of the CRT display has the following format:

AA BB CC DEEE FF GG HI JJ KL

The format is defined as follows:

“AA” is the code of the most-recently-activated potentiometer (see Table 6-9 for definition of pot codes).

“BB” is the current value (in hexadecimal) of pot AA. See Table 6-9 for the approximate range of codes for the CCW (counter clockwise) and CW (clockwise) potentiometer rotations.

“CC” is the previous value (in hexadecimal) of pot AA.

“D” is the DAC Multiplexer code used to select pot AA (see Table 6-9).

"EEE" is the 12-bit DAC value (in hexadecimal) associated with pot AA. See Table 6-9 for the approximate range of codes for the CCW (counterclockwise) and CW (clockwise) potentiometer rotations.

"FF" is the code of the previously-activated potentiometer (see Table 6-9).

Table 6-9
Potentiometer Codes and Values (Exerciser 01)

Rotation Values				Potentiometer	
CCW		CW		AA	Name
BB	DEEE	BB	DEEE	Code	
FF	6FFF	00	6000	01	HOLDOFF
FF	3FFF	00	3000	02	TRIGGER LEVEL
00	1000	FF	1FFF	03	SEC/DIV VAR
FF	5FFF	00	5000	04	Horizontal POSITION
00	0000	FF	3FFF	05	Δ (A section [1])
00	0000	FF	3FFF	06	Δ (B section [1])
00	0000	FF	3FFF	07	Δ REF OR DLY POS (A section [1])
00	0000	FF	3FFF	08	Δ REF OR DLY POS (B section [1])
FF	07FF	00	0000	09	CH 1 VOLTS/DIV VAR
FF	27FF	00	2000	0A	CH 2 VOLTS/DIV VAR
FF	0FFF	00	0000	11	CH 1 Vertical POSITION
FF	1FFF	00	1000	12	CH 2 Vertical POSITION
FF	27FF	00	2000	13	CH 3 Vertical POSITION
FF	37FF	00	3000	14	CH 4 Vertical POSITION
FF	4FFF	00	4800	15	TRACE SEP
FF	5FFF	00	5FFF[2]	16	READOUT INTENSITY
80	6800	FF	6FFF	17	Trace INTENSITY

[1]The Δ REF OR DLY POS and Δ controls are both 180° offset pairs that continuously rotate. Displayed BB values jump and the AA code changes when instrument software switches between the A and B sections. The D code position shows the two most-significant bits of the 14-bit DAC output (in hexadecimal), effectively generating 5.5 turn potentiometer values.
[2]The potentiometer midpoint value is 5800, and the intensity is off (MIN). Maximum intensity is at both the CCW and CW positions.

"GG" is the row code of the most-recently-activated switch (see Table 6-10 for definition of row codes).

"H" is the switch-position code: 0 for open; C for closed.

"I" is the column code of the most-recently-activated switch (see Table 6-10).

"JJ" is the row for for the previously-activated switch.

"K" is the switch-position code: 0 for open; C for closed.

"L" is the column code for the previously-activated switch.

NOTE

For all momentary switches (except A/B TRIG) only the closed position will be shown in the switch-position code locations (H and K). The A/B TRIG switch has both the open and the closed positions shown. (MIN). Maximum intensity is at both the CCW and CW positions.

CALIBRATION RAM EXAMINE (Exerciser 02). This routine allows the operator to examine the contents of 256 decimal locations, 00 (Hex) through FF (Hex), in RAM. When entered, the Exerciser displays the contents of RAM location 00 (Hex) on the top line of the CRT display. One hundred and seventy calibration constants reside between addresses 01 (Hex) and AA (Hex). Calibration constants residing between 01 (Hex) and 6E (Hex) should have odd parity as explained below. The remaining locations may be of either parity. The readout display line has the following format:

AA DDDD P

The format is defined as follows:

"AA" is the eight-bit address in hexadecimal notation.

"DDDD" is the 14-bit word stored at that location (13 bits of data and one parity bit).

"P" is a parity indicator for the data word: X indicates even parity; blank is odd parity.

Pushing the upperor lower TRIGGER MODE switch will increment or decrement the RAM address by 16 (10 Hex) respectively. Similarly, pushing the upper or lowerTRIGGER SOURCE switch will increment or decrement the address by 1 respectively.

CYCLE ERROR CLEAR (Exerciser 03). This routine provides a way for the operator to clear the cycle-failure data written to the RAM when a CYCLE mode failure occurs. Interpretation of the cycle failure data is explained in the "Display Format" description provided earlier in this section. Until the data is cleared, each time the instrument is powered up, the Diagnostic Monitor is entered.

Clearing the RAM location (and the CYCLE ERROR message) is done by scrolling to EXER 03 (CLEAR CYCLE ERROR) and pressing the following switches in sequence:

TRIGGER COUPLING upper (starts exerciser),
TRIGGER SOURCE lower,
TRIGGER MODE lower, then
TRIGGER COUPLING lower (exits the exerciser).

Table 6-10

Potentiometers and Switches Column and Row Code Definitions (Exerciser 01)

Row Code (GG)	Column Code (I)	Definition	Row Code (GG)	Column Code (I)	Definition
0	0	Trig COUPLING Down	5	0	READOUT Scale Factors
0	1	Trig COUPLING Up	5	1	Unused
0	2	MEASURE/HELP	5	2	Unused
0	3	CH 1 Coupling Down	5	3	Unused
0	4	CH 1 Coupling Up	5	4	Unused
1	0	CH 4 VOLTS/DIV	6	0	CH 1 VERT MODE
1	1	CH 3 VOLTS/DIV	6	1	CH 2 VERT MODE
1	2	INIT @ 50%	6	2	ADD VERT MODE
1	3	CH 2 Coupling Down	6	3	CH 3 VERT MODE
1	4	CH 2 Coupling Up	6	4	CH 4 VERT MODE
2	0	CH 1 VOLTS/DIV LSB	7	0	STEP/AUTO
2	1	CH 1 VOLTS/DIV Bit 2	7	1	SAVE HELP
2	2	CH 1 VOLTS/DIV Bit 3	7	2	RECALL HELP
2	3	CH 1 VOLTS DIV MSB	7	3	CHOP/ALT
2	4	CH 2 INVERT	7	4	BW LIMIT
3	0	CH 2 VOLTS/DIV LSB	8	0	X10 MAG
3	1	CH 2 VOLTS/DIV Bit 2	8	1	TRACKING INDEP
3	2	CH 2 VOLTS/DIV Bit 3	8	2	Δt
3	3	CH 2 VOLTS/DIV MSB	8	3	ΔV
3	4	B ENDS A	8	4	Trig SLOPE
4	0	SEC/DIV LSB	9	0	Trig SOURCE Down
4	1	SEC/DIV Bit 2	9	1	Trig SOURCE Up
4	2	SEC/DIV Bit 3	9	2	Trig MODE Down
4	3	SEC/DIV MSB	9	3	Trig MODE Up
4	4	A/B SWP Select	9	4	A/B TRIG Select

When the CYCLE ERROR CLEAR routine is successfully executed, the cycle failure data will disappear from the display.

DISPLAY ROM HEADERS (Exerciser 04). This routine displays the Standard Tektronix ROM Header of each system ROM on the top line of the CRT display. Thereabout line has the following format:

CCCC PPPP SS AAAA

The definition of the format is as follows:

"CCCC" is a two-byte hexadecimal checksum.

"PPPP" is the four middle digits of the ROM part number.

"SS" is the suffix of the ROM part number (version number).

"AAAA" is the starting address of the ROM (address where the ROM should be installed).

Pressing the upper TRIGGER COUPLING switch increments the routine to the next ROM Header; pressing the lower TRIGGER COUPLING switch exits the routine.

HRS ON and OFF/ON CYCLES (Exerciser 05). This routine displays the Operating Time and Power Cycle Count.

> HRS ON nnnn OFF/ON CYCLES mmmm
nnnn = Accumulated Number of Hours with Power Applied
mmmm = Accumulated Number of Power Cycles

POWER-UP SETUP (Exerciser 06). This routine selects the setup to use at power-up.

> POWER UP TO POWER DOWN SETUP
Instrument will power up with the setup in effect at power down.

> POWER UP TO SETUP 1
Instrument will power up with the setup stored as setup 1.

SAVE ENABLE (Exerciser 07). This routine will Enable/Disable setup SAVE and sequence definition.

> ENABLE SAVE AND SEQUENCE-CHANGE
All Save and Sequence functions are enabled.

> DISABLE SAVE AND SEQUENCE-CHANGE
All Save and Sequence-definition functions are disabled.

> ENABLE SAVE 1-8, NO SEQ-CHANGE
Only setups 1 through 8 can be changed. BEGIN/STEP/END attributes cannot be changed for any setup.

SETUP INIT (Exerciser 08). This routine destroys all saved setups.

> COUPLING UP CLEARS SAVED SETUPS
Press upper Trigger COUPLING to clear all saved setups.
Press lower Trigger COUPLING to retain saved setups.

CONTROLLER LATCHES EXERCISER. This routine is not user selectable, but it runs automatically when the Diagnostic Monitor is waiting for a key activation.

The routine first sets latches U2301 and U2201 (fig. FO-4, sheet 2). It then pulses the B SWP CLK line (pin 13 of U2660, fig. FO-3, sheet 1), as a scope trigger, and rotates a "0'' through 15 of the 16 latched bits. Bit 16 is not set since it would reset Interrupt Timer U2640 (fig. FO-3, sheet 1) and upset processor interrupt timing. By externally triggering a test oscilloscope on the B SWP CLK signal line and observing the shifted timing relationships of the latched signals, proper operation of the DAC latches may be verified.

NOP KERNEL EXERCISER. This exerciser is not a firmware routine, but rather a forced hardware condition. It is best suited for troubleshooting an inoperative Control Board, as it exercises only the microprocessor address bus (see Table 6-11) and the associated Address Decode circuitry. By moving Jumper P503 (fig. FO-2, sheet 1) to the Diagnostic position, Data Bus Buffers U2350 and U2450 are disabled, and the microprocessor is forced into a NOP (no operation) loop. This causes the address on the address bus to be continuously incremented for exercising the Address Decode circuitry. Troubleshooting of kernel addressing with an oscilloscope or logic analyzer is then possible.

Table 6-11
NOP (No Operation) Test Data

U2140 Pin #	Signal Name	1 Cycle Time	Frequency
9	A0	3.199 µs	312.5 kHz
10	A1	6.39 µs	156.3 kHz
11	A2	12.79 µs	78.15 kHz
12	A3	25.59 µs	39.075 kHz
13	A4	51.18 µs	19.53 kHz
14	A5	102.4 µs	9.769 kHz
15	A6	204.7 µs	4.88 kHz
16	A7	409.4 µs	2.44 kHz
17	A8	818.9 µs	1.22 kHz
18	A9	1638 µs	610.6 Hz
19	A10	3275 µs	305.3 Hz
20	A11	6.55 ms	152.6 Hz
22	A12	13.1 ms	76.3 Hz
23	A13	26.2 ms	38.16 Hz
24	A14	52.4 ms	19.08 Hz
25	A15	104.8 ms	9.54 Hz

CORRECTIVE MAINTENANCE

INTRODUCTION

Corrective maintenance consists of component replacement and instrument repair. This part of the manual describes special techniques and procedures required to replace components in this instrument. If it is necessary to ship your instrument to a Tektronix Service Center for repair or service, refer to the "Repackaging for Shipment" instructions in Section 2.

MAINTENANCE PRECAUTIONS

To reduce the possibility of personal injury or instrument damage, observe the following precautions.

1. Disconnect the instrument from the AC power source before removing or installing components.
2. Verify that the line-rectifier filter capacitors are discharged prior to performing any servicing.
3. Use care not to interconnect instrument grounds which may beat different potentials (cross grounding).
4. When soldering on circuit boards or small insulated wires, use only a 15-watt, pencil-type soldering iron.

WARNING

The battery used in this device may present a fire or chemical burn hazard if mistreated. Do not recharge, rapidly discharge, disassemble, heat above 100°C(212°F), or incinerate.

Replace battery with part number listed in replaceable parts section only. Use of another battery may present a risk of fire or explosion.

Dispose of used battery promptly. Small quantities of *used batteries may be disposed of in normal refuse. Keep away from children. Do not disassemble and do not dispose of in fire. See page E at the beginning of this manual for additional information.*

5. Lithium batteries may be hazardous if mistreated. Follow all safety precautions when working with the batteries.

MAINTENANCE AIDS

The maintenance aids listed in Table 6-12 include items required for performing most of the maintenance procedures in this instrument. Equivalent products may be substituted for the examples given, provided their characteristics are similar.

INTERCONNECTIONS

Interconnections in this instrument are made with pins soldered onto the circuit boards. Several types of mating connectors are used for the interconnecting pins. The following information provides the replacement procedures for the various type connectors.

End-Lead Pin Connectors

Pin connectors used to connect the wires to the interconnect pins are factory assembled. They consist of machine-inserted pin connectors mounted in plastic holders. If the connectors are faulty, the entire wire assembly should be replaced.

Multipin Connectors

When pin connectors are grouped together and mounted in a plastic holder, they are removed, reinstalled, or replaced as a unit. If any individual wire or connector in the assembly is faulty, the entire cable assembly should be replaced. Multipin connector orientation is indexed by a triangle on the cable connector and a 1 or triangle on the circuit board. Slot numbers may be molded into the connector. Be sure these index marks are aligned with each other when the multi pin connector is reinstalled.

TRANSISTORS, INTEGRATED CIRCUITS, AND HYBRID CIRCUITS

Transistors, integrated circuits, and hybrid circuits should not be replaced unless they are actually defective. If removed from their sockets or unsoldered from the circuit board during routine maintenance, return them to their original board locations. Unnecessary replacement or transposing of semiconductor devices may affect the adjustment of the instrument. When a semiconductor is replaced, check the performance of any circuit that maybe affected.

Any replacement component should be of the original type or a direct replacement. Bend transistor leads to fit their circuit board holes, and cut the leads to the same length as the original component.

Table 6-12
Maintenance Aids

Description	Specification	Usage
1. Soldering Iron	15 to 25 W.	General Soldering and unsoldering.
2. Flat-bit Screwdriver	3-inch shaft, 3/32 inch bit.	Assembly and disassembly.
3. Torx Screwdriver	Tip sizes: #T9, #T10, #T15, #T20. Handles: 8-1/2 inch, 3-1/2 inch.	Assembly and disassembly.
4. Nutdrivers	3/16 inch, 1/4 inch and 5/16 inch.	Assembly and disassembly.
5. Open-end Wrenches	1/4 inch, 5/16 inch, 7/16 inch.	Assembly and disassembly.
6. Allen Wrenches	0.050 inch, 1/16 inch.	Assembly and disassembly.
7. Long-nose Pliers		Component removal and replacement.
8. Diagonal Cutters		Component removal and replacement.
9. Vacuum Solder Extractor	No static charge retention.	Unsoldering static sensitive devices and components on multilayer boards.
10. Pin-replacement kit		Replace circuit board connector pins.
11. IC-Removal Tool		Removing DIP IC packages.
12. Isopropyl Alcohol	See Appendix B.	Cleaning attenuator and front panel assemblies.

The heat-sink-mounted power supply transistors are insulated from the heat sink with a heat-transferring insulator pad. Reinstall the insulator pads and bushings when replacing these transistors. Do not use any type of heat-transferring compound on the insulator pads.

CAUTION

After replacing a power transistor, check that the collector is not shorted to the heat sink before applying power to the instrument.

To remove socketed dual-in-line packaged (DIP) integrated circuits, pull slowly and evenly on both ends of the device. Avoid disengaging one end of the integrated circuit from the socket before the other, since this may damage the pins.

To remove a soldered DIP IC when it is going to be replaced, clip all the leads of the device and remove the leads from the circuit board one at a time. If the device must be removed intact for possible reinstallation, do not heat adjacent conductors consecutively. Apply heat to pins at alternate sides and ends of the IC as solder is removed. Allow a moment for the circuit board to cool before proceeding to the next pin.

Hybrid circuits and heatsinks are removed as a unit by removing the mounting nuts at the four corners of the heatsink/housing. A firm downward pressure at the center of the heatsink will aid in installation/removal of the nuts. The hybrid circuit substrate is bonded to the heatsink/housing casting. Attempting to separate the hybrid device from its heatsink will damage the device.

SOLDERING TECHNIQUES

The reliability and accuracy of this instrument can be maintained only if proper soldering techniques are used to remove or replace parts. General soldering techniques, which apply to maintenance of any precision electronic equipment, should be used when working on this instrument.

WARNING

To avoid an electric-shock hazard, observe the following precautions before attempting any soldering: turn the instrument off, disconnect it from the AC power source, and verify that the line-rectifier filter capacitors have discharged (see label on the primary power shield). If, due to a component failure, the capacitors are not discharging, it maybe necessary to discharge them. Use a 1-k 5-watt resistor and discharge the capacitors from point to point through the access holes in the primary power shield.

Use rosin-core wire solder containing 63% tin and 37% lead. Contact your local Tektronix Field Office or representative to obtain the names of approved solder types.

When soldering on circuits boards or small insulated wires, use only a 15-watt, pencil-type soldering iron. A higher wattage soldering iron may cause etched circuit conductors to separate from the board base material and melt the insulation on small wires. Always keep the soldering-iron tip properly tinned to ensure best heat transfer from the iron tip to the solder joint. Apply only enough solder to make a firm joint. After soldering, clean the area around the solder connection with isopropyl alcohol and allow it to air dry.

Circuit boards in this instrument may have as many as four conductive layers. Conductive paths between the top and bottom board layers may connect to one or more inner layers. lf any inner-layer conductive path becomes broken due to poor soldering practices, the board becomes unusable and must be replaced. Damage of this nature can void the instrument warranty.

Only an experienced maintenance person, proficient in the use of vacuum-type resoldering equipment should attempt repair of any circuit board in this instrument.

Resoldering parts from multi layer circuit boards is especially critical. Many integrated circuits are static sensitive and may be damaged by solder extractors that generate static charges. Perform work involving static-sensitive devices only at a static-free work station while wearing a grounded antistatic wrist strap. Use only an antistatic vacuum solder extractor approved by a Tektronix Service Center.

Attempts to unsolder, remove, and resolder leads from the component side of a circuit board may cause damage to the reverse side of the circuit board.

The following techniques should be used to replace a component on a circuit board:

1. Touch the vacuum desoldering tool to the lead at the solder connection. Never place the iron directly on the board; doing so may damage the board.

NOTE

Some components are difficult to remove from the circuit board due to a bend placed in the component leads during machine insertion. To make removal of machine-inserted components easier, straighten the component leads on the reverse side of the circuit board.

2. When removing a multipin component, especially an IC, do not heat adjacent pins consecutively. Apply heat to the pins at alternate sides and ends of the lC as solder is removed. Allow a moment for the circuit board to cool before proceeding to the next pin.

Excessive *heat can cause the etched circuit conductors to separate from the circuit board. Never allow the solder extractor tip to remain at one place on the board for more than three seconds. Solder wick, spring-actuated or squeeze-bulb solder suckers, and heat blocks (for resoldering multipin components) must not be used. Damage caused by poor soldering techniques can void the instrument warranty.*

3. Bend the leads of the replacement component to fit the holes in the circuit board. If the component is replaced while the board is installed in the instrument, cut the leads so they protrude only a small amount through the reverse side of the circuit board. Excess lead length may cause shorting to other conductive parts.

4. Insert the leads into the holes of the board so that the replacement component is positioned the same as the original component. Most components should be firmly seated against the circuit board.

5. Touch the soldering iron to the connection and apply enough solder to make a firm solder joint. Do not move the component while the solder hardens.

6. Cut off any excess lead protruding through the circuit board (if not clipped to the correct length in step 3).

7. Clean the area around the solder connection with isopropyl alcohol. Be careful not to remove any of the printed information from the circuit board.

8. When soldering to the ceramic CRT-termination network, a slightly larger soldering iron can be used. It is recommended that a solder containing about 3% silver be used when soldering to the ceramic material to avoid destroying the bond. The bond can be broken by repeated use of ordinary tin-lead solder or by the application of too much heat; however, occasional use of ordinary solder will not break the bond, provided excessive heat is not applied when making the connection.

REMOVAL AND REPLACEMENT INSTRUCTIONS

WARNING

To avoid electric shock, disconnect the instrument from the AC power source before removing or replacing any component or assembly.

WARNING

Removal of the cabinet and other external panels leaves the CRT exposed for possible damage. All procedures in these instructions require careful attention to avoid damage to the CRT which could cause it to implode. An implosion creates high speed glass fragments. Wear protective clothing and use safety shields as required. See "WARNING" in "CRT REMOVAL later in this section. "

The exploded view drawing in the Unit, Direct Support, and General Support Repair Parts and special Tools List for Oscilloscope OS-288/G may be helpful during the removal and reinstallation of individual components or subassemblies. Circuit boards and component locations are illustrated on foldout pages at the rear of this manual.

Cabinet Removal

Removal of the instrument wrap-around cabinet is accomplished by the following steps:

1. Unplug the power cord from the AC power source.
2. Unplug the power cord from the rear-panel connector.
3. Install the front cover, place the cabinet carrying handle against the bottom of the cabinet, and set the instrument face down on a flat surface.
4. Unwrap the power cord and remove it.
5. Remove the four screws in the rear feet.
6. Remove the two screws from the top-center and bottom-center of the rear cover.
7. Lift the rear cover and power cord away from the instrument, leaving the rear feet attached.

WARNING

Dangerous potentials exist at several points throughout this instrument. If it is operated with the cabinet removed, do not touch exposed connections or components. Some transistors may have elevated case voltages. Disconnect the AC power source from the instrument and verify that the line-rectifier filter capacitors have discharged before cleaning the instrument or replacing parts (see label on the primary power shield).

8. Slide the cabinet off the instrument.

To reinstall the wrap-around cabinet, perform the reverse of the preceding instructions. Ensure that the cabinet fits properly into the EMI gasket grooves in the front frame and rear panel.

WARNING

The line-rectifier filter capacitors normally retain a charge for a short period (approximately 15 to 20 seconds) after the instruments turned off and can remain charged for a longer period if a bleeder-resistor or power-supply problem occurs. Before beginning any cleaning or work on the internal circuitry of the oscilloscope, disconnect the AC power source from the instrument and verify that the capacitors have discharged to 24 V or less. Measurement is made at the three points indicated on the plastic primary input shield at the rear of the instrument (after the Top-Cover Plate is removed). If the capacitors retain charges of greater than 24 V for more than 20 seconds, discharge them using a 1-k 5-watt resistor connected point-to-point across the capacitors through the access holes. Ensure that the capacitors are discharged before starting to troubleshoot.

Vertical Bracket (Top-Cover Plate) Removal

To remove the Vertical Bracket, perform the following steps:

1. Remove the instrument cabinet as described in that procedure.
2. Set the instrument, bottom down, on a flat surface.
3. Remove two top securing screws at the front edge of the Vertical Bracket.
4. Remove the two screws in the right-center of the Vertical Bracket.
5. Remove the top securing screw at the left-rear of the Vertical Bracket.
6. Remove the securing screw from the chassis rear plate.
7. Remove the securing screw from the left side of the chassis.
8. Lift the Vertical Bracket up and away from the instrument.

To reinstall the Vertical Bracket, perform the reverse of the preceding instructions. Be certain to align the circuit board at the right rear with the two black grommets installed in the Vertical Bracket. Align the two black plastic pins on the power supply assembly with their mating holes before installing and tightening screws.

A5 Control Circuit Board Removal

Removal of the Control board is accomplished by the following steps:

1. Remove the instrument wrap-around cabinet as described in the Cabinet Removal procedure.
2. Place the instrument on its left side on a flat surface.
3. Disconnect the two ribbon-cable and one flex-circuit connectors (P251, P651, and P652) from the Control board (see fig. 6-2).
4. Disconnect the two ribbon-cable connectors (P511 and P512) from the Main board.
5. Remove the five mounting screws securing the Control board to the chassis, one at each corner of the board and one at the center.
6. Lift the Control board away from the chassis.

To reinstall the Control board, perform the reverse of the preceding instructions.

Fan Removal

To remove the Fan:

1. Desolder the wires from the feed-through capacitor (C10) and ground lug, noting color code for reassembly.
2. Remove the Fan retainer screw, located above the Fan.
3. Remove the Fan retainer and Fan.

To reinstall the Fan, perform the reverse of the above instructions. Align the holes in the Fan flange with the pins on the rear plate before tightening the screw.

Power Supply Assembly Removal

Removal of the Power Supply assembly is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.
2. Remove the Vertical Bracket as described in the Vertical Bracket Removal procedure.
3. Remove the Fan as described in the Fan Removal procedure.
4. Desolder the Fan power cable connecting the power supply to the feed-through capacitor (C10) on the inside of the rear plate.
5. Remove the two screws in the rear plate holding the black plastic primary circuit shield (located inside the chassis) and remove the shield.
6. Remove the two screws holding the rear of the Power Supply assembly to the rear plate.
7. Remove the three screws securing the power-transistor heatsink to the chassis.
8. Disconnect the power supply ribbon-cable connector (P251) from the Control board and feed the cable through the notch in the Control board and slot in the chassis.
9. Disconnect the two cables (P121 and P122) connecting the Main board to the Power Supply from the side of the Power Supply assembly.
10. Disconnect the four primary power connectors (P204, P205, P206, and P207) at the rear of the Power Supply assembly. Note their orientation for reinstallation.
11. Lift the Power Supply assembly from the instrument.

To reinstall the Power Supply assembly, perform the reverse of the preceding instructions.

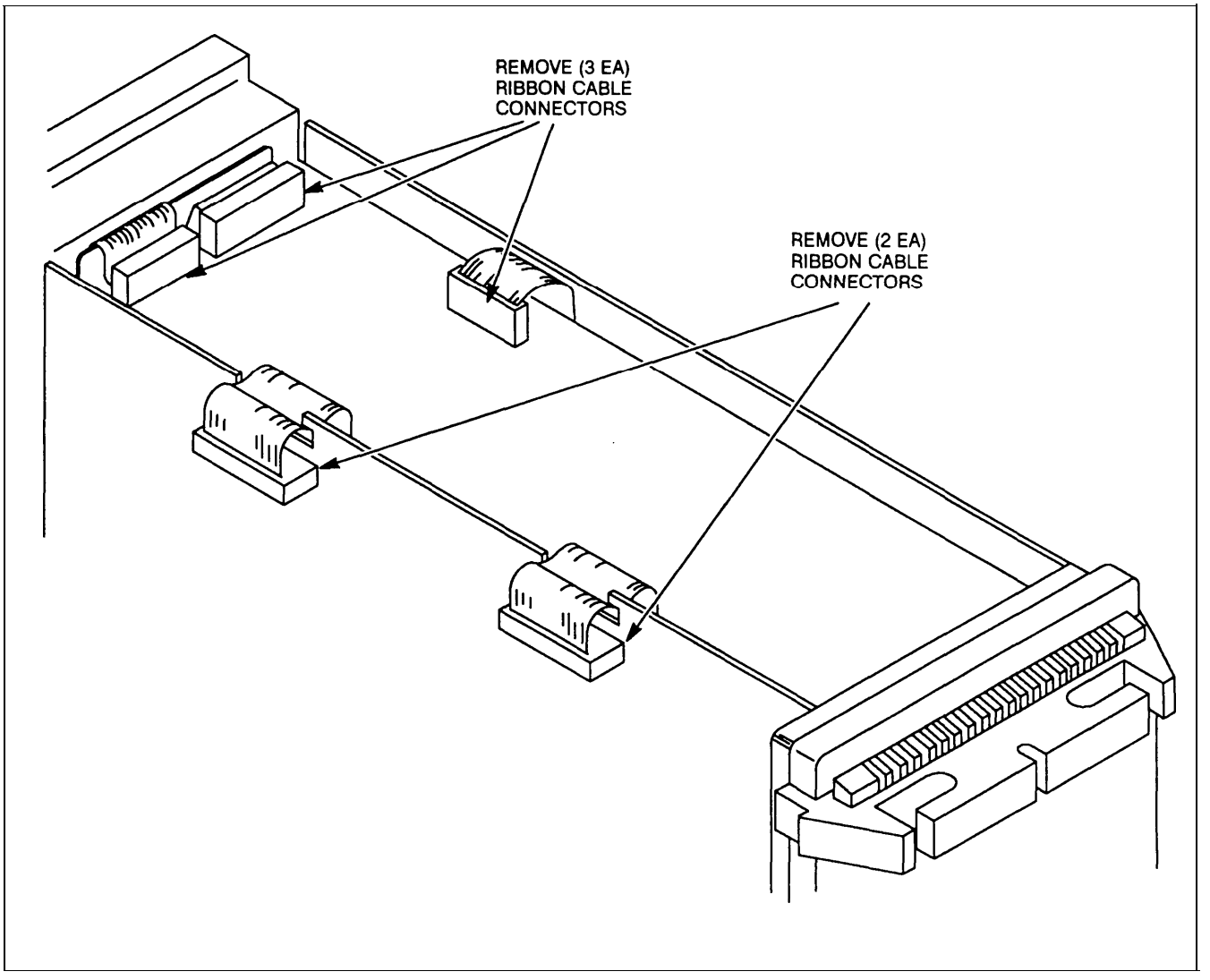


Figure 6-2. Ribbon cable removal.

The following procedure describes the further disassembly of the Power Supply assembly circuit boards once the assembly is removed from the instrument.

INVERTER BOARD AND REGULATOR BOARD SEPARATION. To separate the Inverter and Regulator boards, perform the following steps:

1. Remove the rear-corner securing screw from the Regulator board and the two screws at the front edge of the board.

2. Unplug the four pin-disconnect terminals (J231, J232, J233, and J234) while disabling the locking leg on the connector retainer.

3. Separate the two circuit boards by removing the four black plastic spacers from the top and bottom edges of the assembly.

To rejoin the Inverter and Regulator boards, perform the reverse of the preceding steps.

A9 High-Voltage Circuit Board Removal

Removal of the High-Voltage board is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Remove the Vertical Bracket as described in the Fan Removal procedure.

WARNING

The CRT anode lead may retain a high-voltage charge after the instrument is turned off. To avoid electrical shock, ground the CRT anode lead to the chassis after disconnecting the plug. Reconnect and disconnect the anode-lead plug several times, grounding the anode lead to chassis ground each time it is disconnected to fully dissipate the charge.

3. Unplug the CRT anode lead and discharge it to chassis ground.

4. Remove the high-voltage lead from the retainer cap.

5. Unplug the two leads connecting the CRT to the ceramic CRT terminator. Use long-nose pliers to pull the connectors straight away from the CRT neck pins. Avoid putting pressure on the metal-to-glass seal at the base of the pins.

6. Disconnect the single conductor connector from the ceramic CRT terminator.

7. Remove the two nuts retaining the ceramic CRT terminator to the chassis and remove the terminator.

8. Remove the nut retaining the high-voltage lead clamp to the chassis and remove the clamp.

9. Remove three screws on the rear CRT cover. Remove the cover.

10. Remove the five screws securing the High-Voltage Shield and remove the shield.

11. Remove the high-voltage lead from the u-shaped grommet in the rear plate.

12 Unplug the CRT socket by gently prying evenly on both sides of the socket until the socket can be disengaged from the CRT pins. Do not apply side pressure on the socket.

13. Disconnect the connectors (P901, P902, P903, and P904) from the High-Voltage board. Note connector orientation for reinstallation.

14. Remove the four spacer posts securing the High-Voltage Board to the chassis.

15, Carefully tilt the top of the High Voltage board out far enough to clear the chassis side flange while pulling the board up gently to disengage the High-Voltage board pin connectors from the Main board.

16. Lift the board from the chassis while carefully feeding the CRT socket, cabling, and high-voltage lead through the rear plate slot.

To reinstall the High-Voltage Board, perform the reverse of the preceding instructions.

A4 Readout Circuit Board Removal

Removal of the Readout board is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Remove the Vertical bracket as described in the Vertical Bracket Removal procedure.

3. Place the instrument, left side down, on a flat surface.

4. Disconnect the Readout board ribbon-cable connector (P411) from the Main board.

5. With the instrument still on its side, pull the Readout board out of its plastic board mounts. Remove it from the instrument while guiding the ribbon cable and connector through the slots in the Main board and chassis.

To reinstall the Readout board, perform the reverse of the preceding steps.

A6A1 Front Panel Circuit Board Assembly Removal

Removal of the Front Panel circuit board assembly is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Set the instrument back into its rear cover with the CRT facing up. Using a small-bladed screwdriver, gently pry up on the top cover trim strip to release it from the top edge of the front decorative trim ring.

3. Remove the four screws from the top edge of the front decorative trim ring.

4. Remove the four screws and the two plastic feet from the bottom edge of the front decorative trim ring.

5. Using firm outward pressure, pull the knobs from the four controls directly below the CRT (INTENSITY, FOCUS, READOUT INTENSITY, and SCALE ILLUM).

6. Slide off the front decorative trim ring. The clear implosion shield is retained by the trim ring. Use care to avoid dislodging the shield accidentally from its recess in the CRT frame.

7. Disconnect the ribbon-cable connector (P652) and the flex-circuit connector (P651) from the front of the Control board. Feed the flex-circuit connector through the slot carefully while sliding the front panel gently outward.

8. Pull out the Front Panel circuit board assembly.

The following steps describe the further disassembly of the Front Panel circuit board assembly once it is removed from the instrument.

ASSEMBLY SEPARATION. Separation of the potentiometer holder module from the Front Panel Board is accomplished by the following steps:

1. Using a 1/16-inch Allen wrench, loosen the set screws in the CH 1 VOLTS/DIV VAR, CH 2 VOLTS/DIV VAR, and A and B SEC/DIV VAR knobs and remove the three knobs from their control shafts.

2. Using a 1/16-inch Allen wrench, loosen the six set screws in the CH 1 and CH 2 VOLTS/DIV knobs, and the SEC/DIV knob. Remove the three knobs from their control shafts.

3. Using firm outward pressure, pull off the remaining knobs. Note the locations of the knobs with indicator bars for reference during reinstallation.

4. On the rear of the assembly, remove the four screws securing the black variable resistor holder assembly.

5. Separate and slide out the above assembly with attached variable-control shafts. Avoid stressing the shafts to the side while sliding the assembly out.

FRONT PANEL REMOVAL. Use the following procedure to further disassemble the Front Panel circuit board assembly.

1. Separate the Front Panel circuit board and potentiometer holder module as described above (if not already done).

2. Lift up the circuit board carefully to avoid dislodging any of the square push buttons from their switches.

3. Lift off the black plastic switch guide and mounting ring.

To reassemble and reinstall the Front Panel assembly, perform the reverse of the preceding instructions. When reinstalling the circuit board, align all push buttons and LEDs with the black plastic switch guides before installing and tightening the screws.

A11 Channel 1 and A12 Channel 2 Attenuator Assembly Removal

Removal of either the Channel 1 or Channe1 2 Attenuator assembly is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Remove the Front Panel assembly as described in the Front Panel Circuit Board Assembly Removal procedure.

3. Remove the two screws holding the Attenuator support bar and remove the bar.

4. For each Attenuator, remove the two screws holding the Attenuator to the front subpanel and the two screws holding it to the Main board (through access holes in the front panel compartment of the chassis).

5. Disconnect the associated multipin connector (either P10 for Channel 1 or P11 for Channel 2) from the Main board.

6. Remove the two screws holding the preamplifier shield and ground clip and remove them.

7. Desolder the two Attenuator output leads and the compensation capacitor lead.

8. Unplug the Attenuator by gently pulling the assembly straight up and away from the Main board.

To reinstall are moved Attenuator assembly, perform the reverse of the preceding steps.

A1 Main Board Removal

Removal of the Main Board is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Remove the Vertical Bracket as described in the Vertical Bracket procedure.

3. Remove the Front Panel circuit board assembly as described in the Front Panel Circuit Board Assembly Removal procedure.

4. Disconnect the two power-supply multipin connectors (P121 and P122) from the side of the Power Supply assembly.

5. Disconnect the three ribbon-cable connectors (P411, P511, and P512) from the bottom of the Main board.

See "WARNING" under CRT removal instructions before proceeding.

6. Disconnect the vertical and horizontal deflection leads from the neck pins of the CRT. Access is via holes in the Main board. Use long-nose pliers to disconnect the pins by gently pulling straight upon the connectors. Avoid putting side pressure on the metal-to-glass seal of the CRT neck pins.

7. Desolder the rear-panel BNC connector leads from the BNCS. Unplug the CH 2 OUT cable (P105) from the Main board, and remove its cable retaining clamp.

8. Disconnect the flex-circuit connector (P120) for the CRT controls from the Main board.

9. Disconnect the two-conductor connector (P181) for the Scale Illumination board near the ASTIG and the SCALE ILLUM controls.

10. Remove the STEP/AUTO jack (J 12) retaining nut from the rear plate after resoldering its wire from the Main board using correct vacuum resoldering techniques. Remove the jack.

11. Turn the long extension shaft (see fig. 6-3) CCW and unsnap it from the pivot bracket at the rear middle of the Main board, sliding it out of the bracket sideways.

CAUTION

Do not pull on the power switch push button or it will be damaged.

12. Remove the power switch push button mounting screw shown in Figure 6-3 (item A). Separate the long extension shaft from the short extension shaft at point B by inserting a small screwdriver tip in the slot while pulling out on the bracket at point C. Remove the screw (item D) and slide the long extension shaft out the rear of the front frame.

13. Remove the two screws holding the Attenuator support bar and remove the bar.

14. Remove the six screws holding the Attenuator assemblies and the CH3 and CH4 input connectors to the front subpanel.

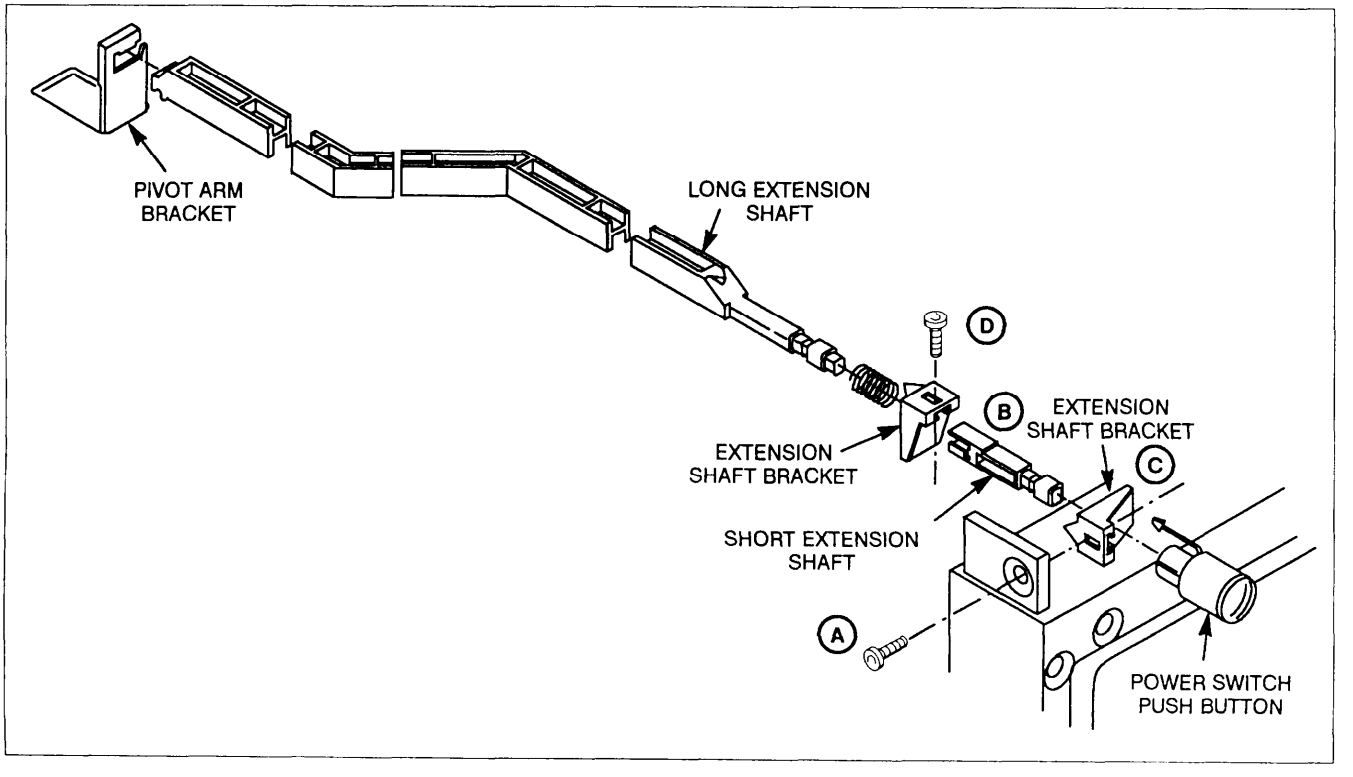


Figure 6-3. Power Switch Push Button Disassembly.

15. Remove the Main board mounting screws (ten screws securing the Main board to the chassis).

16. Lift the rear of the Main board away from the chassis to unplug J191 and separate the Main board from the High Voltage board. When the plug pins are completely disengaged and the rear of the board clears the rear frame, slide the Main board rearward out of the front subpanel. Lift the Main board (with attached Delay Line) clear of the instrument while working the power supply cables through the slot in the chassis.

To reinstall the Main board, perform the reverse of the preceding instructions.

A8 Scale Illumination Circuit Board Removal

See "WARNING" under CRT Removal before proceeding.

Removal of the Scale-illumination circuit board is accomplished by the following steps:

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Remove the front decorative trim ring as described in the Front Panel circuit board assembly removal procedure.

3. Remove the eight screws in the CRT frame. Remove frame and black plastic gasket. Note the difference in length of the screws for reinstallation.

4. Remove the clear plastic light reflector from the Scale-illumination circuit board and the black plastic mounting spacer.

5. Disconnect the scale-illumination multipin connector (P181) from the Main board.

6. Remove the Scale-illumination circuit board by lifting it away from the front subpanel while working the wires and connector through the slot in the subpanel.

To reinstall the Scale-lllumirtation circuit board, perform the reverse of the preceding instructions.

CRT Removal

WARNING

Use care when handling a CRT. Breakage of the CRT may cause high-speed scattering of glass fragments (implosion). Protective clothing and safety glasses (preferably a full-face shield) should be worn. Avoid striking the CRT on any object which may cause it to crack or implode. When storing a CRT place it in a protective carton or set it face down on a smooth surface in a protected location. When stored face down, it should be placed on a soft, nonabrasive surface to prevent the CRT face plate from being scratched.

1. Remove the instrument cabinet as described in the Cabinet Removal procedure.

2. Remove the Vertical Bracket as described in the Vertical Bracket Removal procedure.

3. Remove three screws on the rear CRT cover. Remove the cover.

4. Unplug the CRT socket by gently prying the socket evenly on both sides until the pins can be disengaged. Do not apply side pressure on the socket.

WARNING

The CRT anode lead and the output terminal of the High-Voltage Multiplier can retain a high-voltage charge after the instrument is turned off. To avoid electrical shock, ground both the CRT anode lead and the high-voltage lead to the main instrument chassis. Repeat the grounding process several times to fully *dissipate the charge.*

5. Disconnect the CRT anode lead connector and discharge it to chassis ground.

6. Using long-nosed pliers, disconnect the horizontal and vertical deflection leads from the bottom of the CRT. Pull straight out on these connectors to prevent strain on the metal-to-glass seal. (Access to the connectors is through holes in the Main board.)

7. Using long-nosed pliers, disconnect the vertical termination leads from the top of the CRT. Also disconnect the CRT shield ground lead from the top of the CRT.

8. Remove the five screws securing the High-Voltage Shield and remove the shield. If optional assembly cables are mounted in the shield's groove, it will be necessary to loosen these cables from the option board enough to slip the cover out underneath them.

9. Disconnect the connector P903 from the front of the High-Voltage board. Note connector orientation for reinstallation.

10. Remove the front decorative trim ring as described in the A6-Front-Panel circuit board assembly removal instructions.

11. Remove the eight retaining screws from the CRT-mounting bezel at the front of the CRT. Note the difference in length of the screws for reinstallation. Push in on the four longer (outer) screws to disengage the CRT retainers.

12. Remove the CRT frame and black plastic gasket from the front of the instrument, working the frame gently from side to side to free it from the CRT (if required).

13. Slide the CRT out of the instrument while feeding the CRT leads through their respective holes in the CRT shield and front subpanel.

NOTE

Once the CRT is removed, it should be stored in such a manner as to protect it from impact. If stored face down, it should be placed on a soft, nonabrasive surface to prevent the CRT face plate from being scratched. To reinstall the CRT perform the reverse of the preceding instructions. Be certain the two pins on the lower edge of the CRT frame align with the hole and slot in the front subpanel of the chassis. Tighten the shorter screws to 10 in-lb of torque before tightening any of the longer screws. Then tighten the longer screws in sequence:

2 1
4 3

Screw number one aligns the CRT. On the third time through the sequence, tighten each screw to 10 in-lb of torque.

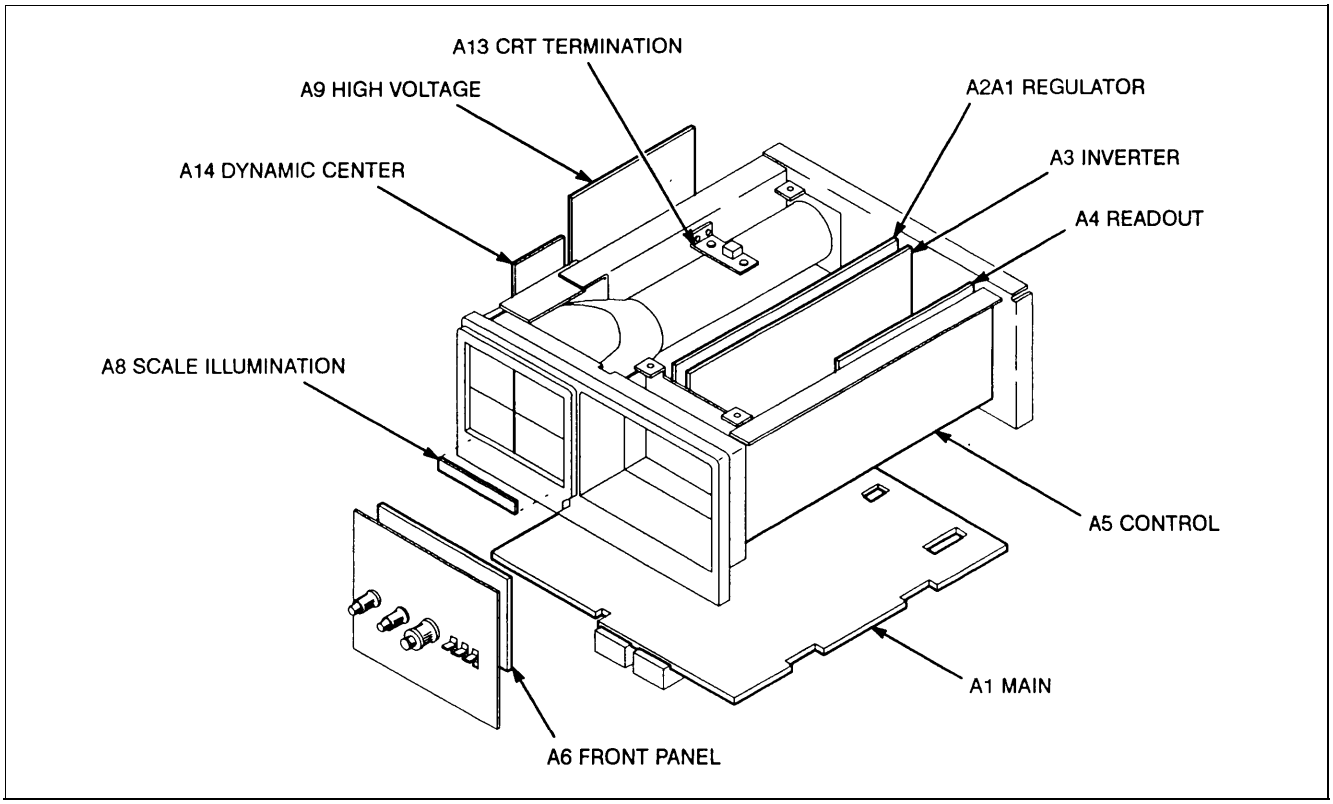


Figure 6-4. Circuit Board Locations

Appendix A
REFERENCES

SCOPE

This appendix lists all forms, field manuals, technical manuals, and miscellaneous publications referenced in this manual.

FORMS

Equipment inspection and Maintenance Worksheet . . . . . DA Form 2404
Product Quality Deficiency Report. . . . . Form SF 368
Recommended Changes to Equipment Technical Manuals . . . . . DA Form 2028-2
Recommended Changes to Publications and Blank Forms . . . . . DA Form 2028
Report of Discrepancy (ROD). . . . . Form SF 364
Transportation Discrepancy Report . . . . . Form SF 361

TECHNICAL MANUALS

Operator's and Unit Maintenance Manual for Oscilloscope OS-288/G . . . . . TM 11-6625-3234-12
Procedures for Destruction of Electronics Materiel to Prevent Enemy Use (Electronics Command) . . . . . TM 750-244-2
Unit, Direct Support, and General Support Repair Parts and Special Tools List for Oscilloscope OS-288/G . . . . . TM 11-6625-3234-24P

MISCELLANEOUS

Abbreviations for Use on Drawings, Specifications Standards and in Technical Documents MIL-STD-12
Common Table of Allowances . . . . . CTA 50-970
Consolidated lndex of Army Publications and Blank Forms . . . . . DA Pam 25-30
First Aid for Soldiers . . . . . FM 21-11
Safety Precautions for Maintenance of Electrical/Electronic Equipment . . . . . TB 385-4
The Army Maintenance Management System (TAMMS) . . . . . DA Pam 738-750

Appendix B
EXPENDABLE SUPPLIES AND MATERIALS LIST

INTRODUCTION

SCOPE

This appendix lists expendable supplies and materials you will need to operate and maintain the Oscilloscope OS-288/G. These items are authorized to you by CTA 50-970, Expendable Items (except Medical, Class V, Repair Parts, and Heraldic Items).

EXPLANATION OF COLUMNS

a. *Column (1) - Item Number,* This number is assigned to the entry in the listing and is referenced in the narrative instructions to identify the material.

b. *Column (2) - Level.* This column identifies the lowest level of maintenance that requires the listed item. Enter as applicable:

C – Operator/Crew
O – Unit Maintenance
F – Direct Support Maintenance
H – General Support Maintenance

c. *Column (3) - National Stock Number.* This is the National Stock Number assigned to the item; use it to request or requisition the item.

d. *Column (4) - Description.* Indicates the Federal item name and, if required, a description to identify the item. The last line for each item indicates the Federal Supply Code for Manufacturer (FSCM) (in parentheses) followed by the part number.

e. *Column (5) - Unit of Measure (U/M).* Indicates the measure used in performing the actual maintenance function. This measure is expressed by a two-character alphabetical abbreviation (e.g., ea, in, pr). If the unit of measure differs from the unit of issue, requisition the lowest unit of issue that will satisfy your requirements.

EXPENDABLE SUPPLIES AND MATERIALS

(1) Item No.	(2) Level	(3) National Stock Number	(4) Description	(5) U/M
1	C	8305-00-267-3015	Cloth, Cheesecloth, Cotton, Lintless, CCC-C-440, Type II, Class 2 (81349)	yd
2	C	7930-00-068-1669	Detergent, General Purpose	oz
3	C	6810-00-753-4993	Alcohol, Isopropyl, 8 oz. can, MIL-A-10428, Grade A (81349)	oz
4	H		Solder, Rosin Core, 63% Tin, 37% Lead	lb
5	H		Solder, 3% Silver	lb
6	H		Applicator, Cotton Tipped, 6 inch	ea

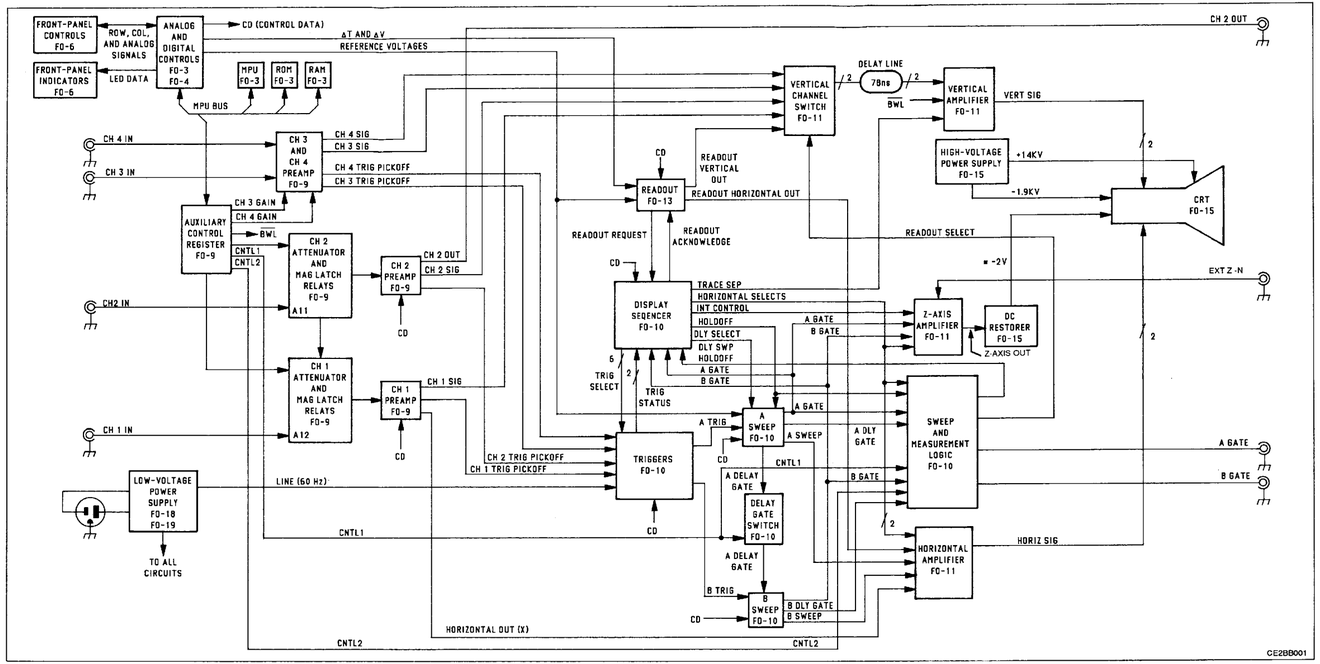
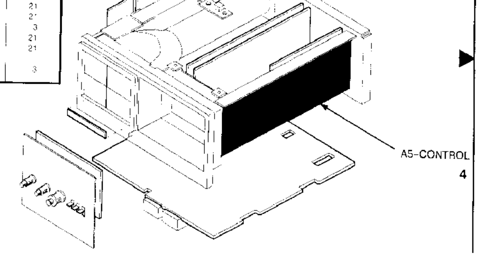


Figure FO-1. Block Diagram.
FP-1/(FP-2 blank)

A5 Control Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
BT2570	3	C2732	4	R2172	3	R2431	4	R2632	4	U2301	4
		C2733	4	R2201	4	R2432	4	R2640	4	U2301	21
C2010	4	C2740	21	R2202	4	R2433	4	R2641	4	U2310	3
C2011	21			R2203	4	R2434	4	R2642	4	U2310	4
C2101	21	CR2070	3	R2204	4	R2440	3	R2643	4	U2350	3
C2110	4	CR2071	3	R2205	4	R2441	3	R2644	4	U2401	4
C2111	21	CR2170	3	R2206	4	R2442	3	R2645	4	U2401	21
C2112	21	CR2230	4	R2220	4	R2443	3	R2660	3	U2410	4
C2113	21	CR2231	4	R2230	4	R2444	3	R2661	3	U2410	21
C2160	21	CR2232	4	R2231	4	R2470	3	R2701	4	U2420	4
C2220	21	CR2233	4	R2232	4	R2471	3	R2702	4	U2420	21
C2221	21	CR2370	3	R2241	3	R2500	3	R2703	4	U2430	4
C2230	4	CR2371	3	R2242	3	R2501	4	R2704	4	U2430	21
C2240	3	CR2420	4	R2244	3	R2502	4	R2705	4	U2440	3
C2320	21	CR2610	4	R2250	3	R2503	4	R2706	4	U2440	21
C2321	4	CR2620	4	R2251	3	R2504	4	R2707	4	U2450	3
C2322	4	CR2621	4	R2301	4	R2505	4	R2708	4	U2460	3
C2330	4	CR2622	4	R2302	4	R2506	4	R2709	4	U2501	4
C2331	21	CR2630	4	R2303	4	R2510	4	R2710	4	U2501	21
C2332	4	CR2631	4	R2304	4	R2511	4	R2711	4	U2510	4
C2333	4	CR2640	4	R2305	4	R2512	4	R2712	4	U2510	21
C2340	3	CR2770	3	R2306	4	R2513	4	R2720	4	U2520	4
C2350	3			R2320	4	R2520	4	R2721	4	U2520	21
C2351	3	J251	3	R2330	4	R2521	4	R2730	4	U2521	4
C2360	3	J251	21	R2331	4	R2522	4	R2731	4	U2521	21
C2420	4	J500	3	R2332	4	R2523	4	R2732	4	U2530	4
C2421	4	J651	4	R2333	4	R2524	4	R2733	4	U2530	21
C2422	4	J652	3	R2334	4	R2530	4	R2734	4	U2540	3
C2430	4	J652	4	R2340	4	R2531	4	R2735	4	U2540	21
C2431	4	J652	21	R2341	4	R2532	4	R2740	4	U2550	3
C2432	4			R2342	3	R2533	4	R2741	4	U2550	21
C2450	21	P501	4	R2343	3	R2534	4	R2742	3	U2601	4
C2470	3	P503	3	R2344	3	R2535	4	R2770	3	U2601	21
C2501	21			R2345	3	R2536	4			U2620	4
C2510	21	Q2070	3	R2346	3	R2537	4	TP2070	21	U2620	21
C2511	4	Q2170	3	R2370	3	R2540	4	TP2420	4	U2630	4
C2520	21	Q2270	3	R2401	4	R2541	3	TP2421	4	U2630	21
C2521	4	Q2320	4	R2402	4	R2542	3	TP2701	21	U2640	3
C2530	21			R2403	4	R2543	3			U2640	21
C2550	3	R2001	4	R2404	4	R2544	3	U2101	4	U2650	3
C2551	3	R2002	4	R2405	4	R2545	3	U2101	21	U2650	21
C2562	21	R2004	4	R2406	4	R2560	3	U2140	3	U2660	3
C2601	21	R2005	4	R2407	4	R2601	4	U2140	21	U2660	21
C2610	21	R2006	4	R2408	4	R2602	4	U2160	3		
C2620	21	R2007	4	R2409	4	R2603	4	U2160	21	VR2420	4
C2621	4	R2010	4	R2410	4	R2604	4	U2201	4		
C2622	4	R2011	4	R2411	4	R2610	4	U2201	21	W511	4
C2630	4	R2012	4	R2412	4	R2611	4	U2210	4	W511	21
C2631	4	R2013	4	R2413	4	R2612	4	U2210	21	W512	3
C2632	21	R2070	3	R2414	4	R2613	4	U2220	4	W512	4
C2640	3	R2101	4	R2415	4	R2620	4	U2220	21	W512	21
C2650	21	R2102	4	R2416	4	R2621	4	U2240	3	W2070	21
C2660	21	R2103	4	R2417	4	R2622	4	U2240	21	W2540	3
C2720	4	R2104	4	R2420	4	R2623	4	U2250	3	W2610	21
C2721	4	R2110	4	R2421	4	R2624	4	U2250	21	W2701	21
C2730	4	R2170	3	R2422	4	R2630	4	U2260	3		
C2731	4	R2171	3	R2430	4	R2631	4	U2260	21	Y2540	3



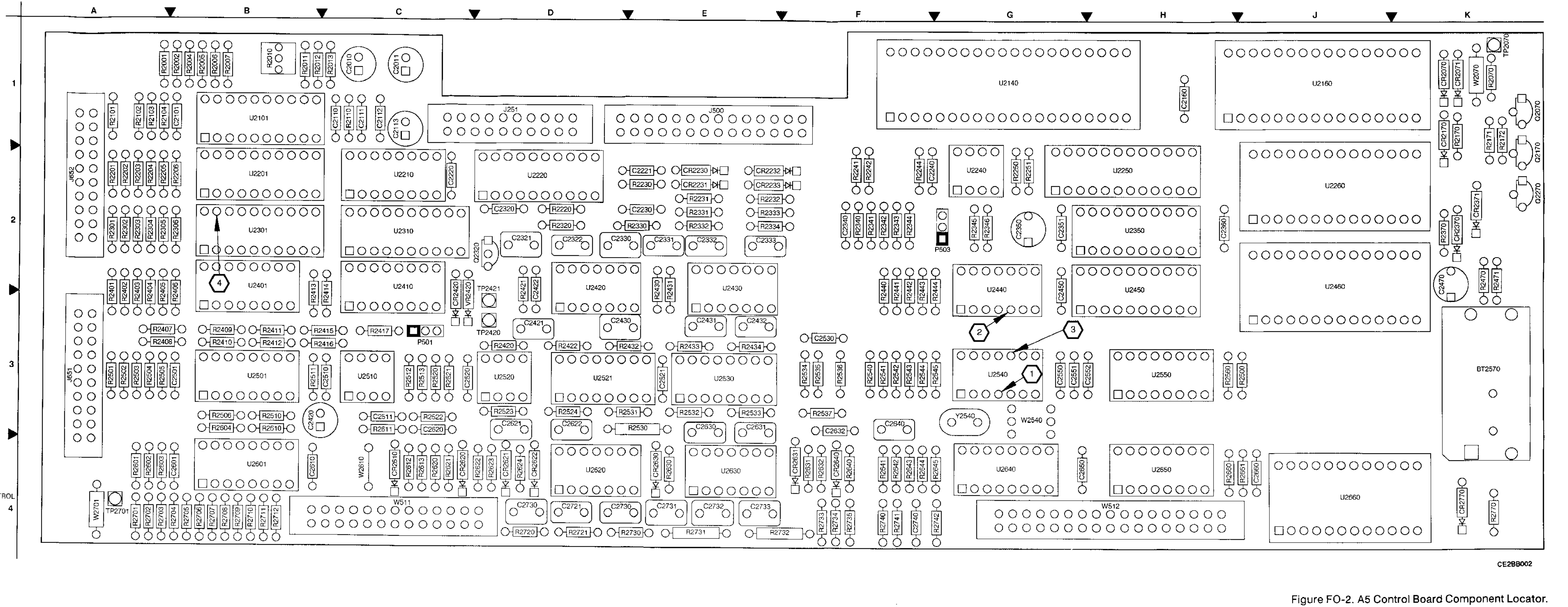


Figure FO-2. A5 Control Board Component Locator.

Location of the Components Shown in this Figure and in Figure FO-2.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A5 CONTROL BOARD[1]											
BT2570	8M	3K	P503	4C	2G	R2443	7D	2G	U2440A	2D	2G
C2240	4C	2G	Q2070	7F	1K	R2444	2C	2G	U2440B	3G	2G
C2340	7C	2F	Q2170	7G	2K	R2470	8G	2K	U2450	5C	2H
C2350	3C	2H	Q2270	7G	2K	R2471	9G	2L	U2450	7E	2H
C2351	7C	2H	R2070	8F	1K	R2500	1N	3J	U2460	8L	3J
C2360	8L	2J	R2170	7F	1K	R2541	2B	3G	U2540A	2B	3G
C2470	8M	3K	R2171	7G	1K	R2542	2B	3G	U2540B	2C	3G
C2550	1B	3H	R2172	7F	1K	R2543	2B	3G	U2540C	10D	3G
C2551	1B	3H	R2241	8D	2F	R2544	2C	3G	U2540D	10D	3G
C2540	2B	3G	R2242	8D	2F	R2545	1B	3G	U2540E	2H	3G
CR2070	8F	1K	R2244	3D	2G	R2560	3H	3J	U2540F	4G	3G
CR2071	7F	1K	R2250	1D	2G	R2660	2M	4J	U2550	4K	3H
CR2170	8F	1K	R2251	3D	2H	R2661	3M	4J	U2640	2J	4G
CR2370	8M	2K	R2342	3D	2G	R2742	3M	4G	U2650C	4B	4H
CR2371	8M	2K	R2343	8D	2G	R2770	8M	4K	U2650	2M	4H
CR2770	8M	4K	R2344	8D	2G	U2140	2E	1G	U2660	3L	4J
J251	3A	1C	R2345	4C	2G	U2160	6J	1J	W512	10P	4G
J500	1N	1E	R2346	4C	2G	U2240	3C	2G	W512	5P	4G
J500	5N	1E	R2370	8F	2K	U2250	4G	2H	W2540	3K	3H
J652	1N	2A	R2440	8D	2G	U2260	8J	2J	Y2540	1B	3G
			R2441	8D	2G	U2310	6C	2B			
			R2442	8D	2G	U2350	5C	2H			
						U2350	9E	2H			
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
P512	1P	CHASSIS	P512	9P	CHASSIS						

[1]A partial schematic of the A5 Control board is also shown in fig. FO-4 and FO-21. Component locations are shown in fig. FO-2.

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-21 for IC power connections and power distribution.
- An asterisk (*) beside components in this figure indicates components that would be installed if the memory were expanded. The OS-288 does not have expanded memory; however, because mounting holes for the missing components are provided on the circuit board, connections for them are shown in the schematic to aid in troubleshooting other parts of the circuit.

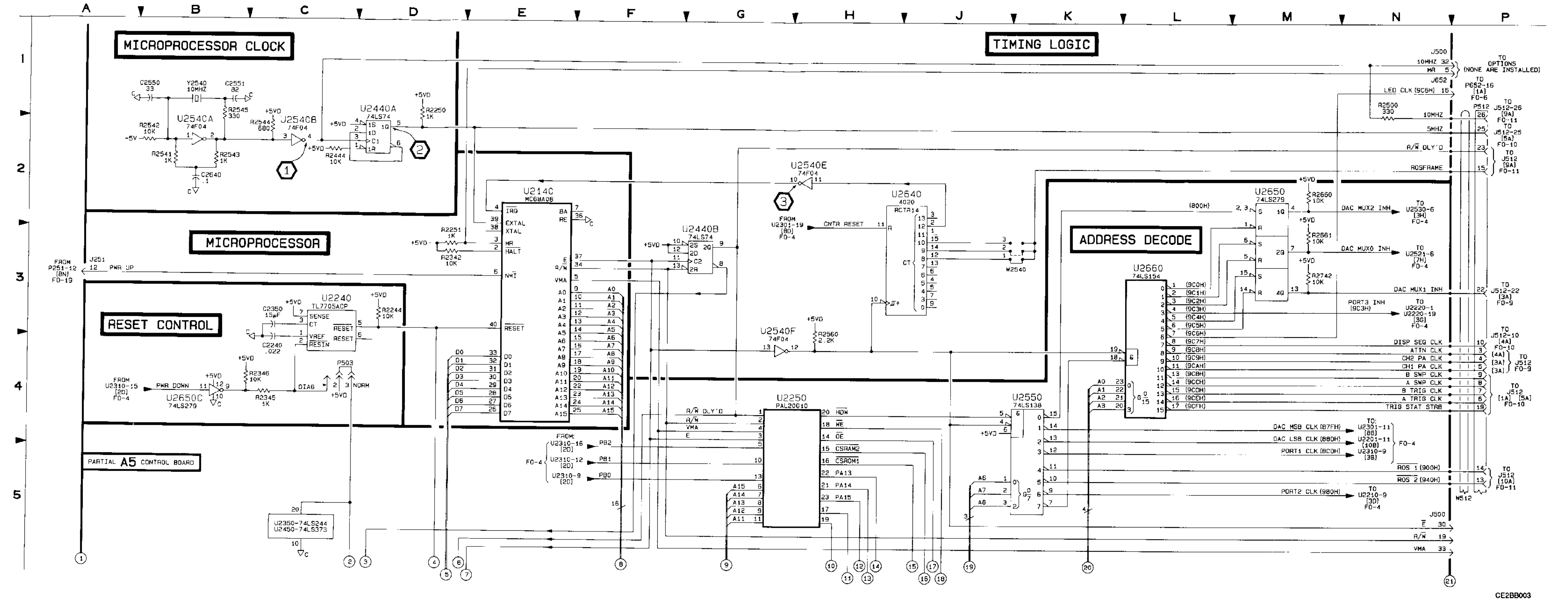
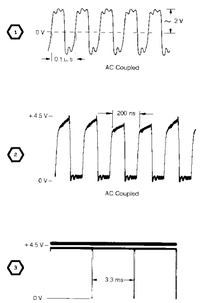


Figure FO-3. Processor and Digital Control Schematic (Sheet 1 of 2).

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated on sheet 1 of this figure and in fig. FO-2. The waveforms are representative of signals that may be expected at the associated points whenever the instrument is running.



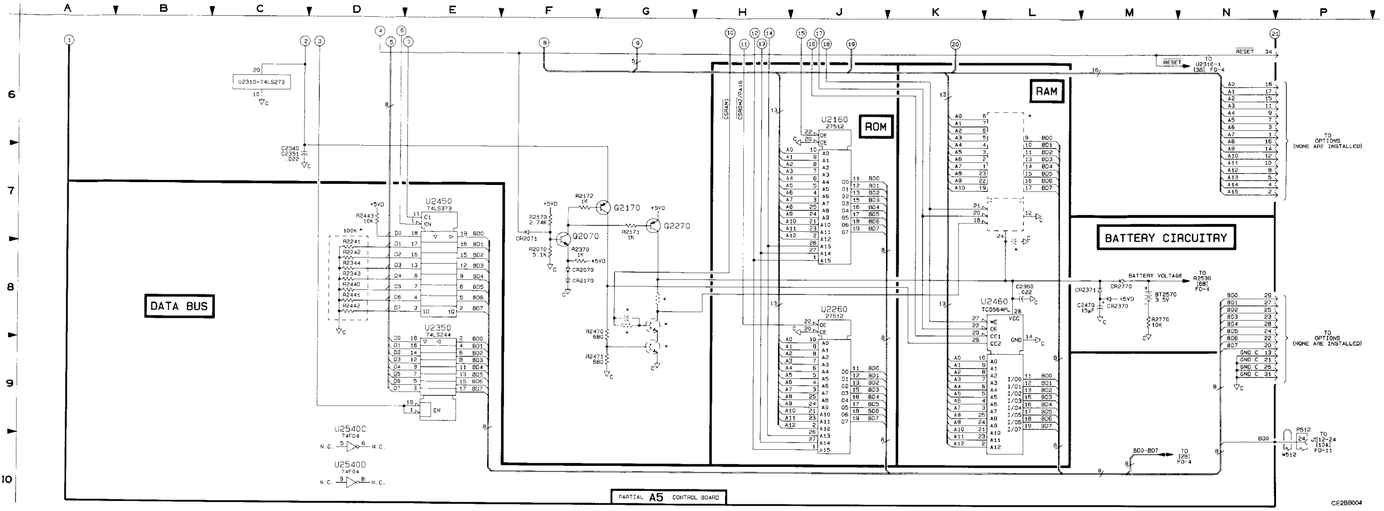


Figure FO-3. Processor and Digital Control Schematic (Sheet 2 of 2).
FP-7/(FP-8 blank)

Location of the Components Shown in this Figure and in Figure FO-2.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A5 CONTROL BOARD[1]											
C2016	10F	1C	R2011	10E	1B	R2502	8D	3A	R2720	8N	4D
C2110	10F	1C	R2012	10E	1C	R2503	8D	3B	R2721	8J	4D
C2230	9M	2D	R2013	10K	1A	R2504	8D	3A	R2730	7J	4E
C2321	8J	2D	R2101	10N	1A	R2505	8D	3A	R2731	4J	4E
C2330	6J	2E	R2160	9N	1A	R2510	6D	3B	R2732	4L	4F
C2331	2J	3E	R2164	9N	1A	R2511	3F	3C	R2733	4K	4F
C2333	3J	3F	R2110	3E	1C	R2512	3G	3C	R2734	3L	4F
C2420	5M	3C	R2201	7G	2A	R2513	3F	3C	R2740	4M	4G
C2421	6J	3D	R2202	7G	2A	R2520	5J	3C	R2741	4M	4G
C2422	5J	3E	R2203	7D	2A	R2521	6K	3C			
C2431	2J	3E	R2254	7D	2A	R2522	7L	3C	TP2420	5M	3D
C2432	2J	3F	R2255	7D	2A	R2523	7K	3D	TP2421	5M	3D
C2512	9G	3C	R2200	5L	2B	R2524	7M	3D			
C2521	5L	3E	R2230	8L	2B	R2531	2K	3E	U2101	9F	1B
C2621	7J	3D	R2231	2M	2E	R2532	2M	3E	U2201	9C	2B
C2622	7J	3D	R2232	3K	2F	R2533	3K	3E	U2210	7C	2C
C2830	4J	3E	R2501	7D	2A	R2534	2L	3F	U2220	2H	2D
C2831	3J	3F	R2502	7D	2A	R2535	2K	3F	U2310	9C	2B
C2731	4J	4E	R2503	7D	2A	R2536	1G	3F	U2401	9C	2C
C2732	3J	4E	R2505	7D	2A	R2537	3M	3F	U2415	7F	2E
C2733	4J	4F	R2530	8M	2D	R2540	4M	3F	U2425A	4L	2D
			R2231	2M	2E	R2601	6K	4A	U2425B	6M	2D
C2230	2M	2E	R2232	3L	2F	R2602	4K	4A	U2430C	5M	2D
C2231	2K	2E	R2233	3K	2F	R2603	4J	4A	U2430A	2K	2E
C2232	3L	2F	R2234	3K	2F	R2610	6G	4B	U2430B	2K	2E
C2233	3L	2F	R2240	1G	2F	R2611	5G	4B	U2630A	3K	2F
C2421	5M	3D	R2241	1G	2F	R2612	6N	4C	U2630B	3K	2F
C2422	5J	3E	R2401	3D	2A	R2620	7M	4C	U2501	5F	3A
C2431	2J	4D	R2402	3D	2A	R2621	7L	4C	U2502	5D	3B
C2432	2J	4D	R2403	3D	2A	R2622	7M	4C	U2503	6J	3B
C2433	3J	4D	R2404	3D	2A	R2623	8M	4C	U2530	3J	3E
C2830	7K	4E	R2405	3D	2A	R2624	8M	4C	U301	6K	4B
C2831	4N	4F	R2406	4D	2B	R2630	3L	4E	U2620A	8M	4D
C2842	3N	4F	R2407	3D	3A	R2631	4L	4F	U2620B	8L	4D
J551	3A	3A	R2409	4D	3B	R2632	4K	4F	U2620C	6C	4D
J651	6A	3A	R2410	4C	3B	R2640	6K	4F	U2620D	6C	4D
J751	6A	3A	R2411	4D	3B	R2641	6Q	4G	U2630A	3K	4E
J851	7A	2A	R2412	4C	3B	R2642	8H	4G	U2630B	3K	4E
J852	7A	2A	R2413	2D	2C	R2643	8J	4G	U2630C	4K	4E
J862		3A	R2414	5D	2C	R2644	8J	4G	U2630D	3K	4E
			R2415	5D	3C	R2645	8J	4G			
P501	7E	3C	R2416	7E	3C	R2701	6D	4A	V2420	5L	3D
			R2417	7E	3C	R2702	6D	4A			
Q2320	4M	2D	R2420	6M	3D	R2703	5D	4A	W511	2N	4C
			R2421	5L	3D	R2704	5D	4B	W511	3A	4C
R2001	10N	1A	R2422	5L	3D	R2705	5D	4B	W511	5N	4C
R2002	10N	1B	R2430	9K	2E	R2706	5D	4B	W512	1N	4D
R2003	10N	1B	R2431	2M	2E	R2707	5D	4B	W512	2A	4D
R2004	10N	1B	R2432	6K	3E	R2708	5D	4B	W512	4A	4D
R2005	10N	1B	R2433	2K	3E	R2709	5D	4B	W512	6A	4D
R2010	10E	1B	R2501	5F	3A	R2710	5C	4B	W512	8H	4D
			R2502	5D	3A	R2711	5D	4B			
						R2712	6D	4B			
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
P511	2N	CHASSIS	P511	5N	CHASSIS	P512	1N	CHASSIS	P512	8A	CHASSIS
P511	4A	CHASSIS	P512	1A	CHASSIS	P512	3N	CHASSIS	P512	8N	CHASSIS

[1]A partial schematic of the A5 Control board is also shown in fig. FO-3 and FO-21. Component locations are shown in fig. FO-2.

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-21 for IC power connections and power distribution.

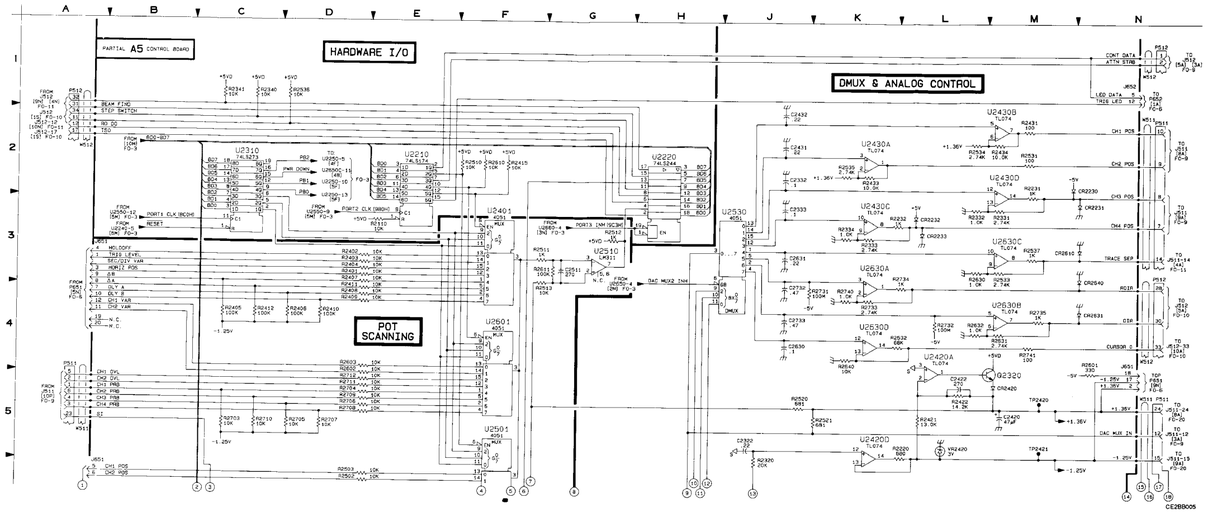
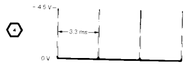


Figure FO-4. Analog Control Schematic (Sheet 1 of 2).
FP-9/(FP-10 blank)

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveform below was obtained at the test point indicated on sheet 2 of this figure and in fig. FO-2. The waveform is representative of the signal that may be expected at the associated point whenever the instrument is running.



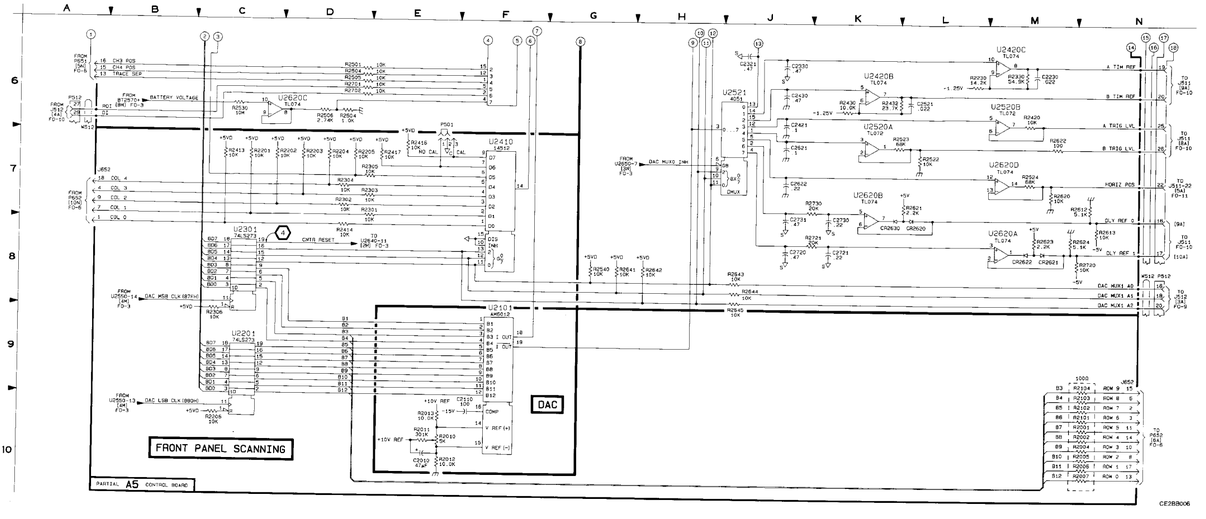
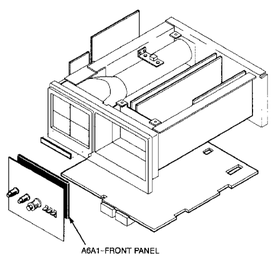
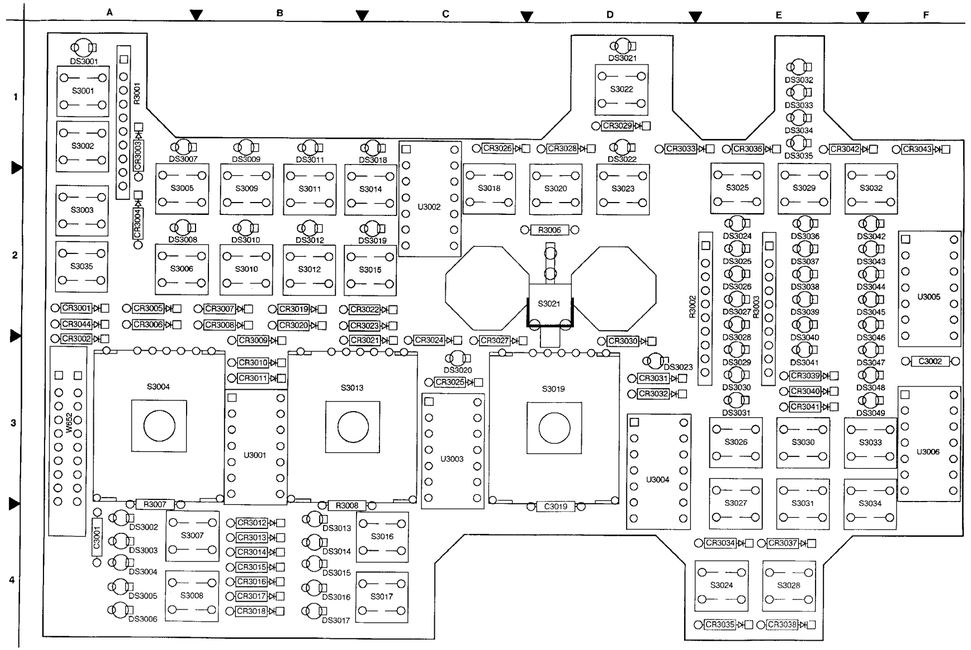


Figure FO-4. Analog Control Schematic (Sheet 2 of 2).
FP-11/(FP-12 blank)

A6A1 Front Panel Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
C3001	21	CR3037	6	DS3032	6	S3015	6
C3002	21	CR3038	6	DS3033	6	S3016	6
C3019	21	CR3039	6	DS3034	6	S3017	6
		CR3040	6	DS3035	6	S3018	6
CR3001	6	CR3041	6	DS3036	6	S3019	6
CR3002	6	CR3042	6	DS3037	6	S3020	6
CR3003	6	CR3043	6	DS3038	6	S3021	6
CR3004	6	CR3044	6	DS3039	6	S3022	6
CR3005	6			DS3040	6	S3023	6
CR3006	6	DS3001	6	DS3041	6	S3024	6
CR3007	6	DS3002	6	DS3042	6	S3025	6
CR3008	6	DS3003	6	DS3043	6	S3026	6
CR3009	6	DS3004	6	DS3044	6	S3027	6
CR3010	6	DS3005	6	DS3045	6	S3028	6
CR3011	6	DS3006	6	DS3046	6	S3029	6
CR3012	6	DS3007	6	DS3047	6	S3030	6
CR3013	6	DS3008	6	DS3048	6	S3031	6
CR3014	6	DS3009	6	DS3049	6	S3032	6
CR3015	6	DS3010	6			S3033	6
CR3016	6	DS3011	6	R3001	6	S3034	6
CR3017	6	DS3012	6	R3002	6	S3035	6
CR3018	6	DS3013	6	R3003	6		
CR3019	6	DS3014	6	R3006	6	U3001	6
CR3020	6	DS3015	6	R3007	6	U3001	21
CR3021	6	DS3016	6	R3008	6	U3002	6
CR3022	6	DS3017	6			U3002	21
CR3023	6	DS3018	6	S3001	6	U3003	6
CR3024	6	DS3019	6	S3002	6	U3003	21
CR3025	6	DS3020	6	S3003	6	U3004	6
CR3026	6	DS3021	6	S3004	6	U3004	21
CR3027	6	DS3022	6	S3005	6	U3005	6
CR3028	6	DS3023	6	S3006	6	U3005	21
CR3029	6	DS3024	6	S3007	6	U3006	6
CR3030	6	DS3025	6	S3008	6	U3006	21
CR3031	6	DS3026	6	S3009	6		
CR3032	6	DS3027	6	S3010	6	W652	6
CR3033	6	DS3028	6	S3011	6	W652	21
CR3034	6	DS3029	6	S3012	6		
CR3035	6	DS3030	6	S3013	6		
CR3036	6	DS3031	6	S3014	6		





CE2BB007

Figure FO-5. A6A1 Front Panel Board Component Locator.
FP-13/(FP-14 blank)

Location of the Components Shown in this Figure and in Figure FO-5.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A5A1 FRONT PANEL BOARD[1]											
CR3001	1C	3A	DS3045	2D	1F	DS3046	1M	4A	S3001	5B	7A
CR3002	1C	3A	DS3044	2D	3A	DS3041	1K	7E	S3008	6C	2A
CR3003	4C	3A				DS3042	8H	2E	S3007	1C	4A
CR3004	1D	2A	DS3001	2L	1A	DS3043	8J	2E	S3006	1C	6A
CR3005	4D	3A	DS3002	1G	4A	DS3044	8J	2E	S3009	5B	2B
CR3006	4D	3A	DS3003	1G	4A	DS3045	1K	2E	S3010	5B	2B
CR3007	4C	2B	DS3004	1H	4A	DS3046	1K	2E	S3011	6C	2B
CR3008	4D	3B	DS3005	1H	4A	DS3047	4L	3F	S3012	7C	2B
CR3009	5D	2B	DS3006	1J	4A	DS3048	4K	3E	S3013	4C	2B
CR3010	5D	2B	DS3007	2G	1A	DS3049	4K	3F	S3014	6C	2B
CR3011	5D	3B	DS3008	2H	2A				S3015	7C	2B
CR3012	1D	4B	DS3009	2G	1B	R3001	1H	1A	S3016	2J	4C
CR3013	1E	4B	DS3010	2H	2B	R3002	2G	1A	S3017	2C	4C
CR3014	4D	4B	DS3011	2H	2B	R3003	2H	1A	S3018	5C	2C
CR3015	3D	4B	DS3012	2K	3B	R3004	2L	1A	S3019	5C	3C
CR3016	3D	4B	DS3013	5K	4B	R3005	2L	1A	S3020	6C	3D
CR3017	2D	4B	DS3014	5K	4B	R3006	3H	1A	S3021	6C	3D
CR3018	2D	4B	DS3015	5L	4B	R3007	6G	1A	S3022	4B	1D
CR3019	7D	2B	DS3016	7G	4B	R3008	1H	2B	S3023	6B	2D
CR3020	7D	3B	DS3017	7G	4B	R3009	2G	2C	S3024	7B	4D
CR3021	6C	3B	DS3018	2J	1B	R3010	3L	2C	S3025	10D	3E
CR3022	7D	2B	DS3019	4G	2B	R3011	5J	2C	S3026	10C	3E
CR3023	7D	3C	DS3020	4H	3C	R3012	6G	2C	S3027	10C	3E
CR3024	6C	3C	DS3021	4H	3C	R3013	6H	2C	S3028	7B	4E
CR3025	5D	3C	DS3022	4G	1D	R3014	6H	2C	S3029	8D	4E
CR3026	9D	1C	DS3023	4F	1D	R3015	6H	2C	S3030	10B	3E
CR3027	6D	3C	DS3024	7L	2E	R3016	5G	2C	S3031	10B	3F
CR3028	9D	1D	DS3025	7K	2E	R3017	7L	2E	S3032	9B	3E
CR3029	8D	1D	DS3026	7K	2E	R3018	7L	2E	S3033	9B	3E
CR3030	6C	3D	DS3027	7J	2E	R3019	7L	2E	S3034	11B	3C
CR3031	6D	3D	DS3028	10H	2E	R3020	9H	2E	S3035	7C	2A
CR3032	10D	1D	DS3029	8G	3E	R3021	9G	2F	J3001	5F	3B
CR3033	10D	1D	DS3030	8G	3E	R3022	9F	2F	J3002	2F	2C
CR3034	9D	1C	DS3031	7G	3E	R3023	9J	2E	J3003	2F	2C
CR3035	3D	4D	DS3032	7H	3E	R3024	9J	2E	J3004	3F	2C
CR3036	10D	1E	DS3033	7H	1E	R3025	2H	2D	L3001	8F	3C
CR3037	10D	4E	DS3034	8L	1E	R3026	2K	4A	L3002	7F	3C
CR3038	3D	4E	DS3035	7H	3E				L3003	8F	2F
CR3039	2D	3E	DS3036	10G	2L	S3001	7B	1A	U3005	10F	3F
CR3040	10D	3E	DS3037	10G	2E	S3002	7B	1A			
CR3041	2D	3E	DS3038	10H	2E	S3003	7D	2A	W652	10A	3A
CR3042	1D	1E	DS3039	10H	2D	S3004	3C	3A	W653	10K	3A
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
H651	7K	CHASSIS	R3008	2M	CHASSIS	R3213	8M	CHASSIS	R3018	6M	CHASSIS
H652	10K	CHASSIS	R3009	4M	CHASSIS	R3214	7M	CHASSIS	R3019	4M	CHASSIS
H653	1A	CHASSIS	R3010	7M	CHASSIS	R3215	7M	CHASSIS			
			R3211	6M	CHASSIS	R3216	7M	CHASSIS	W651	9K	CHASSIS
R3007	6M	CHASSIS	R3212	5M	CHASSIS	R3217	3M	CHASSIS			

[1] A partial schematic of the A5A1 Front Panel board is also shown in FO-21. Component locations are shown in fig. FO-5.

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-21 for IC power connections and power distribution.

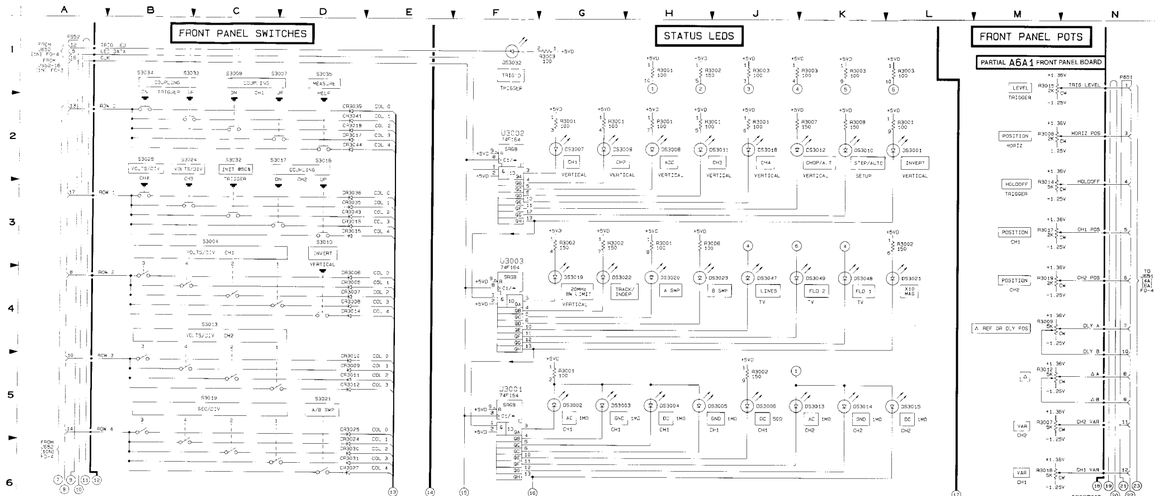


Figure FO-6. Front Panel Controls Schematic (Sheet 1 of 2).

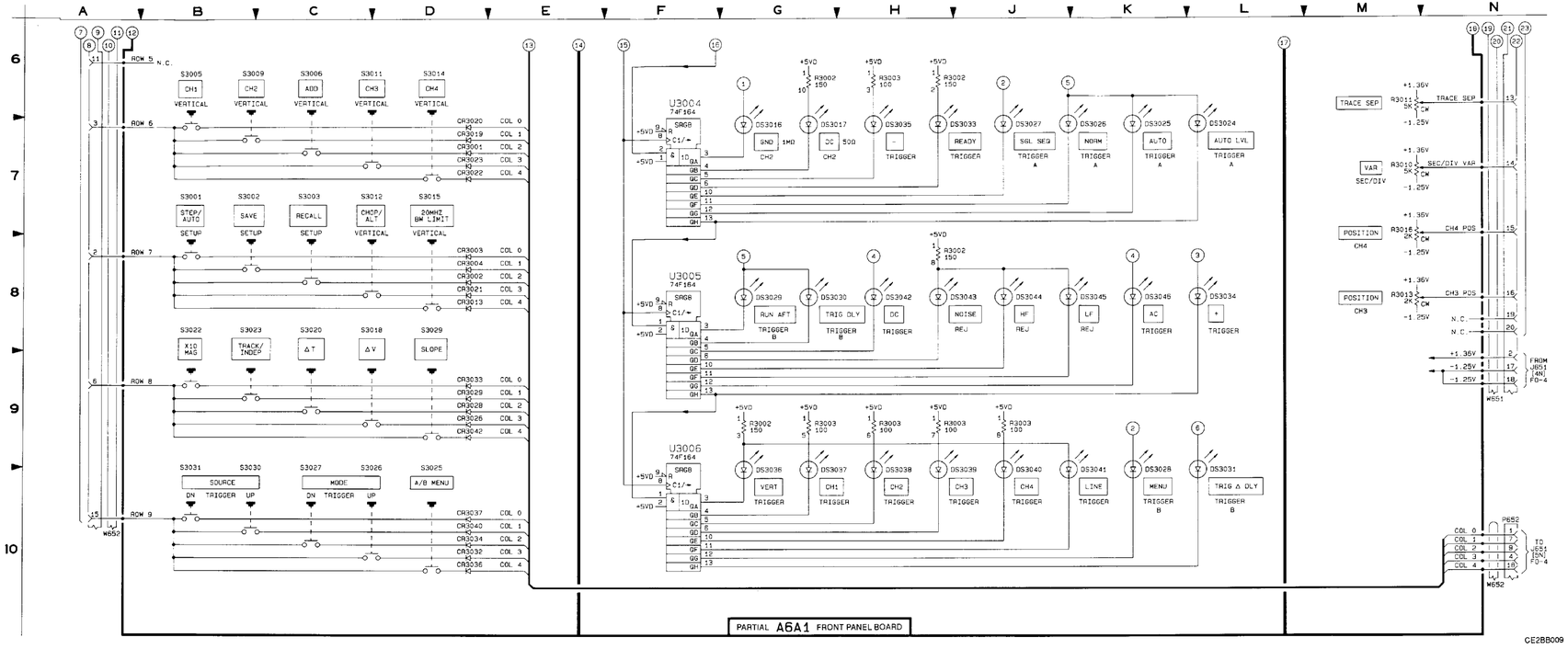


Figure FO-6. Front Panel Controls Schematic (Sheet 2 of 2).

A1 Main Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER
C100	9
C102	20
C103	9
C105	9
C106	20
C107	20
C108	20
C109	10
C110	9
C113	20
C114	20
C115	9
C116	9
C117	9
C118	9
C119	20
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C175	9
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C179	9
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C182	9
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C220	20
C221	20
C223	9
C225	20
C301	9
C302	9
C307	20
C310	9
C311	9
C325	20
C329	9
C332	9
C336	20
C351	10
C402	11
C403	11
C404	11
C412	11
C415	20
C458	20
C460	9
C464	9
C466	9
C478	11
C480	20
C487	11
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C500	20
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C513	10
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C521	20
C528	10
C536	10
C537	10
C544	10
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C985	20
C988	20
C990	20
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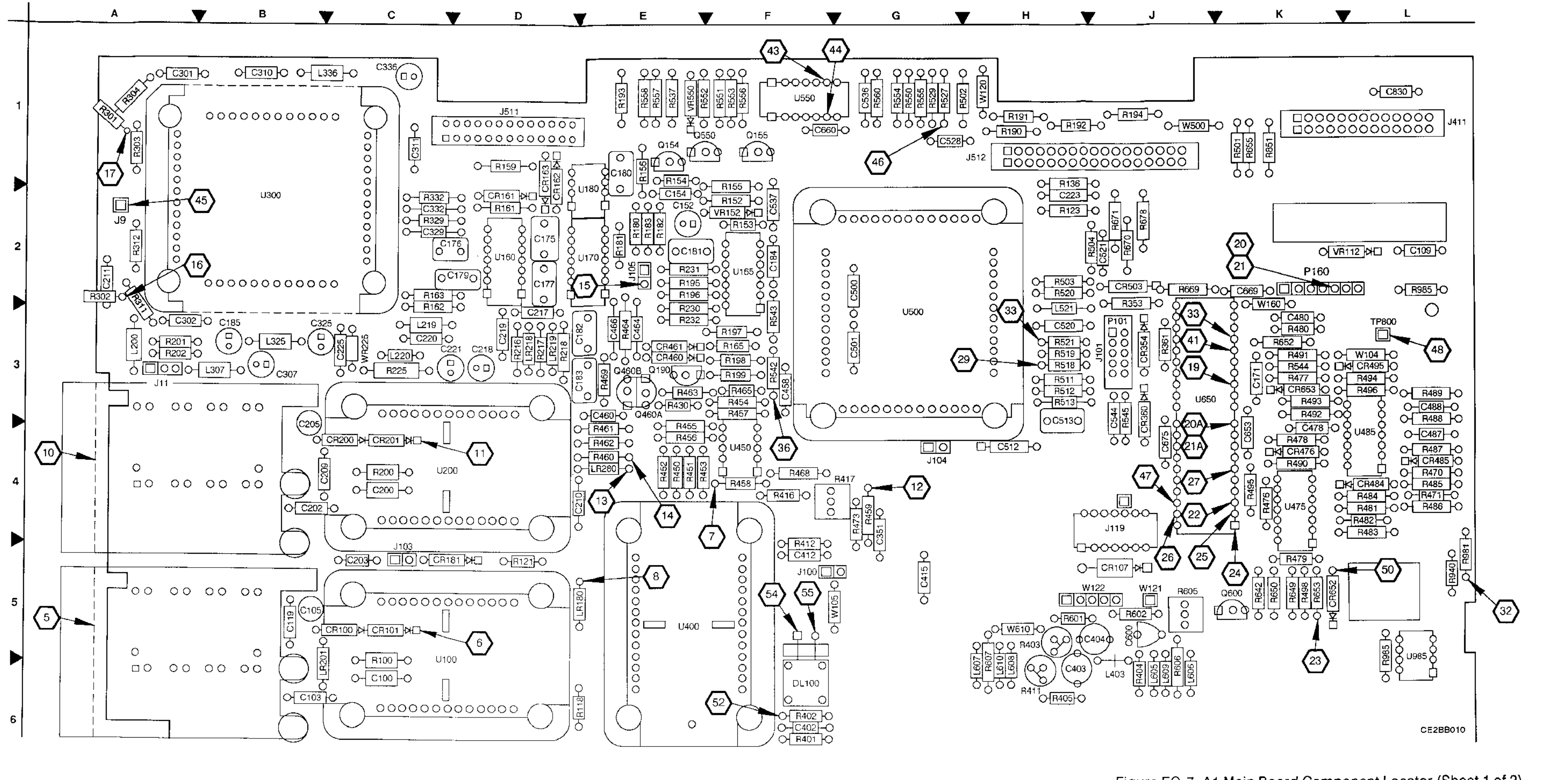
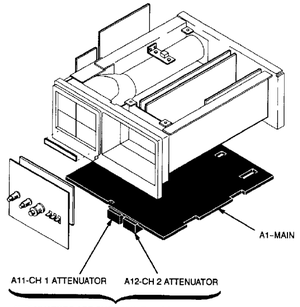


Figure FO-7. A1 Main Board Component Locator (Sheet 1 of 2).



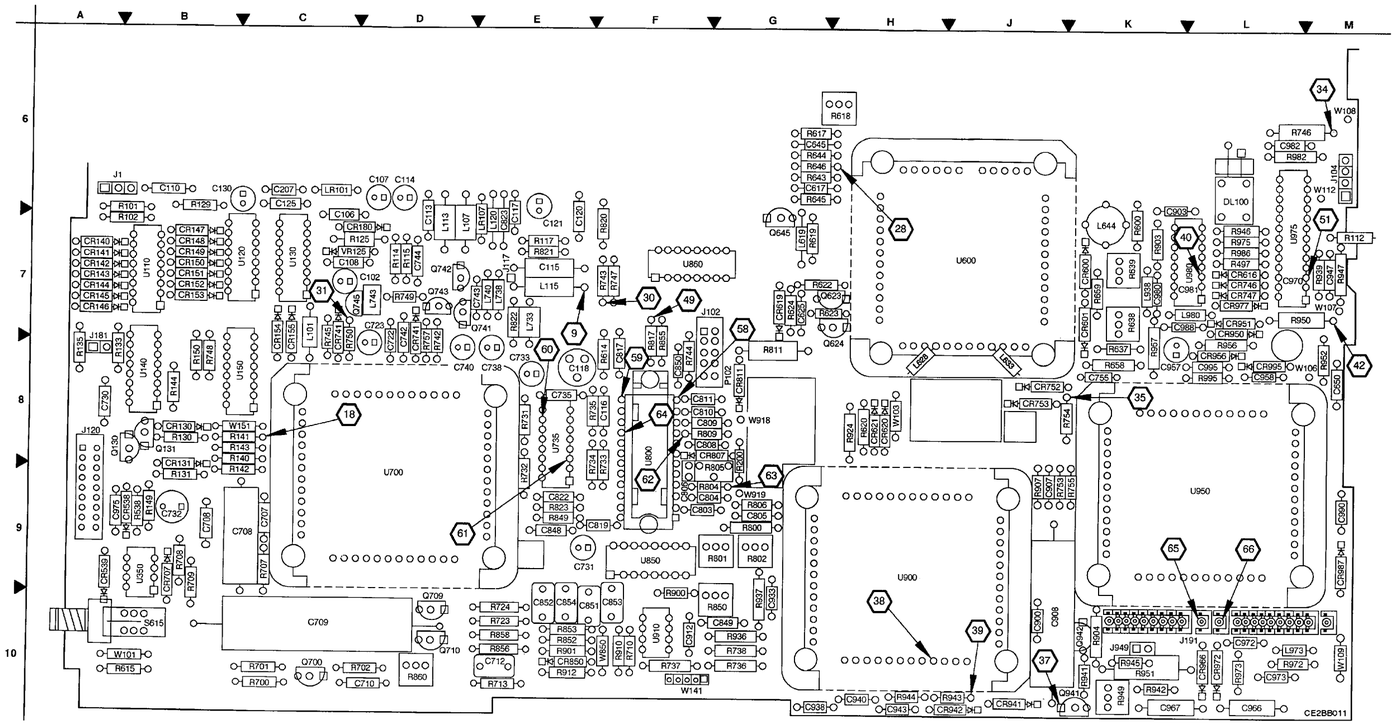
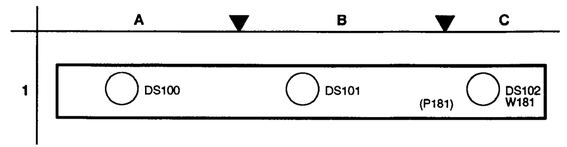


Figure FO-7. A1 Main Board Component Locator (Sheet 2 of 2).

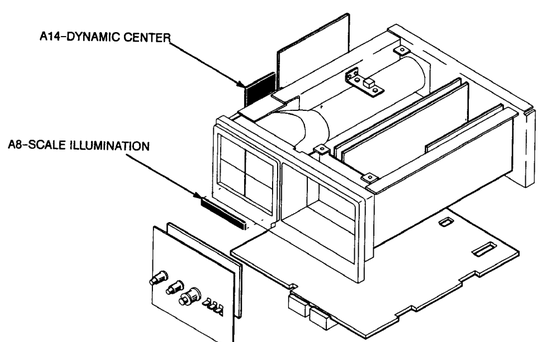
A8 Scale Illumination Board Component-to-Schematic Cross Reference

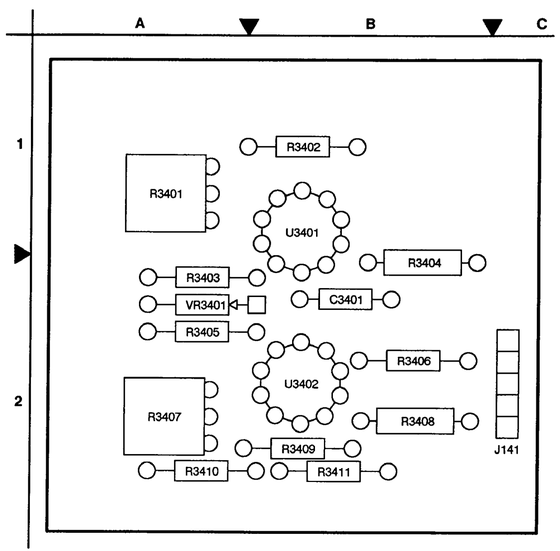
CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
DS100 DS101	9 9	DS102	9	W181	9		



A14 Dynamic Centering Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
C3401	11	R3402	11	R3407	11		
		R3403	11	R3408	11	U3401	11
J141	11	R3404	11	R3409	11	U3402	11
		R3405	11	R3410	11		
R3401	11	R3406	11	R3411	11	VR3401	11





CE2BB012

Figure FO-8. A8 Scale Illumination Board and A14 Dynamic Centering Board Component Locator.

Location of the Components Shown in this Figure and in Figures FO-7 and FO-8.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A1 MAIN BOARD[1]											
C100	1H	5C	CR151	6F	7C	R121	3L	5D	R450	7H	3E
C103	4F	6C	CR152	6E	7C	R123	3B	4C	R451	3H	4E
C105	1H	5C	CR153	6E	7C	R126	5B	4C	R452	3H	4F
C106	2H	6B	CR154	4G	7C	R130	5C	6B	R453	3H	4G
C115	2H	7C	CR156	5G	7C	R131	5C	6B	R454	3H	4G
C117	3L	6E	CR161	5K	2D	R133	4M	6A	R455	6K	4F
C118	2N	6E	CR162	2K	1D	R135	4N	6A	R456	6K	4F
C130	5B	6C	CR163	2K	2D	R136	4C	2J	R457	6N	4F
C175	6J	2C	CR191	7K	7D	R140	6C	6C	R458	6N	4F
C178	5L	2C	CR200	7H	4C	R141	5C	6C	R459	7F	4F
C177	2J	2D	CR201	7H	4C	R142	5C	6C	R460	8M	4L
C182	6J	3E	CR461	7N	3K	R144	5C	6B	R461	8M	4L
C184	3L	3F	J16	2H	6B	R149	5C	6B	R462	8M	4L
C185	3L	3F	J17	7H	3A	R158	6K	2C	R463	7M	3E
C200	7H	4C	J100	7F	5D	R161	6K	2C	R464	7P	3F
C202	5F	4C	J103	7F	5C	R163	2K	3C	R465	7P	3F
C203	7L	5C	J105	3F	2B	R180	3K	2B	R466	8P	3F
C205	7H	4C	J107	2M	2B	R181	3K	2B	R473	7N	3G
C211	8K	3A	J120	4M	3A	R182	7K	2C	R502	3C	1H
C217	8L	3G	J161	4N	3A	R183	7K	2C			
C225	3G	2J	J211	1P	1D	R191	3H	1H	U100	1L	6C
C300	10A	1A	J511	2A	1D	R192	3H	1H	U110	4E	6B
C310	10A	1A	J512	3A	1H	R193	3H	1F	U120	5E	6C
C311	10H	1G	J513	3A	1H	R194	3H	1F	U130A	4F	6C
C376	8H	2C				R195	3L	2F	U130B	5F	6C
C392	9J	2C	L116	2N	7E	R196	3L	2E	U130C	6M	6C
C462	8K	4E	L200	7H	3A	R197	4L	2F	U130D	5M	6C
C464	7P	3E	LR180	3M	5E	R198	4K	3F	U130E	4M	6C
C466	8N	3E	LR380	4E	4E	R200	7H	3F	U130F	4M	6C
CR100	1K	5C	P103	7K	5D	R201	7H	4C	U140	4G	6B
CR101	1H	5C				R202	8H	3A	U150	5D	6C
CR130	5C	6C	Q130	4C	6B	R216	7L	3A	U160A	2K	3D
CR131	5C	6C	Q131	5C	6B	R217	7K	3D	U160B	6K	3D
CR140	6G	6C	Q150	5L	3E	R218	9K	3E	U170A	2K	3D
CR141	4F	7B	Q160A	7N	3E	R230	3D	3E	U180A	2K	3D
CR142	4F	7B	Q160B	7N	3E	R231	3C	2E	U180B	9K	3E
CR143	4F	7B				R232	3E	2E	U200	3K	2E
CR144	4F	7B	R100	1H	6C	R301	10A	1A	U300	5L	4C
CR145	4G	7B	R101	2H	6B	R302	8A	1A	U301	8L	1A
CR146	4G	7B	R102	2H	7B	R304	9A	1A	U306	8L	1A
CR147	5G	7C	R114	2H	7B	R311	10A	1A	U450A	2M	4F
CR148	5F	7C	R115	2M	7D	R312	9A	2A	U450B	2M	4F
CR150	6F	7C	R116	2K	7E	R313	9A	2A			
			R118	3K	6E	R329	9H	2C			
A8 SCALE ILLUMINATION BOARD[2]											
DS100	4P	7M	DS101	5P	7K	DS102	5P	5P	W181	5P	3P
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
E200	7P	CHASSIS	J2	7A	CHASSIS	P10	2G	CHASSIS	R134	4L	CHASSIS
J1	1A	CHASSIS	J3	9A	CHASSIS	P11	7G	CHASSIS			
J1	1A	CHASSIS	J4	10A	CHASSIS	P105	7F	CHASSIS			
J2	7A	CHASSIS	J5	7P	CHASSIS	P120	4M	CHASSIS	W10	2G	CHASSIS
						P181	4N	CHASSIS	W11	7G	CHASSIS

[1]A partial schematic of the A1 Main board is also shown in fig. FO-10, FO-11, FO-15, and FO-20. Component locations are shown in fig. FO-7.
[2]Component locations for the A8 Scale Illumination board are shown in fig. FO-8.

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-20 for IC power connections and power distribution.
- The A11 CH 1 Attenuator Assembly and A12 CH 2 Attenuator Assembly contain no replaceable parts.
- An asterisk (*) beside components in this figure indicate the components are part of a matched pair.
- Two asterisks (**) beside components in this figure indicates the component is an integral part of the circuit board.
- Three asterisks (***) beside components in this figure indicates the component is not connected to the hybrid's internal circuitry. In those cases, the hybrid socket hole in the circuit board is used as an interlayer feedthrough.

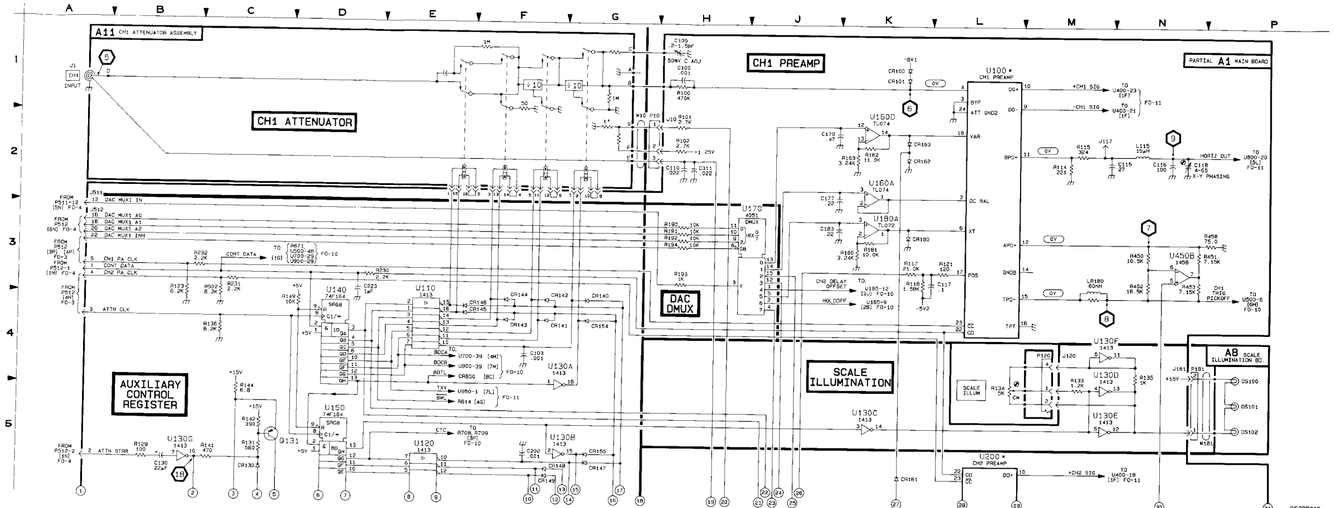


Figure FO-9. Attenuators and Preamps Schematic (Sheet 1 of 2).
FP-25/(FP-26 blank)

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated in this figure and in figure FO-7. The waveforms are representative of signals that may be expected at the associated points when the following setup conditions are observed. Any change(s) from the given setup conditions required to produce a given waveform are noted with that waveform illustration.

SETUP

Connect a 200 mV, 1 kHz square wave signal from a signal generator to each Vertical Channel as appropriate via a BNC T connector, a 50 Ω BNC cable and a dual-input coupler.

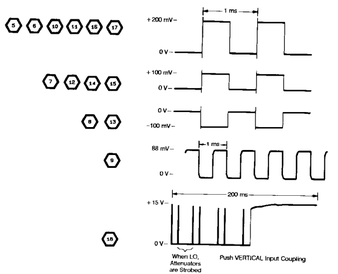
Set:

VERTICAL MODE	CH 1
Input Coupling	
CH 1 and CH 2	1 MΩ DC
VOLTS/DIV	
CH 1 and CH 2	50 mV
A and B SEC/DIV	0.5 ms (knobs locked)
TRIGGER	
MODE	AUTO
CH 1 and CH 2	1 MΩ DC
SOURCE	VERT
COUPLING	DC

All other control settings are irrelevant.

TEST OSCILLOSCOPE SETUP

Connect the 200 mV, 1 kHz square wave from the BNC T connector to the Trigger input of the test oscilloscope using a BNC cable. Trigger the test oscilloscope on the rising edge of the 1 kHz signal and, using a 10X probe with the test oscilloscope, set its Volts/Div and Time/Div ranges as required to obtain the indicated displays.



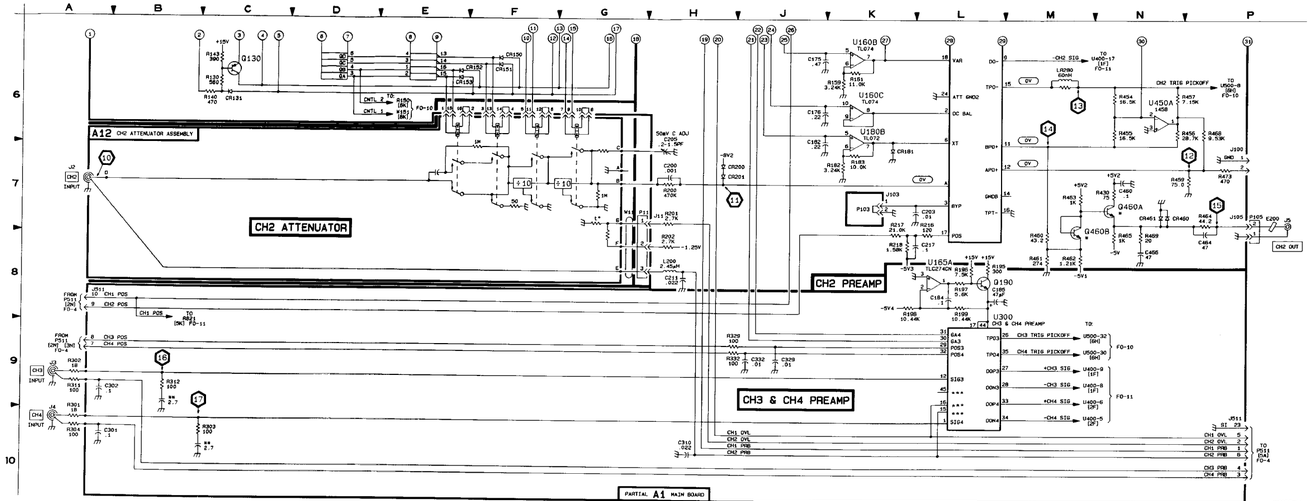


Figure FO-9. Attenuators and Preamps Schematic (Sheet 2 of 2).
FP-27/(FP-28 blank)

Location of the Components Shown in this Figure and in Figure FO-7.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A1 MAIN BOARD[1]														
C108	1B	2L	CR742	4N	7D	Q542	8P	10K	R071	2G	2J	R681	5N	6M
C152	2E	2K	CR746	5P	7L				R078	5C	2J	R682	6K	6L
C154	3Q	2E	CR747	6P	7L	R112	1A	7M	R207	3P	9K	R683	6K	7L
C156	3P	3K	CR752	3P	8J	R150	7L	8B	R726	3P	9B	R685	7P	7L
C160	2K	1E	DR753	4P	8J	R152	2D	2F	R727	3P	10B			
C161	4B	4K	DR800	9C	10E	R153	2D	2F	R728	3P	10E			
C551	4B	4L	DR841	6N	11J	R154	3D	2E	R731	1M	10F			
C613	6H	6H	DR842	6N	11J	R155	2E	2F	R733	2L	10G			
C620	7F	3H	DR851	6R	7L	R156	3D	2E	R734	2M	10G			
C628	6H	1H				R163	2K	3F	R736	2M	10G			
C636	5J	1G	J9	7A	2A	R207	5E	3J	R737	2N	10F			
C637	5F	2F	J101	8F	3J	R503	6H	2H	R738	2L	10G			
C644	7E	3J	J102	10M	7G	R604	4H	2H	R742	4N	8D			
C645	6H	6G	J103	1J	7G	R611	4H	3H	R743	4M	7F			
C650	5E	6F	J105	6M	7G	R612	4H	3H	R744	4M	8F			
C652	5E	2K	J106	5E	6M	R613	4H	3H	R745	4M	8D			
C707	3N	3K	J109	6K	4H	R618	4K	3H	R746	4N	8D			
C708	2P	9C	J120	9B	2A	R619	4K	3H	R747	5M	8L			
C709	2P	10B	J181	5A	8A	R720	7F	2H	R748	5L	7D			
C712	1M	10E	J411	10K	7K	R721	7F	2H	R749	6M	7D			
C742	2N	7D	J411	5A	1K	R727	8H	1H	R750	2N	8D			
C743	2N	7D	J411	1K	1K	R728	8H	1H	R753	3P	9K			
C744	6M	7D	J511	8A	1K	R735	8F	1F	R754	3P	9K			
C745	6N	8K	J512	10A	9H	R736	8F	1F	R755	3K	9K			
C833	9D	7L	J512	1A	1H	R737	8F	1F	R756	4N	9D			
C845	10D	7L	J512	1C	1H	R738	8F	1F	R757	4N	9D			
C849	10B	10E	J512	4A	1H	R739	8F	1F	R842	9D	9E			
C851	3K	10F				R740	8F	1F	R843	9D	9E			
C853	3K	10F	P1014	7E	3J	R741	8F	1F	R844	9D	10E			
C854	3L	10F	P1016	7L	3J	R742	7B	1F	R845	7F	3K			
C900	7M	10J	P1020	10M	7G	R743	7C	1F	R900	2M	10K			
C901	8M	10J	P1021	10M	7G	R744	7C	1G	R901	4M	10K			
C902	9N	11K	P1160	2E	2K	R745	7C	1G	R902	6M	10K			
C903	9N	11K				R746	7C	1G	R903	8M	10K			
C947	5K	7M	Q154	3D	2E	R747	7C	1G	R904	10M	10K			
C952	6K	7L	Q155	2D	2F	R748	7C	1G	R905	4M	10F			
			Q350	7D	2F	R749	7C	1G	R906	6M	10F			
CR364	5D	2J	Q542	8P	10K	R750	7C	1G	R907	8M	10F			
CR380	5D	3J	Q709	2P	10D	R751	7C	1G	R908	10M	10F			
CR503	6H	2J	Q710	3N	7D	R752	8C	1G	R909	2M	10K			
CR538	6E	10B	Q740	4N	7D	R753	8C	1G	R910	7M	10K			
CR539	9E	10B	Q741	5M	7D	R754	8C	1G	R911	9M	10K			
CR552	5H	7L	Q742	5M	7D	R755	8C	1G	R912	1P	2L			
CR553	5E	2K	Q743	4P	7D	R756	8C	1G	R913	2P	2L			
CR741	3K	7D	Q745	4P	7D	R757	8C	1G	R914	3P	2L			
CR747	3K	7C	Q841	8P	11K	R758	8C	1G	R915	4P	2L			
						R870	4C	2J	R916	5P	2L			
									R925	7N	7L			

CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)														
J7	6B	CHASSIS	P107	6B	CHASSIS	P120	2B	CHASSIS	R351	4A	CHASSIS			
J9	6B	CHASSIS	P108	6B	CHASSIS	P122	8A	CHASSIS	R352	4B	CHASSIS			
J12	1A	CHASSIS	P109	4K	CHASSIS									

[1]A partial schematic of the A1 Main board is also shown in fig. FO-9, FO-11, FO-15, and FO-20. Component locations are shown in fig. FO-7.

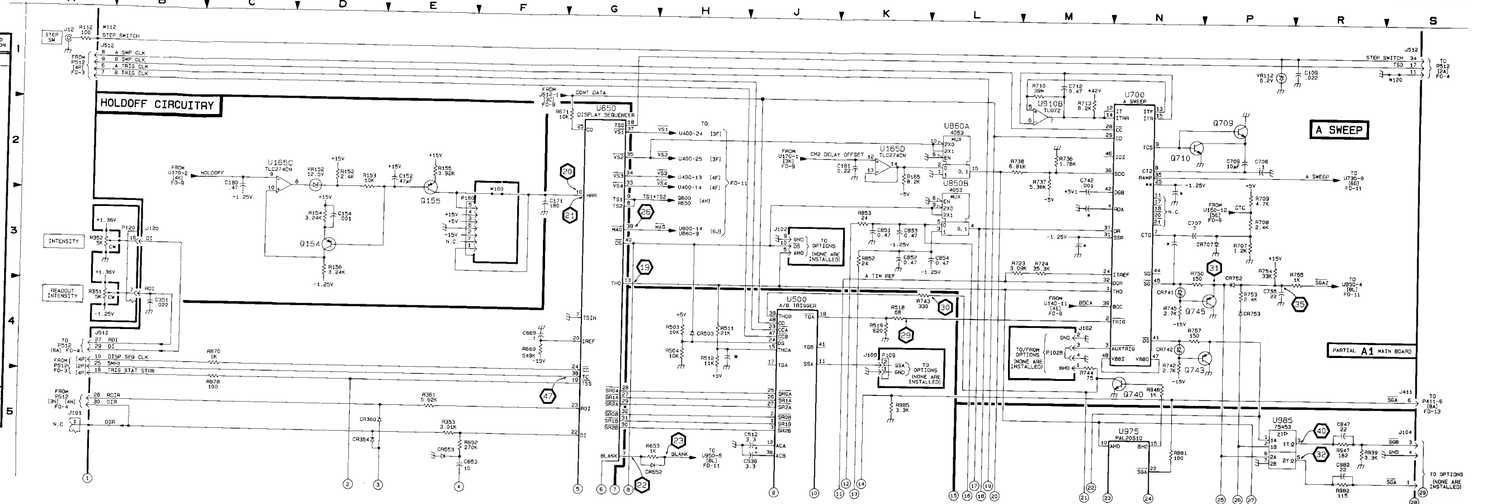


Figure FO-10. Holdoff, Display Sequencer, Triggering and Sweeps Schematic (Sheet 1 of 3).

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-20 for IC power connections and power distribution.
- An asterisk (*) beside components in this figure indicates the component is an integral part of the circuit board.
- Two asterisks (**) beside components in this figure indicates the component is not connected to the hybrid's internal circuitry. In those cases, the hybrid socket hole in the circuit board is used as an interlayer feedthrough.

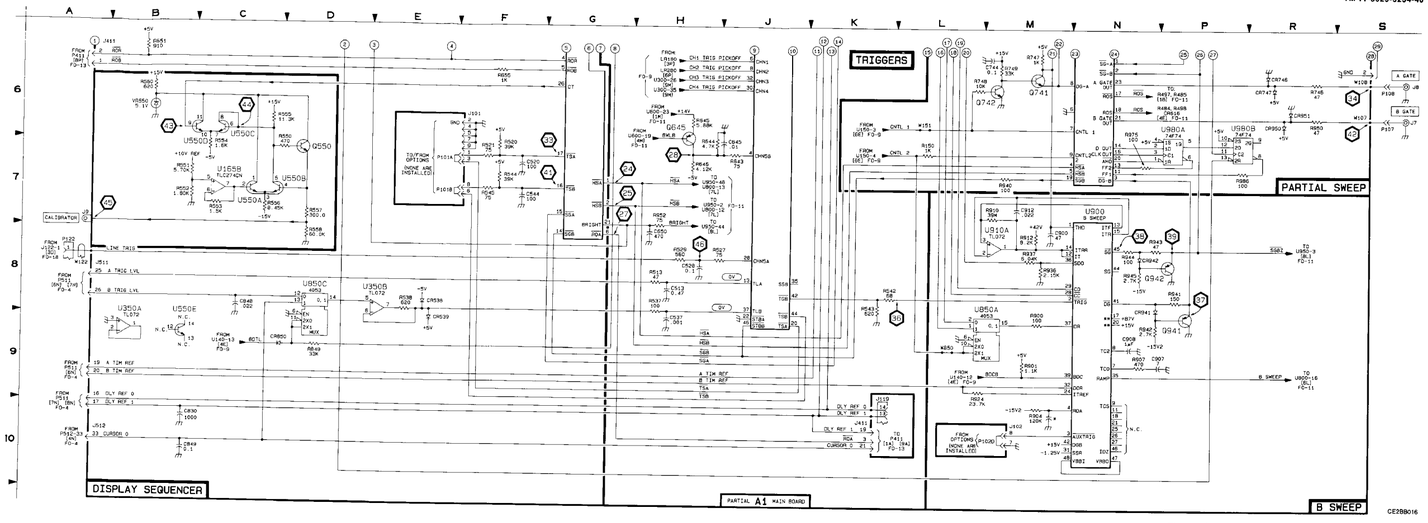


Figure FO-10. Holdoff, Display Sequencer, Triggering and Sweeps Schematic (Sheet 2 of 3).

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated on sheets 1 and 2 of this figure and in figure FO-7. The waveforms are representative of signals that may be expected at the associated points when the following setup conditions are observed. Any change(s) from the given setup conditions required to produce a given waveform are noted with that waveform illustration. Where B Sweep setup conditions are referenced with a waveform, it is assumed that the B SEC/DIV knob is set to 100 µs/div unless otherwise noted.

SETUP

Connect a 200 mV, 1 kHz squarewave to the CH 1 input of the oscilloscope using a BNC cable.

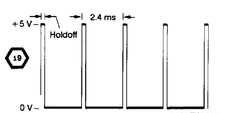
Set:

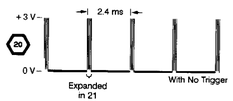
VERTICAL MODE	CH 1
Input Coupling	
CH 1 and CH 2	1 MΩ DC
VOLTS/DIV	
CH 1 and CH 2	50 mV
CH 1 and CH 2 VAR	In detent
A and B SEC/DIV	200 µs (knobs locked)
A and B SEC/DIV VAR	In detent
TRIGGER	
MODE	AUTO
SOURCE	VERT
COUPLING	NOISE REG
HOLDOFF	In detent
SLOPE	+ (plus)
LEVEL	Stably triggered display
Δt	DLY readout
Δ REF OR DLY POS	1000.0 µs readout
INTENSITY	Midrange
READOUT INTENSITY	Minimum (once DLY readout is set)
HOLDOFF	CCW (counterclockwise)

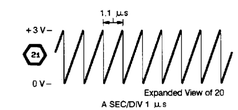
All other control settings are irrelevant.

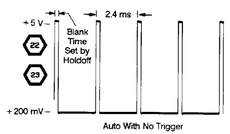
TEST OSCILLOSCOPE SETUP

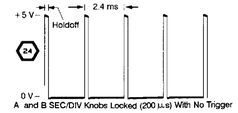
Using a 10X probe with the test oscilloscope, set its Trigger Slope, Trigger Level, Volts/Div and Time/Div ranges as required to obtain the indicated displays.

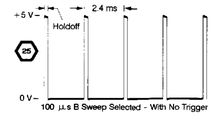


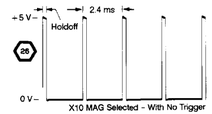


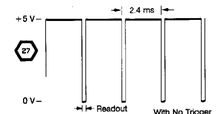


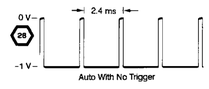


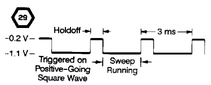


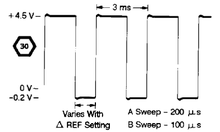


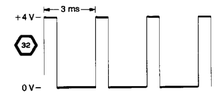


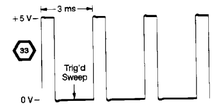


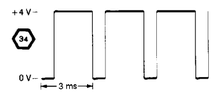


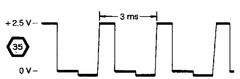


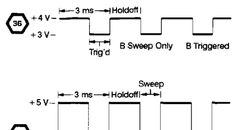


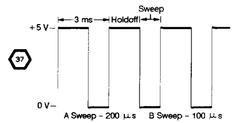


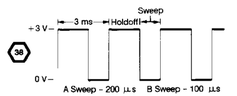


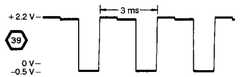


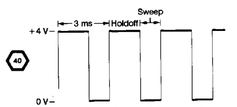


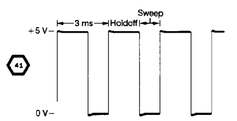


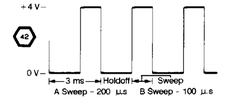


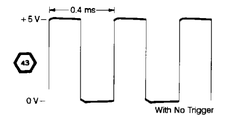


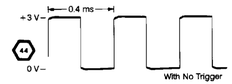


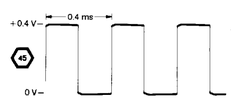


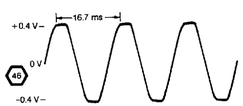


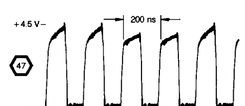












CE2BB017

Figure FO-10. Holdoff, Display Sequencer, Triggering and Sweeps Schematic (Sheet 3 of 3).
FP-33/(FP-34 blank)

Location of the Components Shown in this *Figure* and in Figures FO-7, FO-8, and FO-14.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A1 MAIN BOARD[1]														
C402	3F	5F	E900	6N	9G	R416	2F	4F	R823	7L	7H	U400	1F	5F
C403	2H	5J				R417	2F	4G	R824	1M	7D	U475A	3D	7L
C404	2J	5J	J191	8K	10K	R470	2D	4M	R827	3L	6K	U475B	3D	7L
C412	2F	5F	J191	8H	10K	R471	4D	4M	R835	3L	7K	U475C	3D	5L
C467	2D	4M	J191	8A	10K	R472	2D	4K	R839	3J	7K	U475D	3D	7L
C468	2C	3M	J411	2A	1K	R477	3E	5K	R840	4J	6K	U479D	1C	4L
C601	2K	5J	J411	4A	1K	R478	2E	5K	R841	4J	5K	U485A	2D	5L
C602	4L	9G	J411	5N	1K	R480	2D	5K	R859	2K	6K	U485B	2C	4L
C625	4L	9G	J411	4M	1K	R484	2D	4L	R859	2K	7K	U485C	1C	4L
C735	5M	8F	J511	4A	1D	R485	3D	4L	R731	2H	8F	U485D	1C	4L
C803	6L	9G	J511	5A	1D	R486	3D	5L	R732	6H	9F	U600	7L	5J
C804	5M	9G	J512	10N	1H	R487	3D	4L	R733	6J	9F	U735A	5J	9F
C805	7M	9G	J512	4N	1H	R494	4D	4L	R734	6J	8F	U735B	6H	9F
C806	5M	8F	J512	9A	1H	R495	1C	4M	R735	6H	8F	U735C	6H	9F
C808	5M	8G	J512	8K	1H	R496	2C	4M	R802	7L	9G	U735D	6H	9F
C809	5M	8G	J843	6K	9K	R497	2C	4M	R831	7K	9G	U801	8N	9F
C817	5C	6F	L462	2H	5J	R498	2C	4M	R837	5L	9G	U803	8N	9F
C820	1B	9E	L605	2L	6K	R499	2B	4M	R838	6L	9G	U850	8H	7F
C821	3K	8E	L606	2K	6K	R491	1C	5K	R839	6M	9G	U950	7M	8K
C822	3K	8L	L607	2K	6H	R492	2E	5L	R839	6M	8G			
C965	9B	8L	L608	2L	6H	R493	2E	5L	R817	5C	6F	W105	8A	8M
			L609	2K	6H	R494	2D	3L	R820	5K	6F	W141	7C	10Q
C8416	3E	4K	L610	2K	8H	R495	2K	4K	R821	6K	7E	W141	7F	10Q
C8424	4D	4L	L619	4M	7K	R496	1C	5L	R822	5B	7E	W500	9B	1K
C8465	2C	4M	L629	3N	7K	R497	1C	7L	R823	5K	9E	W810	2K	5H
C8466	2C	3L	L630	2N	6J	R498	4D	5K	R950	8J	10Q	W918	8N	9G
C9001	4J	7K	L644	3N	6K	R499	10B	1K	R958	6B	7F	W919	8N	9G
C9009	3K	7K				R900	9M	7H	R959	6L	10E			
C9010	4M	7L	Q800	4J	6K	R901	9M	7J	R960	6B	10B			
C9019	4M	8H	Q822	1M	7K	R902	2L	5J	R961	7L	10Q			
C9020	3K	8H	Q824	7L	7H	R903	2L	5J	R963	7L	9Q			
C9021	3K	8H				R904	2K	5J	R966	6K	8L			
C9066	8L	8L	R401	3F	6F	R907	2K	6H	R827	8L	8G			
C9067	8M	10L	R402	2F	6F	R914	4H	6F	R972	9N	10L			
C9072	6M	10L	R403	2F	5F	R915	4K	10B	R973	9M	10L			
C9085	9B	8L	R404	2J	5J	R917	4L	6Q	R965	6B	8L			
			R405	2J	5J	R918	4L	6H						
DL100	1Q	5L	R406	2J	5J	R919	4M	7H	S815	4K	10B			
DL100	1Q	6F	R411	2H	5F	R920	4L	8H						
			R412	2F	5F	R922	4L	7H	TP930	2B	3L			
A9 HIGH VOLTAGE BOARD[2]														
P191	8K	4B	R1833	8J	1D	R1834	AJ	1B	R1842	AJ	1D			
A14 DYNAMIC CENTERING BOARD[3]														
C2401	7C	2B	R2401	7E	1A	R2405	6C	2A	R2409	6C	2B	U2401	7B	1B
J141	5E	2C	R2402	6D	1B	R2406	6C	2B	R2410	6C	2A	U2402	5E	2B
J141	7C	2D	R2403	6D	2B	R2407	6E	2A	R2411	6C	2B			
			R2404	6E	2B	R2408	6E	2B				W2401	5C	2A
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)														
J6	9A	CHASSIS	P106	9A	CHASSIS	P141	7C	CHASSIS	W916	2N	CHASSIS			
			P141	5F	CHASSIS				W917	3N	CHASSIS			

[1]A partial schematic of the A1 Main board is also shown in fig. FO-9, FO-10, FO-15, and FO-20. Component locations are shown in fig. FO-7.
[2]A partial schematic of the A9 High Voltage board is also shown in fig. FO-15 and FO-21. Component locations are shown in fig. FO-14.
[3]Component locations for the A14 Dynamic Centering board are shown in fig. FO-8.

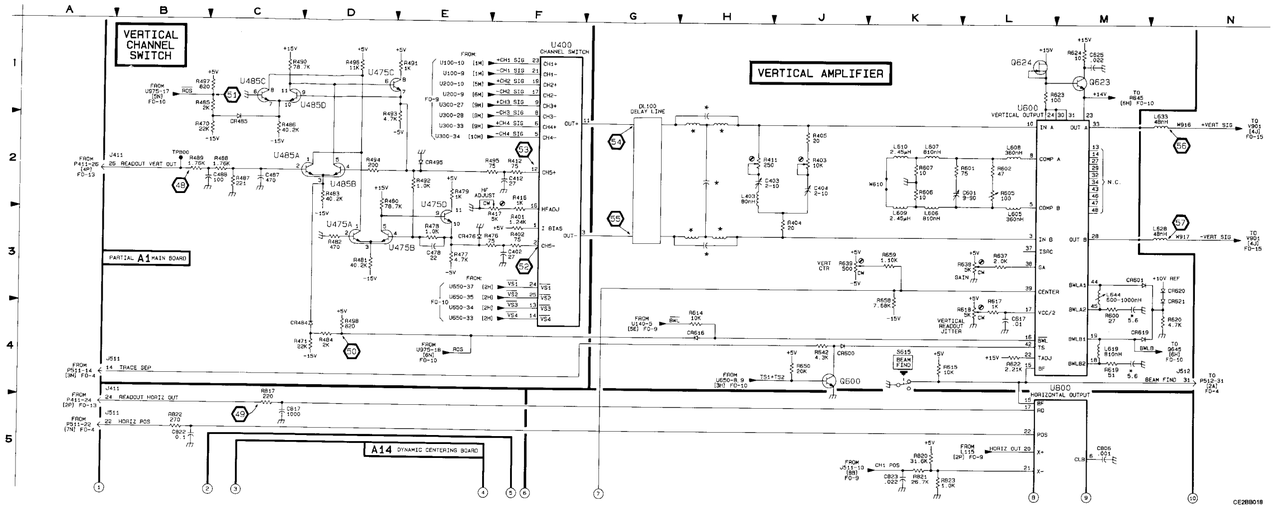


Figure FO-11. Channel Switch and Output Amplifier Schematic (Sheet 1 of 3).

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-20 for IC power connections and power distribution.
- An asterisk (*) beside components in this figure indicates the component is an integral part of the circuit board.

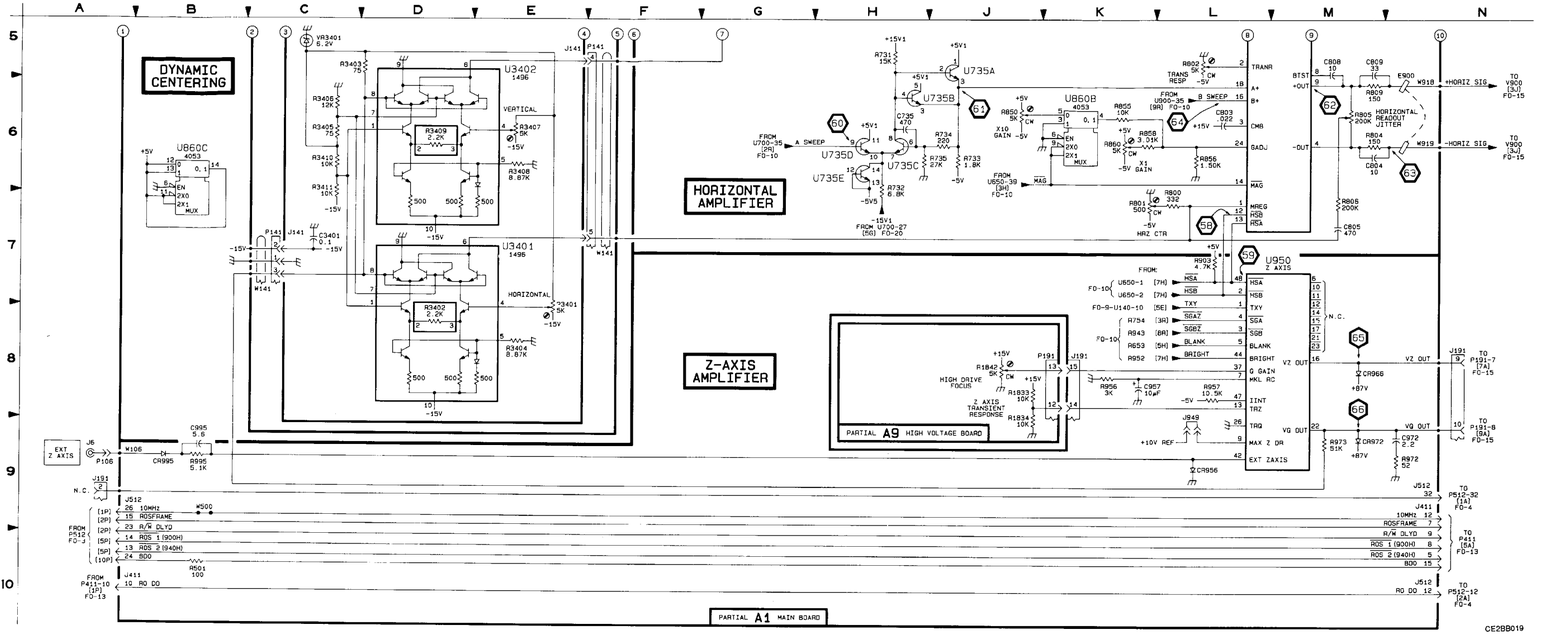


Figure FO-11. Channel Switch and Output Amplifier Schematic (Sheet 2 of 3).
FP-37/(FP-38 blank)

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated on sheets 1 and 2 of this figure and in figure FO-7. The waveforms are representative of signals that may be expected at the associated points when the following setup conditions are observed. Any change(s) from the given setup conditions required to produce a given waveform are noted with that waveform illustration. Where B Sweep setup conditions are referenced with a waveform, it is assumed that the B SEC/DIV knob is set to 100 µs/div unless otherwise noted.

SETUP

Connect a 200 mV, 1 kHz squarewave to the CH 1 input of the oscilloscope using a BNC cable.

Set:

VERTICAL MODE	CH 1
Input Coupling	
CH 1 and CH 2	1 MΩ DC
VOLTS/DIV	
CH 1 and CH 2	50 mV
CH 1 and CH 2 VAR	In detent
A and B SEC/DIV	200 µs (knobs locked)
A and B SEC/DIV VAR	In detent
TRIGGER	
MODE	AUTO
SOURCE	VERT
COUPLING	NOISE REG
HOLDOFF	In detent
SLOPE	+ (plus)
LEVEL	Stably triggered display

Δt	Δt readout
Δ REF OR DLY POS	1000.0 µs readout
INTENSITY	Midrange
READOUT INTENSITY	Minimum (once Δt readout is set)

All other control settings are irrelevant.

TEST OSCILLOSCOPE SETUP

Using a 10X probe with the test oscilloscope, set its Trigger Slope, Trigger Level, Volts/Div and Time/Div ranges as required to obtain the indicated displays.

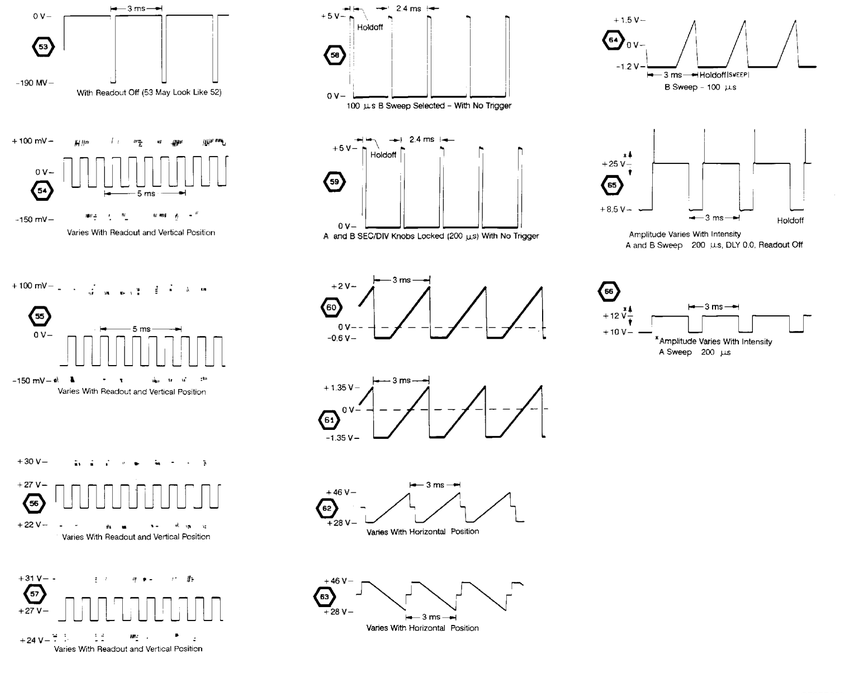


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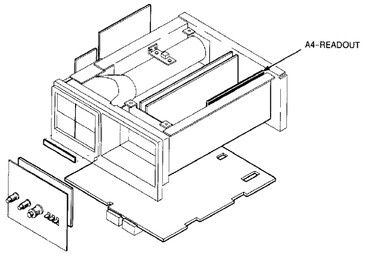
Figure FO-11. Channel Switch and Output Amplifier Schematic (Sheet 3 of 3).

A4 Readout Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
C2830	21	R2910	13	U2805	13	U2920	13
C2835	21	R2911	13	U2805	21	U2920	21
C2851	21	R2912	13	U2810	13	U2930	13
C2855	21	R2913	13	U2810	21	U2930	21
C2860	21	R2914	13	U2820	13	U2935	13
C2885	21	R2915	13	U2820	21	U2935	21
C2901	21	R2916	13	U2830	13	U2940	13
C2911	13	R2917	13	U2830	21	U2940	21
C2912	21	R2918	13	U2835	13	U2950	13
C2913	21	R2919	13	U2835	21	U2950	21
C2936	21	R2920	13	U2850	13	U2960	13
C2940	21	R2921	13	U2850	21	U2960	21
C2950	21	R2922	13	U2855	13	U2965	13
C2960	21	R2923	13	U2855	21	U2965	21
C2970	21	R2924	13	U2860	13	U2970	13
C2980	21	R2925	13	U2860	21	U2970	21
C2990	21	R2926	13	U2865	13	U2980	13
		R2927	13	U2865	21	U2980	21
J401	13	R2928	13	U2870	13	U2985	13
J402	13	R2929	13	U2870	21	U2985	21
		R2930	13	U2880	13	U2990	13
R2805	21	R2931	13	U2880	21	U2990	21
R2830	13	R2932	13	U2885	13	U2995	13
R2841	13	R2933	13	U2885	21	U2995	21
R2842	13	R2934	13	U2890	13		
R2843	13	R2940	13	U2890	21	VR2805	21
R2844	13	R2945	13	U2900	13	VR2925	13
R2850	13	R2975	13	U2900	21		
R2901	13	R2985	13	U2905	13	W411	13
R2902	13			U2905	21	W411	21
R2903	13	U2800	13	U2910	13	W2851	13
R2905	13	U2800	21	U2910	21		



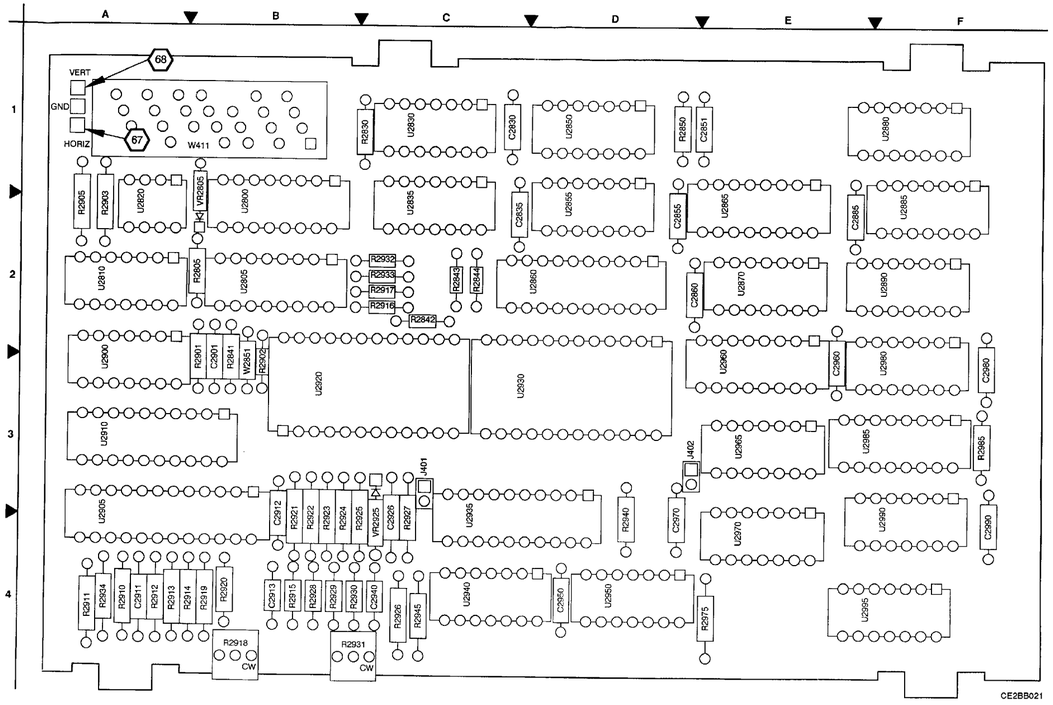


Figure FO-12. A4 Readout Board Component Locator.
FP-41/(FP-42 blank)

Location of the Components Shown in this Figure and in Figure FO-12.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A4 READOUT BOARD[1]											
C2911	2H	4A	R2523	4K	2B	U2835C	7F	2C	U2845	1E	4C
J401	4G	3C	R2524	4K	3B	U2836D	2E	2C	U2850A	7D	4C
J402	6G	3C	R2525	4L	4C	U2850A	7D	1C	U2850B	8H	4C
			R2527	4L	2C	U2850B	7D	1C	U2860	3C	3C
R2830	7B	1A	R2528	3J	2B	U2855A	7J	2C	U2865A	7B	3C
R2841	5K	3B	R2529	3J	4B	U2855B	5E	2C	U2865B	8G	3C
R2842	3B	2C	R2530	3J	4B	U2855C	3E	2C	U2865C	4E	3C
R2843	3B	2C	R2901	4K	4B	U2855D	3E	2C	U2870A	7L	4C
R2844	4B	2C	R2902	5D	2C	U2860	4D	2C	U2870B	7Q	4C
R2901	7C	1D	R2903	5D	2C	U2870	8F	2C	U2870C	8Q	4C
R2902	3B	3B	R2904	5J	4A	U2870D	7F	2C	U2870D	7F	4C
R2903	9K	3B	R2940	7D	3D	U2880A	7J	1C	U2960A	8J	3F
R2905	5K	2A	R2941	8B	4D	U2880B	7M	1F	U2960B	7M	3F
R2910	1H	4A	R2973	7L	4D	U2885A	7M	2F	U2960C	7M	3F
R2911	1H	4A	R2982	7E	3F	U2885B	7J	2F	U2960D	5E	3F
R2912	2J	4A	U2500	4M	2B	U2885C	7H	2F	U2960E	7G	3F
R2913	2K	4A	U2895	2M	2B	U2890A	6K	2F	U2960F	7G	3F
R2914	2K	4B	U2910A	5J	2A	U2890B	6J	2F	U2960G	7L	3F
R2915	3K	4B	U2910B	5J	2A	U2900A	7J	3A	U2960J	7K	3F
R2916	6D	2D	U2910C	5M	2A	U2900B	6J	3A	U2965	7K	4E
R2918	6C	2C	U2910D	5M	2A	U2900C	6J	3A	VR2925	2K	3C
R2919	4L	4B	U2920A	4L	2A	U2905	4H	3A			
R2920	4K	4B	U2920B	2N	2A	U2910	1J	3A	W411	8F	1B
R2921	4K	3B	U2930	6B	1C	U2920	5F	3E	W411	8A	1B
R2922	4K	3B	U2935A	6D	2C	U2930	4G	2D	W2851	2D	1B
						U2935	1D	3C			
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
P411	1A	CHASSIS	P411	1F	CHASSIS						

[1]A partial schematic of the A4 Readout board is also shown in fig. FO-21. Component locations are shown in fig. FO-12.

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-21 for IC power connections and power distribution.

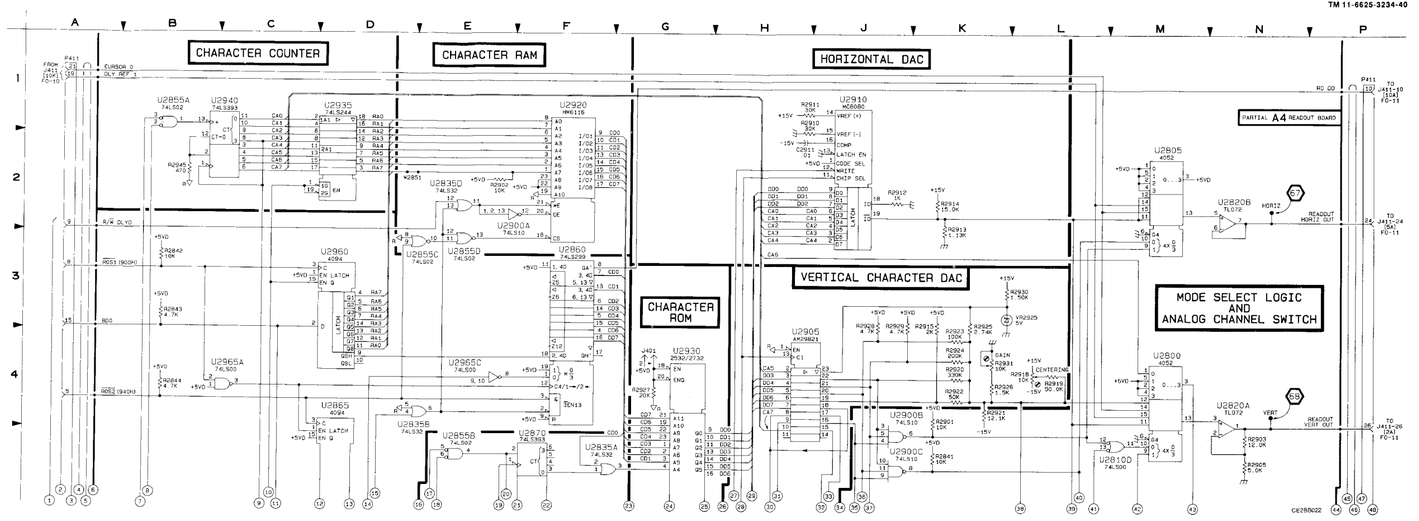
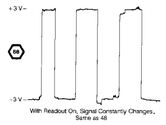


Figure FO-13. Readout Schematic (Sheet 1 of 2).

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated on sheet 1 of this figure and in figure FO-12. The waveforms are representative of signals that may be expected at the associated points when the following setup conditions are observed.



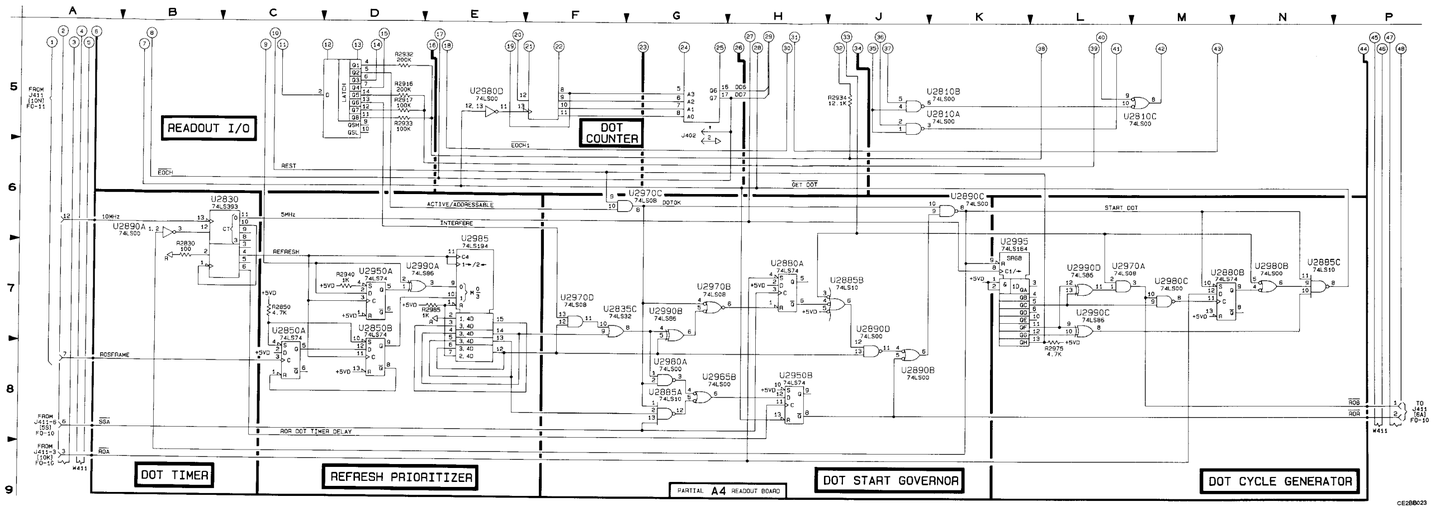
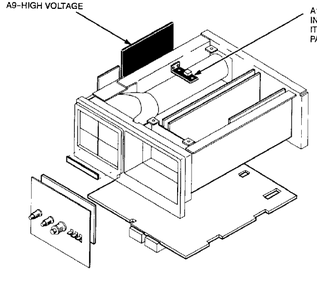


Figure FO-13. Readout Schematic (Sheet 2 of 2).

A9 High Voltage Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
C91	15	CR1990	15	R1834	11	R1913	15
C1812	15			R1842	11	R1920	15
C1813	15	DS90	15	R1848	15	R1922	15
C1814	15	DS91	15	R1853	15	R1941	15
C1815	15			R1854	15	R1944	15
C1870	15	F1900	15	R1855	15	R1945	15
C1885	15			R1856	15	R1950	15
C1886	15	J901	15	R1857	15	R1951	15
C1888	15	J902	15	R1858	15	R1952	15
C1889	15	J903	15	R1864	15	R1953	15
C1890	15	J904	15	R1870	15	R1971	15
C1891	15			R1871	15	R1972	15
C1912	15	L1921	15	R1872	15	R1973	15
C1915	15	L1974	15	R1873	15	R1990	15
C1932	15			R1878	15	R1991	15
C1950	15	P191	11	R1880	15	R1992	15
C1951	15	P191	15	R1881	15	R1994	15
C1971	15	P191	21	R1885	15		
C1972	15			R1888	15	T1970	15
C1973	15	Q1851	15	R1890	15		
C1980	15	Q1852	15	R1891	15	U1830	15
C1990	15	Q1890	15	R1892	15	U1890	15
C1991	15	Q1980	15	R1893	15	U1890	21
		Q1981	15	R1895	15	U1956	15
CR1894	15			R1896	15	U1956	21
CR1895	15	R1812	15	R1897	15		
CR1915	15	R1813	15	R1898	15	VR1891	15
CR1930	15	R1814	15	R1901	15		
CR1950	15	R1815	15	R1910	15	W1909	21
CR1953	15	R1833	11	R1911	15		



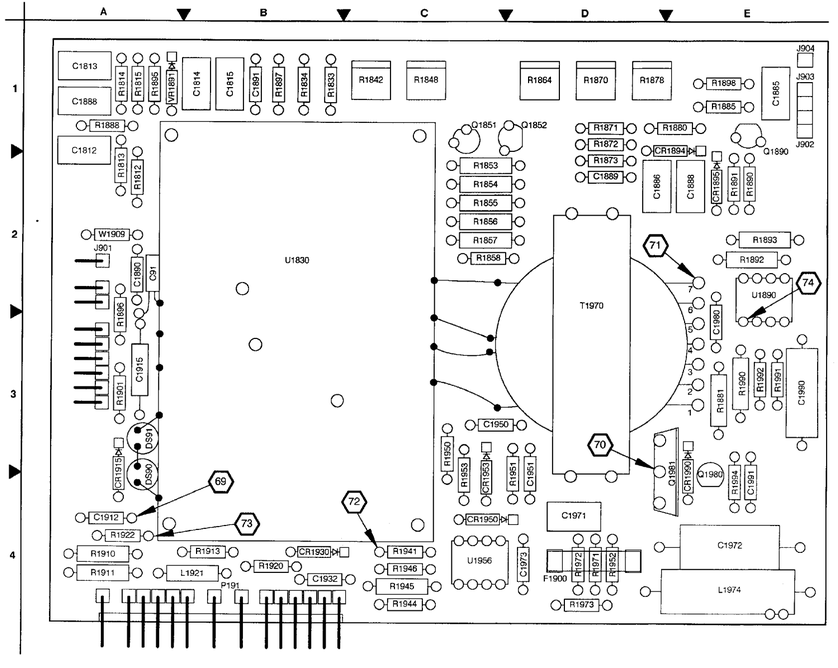


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Figure FO-14. A9 High Voltage Board Component Locator.
FP-47/(FP-48 blank)

Location of the Components Shown in this Figure and in Figures FO-7 and FO-14.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A1 MAIN BOARD[1]											
CR75	2C	9B	J120	2C	6A	J191	2D	10A			
A9 HIGH VOLTAGE BOARD[2]											
C91	3H	2A	CR1953	6D	3D	R1814	6F	1A	R1915	6M	4A
C1612	5F	1A	CR1960	5E	3E	R1815	6F	1A	R1913	7E	4B
C1613	6F	1A				R1846	4G	1C	R1920	7E	4B
C1614	5F	1B	D590	5J	3A	R1853	5E	2D	R1922	7F	4A
C1615	5H	1B	D591	5J	3A	R1854	6E	2D	R1941	6F	4C
C1670	3H	1C				R1855	5D	2D	R1944	7E	4C
C1695	4G	1E	F1906	9B	10Z	R1870	5E	2D	R1945	6E	4C
C1696	6D	2D				R1871	5E	2D	R1950	6D	3C
C1888	3G	1A	J901	3H	2A	R1872	5E	2D	R1951	6D	3C
C1889	3C	2E	J901	5H	2A	R1884	3E	1D	R1952	7D	3C
C1890	3G	2A	J901	8L	2A	R1870	3G	1D	R1953	6D	3C
C1891	3G	1B	J902	2H	1Y	R1871	5E	1D	R1971	6C	4D
C1912	6M	4A	J903	4H	1F	R1872	6E	1D	R1972	6D	4D
C1915	7F	3A	J904	7K	1F	R1873	3E	1D	R1973	7E	4D
C1952	7E	4B				R1878	6F	1E	R1960	4E	3E
C1960	7D	3D	L1021	7M	4B	R1880	4G	1E	R1961	5D	3E
C1961	7D	3D	L1974	9B	4E	R1881	6E	3E	R1962	6E	3E
C1972	5B	4E	P191	2D	6B	R1885	3G	1E	R1994	6F	4B
C1973	6E	4D	P591	7A	6B	R1886	4G	2A	T1970	7C	3D
C1980	6B	2E				R1891	4F	2E			
C1990	6D	3E	Q1851	5E	1C	R1892	4E	2E	U1930	9G	2B
C1991	6F	4E	Q1852	5E	1D	R1893	3E	2E	U1960	8D	2C
C1994	6C	1E	Q1890	4D	1E	R1894	3F	1A	U18908	3F	2E
CR1665	6C	2E	Q1981	6B	3E	R1896	3G	2A	U18954	7D	4C
CR1666	6C	2E				R1927	3G	1B	U19569	7D	4C
CR1950	6B	4B	Q1952	6F	2A	R1958	4H	1E			
CR1990	6F	4C	R1913	6F	2A	R1951	5H	3A	VR1891	3F	1A
						R1970	6H	4A			
A13 CRT TERMINATOR											
J904	5M	5M	R1951	5L	5L						
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
LR1513	1L	CHASSIS	P901	8L	CHASSIS	R477	5A	CHASSIS	W900	7H	CHASSIS
LR1514	1L	CHASSIS	P902	2H	CHASSIS				W901	5H	CHASSIS
			P903	4H	CHASSIS	V900	1K	CHASSIS	W902	2H	CHASSIS
P125	2B	CHASSIS							W903	4H	CHASSIS
P871	5H	CHASSIS	T870	2A	CHASSIS	W900	2H	CHASSIS			
P901	5H	CHASSIS	T870	2A	CHASSIS	W900	8L	CHASSIS			

[1]A partial schematic of the A1 Main board is also shown in fig. FO-9, FO-10, FO-11, and FO-20. Component locations are shown in fig. FO-7.
[2]A partial schematic of the A9 High Voltage board is also shown in fig. FO-11 and FO-21. Component locations are shown in fig. FO-14.

NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- See fig. FO-21 for IC power connections and power distribution.

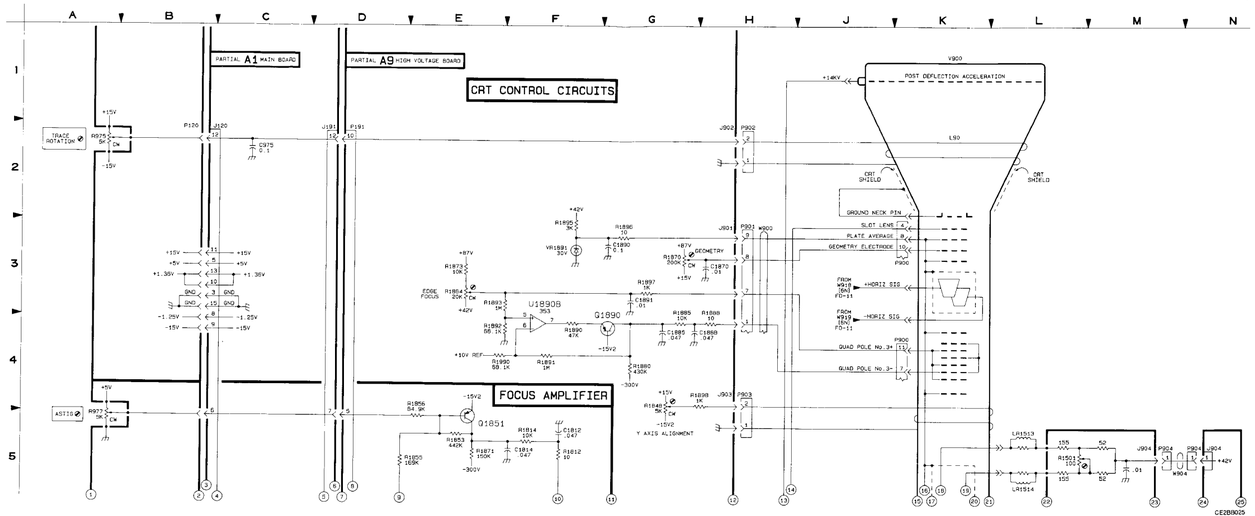
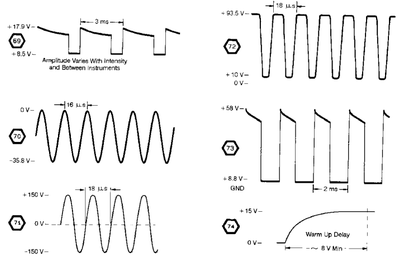


Figure FO-15. High Voltage Supply and CRT Schematic (Sheet 1 of 2).

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated on sheet 2 of this figure and in figure FO-14. The waveforms are representative of signals that may be expected at the associated points whenever the instrument is running.



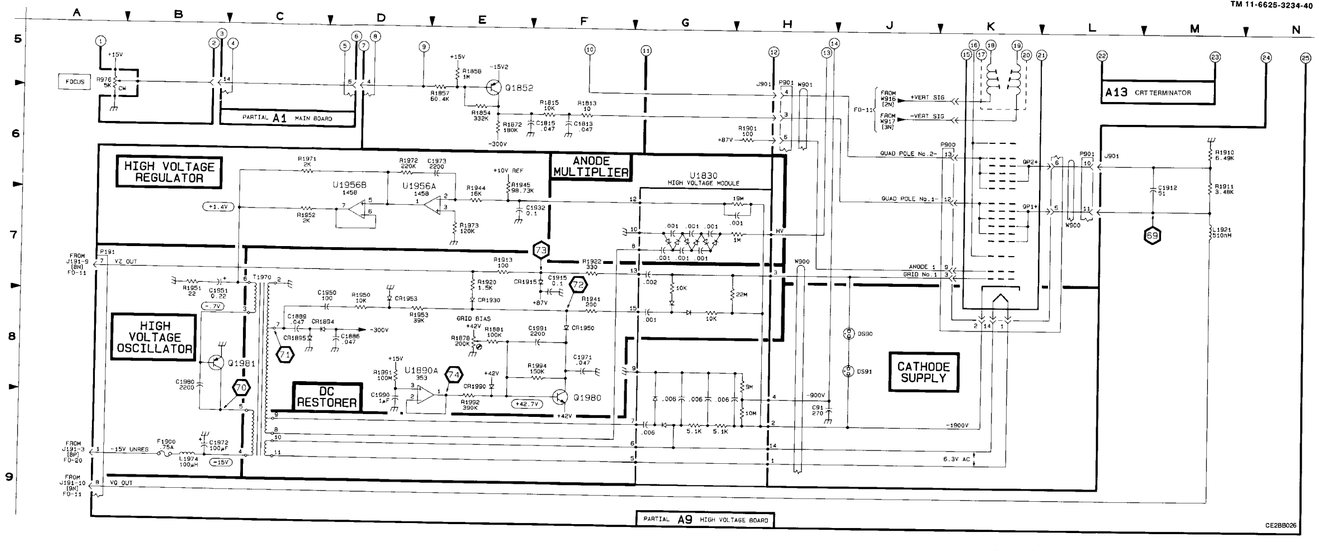
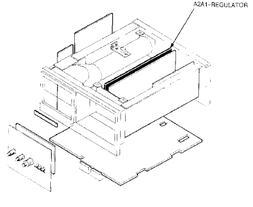


Figure FO-15. High Voltage Supply and CRT Schematic (Sheet 2 of 2).

A2A1 Regulator Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
C1015	18	CR1332	19	R1211	18	R1299	19
C1216	18	CR1334	19	R1212	18	R1300	19
C1256	18	CR1351	19	R1213	18	R1301	19
C1220	19	CR1376	19	R1214	18	R1302	19
C1222	19			R1215	18	R1304	19
C1240	19	E1001	18	R1216	18	R1305	19
C1243	19	E1002	18	R1217	18	R1306	19
C1245	19			R1218	18	R1307	19
C1248	19	F1330	19	R1219	18	R1308	19
C1260	19			R1220	19	R1309	19
C1261	19	J124	19	R1221	19	R1310	19
C1270	19	J132	18	R1222	19	R1332	19
C1272	19	J133	18	R1223	19	R1333	19
C1274	19	J201	19	R1224	19	R1334	19
C1280	19	J202	19	R1225	19	R1351	19
C1290	19	J204	19	R1227	19	R1352	19
C1291	19	J205	19	R1228	19	R1353	19
C1292	19	J206	18	R1229	19	R1354	19
C1300	19	J208	18	R1230	19	R1355	19
C1330	19	J207	19	R1231	19	R1357	19
C1331	19	J208	19	R1232	19	R1358	19
C1351	19	J231	19	R1241	19	R1359	19
C1361	19	J232	19	R1242	19	R1370	19
C1374	19	J233	19	R1243	19	R1372	19
C1400	19	J234	19	R1244	19	R1374	19
C1402	19			R1245	19	R1376	19
		L1011	18	R1247	19	R1378	19
CR1011	18	L1012	18	R1248	19	R1379	19
CR1220	18	L1402	19	R1249	19	R1380	19
CR1221	19			R1261	19	R1381	19
CR1240	19	P208	19	R1262	19	R1382	19
CR1242	19			R1263	19	R1383	19
CR1243	19	Q1220	19	R1264	19	R1384	19
CR1244	19	Q1221	19	R1270	19	S350	18
CR1256	19	Q1222	19	R1271	19		
CR1261	19	Q1223	19	R1274	19	T1229	19
CR1262	19	Q1240	19	R1280	19		
CR1263	19	Q1241	19	R1281	19	TP208	19
CR1264	19	Q1243	19	R1282	19		
CR1281	19	Q1244	19	R1283	19	U1202	19
CR1282	19	Q1245	19	R1284	19	U1210	19
CR1283	19	Q1261	19	R1285	19	U1270	19
CR1290	19	Q1280	19	R1286	19	U1271	19
CR1294	19	Q1300	19	R1287	19	U1280	19
CR1295	19	Q1301	19	R1290	19	U1300	19
CR1301	19	Q1351	19	R1291	19	U1330	19
CR1302	19	Q1370	19	R1293	19	U1371	19
CR1303	19	Q1371	19	R1294	19		
CR1330	19			R1295	19	VR1233	19
CR1331	19	R1010	18	R1296	19	W251	19
				R1298	19		



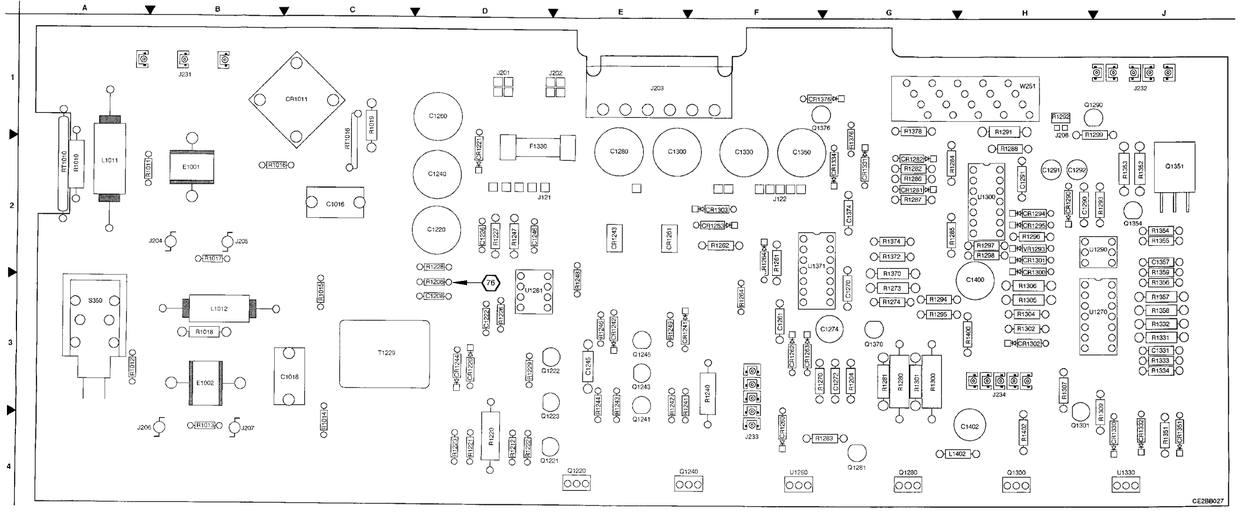
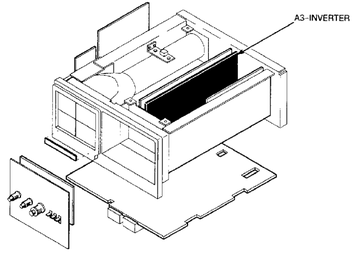


Figure FO-16. A2A1 Regulator Board Component Locator.
FP-53/(FP-54 blank)

A3 Inverter Board Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
C1020	18	CR1050	18			R1063	18
C1021	18	CR1060	18	LR1060	18	R1064	18
C1022	18	CR1062	18			R1065	18
C1023	18	CR1063	18	Q1021	18	R1066	18
C1025	18	CR1064	18	Q1022	18	R1067	18
C1029	18	CR1065	18	Q1029	18	R1068	18
C1032	18	CR1070	18	Q1030	18	R1069	18
C1033	18	CR1072	18	Q1040	18	R1070	18
C1034	18	CR1101	18	Q1050	18	R1071	18
C1035	18	CR1102	18	Q1060	18	R1072	18
C1040	18	CR1103	18	Q1062	18	R1075	18
C1042	18	CR1104	18	Q1070	18	R1110	18
C1048	18	CR1105	18	Q1110	18	R1111	18
C1050	18	CR1106	18			R1112	18
C1051	18	CR1110	18	R1018	18	R1113	18
C1052	18	CR1113	18	R1019	18	R1114	18
C1062	18	CR1114	18	R1020	18	R1115	18
C1065	18	CR1115	18	R1022	18	R1129	18
C1066	18	CR1116	18	R1023	18	R1130	18
C1067	18	CR1121	18	R1024	18		
C1071	18	CR1122	18	R1025	18	RT1110	18
C1072	18	CR1123	18	R1027	18		
C1075	18	CR1124	18	R1028	18	T1020	18
C1101	18	CR1131	18	R1029	18	T1050	18
C1102	18	CR1132	18	R1030	18	T1060	18
C1110	18			R1031	18		
C1111	18	F1101	18	R1032	18	U1029	18
C1112	18	F1102	18	R1033	18	U1030	18
C1113	18			R1034	18	U1040	18
C1114	18	J231	18	R1035	18	U1062	18
C1115	18	J232	18	R1036	18	U1064	18
C1116	18	J233	18	R1037	18	U1066	18
C1120	18	J234	18	R1040	18	U1110	18
C1130	18	J301	18	R1041	18		
C1132	18	J302	18	R1042	18	VR1020	18
		J303	18	R1044	18	VR1062	18
CR1022	18	J304	18	R1045	18		
CR1023	18			R1046	18	W1021	18
CR1028	18	L1110	18	R1050	18	W1022	18
CR1030	18	L1113	18	R1052	18	W1050	18
CR1034	18	L1114	18	R1060	18	W1060	18
CR1035	18	L1115	18	R1061	18	W1101	18
CR1040	18	L1116	18	R1062	18	W1102	18



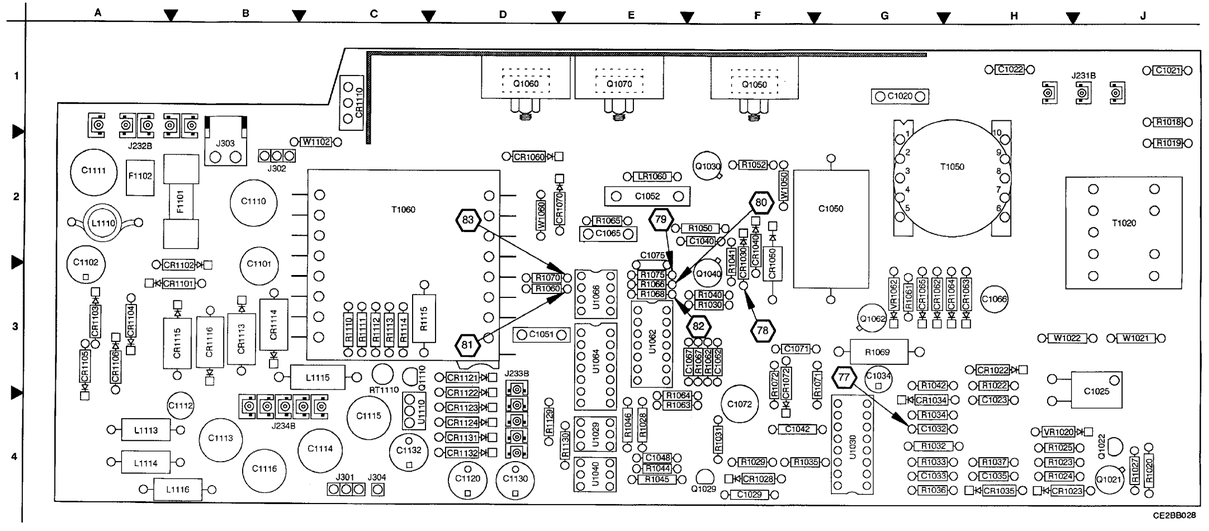


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Figure FO-17. A3 Inverter Board Component Locator.
FP-55/(FP-56 blank)

Location of the Components Shown in this Figure and in Figures FO-16 and FO-17.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A2A1 REGULATOR BOARD[1]														
C1018	6D	2C	J122	3D	2F	L1012	6C	3B	R1016	6D	2B	S950	6B	3A
C1019	6C	3C	J204	5B	2B				R1017	6B	2B			
C1036	3C	3D	J205	6B	2B	R1035	5C	2A	R1018	6C	3B	T1229	3C	3D
			J206	6B	4B	R1051	5C	2A	R1019	6D	1C			
CR1011	5D	1C	J207	6B	4B	R1052	6C	3A	R1209	6D	2D			
			J211A	5D	1B	R1053	6C	4B	R1209	3C	2D			
E1001	6C	2B				R1014	3C	4C	RT1010	5C	2A			
L1002	6D	2B	L1011	5C	2A	R1015	3C	3C	RT1018	6D	1C			
A3 INVERTER BOARD[2]														
C1020	4E	1D	CR1022	3F	3H	J2328	9F	*A	R1020	5N	4F	R1115	1L	3D
C1021	7E	1J	CR1023	3H	4H	J2330	4F	4D	R1030	6H	3F	R1129	4N	4D
C1022	5E	1H	CR1026	3N	4F	J2340	7F	4B	R1031	4L	4F	R1130	4N	4D
C1023	4D	1H	CR1035	6H	2F	J301	9F	4D	R1032	4L	4G			
C1026	3F	3J	CR1054	4L	4G	J302	8F	2B	R1033	5L	3G	R1116	2M	3C
C1027	4N	4D	CR1055	5L	4H	J303	8F	1A	R1034	3L	4G			
C1030	7L	4D	CR1062	6H	2F	J304	1N	4C	R1035	4L	4F	T1002	6E	2J
C1033	7L	4D	CR1063	6L	2H				R1036	5L	4G	T1050	6F	2H
C1034	3L	3G	CR1090	6L	2H	L1110	9N	2A	R1037	4L	4H	T1060	6L	2C
C1035	5L	4H	CR1092	7F	2H	L1113	8N	4A	R1042	6H	3F			
C1042	6J	2F	CR1093	7G	3H	L1114	8N	4A	R1061	6H	2F	U1026	3N	4F
C1043	4J	4F	CR1094	7F	3H	L1115	7N	3B	R1062	3H	4G	U1230	5K	4G
C1060	6G	2G	CR1095	7G	3G	L1116	7N	4A	R1063	3H	4E	U1040	3G	4E
C1061	9F	2D	CR1072	6G	3F	LR1060	6K	2E	R1064	4M	4E	U1062A	8H	2E
C1062	9G	2E	CR1101	9M	3A				R1065	5M	4E	U1062B	8H	3E
C1063	9F	3F	CR1102	9M	2M	Q1021	3G	4J	R1066	5M	2F	U1062C	9F	3C
C1065	6L	2E	CR1103	9M	3A	Q1022	4G	4J	R1067	6M	2G	U1062D	9G	3E
C1066	8G	3H	CR1104	8N	3A	Q1028	3N	4F	R1081	7G	3G	U1064A	9H	3C
C1067	9F	3F	CR1105	7N	3A	Q1030	6H	2F	R1082	8F	3F	U1064B	9G	3E
C1072	9H	3F	CR1106	7N	3A	Q1040	6J	2F	R1083	9F	4E	U1064	8H	3E
C1073	7J	2E	CR1112	7M	1C	Q1060	6G	1F	R1084	9F	3E	U1090A	7L	3E
C1074	7J	2E	CR1113	6M	3B	Q1080	6K	1D	R1085	6L	2E	U1090B	5J	3E
C1101	9M	2B	CR1114	7M	3B	Q1082	7H	3G	R1086	8J	3E	U1098	7G	3E
C1102	9M	2A	CR1115	7M	3B	Q1072	9K	3E	R1087	8F	3E	U1110	1L	4C
C1110	9M	2B	CR1116	7M	3B	Q1110	2L	3C	R1088	8J	3E			
C1111	9M	2A	CR1121	6M	2D				R1089	7H	3G	VR1020	4G	4H
C1112	8N	4B	CR1122	6M	3D	R1018	7E	1J	R1029	9K	2G	VR1028	7G	3G
C1113	8N	4B	CR1123	6M	4D	R1019	6E	2J	R1071	6H	3D			
C1114	8N	4B	CR1124	6M	4D	R1020	3F	2J	R1072	6H	3F	W1023	7E	3J
C1115	7N	4C	CR1132	5M	4D	R1022	3G	3H	R1073	8G	3E	W1202	6E	3H
C1116	7N	4C				R1023	3G	4H	R1075	8H	3C	W1203	6G	2H
C1120	6M	4D	T1103	8N	2B	R1024	3H	4H	R1111	2M	3C	W1060	6L	2D
C1130	5M	4D	T1102	9H	2A	R1025	5G	4H	R1112	2M	3C	W1101	6K	2C
C1132	6M	4C	A3T19	5E	1J	R1026	3M	4E	R1113	2L	3C	W1102	6N	2B
						R1028	3M	4E	R1114	2L	3C			
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)														
B10	1P	CHASSIS	F90	5A	CHASSIS	F205	6B	CHASSIS	P233	4F	CHASSIS	S1020	5C	CHASSIS
C10	1N	CHASSIS	FD1	5E	CHASSIS	F207	6B	CHASSIS	P234	7F	CHASSIS			
			F205	6B	CHASSIS	P231	5E	CHASSIS						
						P232	9F	CHASSIS	S90	6A	CHASSIS			

[1]A partial schematic of the A2A1 Regulator board is also shown in fig. FO-19. Component locations are shown in fig. FO-16.
[2]Component locations for the A3 Inverter board are shown in fig. FO-17.

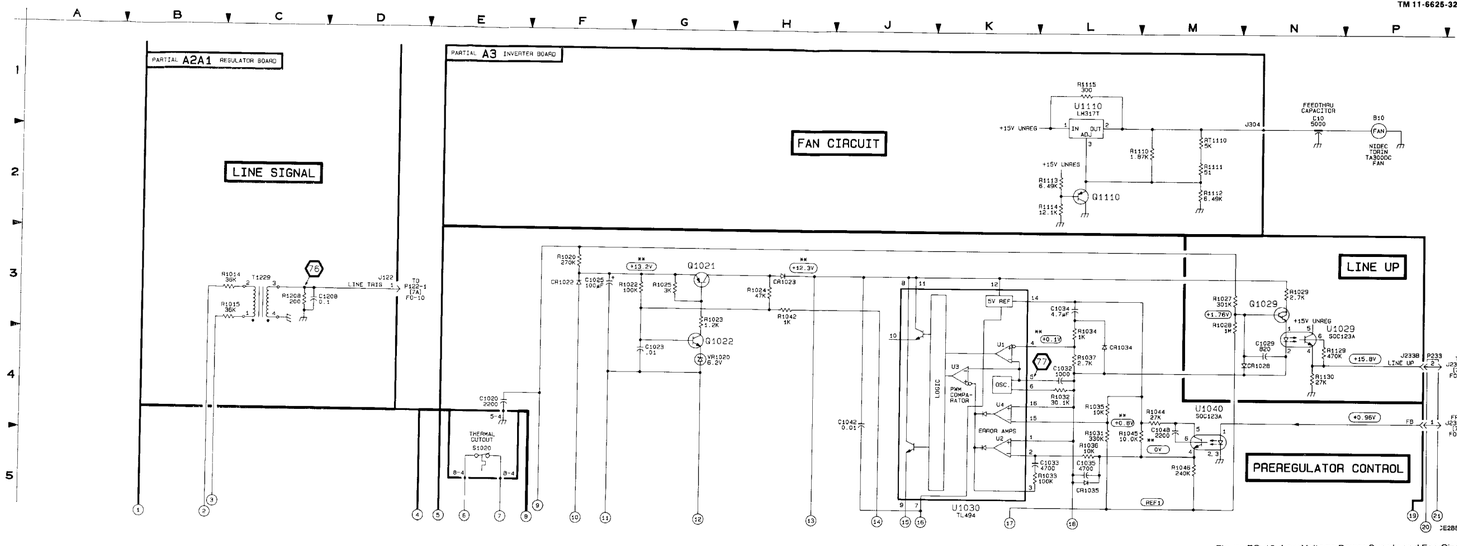
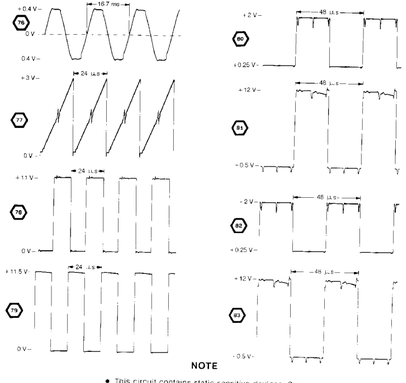


Figure FO-18. Low Voltage Power Supply and Fan Circuit Schematic (Sheet 1 of 2).
FP-57/(FP-58 blank)

TEST WAVEFORMS FOR THIS FIGURE

The numbered waveforms below were obtained at the test points indicated on sheets 1 and 2 of this figure and in figures FO-16 and FO-17. The waveforms are representative of signals that may be expected at the associated points whenever the instrument is running.



NOTE

- This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.
- In this figure, an asterisk (*) indicates a voltage with respect to REF1. Two asterisks (**) indicate a voltage with respect to REF2.

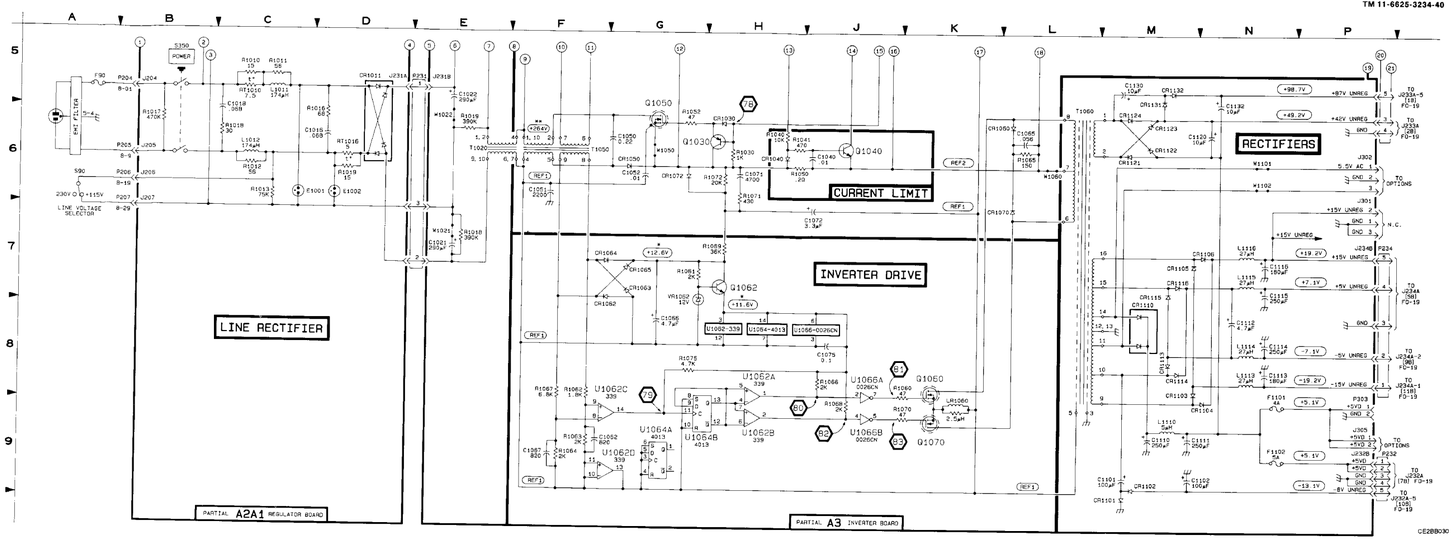


Figure FO-18. Low Voltage Power Supply and Fan Circuit Schematic (Sheet 2 of 2).

Location of the Components Shown in this Figure and in Figure FO-16.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A2A1 REGULATOR BOARD[1]											
C1220	2L	2D	CR1334	9L	2G	R1223	1D	4D	R1334	11E	3J
C1222	1D	3D	CR1351	10G	4J	R1226	2C	3D	R1351	10G	4J
C1226	2D	2D	CR1376	8H	1G	R1227	2D	2D	R1352	10J	2J
C1240	3L	2D	F1330	11F	2D	R1228	2D	2D	R1353	10J	2J
C1245	3F	3E	J121	1N	2E	R1229	1C	3D	R1354	10J	2J
C1246	3F	2E	J122	3N	2F	R1240	3G	3F	R1355	10J	2J
C1260	5L	1D	J201	4N	1D	R1241	3G	3F	R1356	10G	3J
C1261	4J	3F	J202	5N	1E	R1242	3G	3F	R1357	10K	3J
C1270	7K	3G	J203	6N	1E	R1243	3G	3E	R1358	9H	3J
C1272	7K	3G	J208	6E	1H	R1244	3F	3E	R1359	10G	2J
C1274	7K	3G	J232A	10B	1J	R1246	3F	3E	R1370	8G	2G
C1280	6L	2E	J232A	7B	1J	R1247	3F	2E	R1372	8G	2G
C1290	6D	2H	J233A	1B	3F	R1248	4F	3E	R1374	7G	2G
C1291	6E	2J	J233A	7B	3F	R1249	3F	3F	R1376	8H	1G
C1292	7F	2H	J233A	7N	3F	R1261	4H	2F	R1378	7H	1G
C1300	8L	2E	J234A	11B	3H	R1262	5H	2F	R1400	5C	3H
C1330	11L	2F	J234A	5B	3H	R1264	4H	3F	R1402	9C	4H
C1331	11F	3J	J234A	9B	3H	R1270	7K	3G	TP201	6F	2H
C1350	9L	2F	L1402	9C	4H	R1273	7J	3G	U1260	5J	4F
C1357	10H	2J	P208	6E	1H	R1274	7K	3G	U1270A	8J	3J
C1374	8G	2G	Q1220	1E	4E	R1280	6K	3G	U1270B	8J	3J
C1400	6C	3H	Q1221	1D	4E	R1281	6K	3G	U1270C	11F	3J
C1402	9C	4H	Q1222	2C	3E	R1282	6K	2G	U1270D	10H	3J
CR1220	2E	3D	Q1223	1D	3E	R1283	6J	4G	U1270	6C	3J
CR1221	2L	2D	Q1240	3G	4F	R1284	7J	2H	U1281A	2D	3D
CR1241	3G	3F	Q1241	3F	4E	R1285	7J	2H	U1281B	4F	3D
CR1242	3F	3E	Q1243	3F	3E	R1286	6K	2G	U1281	7C	3D
CR1243	4L	2E	Q1245	3F	3E	R1287	6J	2G	U1290	6D	2J
CR1244	2D	3D	Q1280	6K	4G	R1291	6E	1H	U1300A	6J	2H
CR1260	5J	4F	Q1281	6J	4G	R1292	6E	2H	U1300B	6J	2H
CR1261	6L	2E	Q1290	7E	1J	R1293	6E	2H	U1300C	6E	2H
CR1262	4J	3F	Q1300	9K	4H	R1294	7E	3G	U1300D	6E	2H
CR1263	5J	3F	Q1301	9J	4J	R1295	7E	3G	U1300	7C	2H
CR1264	4H	2F	Q1351	10J	2J	R1296	6E	3H	U1330	11E	4J
CR1281	6J	2G	Q1354	10H	2J	R1297	6D	2H	U1371A	4J	2G
CR1282	6J	2G	Q1370	7F	3G	R1298	7D	2H	U1371B	5H	2G
CR1283	6L	2F	Q1376	8H	1G	R1299	7E	1J	U1371C	7K	2G
CR1290	6E	2H	R1204	8F	3G	R1300	8K	3G	U1371D	8G	2G
CR1294	7E	2H	R1212	1C	4D	R1301	8K	3G	U1371	7C	2G
CR1295	7E	2H	R1220	1E	4D	R1302	8K	3H	VR1293	6F	2H
CR1300	8J	2H	R1221	1E	4D	R1304	9J	3H	W251	11N	1H
CR1301	8J	2H	R1222	1D	4D	R1305	8K	3H			
CR1302	8J	3H				R1306	8K	3H			
CR1303	8L	2F				R1307	9J	3H			
CR1330	11E	4J				R1309	9J	4J			
CR1331	10L	2G				R1331	11F	3J			
CR1332	11E	4J				R1332	11F	3J			
						R1333	11E	3J			
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
P251	7N	CHASSIS									

[1]A partial schematic of the A2A1 Regulator board is also shown in fig. FO-18. Component locations are shown in fig. FO-16.

NOTE

This circuit contains static-sensitive devices. See page C at the front of this manual for information on handling static-sensitive devices.

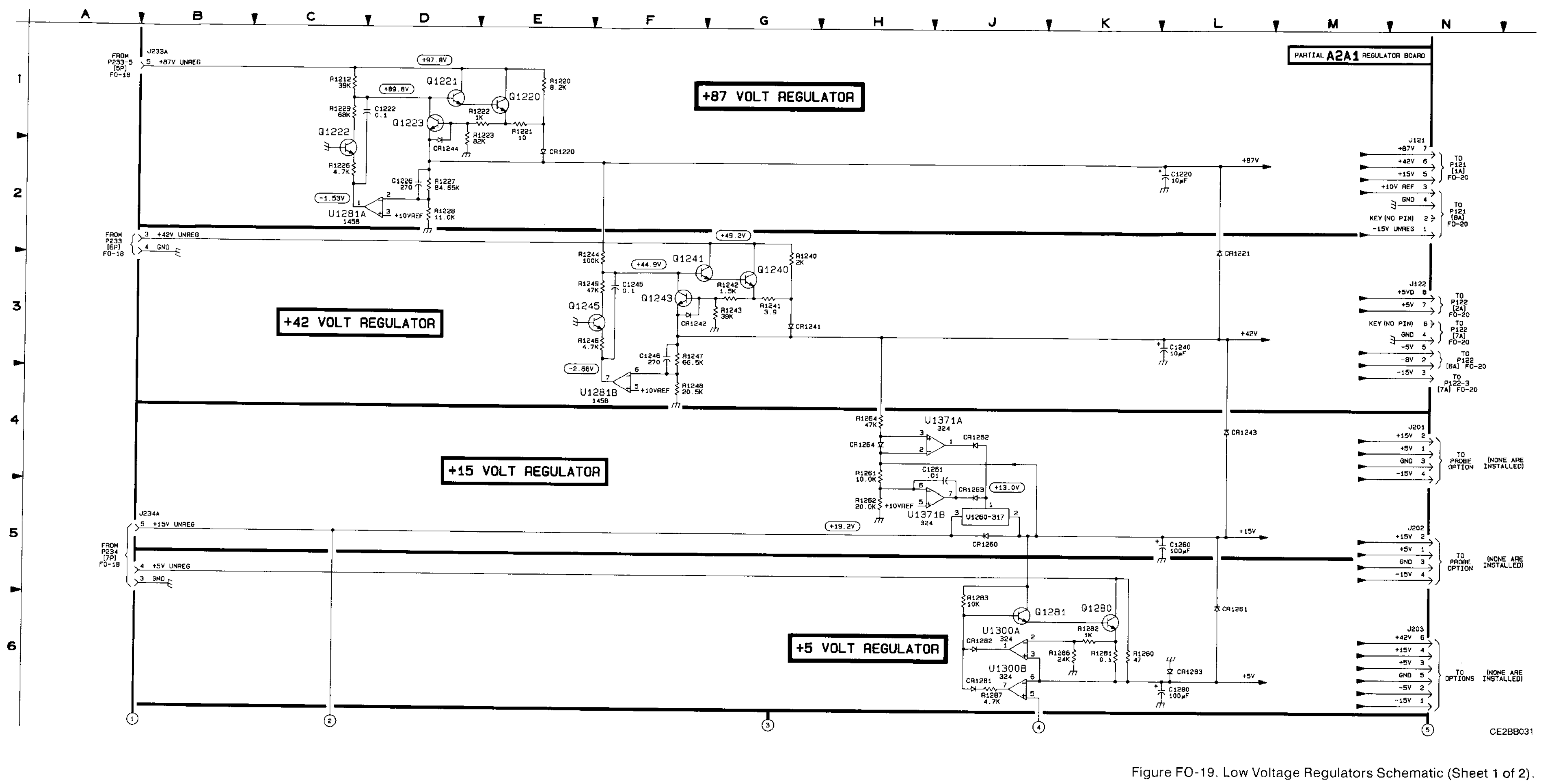


Figure FO-19. Low Voltage Regulators Schematic (Sheet 1 of 2).

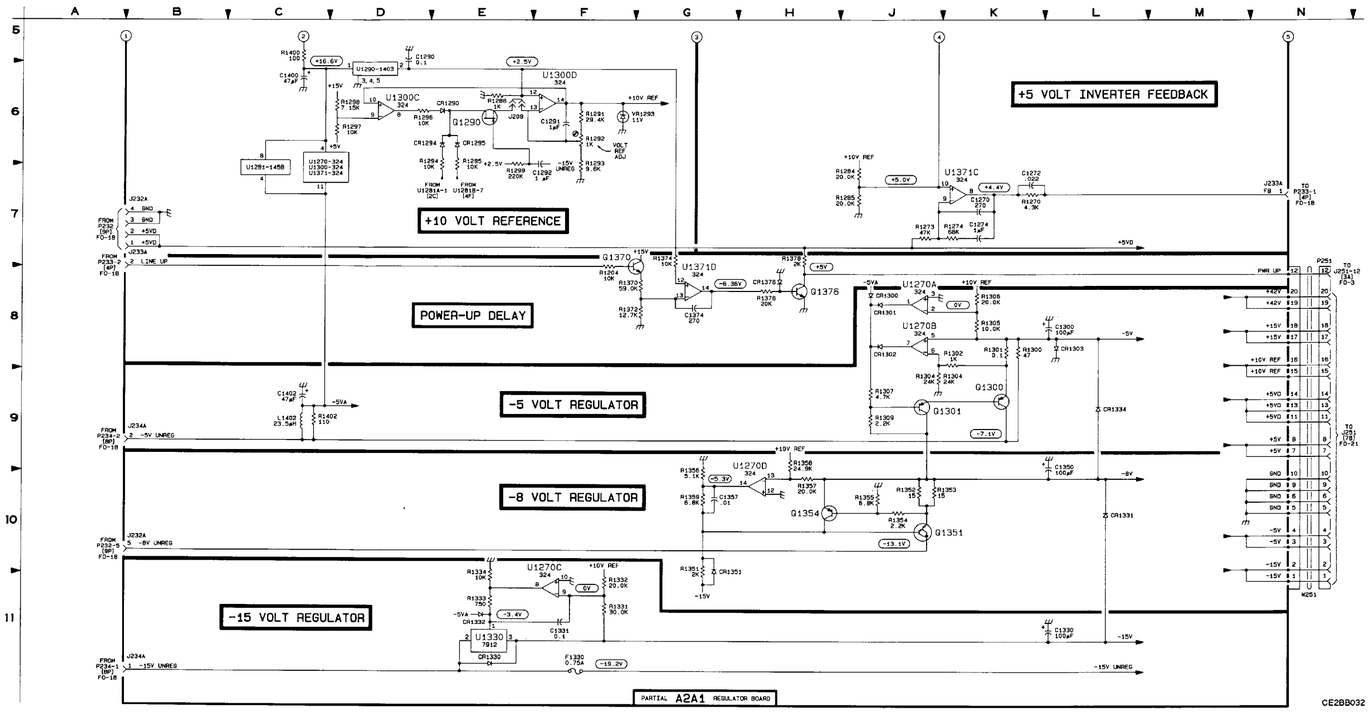


Figure FO-19. Low Voltage Regulators Schematic (Sheet 2 of 2).
FP-63/(FP-64 blank)

Location of the Components Shown in this Figure and in Figure FO-7.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A1 MAIN BOARD[1]											
C102	6A	7D	C810	2L	8G	L120	2B	5E	U160	2C	3D
C106	6B	6D	C811	3L	8G	L219	7B	3C	U165	3K	3F
C107	6B	6D	C819	6L	9F	L220	2B	3C	U170	4K	3E
C108	7B	7D	C850	6L	8F	L307	6D	3B	U180	3C	2E
C113	3B	6D	C903	3K	6K	L325	3D	3B	U200	4B	4C
C114	3B	6D	C933	2L	10G	L336	3D	1C	U300	4D	1A
C119	6B	5B	C938	7L	1G	L521	6E	3H	U350	2L	10B
C120	2B	6E	C940	6L	11H	L733	2G	7E	U400	4D	6F
C121	2B	6E	C943	3L	11H	L738	7G	7E	U450	2L	4F
C125	4A	6C	C958	3L	8L	L740	6G	7E	U500	4E	4G
C207	6A	6C	C966	1L	11L	L743	3G	7D	U600	4F	6J
C209	5C	4C	C967	1L	11K	L938	6J	7K	U650	4F	4K
C210	3C	4E	C973	7L	10L	L973	7L	10L	U700	4G	8C
C218	7C	3D	C976	3E	8M	L980	3E	7L	U800	4J	9F
C219	7C	3D	C977	3E	7L				U850	4K	9E
C220	2C	3C	C980	3E	7K	LR101	5A	6C	U860	4K	7F
C221	2C	3D	C981	3E	7L	LR107	5C	6E	U900	4H	10J
C225	4B	3C	C985	3F	5L	LR201	5B	5C	U910	2F	10G
C307	6D	3B	C988	6J	7L	LR218	6C	3D	U950	4J	8K
C325	3D	3C	C990	2L	9M	LR219	6C	3D	U975	3E	8M
C336	3D	1C							U980	3E	7L
C415	7L	5G	CR107	6B	5J	Q700	1G	10C	U985	3F	6M
C458	2L	3F	CR807	4J	8G						
C460	2L	3K	CR811	2H	8G	R125	3B	7D	VR125	3A	7D
C500	4E	3G	CR987	4J	9M	R225	3B	3C	VR225	3B	3C
C501	5E	3G				R700	1G	10C			
C521	5L	2J	J119	6P	4H	R701	1F	10C	W101	7B	10B
C675	3L	4J	J191	1P	10K	R702	2F	10D	W103	7B	8H
C710	2F	10D	J191	8P	10K	R811	2H	8G	W104	7B	3L
C722	3G	8D	J411	2P	1K	R951	8N	10K	W105	7B	5G
C723	3G	8D	J511	4P	1D				W109	8B	10M
C730	6C	6B	J511	8A	1D	U100	4B	6C	W121	2A	5J
C731	8C	9F	J512	9A	1H	U110	2B	8B	W121	8A	5J
C732	8B	9B				U120	2B	8C	W122	7A	5H
C733	2G	8E	L101	6B	7C	U130	2B	8C			
C738	7G	8E	L107	6B	6D	U140	3K	8B			
C740	6G	8D	L113	3B	6D	U150	3K	8C			
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
P121	1A	CHASSIS	P121	8A	CHASSIS	P122	2A	CHASSIS			

[1]A partial schematic of the A1 Main board is also shown in fig. FO-9, FO-10, FO-11, and FO-15. Component locations are shown in fig. FO-7.

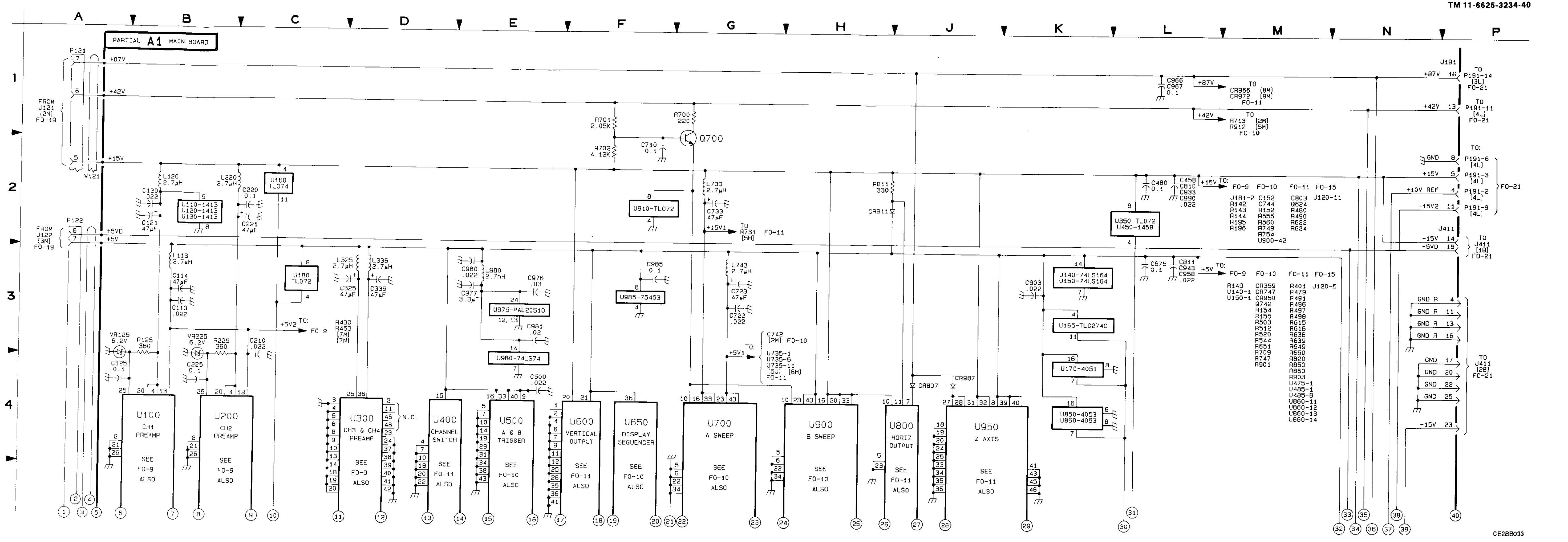


Figure FO-20. Power Distribution A Schematic (Sheet 1 of 2).

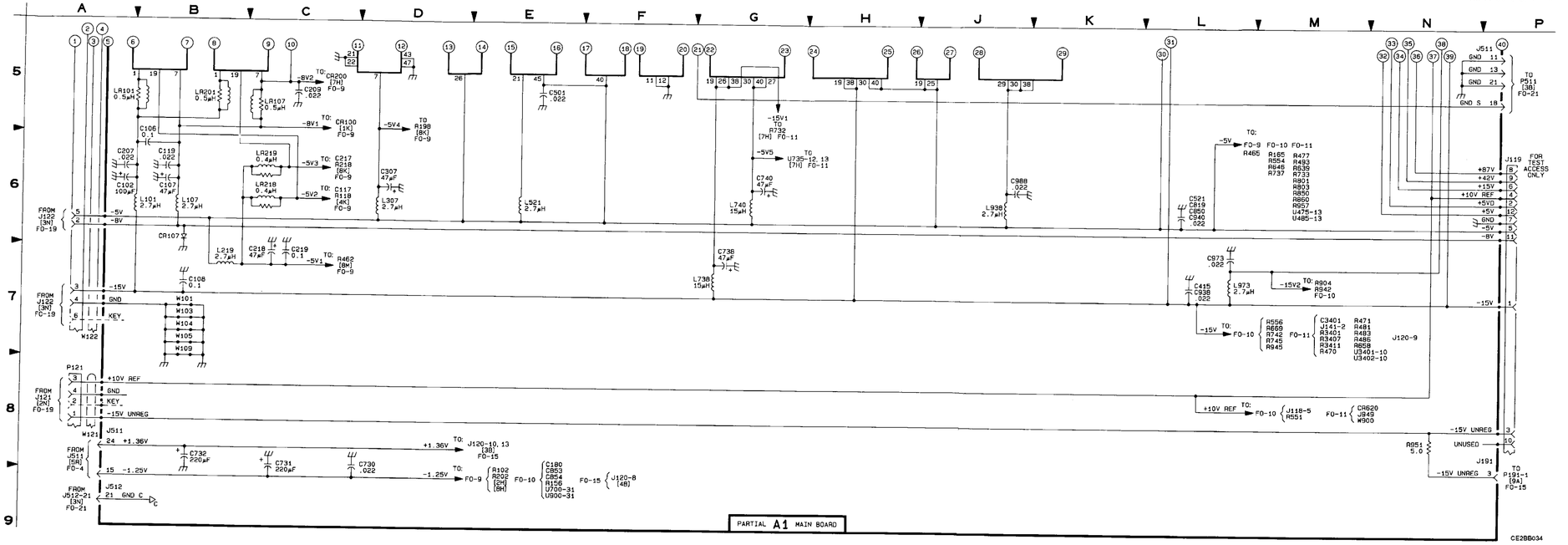


Figure FO-20. Power Distribution A Schematic (Sheet 2 of 2).
FP-67/(FP-68 blank)

Location of the Components Shown in this Figure and in Figures FO-2, FO-5, FO-12, and FO-14.

CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION	CIRCUIT NUMBER	SCHEM LOCATION	BOARD LOCATION
A4 READOUT BOARD[1]											
C2830	3B	7C	C2970	4B	3D	U2855	4H	2D	U2940	4H	4C
C2831	3B	2C	C2980	4B	3F	U2860	3F	3D	U2950	4H	4D
C2855	4B	1D	C2990	4B	3F	U2865	3G	2E	U2960	3G	3E
C2860	4B	2D				U2870	4H	2E	U2965	4H	4E
C2895	4B	2E	R2805	3C	2B	U2880	4H	1F	U2970	4H	4E
C2901	4B	3B				U2885	4H	2F	U2980	4H	3F
C2912	4B	3B	U2800	3D	2B	U2890	4H	2F	U2985	3G	3E
C2913	5B	4B	U2805	3D	2B	U2895	4H	3A	U2990	4H	3F
C2926	4B	3C	U2810	3H	2A	U2900	3F	3A	U2995	4H	4E
C2940	3B	4C	U2830	3H	1C	U2910	3E	3D			
C2950	4B	4D	U2835	3H	2C	U2920	3E	3F	VR2805	4D	2B
C2960	4B	3E	U2850	4H	1D	U2930	3F	2D	W411	5A	1B
A5 CONTROL BOARD[2]											
C2011	7B	1C	C2901	7D	4B	U2100	7B	1J	U2521	7G	3D
C2101	7C	1B	C2910	8B	4C	U2201	7E	2A	U2530	7G	3E
C2111	7C	1E	C2920	8C	4C	U2230	7E	2B	U2540	7J	3D
C2112	8C	1C	C2932	8C	3F	U2232	7E	2C	U2550	7H	3H
C2160	7C	1H	C2950	7D	4H	U2245	7E	2C	U2560	7G	4A
C2220	7B	2D	C2960	7C	4J	U2250	7F	2G	U2620	7C	4D
C2230	6C	2E	C2740	8B	4G	U2280	7G	2J	U2630	8C	4D
C2245	6B	2D				U2501	7E	2A	U2640	7H	4G
C2331	6B	2D	J201	6B	1D	U2401	7E	2A	U2650	7H	4H
C2430	7C	2H	J202	6J	1A	U2410	7H	2B	U2660	7E	4J
C2501	7C	2B	TP2073	5G	1L	U2420	6C	2D			
C2510	7C	3C	TP2124	5E	4A	U2430	6C	2E	W511	8B	4C
C2520	6C	3D				U2440	7J	2G	W512	8K	4G
C2530	6C	3F	U2101	7D	1A	U2450	7G	3A	W2070	5F	1K
C2552	7C	3H	U2140	7D	1F	U2510	7D	3C	W2410	5F	4C
						U2520	8D	3D	W2701	6E	4A
A6A1 FRONT PANEL BOARD[3]											
C2001	7K	4A	U2001	7L	3B	U2003	7L	3C	U2006	7L	3F
C2002	7K	3F	U2002	7L	2D	U2004	7L	3D			
C2019	7K	4D				U2005	7L	3F	W852	7K	3A
A9 HIGH VOLTAGE BOARD[4]											
P191	1B	4B	U1950	2D	2B	W1909	2B	2A			
			U1956	2D	2C						
CHASSIS PARTS (NOT MOUNTED ON ANY CIRCUIT BOARD)											
P411	3A	CHASSIS	P511	5A	CHASSIS	P512	5K	CHASSIS	P852	6J	CHASSIS

[1] A partial schematic of the A4 Readout board is also shown in fig. FO-13. Component locations are shown in fig. FO-12.
[2] A partial schematic of the A5 Control board is also shown in fig. FO-3 and FO-4. Component locations are shown in fig. FO-2.
[3] A partial schematic of the A6A1 Front Panel board is also shown in fig. FO-6. Component locations are shown in fig. FO-5.
[4] A partial schematic of the A9 High Voltage board is also shown in fig. FO-11 and FO-15. Component locations are shown in fig. FO-14.

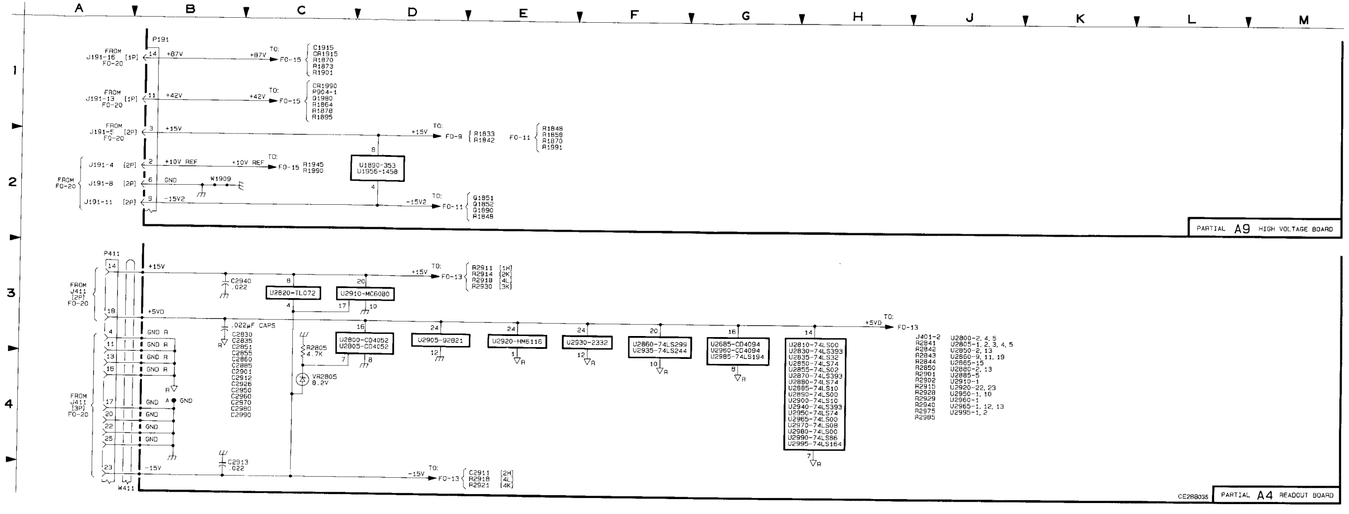


Figure FO-21. Power Distribution B Schematic (Sheet 1 of 2).

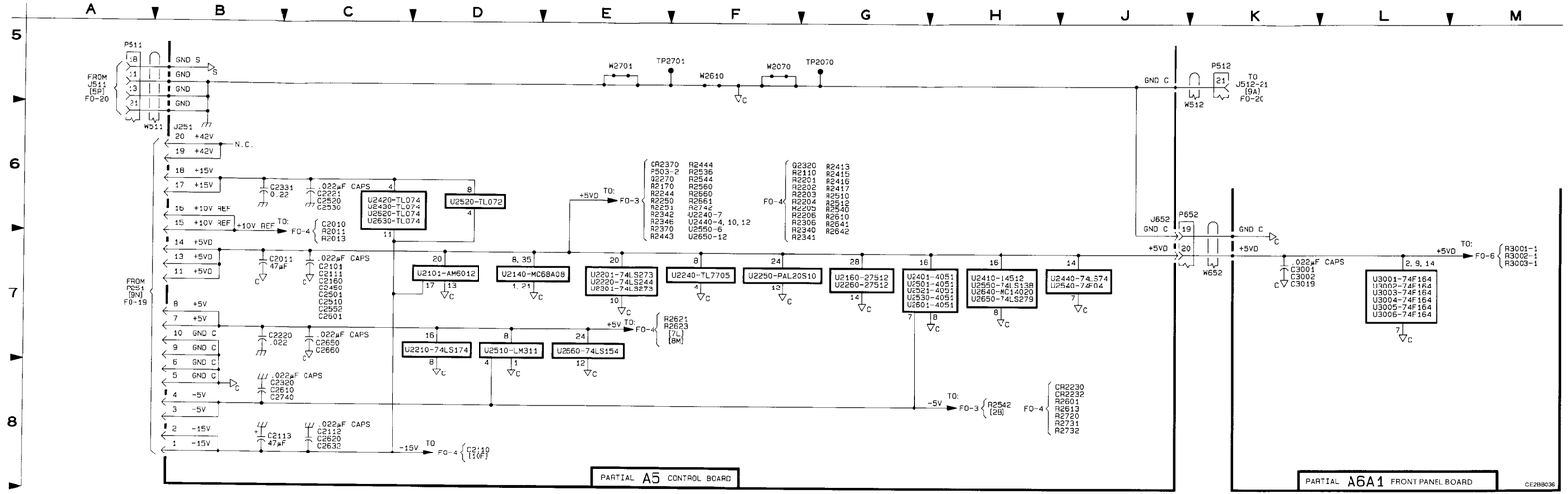


Figure FO-21. Power Distribution B Schematic (Sheet 2 of 2).

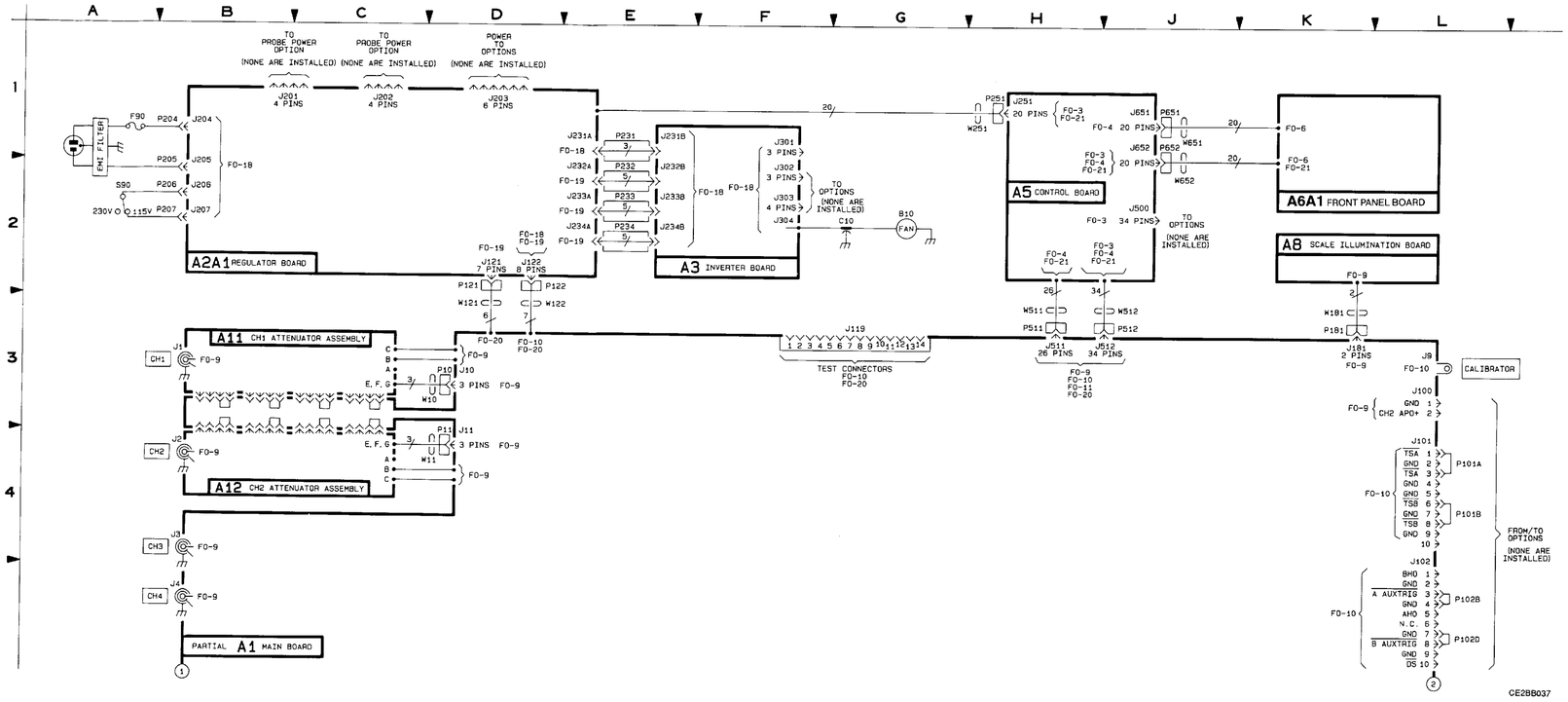


Figure FO-22. Interconnect and Chassis Parts Schematic (Sheet 1 of 2).
FP-73/(FP-74 blank)

Chassis Component-to-Schematic Cross Reference

CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER	CIRCUIT NUMBER	FO NUMBER
B10	18	P106	10	P511	21	R301	6
C15	18	P120	10	P512	3	R305	6
		P126	10	P513	3	R306	6
E350	9	P135	10	P512	21	R307	6
		P190	3	P551	5	R308	6
F90	18	P120	10	P552	6	R309	6
		P120	13	P552	21		
J1	8	P122	10	P901	15	S90	18
J2	9	P122	10	P902	15	S1920	18
J3	9	P123	20	P903	15		
J4	9	P141	11			V960	15
J5	9	P181	9	R134	9		
J6	11	P204	16	R251	10	W10	9
J7	10	P205	18	R352	12	W11	9
J8	10	P207	18	R375	15	W901	6
J12	10	P231	18	R377	15	W900	15
		P232	18	R3007	0	W902	15
LR1513	15	P233	18	R3008	6	W903	15
LR1514	15	P251	18	R3009	6	W910	11
		P251	19	R3010	6	W917	11
P1C	9	P311	3	R3011	6		
P1L	9	P311	21	R3012	6		
P105	9	P511	4	R3013	6		

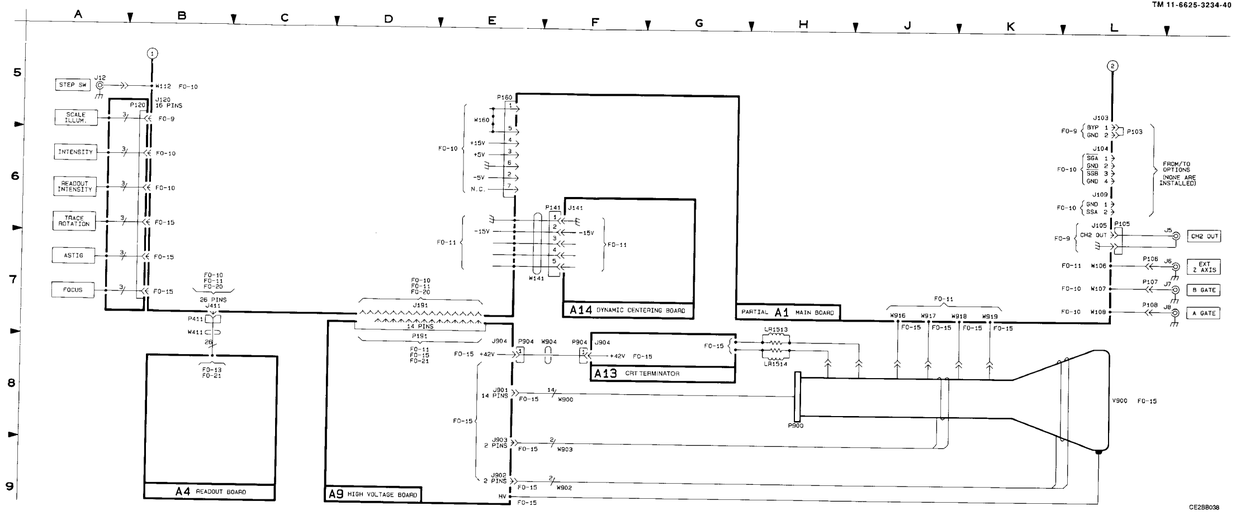
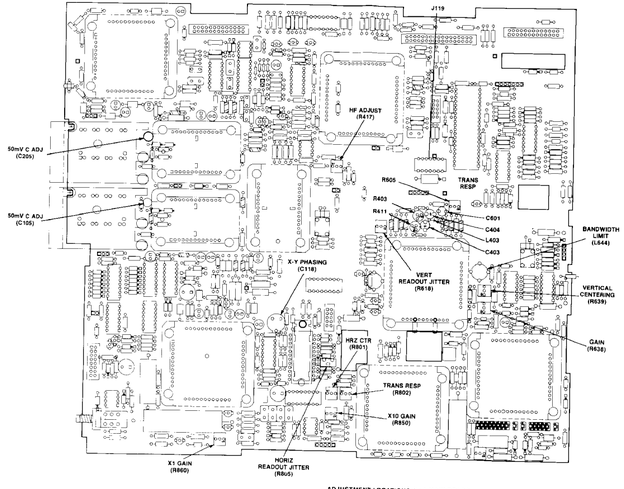
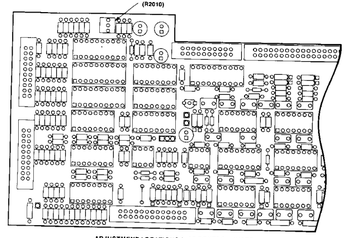


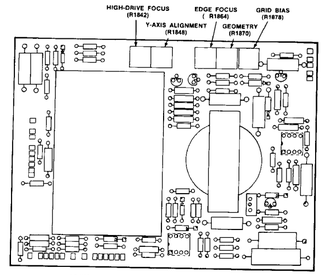
Figure FO-22. Interconnect and Chassis Parts Schematic (Sheet 2 of 2).



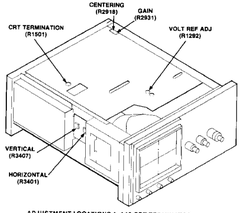
ADJUSTMENT LOCATIONS 4: A1 MAIN BOARD



ADJUSTMENT LOCATIONS 3: A5 CONTROL BOARD



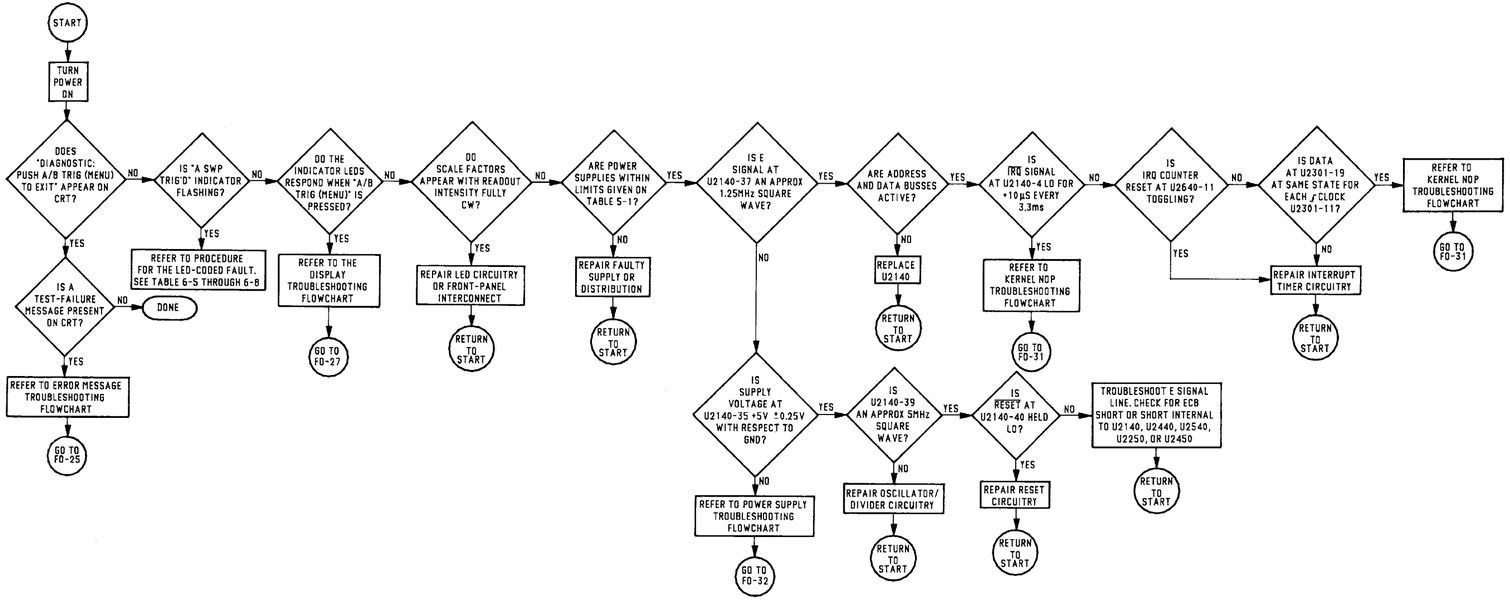
ADJUSTMENT LOCATIONS 2: A9 HIGH VOLTAGE BOARD



ADJUSTMENT LOCATIONS 1: A13 CRT TERMINATOR, A14 DYNAMIC CENTERING BOARD and A2 REGULATOR BOARD.

CE2B8039

Figure FO-23. Adjustment Locations 1, 2, 3, & 4. FP-77/(FP-78 blank)



CE2BB040

Figure FO-24. Preliminary Troubleshooting Flowchart.
FP-79/(FP-80 blank)

Probable Causes of Trigger Error Messages

Test 05 Fail	Probable Causes of Failure
01	a. Line Signal b. U500 (Trigger) c. U650 (Trigger Status Data to Processor)
02 or 22	a. Line Signal b. U500 (Trigger)
04 or 44	a. U2634A, U2235, or U500 b. Line Signal

NOTE

Refer to Maintenance Section, for detailed information on Diagnostic Routines.

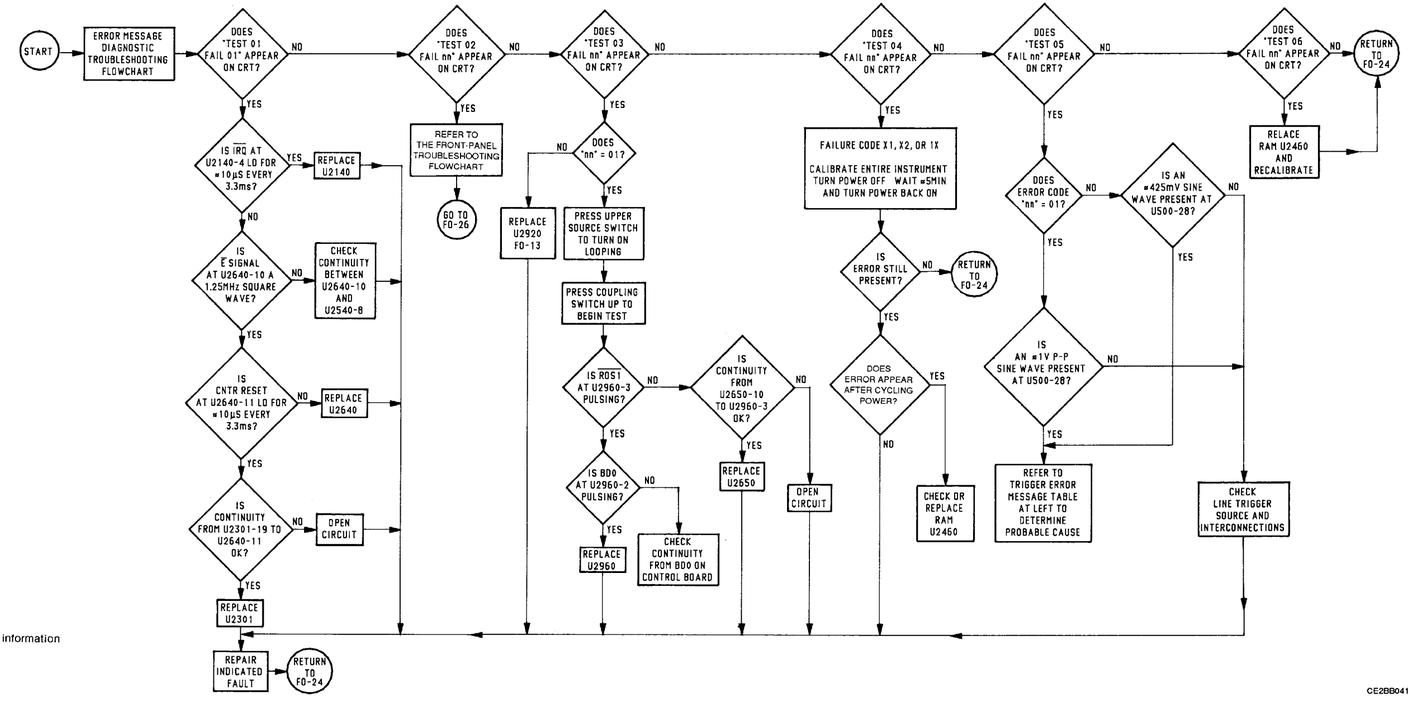


Figure FO-25. Error Message Diagnostic Troubleshooting Flowchart.
FP-81/(FP-82 blank)

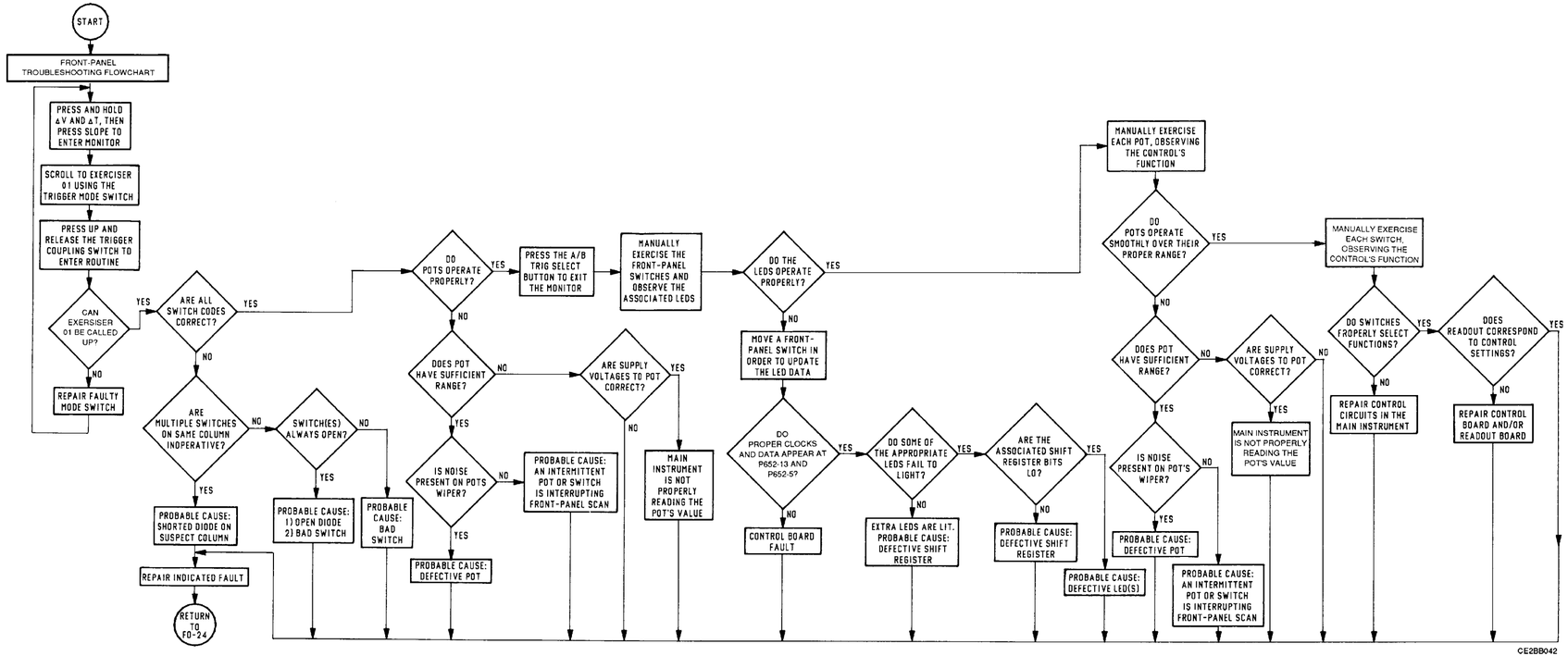
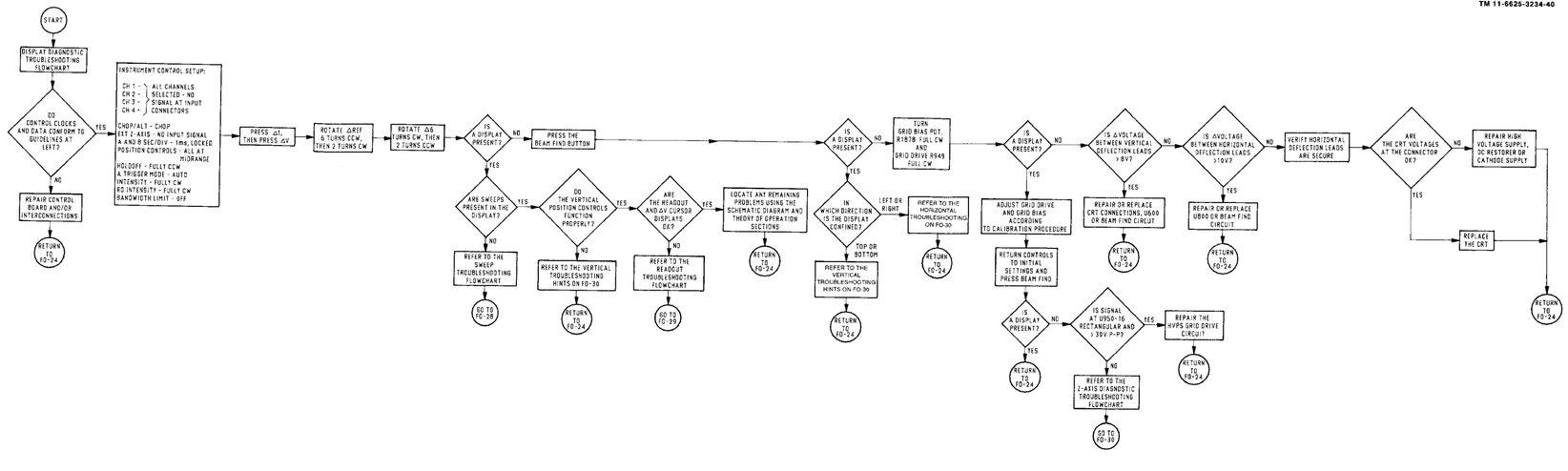


Figure FO-26. Front Panel Troubleshooting Flowchart.
FP-83/(FP-84 blank)

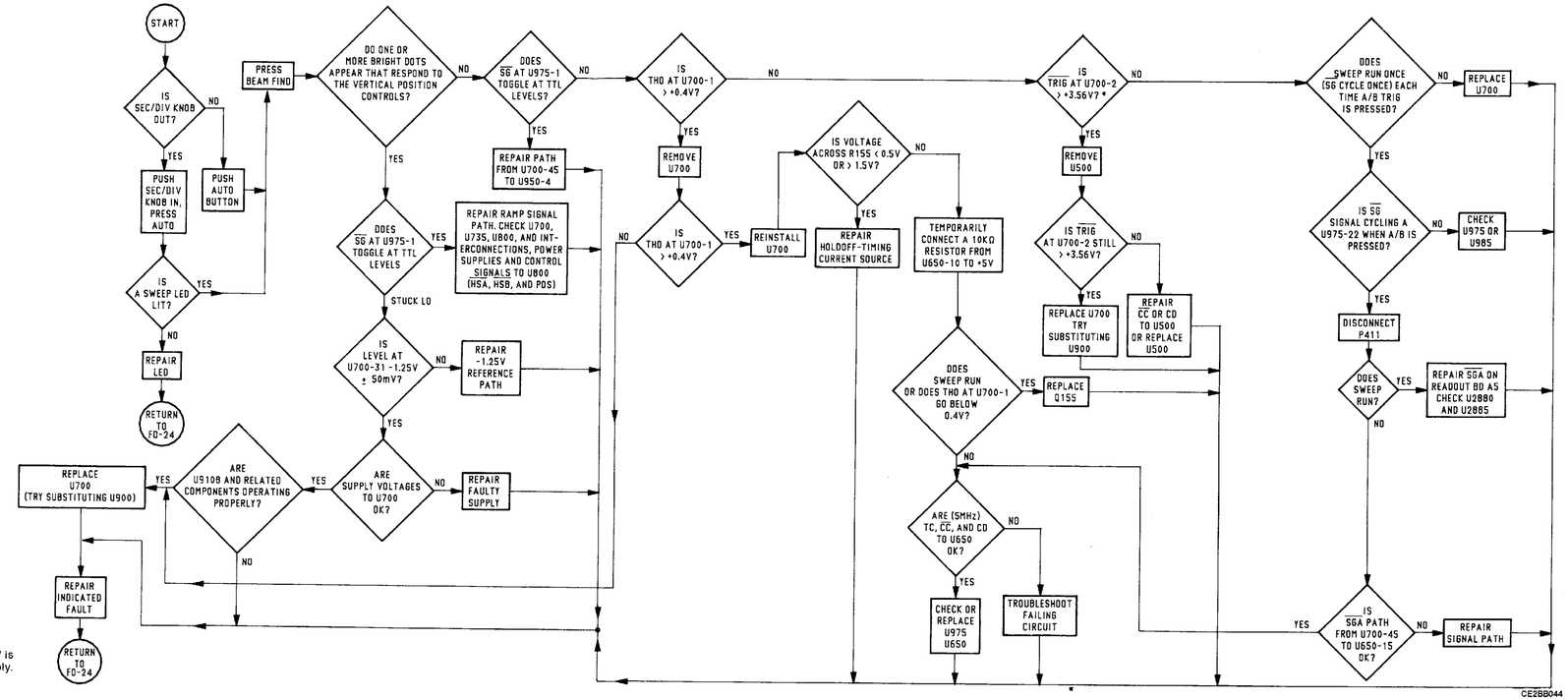


NOTE

An asterisk (*) in this flowchart indicates a voltage measured using a test oscilloscope and 10X probes while holding in the BEAM FIND button.

CE29B043

Figure FO-27. Display Diagnostic Troubleshooting Flowchart.



NOTE

An asterisk (*) in this flowchart indicates +3.56 V is measured as -1.44 V with respect to the +5 V Supply.

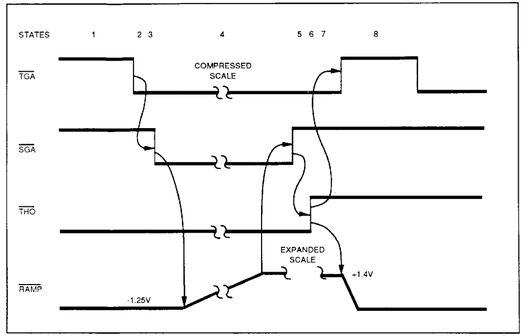
Figure FO-28. Sweep Troubleshooting Flowchart (Sheet 1 of 2).
FP-87/(FP-88 blank)

Sweep Troubleshooting

STATE	PROBABLE CAUSES
1	Trigger signal or Trigger circuit.
2	$\overline{\text{AUXTRIG}}$ input, U700 or U900 pin 3, HI (>3.56 V), or Sweep circuit.
3	Timing current supply to ITREF input (U700 or U900 pin 24). Current mirror comprising U910 and the IT, ITRR, ITF, and ITR terminals (U700 or U900 pins 12-15). Sweep circuit, U700 or U900.
4	(Floating between −1.25 V and +1.4 V): See state 3.
5	Sweep circuit, U700 or U900. Temporarily exchange U700 and U900.
6	**NOTE:** In state 6, the sweep will recover to −1.25 V, even though THO (or $\overline{\text{DG-THOB}}$) remains LO. A Sweep: $\overline{\text{SGA}}$ path to U650, U650 response to $\overline{\text{SGA}}$, or THO path. B Sweep: $\overline{\text{DG}}$ path or generation in U700 (if B Sweep stuck in state 6).
7	**NOTE:** If trigger is in a free-run mode, state 8 follows state 6 immediately. Trigger circuit response to THOA or THOB.
8	THO timer: circuits between U165C and U650 inclusive (A Sweep). Normal rest state for B Sweep.

NOTE

When sweep free runs, as in AUTO MODE, STATES 1 and 7 are omitted and $\overline{\text{TGA}}$ remains LO in state 8.



The following state table, and timing diagram show the sequence of events from initiation through the execution of the A sweep. They can be used to troubleshoot a non-operable sweep. If no sweep is present, use an oscilloscope to observe control signals $\overline{\text{TGA}}$, $\overline{\text{TGB}}$, $\overline{\text{SGA}}$, $\overline{\text{SGB}}$, THO, $\overline{\text{DG}}$, and the A or B SWEEP ramp. Note the condition of the signals and refer to the state table to determine where the sweep is stuck. Then, refer to the probable cause table. Probable cause is listed by sweep state.

Sweep States

State	Action	Nominal Duration at 2 µs/div	$\overline{\text{TGA}}$ or $\overline{\text{TGB}}$ (not Trigger Gate) U500-18 and U500-42	$\overline{\text{SGA}}$ or $\overline{\text{SGB}}$ (not Sweep Gate) U650-15 and U650-14	THO or $\overline{\text{DG}}$ (A or B Trigger Holdoff) U650-13	RAMP U735-9
0	Initialize (only at front-panel change).			HI with THO	HI for 5 ms (Last of three pulses in 240 ms sequence)	
1	Wait for Trigger	Indefinite	HI	HI	LO	−1.25 V
2	Initiate Sweep Gate	< 20 ns	LO	HI	LO	1.25 V
3	Initiate Ramp Up	< 200 ns	LO	LO	LO	1.25 V
4	Run Ramp Up	22 µs	LO	LO	LO	Slew to + 1.36 V
5	Terminate Sweep Gate	< 2 µs	LO	LO	LO	+ 1.36 V
6	Initiate Holdoff	< 100 ns	LO	HI	LO	+ 1.36 V
7	Reset Trigger	< 10 ns	LO	HI	HI	+ 1.36 V
8	RESET SWEEP (Then return to state 1 or 2.)	2 µs	HI	HI	HI	Slew to −1.25 V

CE2BB045

Figure FO-28. Sweep Troubleshooting Flowchart (Sheet 2 of 2).

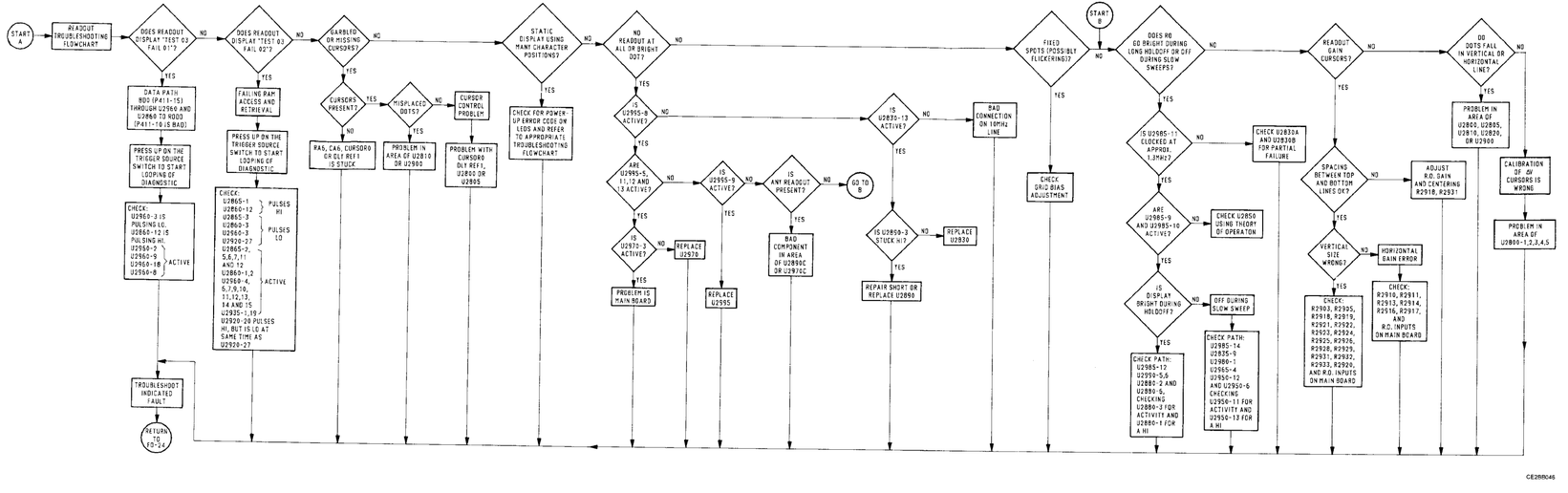


Figure FO-29. Readout Troubleshooting Flowchart.

VERTICAL TROUBLESHOOTING HINTS

With no signals connected to the four Vertical input connectors, select each channel for display and rotate its POSITION control through its entire range.

1. If one or more of the four Vertical channels properly responds to its POSITION control, the problem is in the preamp circuit of the defective channel or in the Vertical Channel Switch circuit. If none of them responds properly, the Channel Switch, Delay Line, Vertical Output Amplifier and the Hybrid power supplies should be suspect.

2. Check the range of the input positioning voltage for a faulty channel. Channel 1 and 2 positioning inputs (pin 17 or U100 and U200) should vary between -4.6 volts and -5.26 volts. Channel 3 and 4 positioning voltages (to pins 29 and 32 of U300) should vary between ground potential and -5 volts.

3. If the faulty channel's input positioning range is okay, check the positioning effect at the outputs of the Channel Switch (connect a DMM across the Delay Line). When the CH 1 or CH 2 POSITION control is rotated through its range, the DMM reading should vary from approximately +700 mV to -700 mV; for Channels 3 and 4, it should vary approximately from +350 mV to -350 mV.

4. If the range at the Delay Line is okay, connect the DMM across the vertical outputs to the CRT (between L626 and L633). Range should vary approximately from +11.5 volts to -11.5 volts as the POSITION control of the displayed channel is rotated through its range.

5. If the output voltages to the CRT are okay, check that the voltage between the CRT termination resistors (LR1513 and LR1514) varies approximately from +11.5 volts to -11.5 volts as the POSITION control is rotated through its range.

See the "Theory of Operation" for further information.

HORIZONTAL TROUBLESHOOTING HINTS

If possible, set the instrument's TRIGGER controls so the TRIG'D LED remains illuminated (triggered sweep is running). Setting the TRIGGER MODE to AUTO LVL will usually do this.

1. Check that the horizontal positioning input (pin 22 of U800) of Output IC varies approximately from -1.25 volts to +1.25 volts as the Horizontal POSITION control is rotated through its range. If it does not, repair the position circuit.

2. Check that the A Sweep Ramp at pin 18 of U800 is ramping from -1.25 volts to +1.25 volts. If it is not, check the buffer amplifier made up of U735 and its associated components. When operating properly, the voltages and waveforms at pins 3 and 9 of U735 will be nearly identical.

3. Check for proper select signals (TTL levels) at the $\overline{HSA}$ and $\overline{HSB}$ inputs of U800.

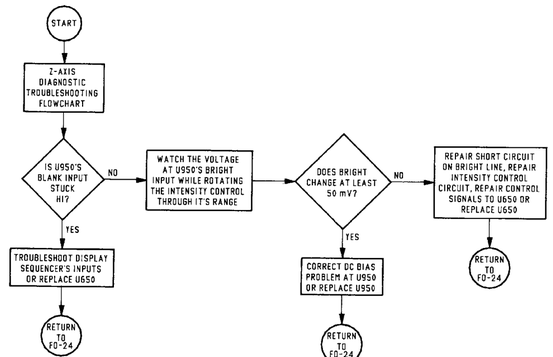
4. Check the power supply levels to U800.

5. Check the voltage on pin 6 of U800. If it is not >+80 volts, check the +OUT and -OUT pins for shorts.

See the "Theory of Operation" for further information.

HOW TO VERIFY THE CONTROL DATA AND CONTROL CLOCK LINES

1. Power-up the instrument under test.
2. Move the NORM/DIAG jumper (P503 on the scope under test) to the DIAG position. This forces the processor into a NOP loop and exercises the Address Decode circuitry.
3. Trigger the test scope on the DAC MSB CLK at pin 14 of U2550 (on the Control Board). Use NORM TRIGGER and -SLOPE. Set TRIGGER LEVEL to +1.4 volts.
4. Verify that four bursts of clocks appear at 52 ms to 53 ms intervals.
5. Check that each of the outputs of U2550 has similar signals present (fig. FO-3).
6. Check that each output of U2660 (fig. FO-3) has four bursts of two pulses each occurring at 52 ms to 53 ms intervals.
7. Turn instrument power off and restore P503 to the NORM position.
8. Power up the instrument again.
9. Set the instrument's CH 1 and CH 2 input coupling to 1 MΩ DC and TRIGGER MODE to NORM.
10. Hold in the upper TRIGGER COUPLING switch.
11. Trigger the test oscilloscope on the DISP SEQ CLK (pin 8 of U2660 or pin 10 of P512).
12. With the test scope still triggered on the DISP SEQ CLK, verify that the ATTN STRB at pin 2 of P512 is eight positive-going strobes.
13. Verify that the control data on pin 1 of P512 is toggling at TTL levels.



CE2BB047

Figure FO-30. Z-Axis Diagnostic Troubleshooting Flowchart and Troubleshooting Hints.

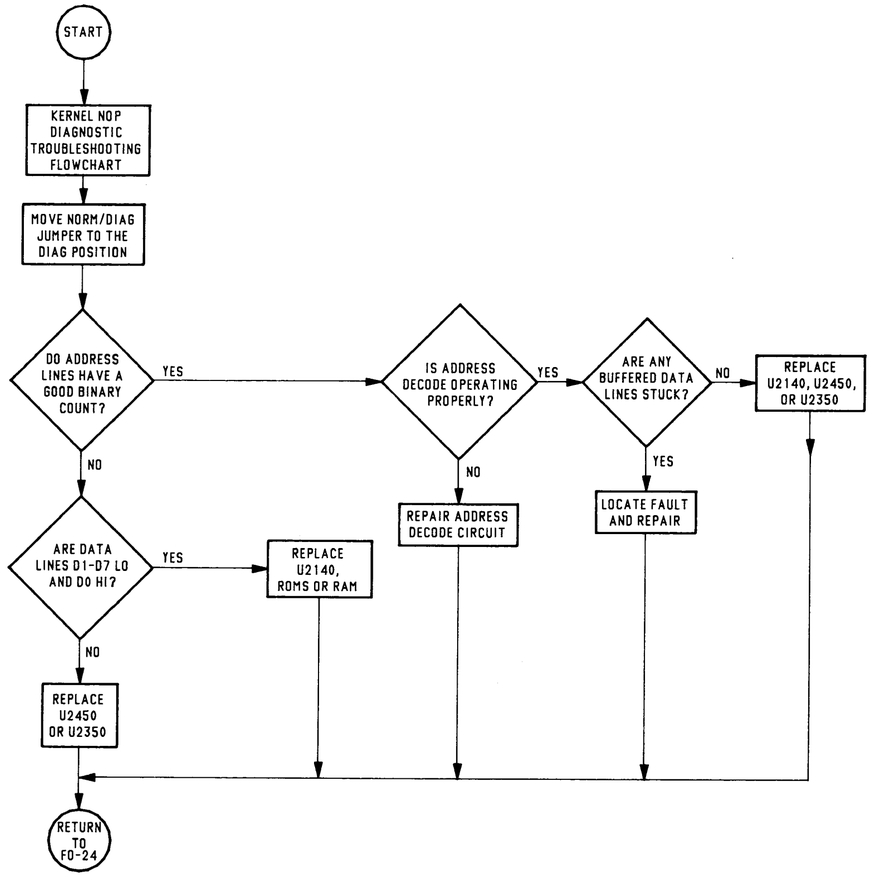


Figure FO-31. Kernel NOP Diagnostic Troubleshooting Flowchart.

Power Supply Voltage Tolerances		
Power Supply	**Test Point (+ Lead)**	**Reading**
+10 V	J119-4	+9.99 to +10.01
+87 V	J119-8	+85.26 to +88.74
+42.4 V	J119-9	+41.55 to +43.25
+15 V	J119-6	+14.775 to +15.225
Digital +5 V	J119-2	+4.85 to +5.15
Analog +5 V	J119-12	+4.925 to +5.075
-5 V	J119-5	-4.965 to -5.035
-8 V	J119-11	-7.88 to -8.12
-15 V	J119-1	-14.775 to -15.225

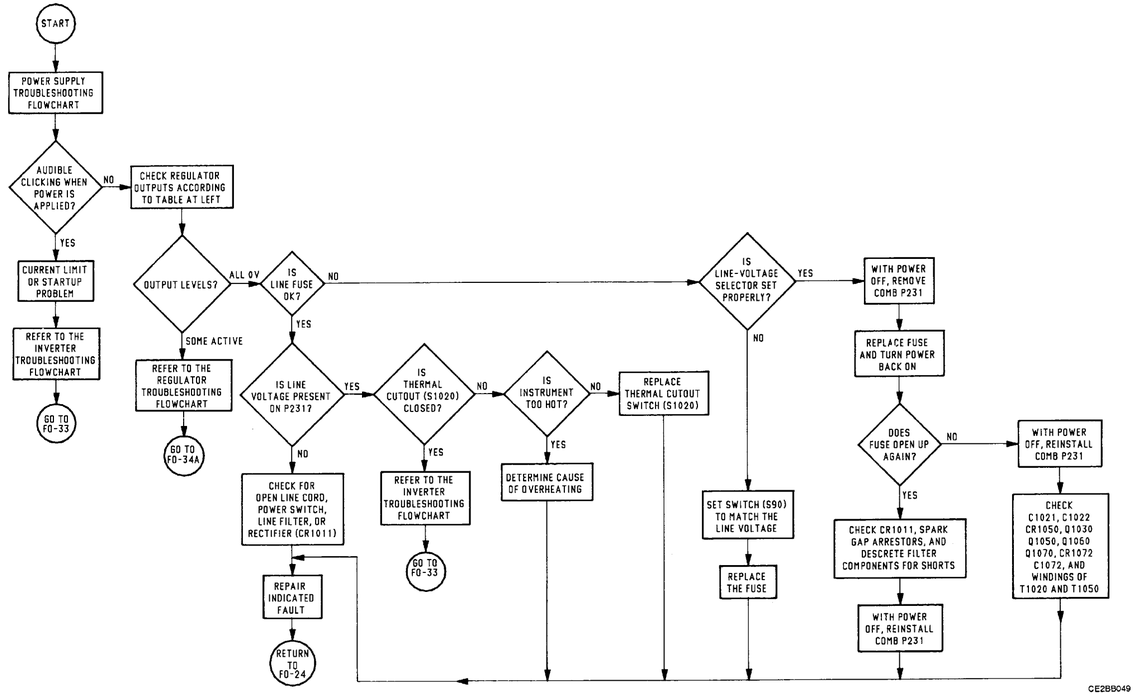
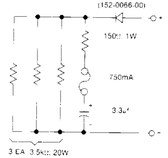


Figure FO-32. Power Supply Troubleshooting Flowchart.
FP-97/(FP-98 blank)

Primary Test Load

The test load illustrated below may be used to test the operation of the inverter with the output transformer (T1060) and drive transistors (Q1060 and Q1070) disconnected. Connect the + lead of the load to the lifted end of W1060 (see procedure in flowchart at right) and the - lead to the sources of Q1060 and Q1070. A schematic diagram is given below.

PRIMARY TEST LOAD



+5 V_D Test Load

Some load is required for the inverter to run. When the Power Supply module is removed from the instrument or when the Regulator Board is disconnected from the Inverter Board's output, the test load described below may be used to check the operation of the inverter.

NOTE

- Each of the Regulators requires a load to regulate properly; this loading is not provided by the +5 V_D load.
- **TEST LOAD.** Connect a 2 Ω, 25 watt resistor from the +5 V_D pins of J303 and J232 (on the Inverter Board) to ground.

NOTE

By using two PS503s, the inverter may be checked without using the line power or line-isolation transformer.

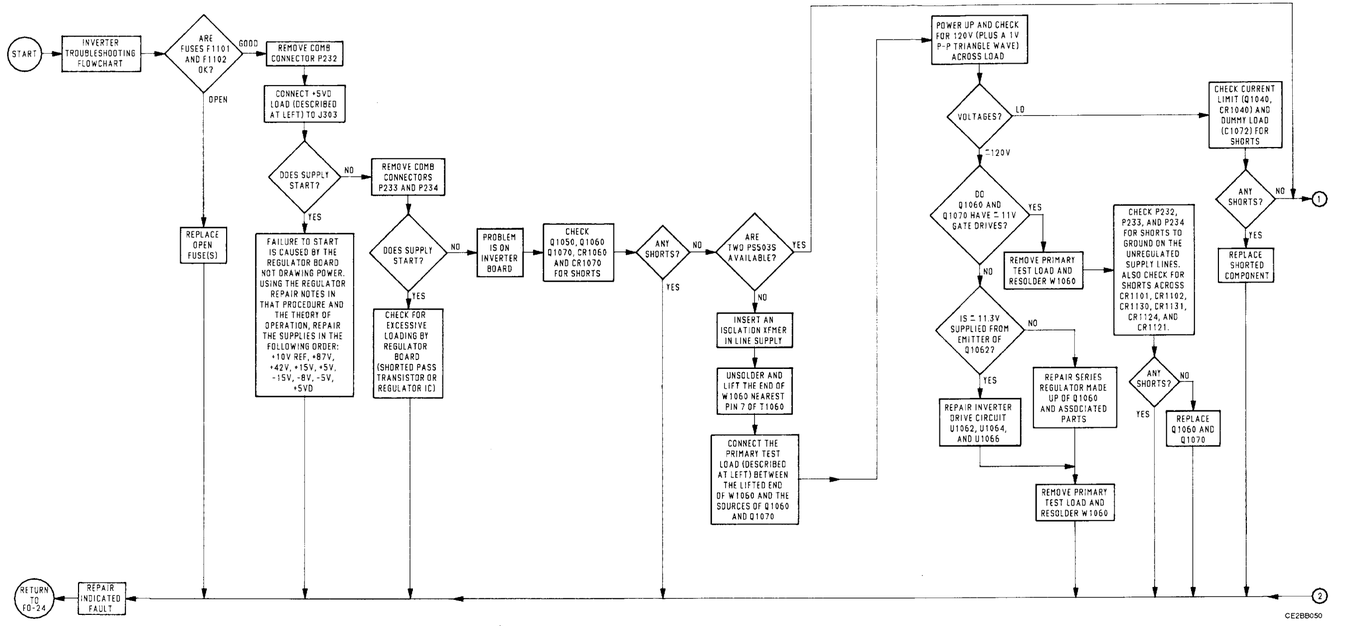


Figure FO-33. Inverter Troubleshooting Flowchart (Sheet 1 of 2).

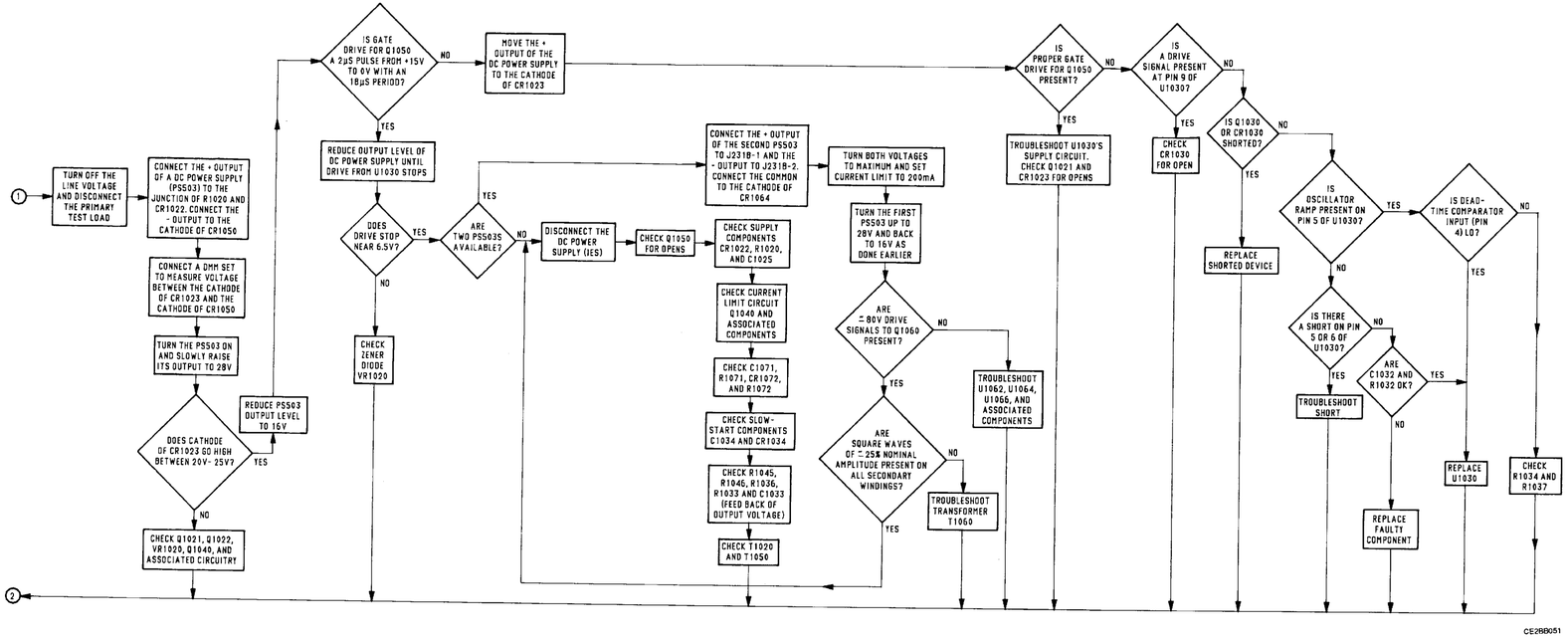
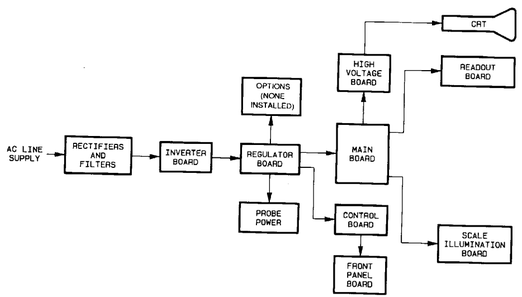


Figure FO-33. Inverter Troubleshooting Flowchart (Sheet 2 of 2).

Regulator Repair Notes

Hints for troubleshooting a faulty supply Regulator:

1. First verify that the + 10 V_{REF} level is correctly adjusted; if it is not, do so (see Adjustment Procedure in Section 5).
2. Regulator output is high:
   a. Is the output loaded? All Regulators (except + 10 V_{REF}) require some load to regulate, the lower voltage supplies requiring greater loads. The Regulators between + 15 V and - 15 V may be loaded using 100 Ω resistors of the proper power ratings.
   b. Check for a short-circuited series-pass device.
   c. Check feedback through to voltage-sense comparator.
3. Regulator output is low:
   a. Check for excessive loading using the Load Isolation diagram below and the Interconnection Schematic (fig. FO-22).
   b. The operation of the supply Regulators is interdependent. If a supply is out of regulation, verify that the supply of next greater magnitude is operating properly. Repair faulty Regulators in the following order: + 87 V, + 42 V, + 15 V, + 5 V, - 15 V, - 8 V, and then - 5 V.
   c. Verify that the current-limit circuit is not activated.
   d. Check drive to series-pass device and verify that the device is not open circuited.
   e. Check feedback through the voltage-sense comparator.
   f. If supply goes low only when fully loaded, suspect an open-circuit diode in the associated rectifier circuit.



NOTE

Adjustment or repair of any power supply regulator necessitates a complete recalibration of the instrument.

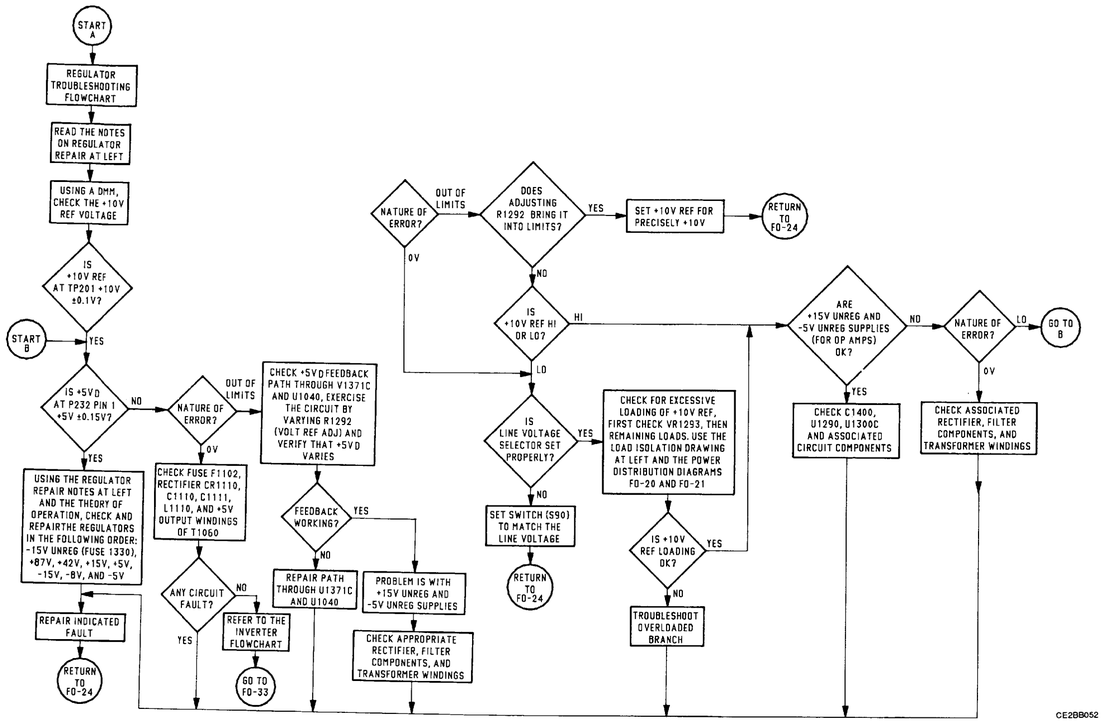
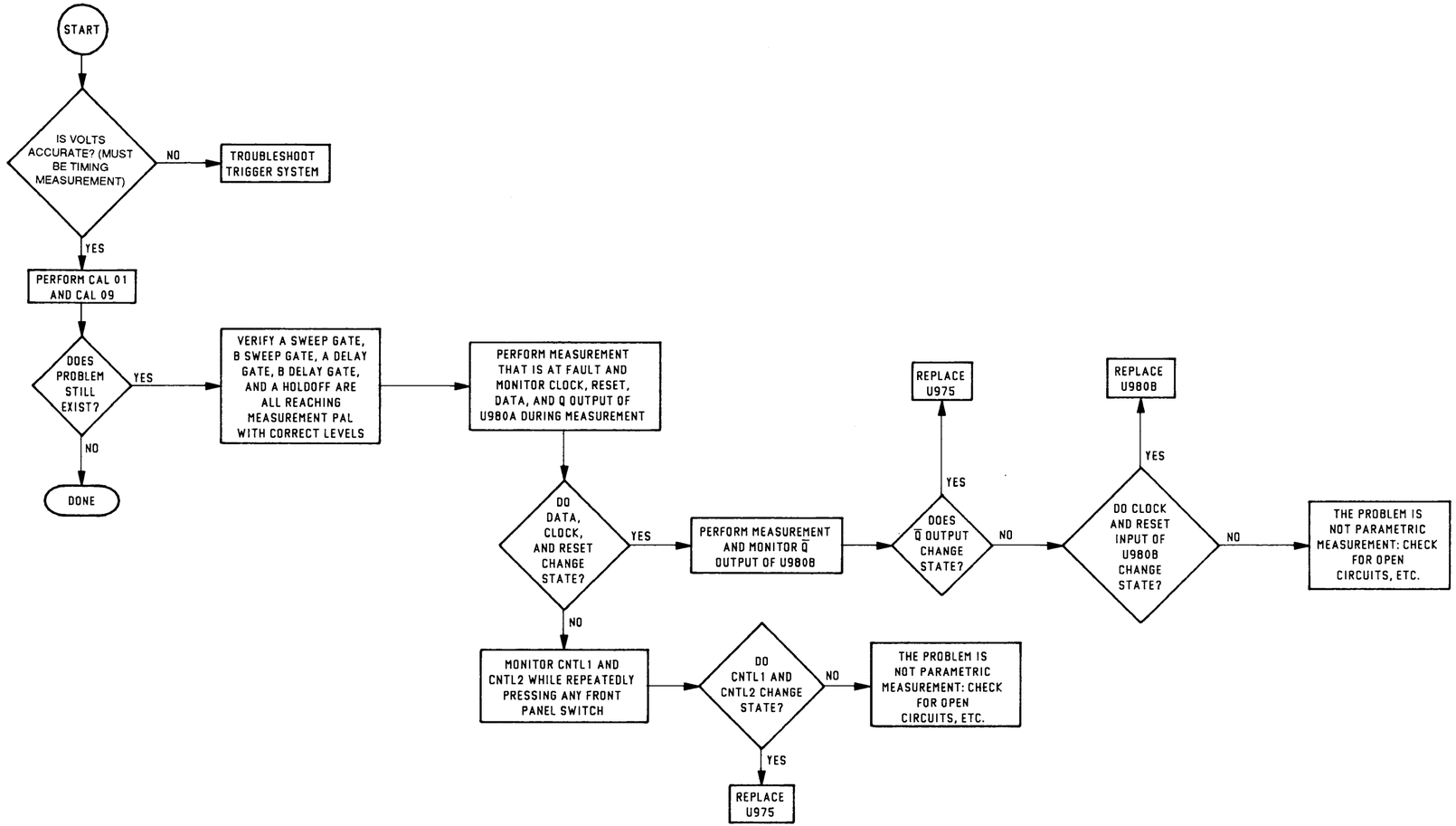


Figure FO-34. Regulator Troubleshooting Flowchart.



CE2BB053

Figure FO-35. Parametric Measurement Troubleshooting Flowchart.

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3-10	3-3		3-1
5-6	5-8		
		F03	

IN THIS SPACE TELL WHAT IS WRONG AND WHAT SHOULD BE DONE ABOUT IT:

Recommend that the installation antenna alignment procedure be changed throughout to specify a 2^{o} IFF antenna lag rather than 1^{o}.

REASON: Experience has shown that with only a 1^{o} lag, the antenna servo system is too sensitive to wind gusting in excess of 25 knots, and has a tendency to rapidly accelerate and decelerate as it hunts, causing strain to the drive train. Hunting is minimized by adjusting the lag to 2^{o} without degradation of operation.

Item 5, Function column. Change "2 db" to "3db."

REASON: The adjustment procedure for the TRANS POWER FAULT indicator calls for a 3 db (500 watts) adjustment to light the TRANS POWER FAULT indicator.

Add new step f.1 to read, "Replace cover plate removed in step e.1, above."

REASON: To replace the cover plate.

Zone C 3. On J1-2, change "+24 VDC to "+5 VDC."

REASON: This is the output line of the 5 VDC power supply. +24 VDC is the input voltage.

SAMPLE

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I. M. DeSpiritof

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